

8-Bit CMOS Microcontrollers

Devices included in this data sheet:

- PIC16C61
- PIC16C62
- PIC16C62A
- PIC16CR62
- PIC16C63
- PIC16CR63
- PIC16C64
- PIC16C67

• PIC16C64A

• PIC16CR64

PIC16C65A

• PIC16C65

PIC16C6X Microcontroller Core Features:

- High performance RISC CPU
- · Only 35 single word instructions to learn
- All single cycle instructions except for program branches which are two-cycle
- Operating speed: DC 20 MHz clock input DC - 200 ns instruction cycle
- Interrupt capability
- · Eight level deep hardware stack
- · Direct, indirect, and relative addressing modes
- · Power-on Reset (POR)
- · Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation
- Programmable code-protection
- · Power saving SLEEP mode
- · Selectable oscillator options

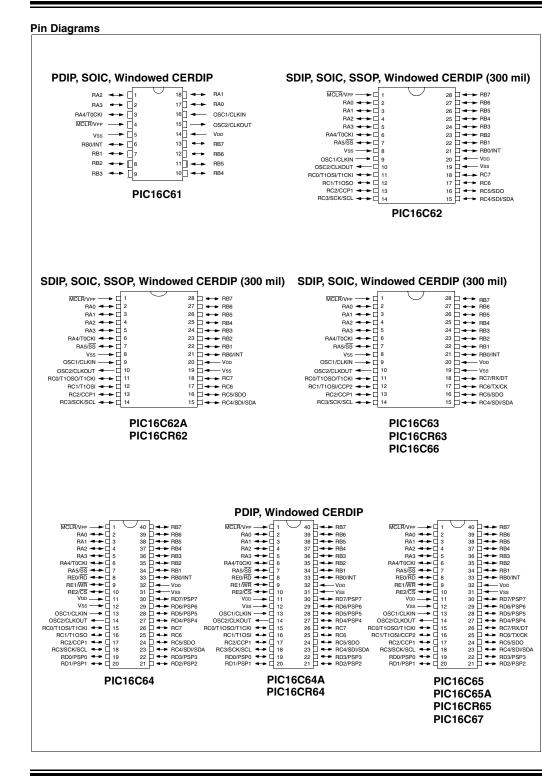
- Low-power, high-speed CMOS EPROM/ROM technology
- · Fully static design
- Wide operating voltage range: 2.5V to 6.0V
- · Commercial, Industrial, and Extended
- temperature ranges
- · Low-power consumption:
 - < 2 mA @ 5V, 4 MHz
 - \bullet 15 μA typical @ 3V, 32 kHz
 - < 1 μA typical standby current

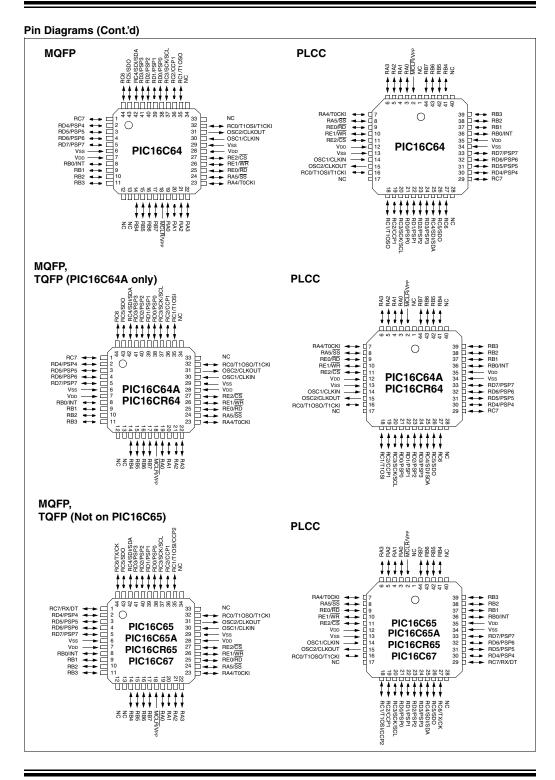
PIC16C6X Peripheral Features:

- Timer0: 8-bit timer/counter with 8-bit prescaler
- Timer1: 16-bit timer/counter with prescaler, can be incremented during sleep via external crystal/clock
- Timer2: 8-bit timer/counter with 8-bit period register, prescaler and postscaler
- Capture/Compare/PWM (CCP) module(s)
- Capture is 16-bit, max resolution is 12.5 ns, Compare is 16-bit, max resolution is 200 ns, PWM max resolution is 10-bit.
- Synchronous Serial Port (SSP) with SPI and I²C[™]
- Universal Synchronous Asynchronous Receiver Transmitter (USART/SCI)
- Parallel Slave Port (PSP) 8-bits wide, with external \overline{RD} , \overline{WR} and \overline{CS} controls
- Brown-out detection circuitry for Brown-out Reset (BOR)

PIC16C6X Features	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
Program Memory (EPROM) x 14	1K	2K	2K	-	4K	—	2K	2K	—	4K	4K	-	8K	8K
(ROM) x 14	—	_	—	2K	—	4K	_	—	2K	_	_	4K		_
Data Memory (Bytes) x 8	36	128	128	128	192	192	128	128	128	192	192	192	368	368
I/O Pins	13	22	22	22	22	22	33	33	33	33	33	33	22	33
Parallel Slave Port	-	—	—	—	—	—	Yes	Yes	Yes	Yes	Yes	Yes	—	Yes
Capture/Compare/PWM Module(s)	_	1	1	1	2	2	1	1	1	2	2	2	2	2
Timer Modules	1	3	3	3	3	3	3	3	3	3	3	3	3	3
Serial Communication	_	SPI/ I ² C	SPI/ I ² C	SPI/ I ² C	SPI/I ² C, USART	SPI/I ² C, USART	SPI/ I ² C	SPI/ I ² C	SPI/ I ² C	SPI/I ² C, USART	SPI/I ² C, USART	,	SPI/I ² C, USART	SPI/I ² C, USART
In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Brown-out Reset	—	—	Yes	Yes	Yes	Yes	—	Yes	Yes	—	Yes	Yes	Yes	Yes
Interrupt Sources	3	7	7	7	10	10	8	8	8	11	11	11	10	11
Sink/Source Current (mA)	25/20	25/25	25/25	25/25	25/25	25/25	25/25	25/25	25/25	25/25	25/25	25/25	25/25	25/25

- PIC16CR65 • PIC16C66





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For register and module descriptions in this data sheet, device legends show which devices apply to those sections. For example, the legend below shows that some features of only the PIC16C62A, PIC16CR62, PIC16C63, PIC16C64A, PIC16CR64, and PIC16C65A are described in this section.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

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1.0 GENERAL DESCRIPTION

The PIC16CXX is a family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers.

All PIC16/17 microcontrollers employ an advanced RISC architecture. The PIC16CXX microcontroller family has enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with separate 8-bit wide data. The two stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16CXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The **PIC16C61** device has 36 bytes of RAM and 13 I/O pins. In addition a timer/counter is available.

The **PIC16C62/62A/R62** devices have 128 bytes of RAM and 22 I/O pins. In addition, several peripheral features are available, including: three timer/counters, one Capture/Compare/PWM module and one serial port. The Synchronous Serial Port can be configured as either a 3-wire Serial Peripheral Interface (SPI[™]) or the two-wire Inter-Integrated Circuit (I²C) bus.

The **PIC16C63/R63** devices have 192 bytes of RAM, while the **PIC16C66** has 368 bytes. All three devices have 22 I/O pins. In addition, several peripheral features are available, including: three timer/counters, two Capture/Compare/PWM modules and two serial ports. The Synchronous Serial Port can be configured as either a 3-wire Serial Peripheral Interface (SPI) or the two-wire Inter-Integrated Circuit (I^2C) bus. The Universal Synchronous Asynchronous Receiver Transmitter (USART) is also know as a Serial Communications Interface or SCI.

The **PIC16C64/64A/R64** devices have 128 bytes of RAM and 33 I/O pins. In addition, several peripheral features are available, including: three timer/counters, one Capture/Compare/PWM module and one serial port. The Synchronous Serial Port can be configured as either a 3-wire Serial Peripheral Interface (SPI) or the two-wire Inter-Integrated Circuit (I²C) bus. An 8-bit Parallel Slave Port is also provided.

The **PIC16C65/65A/R65** devices have 192 bytes of RAM, while the **PIC16C67** has 368 bytes. All four devices have 33 I/O pins. In addition, several peripheral features are available, including: three timer/counters, two Capture/Compare/PWM modules and two serial ports. The Synchronous Serial Port can be configured as either a 3-wire Serial Peripheral Interface (SPI) or the two-wire Inter-Integrated Circuit (I²C) bus. The Universal Synchronous Asynchronous Receiver Transmit-

ter (USART) is also known as a Serial Communications Interface or SCI. An 8-bit Parallel Slave Port is also provided.

The PIC16C6X device family has special features to reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) mode offers a power saving mode. The user can wake the chip from SLEEP through several external and internal interrupts, and resets.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lockup.

A UV erasable CERDIP packaged version is ideal for code development, while the cost-effective One-Time-Programmable (OTP) version is suitable for production in any volume.

The PIC16C6X family fits perfectly in applications ranging from high-speed automotive and appliance control to low-power remote sensors, keyboards and telecom processors. The EPROM technology makes customization of application programs (transmitter codes, motor speeds, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low-cost, low-power, high performance, ease-of-use, and I/O flexibility make the PIC16C6X very versatile even in areas where no microcontroller use has been considered before (e.g. timer functions, serial communication, capture and compare, PWM functions, and co-processor applications).

1.1 Family and Upward Compatibility

Those users familiar with the PIC16C5X family of microcontrollers will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for PIC16C5X can be easily ported to PIC16CXX family of devices (Appendix B).

1.2 Development Support

PIC16C6X devices are supported by the complete line of Microchip Development tools.

Please refer to Section 15.0 for more details about Microchip's development tools.

		PIC16C61	PIC16C62A	PIC16CR62	PIC16C63	PIC16CR63
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20
	EPROM Program Memory (x14 words)	1K	2К	—	4K	_
lemory	ROM Program Memory (x14 words)	—		2К	—	4K
	Data Memory (bytes)	36	128	128	192	192
	Timer Module(s)	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
eripherals	Capture/Compare/ PWM Module(s)	—	1	1	2	2
	Serial Port(s) (SPI/I ² C, USART)	—	SPI/I ² C	SPI/I ² C	SPI/I ² C, USART	SPI/I ² C USART
	Parallel Slave Port	—	_	_	—	_
	Interrupt Sources	3	7	7	10	10
	I/O Pins	13	22	22	22	22
	Voltage Range (Volts)	3.0-6.0	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
eatures	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	—	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SO	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC	28-pin SDIP, SOIC

TABLE 1-1: PIC16C6X FAMILY OF DEVICES

		PIC16C64A	PIC16CR64	PIC16C65A	PIC16CR65	PIC16C66	PIC16C67
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
	EPROM Program Memory (x14 words)	2К	_	4K	_	8K	8K
Memory	ROM Program Memory (x14 words)	—	2К		4K	_	
	Data Memory (bytes)	128	128	192	192	368	368
	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
Peripherals	Capture/Compare/PWM Mod- ule(s)	1	1	2	2	2	2
	Serial Port(s) (SPI/I ² C, USART)	SPI/I ² C	SPI/I ² C	SPI/I ² C, USART	SPI/I ² C, USART	SPI/I ² C, USART	SPI/I ² C, USART
	Parallel Slave Port	Yes	Yes	Yes	Yes	—	Yes
	Interrupt Sources	8	8	11	11	10	11
	I/O Pins	33	33	33	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
eatures	Brown-out Reset	Yes	Yes	Yes	Yes	Yes	Yes
	Packages		40-pin DIP; 44-pin PLCC, MQFP, TQFP		40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C6X Family devices use serial programming with clock pin RB6 and data pin RB7.

2.0 PIC16C6X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C6X Product Identification System section at the end of this data sheet. When placing orders, please use that page of the data sheet to specify the correct part number.

For the PIC16C6X family of devices, there are four device "types" as indicated in the device number:

- 1. **C**, as in PIC16**C**64. These devices have EPROM type memory and operate over the standard voltage range.
- 2. LC, as in PIC16LC64. These devices have EPROM type memory and operate over an extended voltage range.
- 3. **CR**, as in PIC16**CR**64. These devices have ROM program memory and operate over the standard voltage range.
- 4. LCR, as in PIC16LCR64. These devices have ROM program memory and operate over an extended voltage range.

2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the oscillator modes.

Microchip's PICSTART[®] Plus and PRO MATE[®] II programmers both support programming of the PIC16C6X.

2.2 <u>One-Time-Programmable (OTP)</u> <u>Devices</u>

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must also be programmed.

2.3 <u>Quick-Turnaround-Production (QTP)</u> <u>Devices</u>

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

2.4 <u>Serialized Quick-Turnaround</u> Production (SQTPSM) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random, or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password, or ID number.

ROM devices do not allow serialization information in the program memory space. The user may have this information programmed in the data memory space.

For information on submitting ROM code, please contact your regional sales office.

2.5 Read Only Memory (ROM) Devices

Microchip offers masked ROM versions of several of the highest volume parts, thus giving customers a low cost option for high volume, mature products.

For information on submitting ROM code, please contact your regional sales office.

NOTES:

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3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16CXX family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16CXX uses a Harvard architecture, in which, program and data are accessed from separate memories using separate buses. This improves bandwidth over traditional von Neumann architecture where program and data may be fetched from the same memory using the same bus. Separating program and data busses further allows instructions to be sized differently than 8-bit wide data words. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A twostage pipeline overlaps fetch and execution of instructions (Example 3-1). Consequently, all instructions execute in a single cycle (200 ns @ 20 MHz) except for program branches.

The PIC16C61 addresses 1K x 14 of program memory. The PIC16C62/62A/R62/64/64A/R64 address 2K x 14 of program memory, and the PIC16C63/R63/65/65A/R65 devices address 4K x 14 of program memory. The PIC16C66/67 address 8K x 14 program memory. All program memory is internal.

The PIC16CXX can directly or indirectly address its register files or data memory. All special function registers including the program counter are mapped in the data memory. The PIC16CXX has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of "special optimal situations" makes programming with the PIC16CXX simple yet efficient, thus significantly reducing the learning curve. The PIC16CXX device contains an 8-bit ALU and working register (W). The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift, and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register), the other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending upon the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. Bits C and DC operate as a borrow and digit borrow out bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

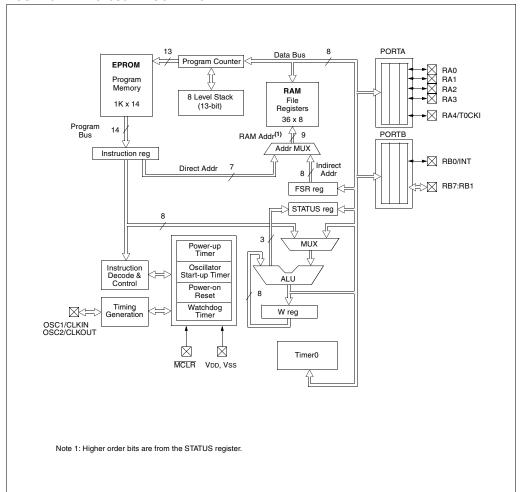


FIGURE 3-1: PIC16C61 BLOCK DIAGRAM

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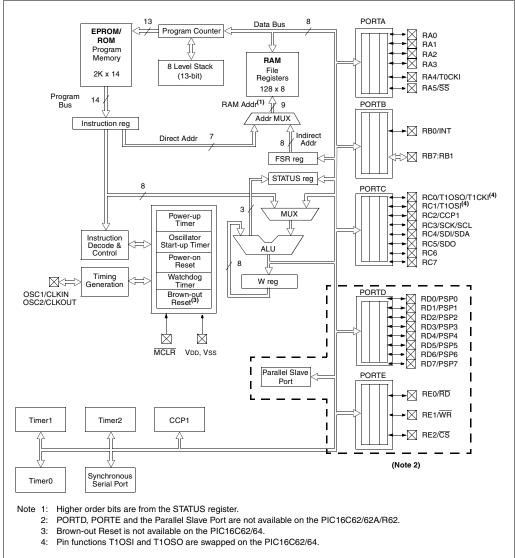


FIGURE 3-2: PIC16C62/62A/R62/64/64A/R64 BLOCK DIAGRAM

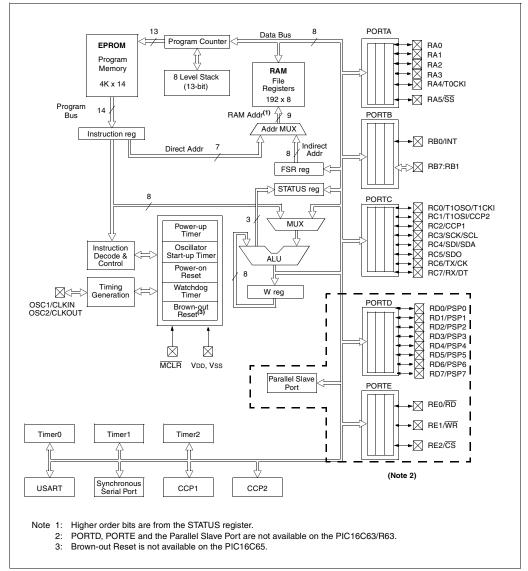


FIGURE 3-3: PIC16C63/R63/65/65A/R65 BLOCK DIAGRAM

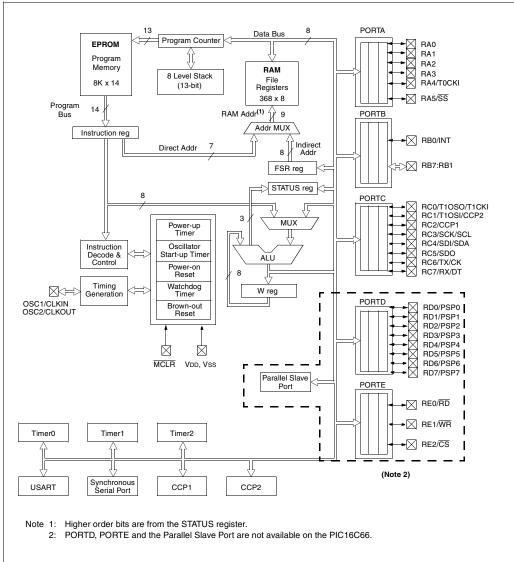


FIGURE 3-4: PIC16C66/67 BLOCK DIAGRAM

Pin Name	DIP Pin#	SOIC Pin#	Pin Type	Buffer Type	Description
OSC1/CLKIN	16	16	I	ST/CMOS ⁽¹⁾	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	0	_	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/VPP	4	4	I/P	ST	Master clear reset input or programming voltage input. This pin is an active low reset to the device.
					PORTA is a bi-directional I/O port.
RA0	17	17	I/O	TTL	
RA1	18	18	I/O	TTL	
RA2	1	1	I/O	TTL	
RA3	2	2	I/O	TTL	
RA4/T0CKI	3	3	I/O	ST	RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.
					PORTB is a bi-directional I/O port. PORTB can be software pro- grammed for internal weak pull-up on all inputs.
RB0/INT	6	6	I/O	TTL/ST ⁽²⁾	RB0 can also be the external interrupt pin.
RB1	7	7	I/O	TTL	
RB2	8	8	I/O	TTL	
RB3	9	9	I/O	TTL	
RB4	10	10	I/O	TTL	Interrupt on change pin.
RB5	11	11	I/O	TTL	Interrupt on change pin.
RB6	12	12	I/O	TTL/ST ⁽³⁾	Interrupt on change pin. Serial programming clock.
RB7	13	13	I/O	TTL/ST ⁽³⁾	Interrupt on change pin. Serial programming data.
Vss	5	5	Р	_	Ground reference for logic and I/O pins.
Vdd	14	14	Р	—	Positive supply for logic and I/O pins.
Legend: I = input	0 = 01 — = N	utput lot used) = input/outpu L = TTL input	

PIC16C61 PINOUT DESCRIPTION TABLE 3-1:

Note 1: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.
2: This buffer is a Schmitt Trigger input when configured as the external interrupt.
3: This buffer is a Schmitt Trigger input when used in serial programming mode.

TABLE 3-2: PIC16C62/62A/R62/63/R63/66 PINOUT DESCRIPTION

Pin Name Pin# Pin Type Buffer Type		Buffer Type	Description		
OSC1/CLKIN	9	I	ST/CMOS ⁽³⁾	Oscillator crystal input/external clock source input.	
OSC2/CLKOUT	10	0	_	Oscillator crystal output. Connects to crystal or resonator in crys- tal oscillator mode. In RC mode, the pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.	
MCLR/Vpp	1	I/P	ST	Master clear reset input or programming voltage input. This pin is an active low reset to the device.	
				PORTA is a bi-directional I/O port.	
RA0	2	I/O	TTL		
RA1	3	I/O	TTL		
RA2	4	I/O	TTL		
RA3	5	I/O	TTL		
RA4/T0CKI	6	I/O	ST	RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.	
RA5/SS	7	I/O	TTL	RA5 can also be the slave select for the synchronous serial port.	
				PORTB is a bi-directional I/O port. PORTB can be software pro- grammed for internal weak pull-up on all inputs.	
RB0/INT	21	I/O	TTL/ST ⁽⁴⁾	RB0 can also be the external interrupt pin.	
RB1	22	I/O	TTL		
RB2	23	I/O	TTL		
RB3	24	I/O	TTL		
RB4	25	I/O	TTL	Interrupt on change pin.	
RB5	26	I/O	TTL	Interrupt on change pin.	
RB6	27	I/O	TTL/ST ⁽⁵⁾	Interrupt on change pin. Serial programming clock.	
RB7	28	I/O	TTL/ST ⁽⁵⁾	Interrupt on change pin. Serial programming data.	
				PORTC is a bi-directional I/O port.	
RC0/T1OSO ⁽¹⁾ /T1CKI	11	I/O	ST	RC0 can also be the Timer1 oscillator output ⁽¹⁾ or Timer1 clock input.	
RC1/T1OSI ⁽¹⁾ /CCP2 ⁽²⁾	12	I/O	ST	RC1 can also be the Timer1 oscillator input ⁽¹⁾ or Capture2 input/Compare2 output/PWM2 output ⁽²⁾ .	
RC2/CCP1	13	I/O	ST	RC2 can also be the Capture1 input/Compare1 out- put/PWM1 output.	
RC3/SCK/SCL	14	I/O	ST	RC3 can also be the synchronous serial clock input/output for both SPI and I ² C modes.	
RC4/SDI/SDA	15	I/O	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode).	
RC5/SDO	16	I/O	ST	RC5 can also be the SPI Data Out (SPI mode).	
RC6/TX/CK ⁽²⁾	17	I/O	ST	RC6 can also be the USART Asynchronous Transmit ⁽²⁾ or Synchronous Clock ⁽²⁾ .	
RC7/RX/DT ⁽²⁾	18	I/O	ST	RC7 can also be the USART Asynchronous Receive ⁽²⁾ or Synchronous Data ⁽²⁾ .	
Vss	8,19	Р		Ground reference for logic and I/O pins.	
VDD	20	Р	_	Positive supply for logic and I/O pins.	
Legend: I = input O =	output	- -	O = input/outpu		

2: The USART and CCP2 are not available on the PIC16C62/62A/R62.

3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

4: This buffer is a Schmitt Trigger input when configured as the external interrupt.

5: This buffer is a Schmitt Trigger input when used in serial programming mode.

Pin Name	DIP Pin#	PLCC Pin#	TQFP MQFP Pin#	Pin Type	Buffer Type	Description
OSC1/CLKIN	13	14	30	Ι	ST/CMOS ⁽³⁾	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	14	15	31	0	_	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the pin outputs CLK- OUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/Vpp	1	2	18	I/P	ST	Master clear reset input or programming voltage input. This pin is an active low reset to the device.
	_	_				PORTA is a bi-directional I/O port.
RA0	2	3	19	I/O	TTL	
RA1	3	4	20	I/O	TTL	
RA2	4	5	21	I/O	TTL	
RA3	5	6	22	I/O	TTL	
RA4/T0CKI	6	7	23	I/O	ST	RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.
RA5/SS	7	8	24	I/O	TTL	RA5 can also be the slave select for the synchronous serial port.
						PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	33	36	8	I/O	TTL/ST ⁽⁴⁾	RB0 can also be the external interrupt pin.
RB1	34	37	9	I/O	TTL	
RB2	35	38	10	I/O	TTL	
RB3	36	39	11	I/O	TTL	
RB4	37	41	14	I/O	TTL	Interrupt on change pin.
RB5	38	42	15	I/O	TTL	Interrupt on change pin.
RB6	39	43	16	I/O	TTL/ST ⁽⁵⁾	Interrupt on change pin. Serial programming clock.
RB7	40	44	17	I/O	TTL/ST ⁽⁵⁾	Interrupt on change pin. Serial programming data.
						PORTC is a bi-directional I/O port.
RC0/T1OSO ⁽¹⁾ /T1CKI	15	16	32	I/O	ST	RC0 can also be the Timer1 oscillator output ⁽¹⁾ or Timer1 clock input.
RC1/T1OSI ⁽¹⁾ /CCP2 ⁽²⁾	16	18	35	I/O	ST	RC1 can also be the Timer1 oscillator input ⁽¹⁾ or Capture2 input/Compare2 output/PWM2 output ⁽²⁾ .
RC2/CCP1	17	19	36	I/O	ST	RC2 can also be the Capture1 input/Compare1 out- put/PWM1 output.
RC3/SCK/SCL	18	20	37	I/O	ST	RC3 can also be the synchronous serial clock input/out- put for both SPI and I ² C modes.
RC4/SDI/SDA	23	25	42	I/O	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode).
RC5/SDO	24	26	43	I/O	ST	RC5 can also be the SPI Data Out (SPI mode).
RC6/TX/CK ⁽²⁾	25	27	44	I/O	ST	RC6 can also be the USART Asynchronous Transmit ⁽²⁾ or Synchronous Clock ⁽²⁾ .
RC7/RX/DT ⁽²⁾	26	29	1	I/O	ST	RC7 can also be the USART Asynchronous Receive ⁽²⁾ or Synchronous Data ⁽²⁾ .
Legend: I = input C) = outp	ut	I/C	D = input	/output	P = power
- Note 1: Pin functions	- = Not			FL = TTL		ST = Schmitt Trigger input

TABLE 3-3: PIC16C64/64A/R64/65/65A/R65/67 PINOUT DESCRIPTION

Note 1: Pin functions T1OSO and T1OSI are reversed on the PIC16C64.

2: CCP2 and the USART are not available on the PIC16C64/64A/R64.

3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

4: This buffer is a Schmitt Trigger input when configured as the external interrupt.

5: This buffer is a Schmitt Trigger input when used in serial programming mode.

6: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).

TABLE 3-3: PIC16C64/64A/R64/65/65A/R65/67 PINOUT DESCRIPTION (Cont.'d)

Pin Name	DIP Pin#	PLCC Pin#	TQFP MQFP Pin#	Pin Type	Buffer Type	Description
						PORTD can be a bi-directional I/O port or parallel slave port for interfacing to a microprocessor bus.
RD0/PSP0	19	21	38	I/O	ST/TTL ⁽⁶⁾	
RD1/PSP1	20	22	39	I/O	ST/TTL ⁽⁶⁾	
RD2/PSP2	21	23	40	I/O	ST/TTL ⁽⁶⁾	
RD3/PSP3	22	24	41	I/O	ST/TTL ⁽⁶⁾	
RD4/PSP4	27	30	2	I/O	ST/TTL ⁽⁶⁾	
RD5/PSP5	28	31	3	I/O	ST/TTL ⁽⁶⁾	
RD6/PSP6	29	32	4	I/O	ST/TTL ⁽⁶⁾	
RD7/PSP7	30	33	5	I/O	ST/TTL ⁽⁶⁾	
						PORTE is a bi-directional I/O port.
RE0/RD	8	9	25	I/O	ST/TTL ⁽⁶⁾	RE0 can also be read control for the parallel slave port.
RE1/WR	9	10	26	I/O	ST/TTL ⁽⁶⁾	RE1 can also be write control for the parallel slave port.
RE2/CS	10	11	27	I/O	ST/TTL ⁽⁶⁾	RE2 can also be select control for the parallel slave port.
Vss	12,31	13,34	6,29	Р	—	Ground reference for logic and I/O pins.
Vdd	11,32	12,35	7,28	Р	—	Positive supply for logic and I/O pins.
NC	-	1,17,	12,13,		—	These pins are not internally connected. These pins should
		28,40	33,34			be left unconnected.
Legend: I = input	O = outp	ut	I/C) = input/	output	P = power

ST = Schmitt Trigger input

- = Not used TTL = TTL input S Note 1: Pin functions T1OSO and T1OSI are reversed on the PIC16C64.

2: CCP2 and the USART are not available on the PIC16C64/64A/R64.

3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

4: This buffer is a Schmitt Trigger input when configured as the external interrupt.

5: This buffer is a Schmitt Trigger input when used in serial programming mode.

6: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).

3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3, and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clock and instruction execution flow is shown in Figure 3-5.

3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3, and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g. GOTO) then two cycles are required to complete the instruction (Example 3-1).

A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

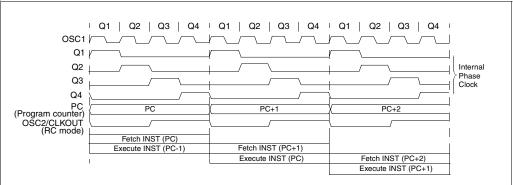
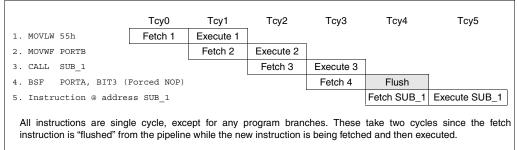


FIGURE 3-5: CLOCK/INSTRUCTION CYCLE





4.0 MEMORY ORGANIZATION

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

4.1 Program Memory Organization

The PIC16C6X family has a 13-bit program counter capable of addressing an $8K \times 14$ program memory space. The amount of program memory available to each device is listed below:

Device	Program Memory	Address Range
PIC16C61	1K x 14	0000h-03FFh
PIC16C62	2K x 14	0000h-07FFh
PIC16C62A	2K x 14	0000h-07FFh
PIC16CR62	2K x 14	0000h-07FFh
PIC16C63	4K x 14	0000h-0FFFh
PIC16CR63	4K x 14	0000h-0FFFh
PIC16C64	2K x 14	0000h-07FFh
PIC16C64A	2K x 14	0000h-07FFh
PIC16CR64	2K x 14	0000h-07FFh
PIC16C65	4K x 14	0000h-0FFFh
PIC16C65A	4K x 14	0000h-0FFFh
PIC16CR65	4K x 14	0000h-0FFFh
PIC16C66	8K x 14	0000h-1FFFh
PIC16C67	8K x 14	0000h-1FFFh

For those devices with less than 8K program memory, accessing a location above the physically implemented address will cause a wraparound.

The reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 4-1: PIC16C61 PROGRAM MEMORY MAP AND STACK

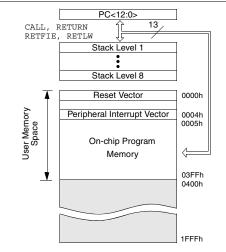


FIGURE 4-2: PIC16C62/62A/R62/64/64A/ R64 PROGRAM MEMORY MAP AND STACK

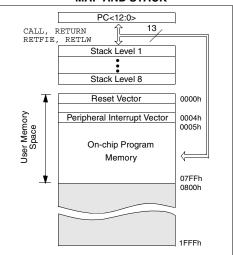
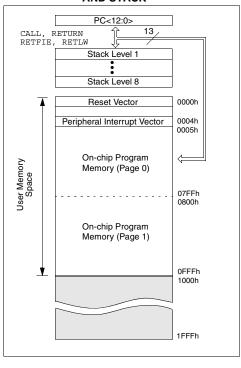
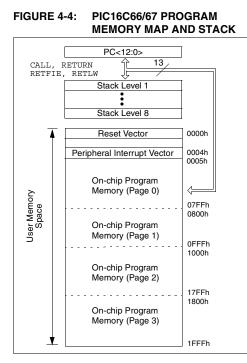


FIGURE 4-3: PIC16C63/R63/65/65A/R65 PROGRAM MEMORY MAP AND STACK





4.2 Data Memory Organization

Applicable Devices

616262A R6263 R636464A R646565A R65667 The data memory is partitioned into multiple banks which contain the General Purpose Registers and the Special Function Registers. Bits RP1 and RP0 are the bank select bits.

RP1:RP0 (STATUS<6:5>)

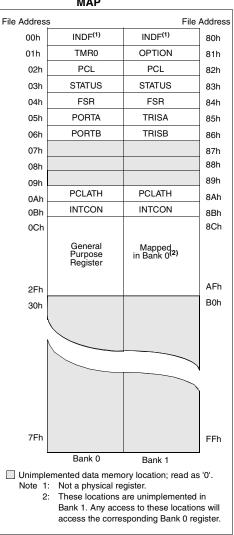
- = $00 \rightarrow Bank0$
- = 01 \rightarrow Bank1
- = $10 \rightarrow \text{Bank2}$ = $11 \rightarrow \text{Bank3}$
- $= 11 \rightarrow \text{Dark}$

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain special function registers. Some "high use" special function registers from one bank may be mirrored in another bank for code reduction and quicker access.

4.2.1 GENERAL PURPOSE REGISTERS

These registers are accessed either directly or indirectly through the File Select Register (FSR) (Section 4.5). For the PIC16C61, general purpose register locations 8Ch-AFh of Bank 1 are not physically implemented. These locations are mapped into 0Ch-2Fh of Bank 0.

FIGURE 4-5:	PIC16C61 REGISTER FILE
	ΜΔΡ



ile Addre	ISS		File Addres
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	PORTC	TRISC	87h
08h	PORTD ⁽²⁾	TRISD ⁽²⁾	88h
09h	PORTE ⁽²⁾	TRISE ⁽²⁾	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh	TMR1L	PCON	8Eh
0Fh	TMR1H		8Fh
10h	T1CON		90h
11h	TMR2		91h
12h	T2CON	PR2	92h
13h	SSPBUF	SSPADD	93h
14h	SSPCON	SSPSTAT	94h
15h	CCPR1L		95h
16h	CCPR1H		96h
17h	CCP1CON		97h
18h			98h
1Fh			9Fh
20h		General	A0h
	General Purpose Register	Purpose Register	BFh C0h
7Fh	Dort 0	Donk 1	FFh
Unim Note	Bank 0 nplemented data m e 1: Not a physica 2: PORTD and	al register.	

FIGURE 4-7: PIC16C63/R63/65/65A/R65 REGISTER FILE MAP

REGISTER FILE MAP									
File Addre	ess		File Address						
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h						
01h	TMR0	OPTION	81h						
02h	PCL	PCL	82h						
03h	STATUS	STATUS	83h						
04h	FSR	FSR	84h						
05h	PORTA	TRISA	85h						
06h	PORTB	TRISB	86h						
07h	PORTC	TRISC	87h						
08h	PORTD ⁽²⁾ PORTE ⁽²⁾	TRISD ⁽²⁾ TRISE ⁽²⁾	88h						
09h	PCLATH	PCLATH	89h 8Ah						
0Ah 0Bh	INTCON	INTCON	8Bh						
0Ch	PIR1	PIE1	8Ch						
0Dh	PIR2	PIE2	8Dh						
	TMR1L	PCON	8Eh						
0Eh 0Fh	TMR1L	FCON	8Fh						
10h	T1CON		90h						
11h	TMR2		91h						
12h	T2CON	PR2	92h						
13h	SSPBUF	SSPADD	93h						
14h	SSPCON	SSPSTAT	94h						
15h	CCPR1L		95h						
16h	CCPR1H		96h						
17h	CCP1CON		97h						
18h	RCSTA	TXSTA	98h						
19h	TXREG	SPBRG	99h						
1Ah	RCREG		9Ah						
1Bh	CCPR2L		9Bh						
1Ch	CCPR2H		9Ch						
1Dh	CCP2CON		9Dh						
1Eh			9Eh						
1Fh			9Fh						
20h	General	General	A0h						
7Fh	Purpose Register	Purpose Register	FFh						
	Bank 0	Bank 1							
Unir 🗌 Unir	nplemented data me e 1: Not a physica		ead as '0'.						
2: PORTD and PORTE are not available on									
the PIC16C63/R63.									

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Indirect addr.(*)	00h	Indirect addr.(*)	80h	Indirect addr.(*)	100h	Indirect addr.(*)	1
TMR0	01h	OPTION	81h	TMR0	101h	OPTION	1
PCL	02h	PCL	82h	PCL	102h	PCL	1
STATUS	03h	STATUS	83h	STATUS	103h	STATUS	1
FSR	04h	FSR	84h	FSR	104h	FSR	1
PORTA	05h	TRISA	85h		105h	1011	1
PORTB	06h	TRISA	86h	PORTB	106h	TRISB	1
PORTC	07h	TRISE	87h	PONTB	107h	THOD	1
PORTD (1)	08h	TRISC (1)	88h		108h		1
PORTE (1)	09h	TRISE (1)	89h		109h		1
PCLATH	0Ah	PCLATH	8Ah	PCLATH	10Ah	PCLATH	1
INTCON	0Bh	INTCON	8Bh	INTCON	10Bh	INTCON	1
PIR1	0Ch		8Ch	introon	10Ch	INTCON	1
PIR2	0Dh	PIE1 PIE2	8Dh		10Dh		1
TMR1L	0Eh	PIE2 PCON	8Dh 8Eh		10Eh		1
TMR1L TMR1H	0En 0Fh	FCON			10En 10Fh		1
T1CON	10h		8Fh 90h		110h		1
TMR2	11h		90n 91h		111h		1
T2CON	12h	DDO			112h		1
SSPBUF	13h	PR2	92h		113h		1
SSPEOF	14h	SSPADD	93h		114h		1
	15h	SSPSTAT	94h		115h		1
CCPR1L	16h		95h		116h		
CCPR1H CCP1CON	17h		96h	General	117h	General	1
	18h	T)(074	97h	Purpose	118h	Purpose	1
RCSTA	-	TXSTA	98h	Register	119h	Register	1
TXREG	19h	SPBRG	99h	16 Bytes	11Ah	16 Bytes	
RCREG	1Ah 1Ph		9Ah		11Bh		1
CCPR2L	1Bh		9Bh		11Ch		1
CCPR2H	1Ch		9Ch		11Dh		1
CCP2CON	1Dh ₁⊏⊳		9Dh		11Eh		1
	1Eh ₁Eh		9Eh				1
	1Fh		9Fh		11Fh		1
	20h		A0h		120h		1
General		General		General		General	
Purpose Register		Purpose Register		Purpose Register		Purpose Register	l
•		80 Bytes		80 Bytes		80 Bytes	1
96 Bytes		-	EFh	-	16Fh	-	1
		accesses 70h-7Fh	F0h	accesses 70h-7Fh	170h	accesses 70h-7Fh	
	7Eh	in Bank 0	EEh	in Bank 0	17Fh	in Bank 0	1
Bank 0	7Fh	Bank 1	FFh	Bank 2	17111	Bank 3	
Unimplemente * Not a physical	register.	emory locations, read					
-		emented on the PIC16		nks 1, 2, and 3 are			

FIGURE 4-8: PIC16C66/67 DATA MEMORY MAP

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SPECIAL FUNCTION REGISTERS: 4.2.2

The Special Function Registers are registers used by the CPU and peripheral modules for controlling the desired operation of the device. These registers are implemented as static RAM.

The special function registers can be classified into two sets (core and peripheral). The registers associated with the "core" functions are described in this section and those related to the operation of the peripheral features are described in the section of that peripheral feature.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR	Value on all other resets ⁽³⁾
Bank 0											
00h ⁽¹⁾	INDF	Addressing	this location	uses conten	ts of FSR to	address data	a memory (n	ot a physical	register)	0000 0000	0000 0000
01h	TMR0	Timer0 mod	dule's register	r						xxxx xxxx	uuuu uuuu
02h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signif	icant Byte					0000 0000	0000 0000
03h ⁽¹⁾	STATUS	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RP0	TO	PD	z	DC	С	0001 1xxx	000q quuu
04h ⁽¹⁾	FSR	Indirect data	a memory ad	dress pointe	r					xxxx xxxx	uuuu uuuu
05h	PORTA	_	-	_	PORTA Dat	a Latch whe	n written: PC	RTA pins wh	en read	x xxxx	u uuuu
06h	PORTB	PORTB Da	ta Latch whe		xxxx xxxx	uuuu uuuu					
07h	-	Unimpleme	nted	_	—						
08h	—	Unimpleme	nted	_	_						
09h	—	Unimpleme	nted		_	_					
0Ah ^(1,2)	PCLATH	_	_	ounter	0 0000	0 0000					
0Bh ⁽¹⁾	INTCON	GIE	_	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0-00 000x	0-00 000u
Bank 1						•	•	•			
80h ⁽¹⁾	INDF	Addressing	this location	uses conten	ts of FSR to	address data	a memory (n	ot a physical	register)	0000 0000	0000 0000
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signif	icant Byte					0000 0000	0000 0000
83h ⁽¹⁾	STATUS	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
84h ⁽¹⁾	FSR	Indirect data	a memory ad	dress pointe	r					xxxx xxxx	uuuu uuuu
85h	TRISA	-	_	_	PORTA Dat	a Direction F	Register			1 1111	1 1111
86h	TRISB	PORTB Da	ta Direction C	Control Regis	ster					1111 1111	1111 1111
87h	-	Unimpleme	Unimplemented								_
88h	-	Unimpleme	nted							_	_
89h	-	Unimpleme	nted							_	—
8Ah ^(1,2)	PCLATH	_	_	_	Write Buffer	for the uppe	er 5 bits of th	e Program C	ounter	0 0000	0 0000
8Bh ⁽¹⁾	INTCON		GIE — TOIE INTE RBIE TOIF INTF F								0-00 000u

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented locations read as '0'.

Shaded locations are unimplemented and read as '0'

Note 1: These registers can be addressed from either bank.

The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose con-2: tents are transferred to the upper byte of the program counter. (PC<12:8>) 3:

Other (non power-up) resets include external reset through MCLR and the Watchdog Timer Reset.

4: The IRP and RP1 bits are reserved on the PIC16C61, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 0											
00h ⁽¹⁾	INDF	Addressing	this location	uses conter	nts of FSR to	address data	a memory (n	ot a physica	register)	0000 0000	0000 0000
01h	TMR0	Timer0 mod	lule's registe	r						xxxx xxxx	uuuu uuuu
02h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signit	ficant Byte					0000 0000	0000 0000
03h ⁽¹⁾	STATUS	IRP ⁽⁵⁾	RP1 ⁽⁵⁾	С	0001 1xxx	000q quuu					
04h ⁽¹⁾	FSR	Indirect data	a memory ac	1	xxxx xxxx	uuuu uuuu					
05h	PORTA	_	—	xx xxxx	uu uuuu						
06h	PORTB	PORTB Dat	a Latch whe	n written: PC	ORTB pins wh	nen read				xxxx xxxx	uuuu uuuu
07h	PORTC	PORTC Dat	ta Latch whe		xxxx xxxx	uuuu uuuu					
08h	_	Unimpleme	nted							—	_
09h	_	Unimpleme	nted							—	_
0Ah ^(1,2)	PCLATH	_	_	_	Write Buffer	for the uppe	r 5 bits of the	e Program C	ounter	0 0000	0 0000
0Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(6)	(6)		—	SSPIF	CCP1IF	TMR2IF	TMR1IF	00 0000	00 0000
0Dh	_	Unimpleme	nted							_	_
0Eh	TMR1L	Holding reg	ister for the L	east Signific	cant Byte of t	he 16-bit TM	R1 register			xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding reg	ister for the M	Most Signific	ant Byte of th	ie 16-bit TMF	R1 register			xxxx xxxx	uuuu uuuu
10h	T1CON	_	_	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00 0000	uu uuuu
11h	TMR2	Timer2 mod	lule's registe	r						0000 0000	0000 0000
12h	T2CON	_	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h	SSPBUF	Synchronou	ynchronous Serial Port Receive Buffer/Transmit Register								uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPM0	0000 0000	0000 0000					
15h	CCPR1L	Capture/Co	apture/Compare/PWM1 (LSB)								uuuu uuuu
16h	CCPR1H	Capture/Co	mpare/PWM	1 (MSB)						xxxx xxxx	uuuu uuuu
17h	CCP1CON	_	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
18h-1Fh	-	Unimpleme	nplemented								—

TABLE 4-2: SPECIAL FUNCTION REGISTERS FOR THE PIC16C62/62A/R62

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

4: The BOR bit is reserved on the PIC16C62, always maintain this bit set.

5: The IRP and RP1 bits are reserved on the PIC16C62/62A/R62, always maintain these bits clear.

6: PIE1<7:6> and PIR1<7:6> are reserved on the PIC16C62/62A/R62, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 1	•		•		•						•
80h ⁽¹⁾	INDF	Addressing	this location	uses conter	nts of FSR to	address data	a memory (n	ot a physical	register)	0000 0000	0000 0000
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Sigr	nificant Byte					0000 0000	0000 0000
83h ⁽¹⁾	STATUS	IRP ⁽⁵⁾	RP1 ⁽⁵⁾	RP0	TO	PD	z	DC	С	0001 1xxx	000q quuu
84h ⁽¹⁾	FSR	Indirect data	a memory ac	Idress pointe	ər					xxxx xxxx	uuuu uuuu
85h	TRISA	—	—		11 1111	11 1111					
86h	TRISB	PORTB Dat	ta Direction F		1111 1111	1111 1111					
87h	TRISC	PORTC Dat	ta Direction I		1111 1111	1111 1111					
88h	—	Unimpleme	nted							-	-
89h	—	Unimpleme	nted							-	-
8Ah ^(1,2)	PCLATH	—	_	_	Write Buffer	for the uppe	r 5 bits of the	e Program C	ounter	0 0000	0 0000
8Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	(6)	(6)	-	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	00 0000	00 0000
8Dh	—	Unimpleme	nted			•				—	-
8Eh	PCON	—	_	_	_	—	—	POR	BOR ⁽⁴⁾	dd	uu
8Fh	_	Unimpleme	nted							_	_
90h	_	Unimpleme	nted							_	_
91h	_	Unimpleme	Inimplemented								_
92h	PR2	Timer2 Peri	imer2 Period Register								1111 1111
93h	SSPADD	Synchronou	us Serial Por	t (I ² C mode)		0000 0000	0000 0000				
94h	SSPSTAT	—	— — D/Ā P S R/W UA I								00 0000
95h-9Fh	_	Unimpleme	nted							_	-

TABLE 4-2: SPECIAL FUNCTION REGISTERS FOR THE PIC16C62/62A/R62 (Cont.'d)

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

4: The BOR bit is reserved on the PIC16C62, always maintain this bit set.

5: The IRP and RP1 bits are reserved on the PIC16C62/62A/R62, always maintain these bits clear.

6: PIE1<7:6> and PIR1<7:6> are reserved on the PIC16C62/62A/R62, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 0											
00h ⁽¹⁾	INDF	Addressing	this location	uses conter	ts of FSR to	address data	a memory (n	ot a physical	register)	0000 0000	0000 000
01h	TMR0	Timer0 mod	lule's registe	r						xxxx xxxx	uuuu uuu
02h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signi	ficant Byte					0000 0000	0000 000
03h ⁽¹⁾	STATUS	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RP0	TO	PD	z	DC	С	0001 1xxx	000q quu
04h ⁽¹⁾	FSR	Indirect data	a memory ac	Idress pointe	ər	1	1	1		xxxx xxxx	uuuu uuu
05h	PORTA		_	PORTA Dat	a Latch wher	n written: PO	RTA pins wh	en read		xx xxxx	uu uuu
06h	PORTB	PORTB Dat	ta Latch whe	n written: PC	ORTB pins wh	nen read				xxxx xxxx	uuuu uuu
07h	PORTC	PORTC Da	ORTC Data Latch when written: PORTC pins when read								uuuu uuu
08h	-	Unimpleme	nimplemented								
09h		Unimpleme	nted							_	
0Ah ^(1,2)	PCLATH	-	Write Buffer for the upper 5 bits of the Program Counter								0 000
0Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000
0Ch	PIR1	(5)	(5)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 000
0Dh	PIR2	-	_	-		_	—	_	CCP2IF	0	
0Eh	TMR1L	Holding reg	ister for the I	east Signific	cant Byte of t	he 16-bit TM	R1 register			xxxx xxxx	uuuu uuu
0Fh	TMR1H	Holding reg	ister for the I	Nost Signific	ant Byte of th	ne 16-bit TMF	R1 register			xxxx xxxx	uuuu uuu
10h	T1CON	_	-	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00 0000	uu uuu
11h	TMR2	Timer2 mod	lule's registe	r						0000 0000	0000 000
12h	T2CON		TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 000
13h	SSPBUF	Synchronou	is Serial Por	t Receive Bu	ffer/Transmit	Register				xxxx xxxx	uuuu uuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 000
15h	CCPR1L	Capture/Co	mpare/PWM	1 (LSB)						xxxx xxxx	uuuu uuu
16h	CCPR1H	Capture/Co	mpare/PWM	1 (MSB)	,	1	1	1		xxxx xxxx	uuuu uuu
17h	CCP1CON	_	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00
19h	TXREG	USART Tra	nsmit Data F	legister						0000 0000	0000 000
1Ah	RCREG	USART Red	ceive Data R	egister						0000 0000	0000 000
1Bh	CCPR2L	Capture/Co	mpare/PWM	2 (LSB)						xxxx xxxx	uuuu uuu
1Ch	CCPR2H	Capture/Co	mpare/PWM	2 (MSB)						xxxx xxxx	uuuu uuu
1Dh	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	00 0000	00 000
1Eh-1Fh	_	Unimpleme	nted							_	_

TABLE 4-3: SPECIAL FUNCTION REGISTERS FOR THE PIC16C63/R63

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)
 Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

4: The IRP and RP1 bits are reserved on the PIC16C63/R63, always maintain these bits clear.

5: PIE1<7:6> and PIR1<7:6> are reserved on the PIC16C63/R63, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 1	1										
80h ⁽¹⁾	INDF	Addressing	this location	uses conter	nts of FSR to	address data	a memory (n	ot a physical	register)	0000 0000	0000 0000
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Sigr	nificant Byte					0000 0000	0000 0000
83h ⁽¹⁾	STATUS	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
84h ⁽¹⁾	FSR	Indirect dat	a memory ac	Idress pointe	ər					xxxx xxxx	uuuu uuuu
85h	TRISA	-	-	PORTA Dat	ta Direction R	egister				11 1111	11 1111
86h	TRISB	PORTB Da	ta Direction I		1111 1111	1111 1111					
87h	TRISC	PORTC Da	ta Direction I		1111 1111	1111 1111					
88h	_	Unimpleme	nted		_	-					
89h	_	Unimpleme	nted		_	_					
8Ah ^(1,2)	PCLATH	-	—	ounter	0 0000	0 0000					
8Bh ⁽¹⁾	INTCON	GIE	PEIE	RBIF	0000 000x	0000 0000					
8Ch	PIE1	(5)	(5)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh	PIE2	-	—	_	_	_	_	_	CCP2IE	0	0
8Eh	PCON	-	—	-	-	—	_	POR	BOR	dd	uu
8Fh	—	Unimpleme	nted							-	—
90h	_	Unimpleme	nted							—	-
91h	-	Unimpleme	nted							-	—
92h	PR2	Timer2 Peri	od Register							1111 1111	1111 1111
93h	SSPADD	Synchronou	us Serial Por	t (I ² C mode)	Address Reg	gister				0000 0000	0000 0000
94h	SSPSTAT	_	—	D/Ā	Р	S	R/W	UA	BF	00 0000	00 0000
95h	—	Unimpleme	nted							_	—
96h	_	Unimpleme	nted							—	—
97h	—	Unimpleme	nted							_	—
98h ⁽²⁾	TXSTA	CSRC	TX9	TX9D	0000 -010	0000 -010					
99h ⁽²⁾	SPBRG	Baud Rate	Generator R		0000 0000	0000 0000					
9Ah	_	Unimpleme	nted							—	_
9Bh	_	Unimpleme	nted							_	_
9Ch	-	Unimpleme	nted							-	-
9Dh	_	Unimpleme	nted							-	—
9Eh	-	Unimpleme	nted			-	—				
9Fh	_	Unimpleme	nted			_	_				

TABLE 4-3: SPECIAL FUNCTION REGISTERS FOR THE PIC16C63/R63 (Cont.'d)

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

Preserve the program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

4: The IRP and RP1 bits are reserved on the PIC16C63/R63, always maintain these bits clear.

5: PIE1<7:6> and PIR1<7:6> are reserved on the PIC16C63/R63, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 0											
00h ⁽¹⁾	INDF	Addressing	this location	uses conten	ts of FSR to	address data	a memory (n	ot a physica	register)	0000 0000	0000 0000
01h	TMR0	Timer0 mod	lule's registe	r						xxxx xxxx	uuuu uuuu
02h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signif	ficant Byte					0000 0000	0000 0000
03h ⁽¹⁾	STATUS	IRP ⁽⁵⁾	RP1 ⁽⁵⁾	С	0001 1xxx	000q quuu					
04h ⁽¹⁾	FSR	Indirect data	a memory ad	ldress pointe	er	1	1			xxxx xxxx	uuuu uuuu
05h	PORTA	_	-		xx xxxx	uu uuuu					
06h	PORTB	PORTB Dat	a Latch whe		xxxx xxxx	uuuu uuuu					
07h	PORTC	PORTC Dat	a Latch whe		xxxx xxxx	uuuu uuuu					
08h	PORTD	PORTD Dat	a Latch whe		xxxx xxxx	uuuu uuuu					
09h	PORTE	_	_	RE0	xxx	uuu					
0Ah ^(1,2)	PCLATH	_		_	Write Buffer	for the uppe	r 5 bits of the	e Program C	ounter	0 0000	0 0000
0Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF	(6)	_	1	SSPIF	CCP1IF	TMR2IF	TMR1IF	00 0000	00 0000
0Dh	_	Unimpleme	nted							-	_
0Eh	TMR1L	Holding reg	ister for the L	east Signific	ant Byte of t	ne 16-bit TM	R1 register			xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding reg	ister for the M	Aost Signific	ant Byte of th	e 16-bit TMF	R1 register			xxxx xxxx	uuuu uuuu
10h	T1CON	_	_	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00 0000	uu uuuu
11h	TMR2	Timer2 mod	lule's registe	r						0000 0000	0000 0000
12h	T2CON	_	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h	SSPBUF	Synchronou	ynchronous Serial Port Receive Buffer/Transmit Register								uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPM0	0000 0000	0000 0000					
15h	CCPR1L	Capture/Co	apture/Compare/PWM1 (LSB)								uuuu uuuu
16h	CCPR1H	Capture/Co	Capture/Compare/PWM1 (MSB)								uuuu uuuu
17h	CCP1CON	_	_	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
18h-1Fh	—	Unimpleme	implemented								_

TABLE 4-4: SPECIAL FUNCTION REGISTERS FOR THE PIC16C64/64A/R64

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

4: The BOR bit is reserved on the PIC16C64, always maintain this bit set.

5: The IRP and RP1 bits are reserved on the PIC16C64/64A/R64, always maintain these bits clear.

6: PIE1<6> and PIR1<6> are reserved on the PIC16C64/64A/R64, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 1					•						
80h ⁽¹⁾	INDF	Addressing	this location	uses conter	nts of FSR to	address data	a memory (n	ot a physical	register)	0000 0000	0000 0000
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Sigr	nificant Byte					0000 0000	0000 0000
83h ⁽¹⁾	STATUS	IRP ⁽⁵⁾	RP1 ⁽⁵⁾	RP0	TO	PD	z	DC	С	0001 1xxx	000q quuu
84h ⁽¹⁾	FSR	Indirect data	a memory ac		XXXX XXXX	uuuu uuuu					
85h	TRISA	—	—	11 1111	11 1111						
86h	TRISB	PORTB Dat	a Direction F	1111 1111	1111 1111						
87h	TRISC	PORTC Dat	ta Direction I	1111 1111	1111 1111						
88h	TRISD	PORTD Dat	ta Direction I		1111 1111	1111 1111					
89h	TRISE	IBF	OBF	IBOV	PSPMODE	_	PORTE Dat	ta Direction E	Bits	0000 -111	0000 -111
8Ah ^(1,2)	PCLATH	—	_	_	Write Buffer	for the uppe	r 5 bits of the	e Program C	ounter	0 0000	0 0000
8Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	PSPIE	(6)	_	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	00 0000	00 0000
8Dh	-	Unimpleme	nted							—	-
8Eh	PCON	—	—	—	-	—	—	POR	BOR ⁽⁴⁾	qq	uu
8Fh	-	Unimpleme	nted							—	-
90h	-	Unimpleme	nted							—	-
91h	-	Unimpleme	nted		—	-					
92h	PR2	Timer2 Peri	imer2 Period Register								1111 1111
93h	SSPADD	Synchronou	is Serial Por		0000 0000	0000 0000					
94h	SSPSTAT	—	—	BF	00 0000	00 0000					
95h-9Fh	-	Unimpleme	nted							-	_

TABLE 4-4: SPECIAL FUNCTION REGISTERS FOR THE PIC16C64/64A/R64 (Cont.'d)

 $\label{eq:logend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.$

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

4: The BOR bit is reserved on the PIC16C64, always maintain this bit set.

5: The IRP and RP1 bits are reserved on the PIC16C64/64A/R64, always maintain these bits clear.

6: PIE1<6> and PIR1<6> are reserved on the PIC16C64/64A/R64, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 0											
00h ⁽¹⁾	INDF	Addressing	this location	uses conter	nts of FSR to	address data	a memory (n	ot a physical	register)	0000 0000	0000 0000
01h	TMR0	Timer0 mod	dule's registe	r						xxxx xxxx	uuuu uuuu
02h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signi	ficant Byte					0000 0000	0000 0000
03h ⁽¹⁾	STATUS	IRP ⁽⁵⁾	RP1 ⁽⁵⁾	RP0	TO	PD	z	DC	С	0001 1xxx	000q quuu
04h ⁽¹⁾	FSR	Indirect dat	a memory ac	Idress pointe	ər	1				xxxx xxxx	uuuu uuuu
05h	PORTA	_	_	PORTA Dat	a Latch wher	written: PO	RTA pins wh	en read		xx xxxx	uu uuuu
06h	PORTB	PORTB Da	ta Latch whe	n written: PC	ORTB pins wh	nen read				xxxx xxxx	นนนน นนนเ
07h	PORTC	PORTC Da	ta Latch whe	n written: PO	ORTC pins wi	nen read				xxxx xxxx	นนนน นนนเ
08h	PORTD	PORTD Da	ta Latch whe	n written: PO	ORTD pins wi	nen read				xxxx xxxx	uuuu uuuu
09h	PORTE	_	-	—	—	-	RE2	RE1	RE0	xxx	uuu
0Ah ^(1,2)	PCLATH	_	_		Write Buffer	for the uppe	r 5 bits of the	e Program C	ounter	0 0000	0 0000
0Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 0001
0Ch	PIR1	PSPIF	(6)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh	PIR2	_	_	-		_	-	—	CCP2IF	0	(
0Eh	TMR1L	Holding reg	ister for the I	east Signific	cant Byte of t	ne 16-bit TM	R1 register			xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding reg	ister for the I	Most Signific	ant Byte of th	e 16-bit TMF	R1 register			xxxx xxxx	นนนน นนนเ
10h	T1CON	_	-	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00 0000	uu uuuu
11h	TMR2	Timer2 mod	dule's registe	r						0000 0000	0000 0000
12h	T2CON	_	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h	SSPBUF	Synchronou	us Serial Por	t Receive Bu	iffer/Transmit	Register				xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	СКР	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
15h	CCPR1L	Capture/Co	mpare/PWM	1 (LSB)						xxxx xxxx	นนนน นนนเ
16h	CCPR1H	Capture/Co	mpare/PWM	1 (MSB)						xxxx xxxx	นนนน นนนเ
17h	CCP1CON	_	_	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	-	FERR	OERR	RX9D	0000 -00x	0000 -002
19h	TXREG	USART Tra	nsmit Data F	legister						0000 0000	0000 0000
1Ah	RCREG	USART Re	ceive Data R	egister						0000 0000	0000 0000
1Bh	CCPR2L	Capture/Co	mpare/PWM	2 (LSB)						xxxx xxxx	นนนน นนนเ
1Ch	CCPR2H	Capture/Co	mpare/PWM	2 (MSB)						xxxx xxxx	นนนน นนนเ
1Dh	CCP2CON	—	_	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	00 0000	00 0000
1Eh-1Fh	—	Unimpleme	nted							—	—
		1									

TABLE 4-5: SPECIAL FUNCTION REGISTERS FOR THE PIC16C65/65A/R65

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8-) 3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

The BOR bit is reserved on the PIC16C65, always maintain this bit set.
 The IRP and RP1 bits are reserved on the PIC16C65/65A/R65, always maintain these bits clear.
 PIE1<6> and PIR1<6> are reserved on the PIC16C65/65A/R65, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 1											
80h ⁽¹⁾	INDF	Addressing	this location	uses conter	nts of FSR to	address dat	a memory (n	ot a physical	register)	0000 0000	0000 0000
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Sigr	nificant Byte					0000 0000	0000 0000
83h ⁽¹⁾	STATUS	IRP ⁽⁵⁾	RP1 ⁽⁵⁾	RP0	TO	PD	z	DC	С	0001 1xxx	000q quuu
84h ⁽¹⁾	FSR	Indirect dat	a memory ac	dress pointe	er			1	1	xxxx xxxx	uuuu uuuu
85h	TRISA	_	_	PORTA Dat	ta Direction R	egister				11 1111	11 1111
86h	TRISB	PORTB Da	ta Direction F	Register						1111 1111	1111 1111
87h	TRISC	PORTC Da	ta Direction I	Register						1111 1111	1111 1111
88h	TRISD	PORTD Da	ta Direction I	Register						1111 1111	1111 1111
89h	TRISE	IBF	OBF	IBOV	PSPMODE	_	PORTE Dat	ta Direction I	Bits	0000 -111	0000 -111
8Ah ^(1,2)	PCLATH	_	_	_	Write Buffer	for the uppe	er 5 bits of the	e Program C	ounter	0 0000	0 0000
8Bh ⁽¹⁾	INTCON	GIE	PEIE	RBIF	0000 000x	0000 000u					
8Ch	PIE1	PSPIE	(6)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh	PIE2	_	_	_	_		_	_	CCP2IE	0	0
8Eh	PCON	_	—	_	_		_	POR	BOR ⁽⁴⁾	qq	uu
8Fh	_	Unimpleme	nted							—	
90h	-	Unimpleme	nted							—	-
91h	-	Unimpleme	nted							—	-
92h	PR2	Timer2 Per	od Register							1111 1111	1111 1111
93h	SSPADD	Synchronou	us Serial Por	t (I ² C mode)	Address Reg	lister				0000 0000	0000 0000
94h	SSPSTAT	_	_	D/A	Р	S	R/W	UA	BF	00 0000	00 0000
95h	-	Unimpleme	nted							—	_
96h	-	Unimpleme	nted							—	_
97h	—	Unimpleme	nted							—	
98h	TXSTA	CSRC	TX9	TX9D	0000 -010	0000 -010					
99h	SPBRG	Baud Rate	Generator R		0000 0000	0000 0000					
9Ah	_	Unimpleme	nted							_	
9Bh	_	Unimpleme	nted							_	
9Ch	_	Unimpleme	nted							_	—
9Dh	_	Unimpleme	nted							—	—
9Eh	_	Unimpleme	nted			_	—				
9Fh	_	Unimpleme	nted			_	_				

TABLE 4-5: SPECIAL FUNCTION REGISTERS FOR THE PIC16C65/65A/R65 (Cont.'d)

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

4: The BOR bit is reserved on the PIC16C65, always maintain this bit set.

5: The IRP and RP1 bits are reserved on the PIC16C65/65A/R65, always maintain these bits clear.

6: PIE1<6> and PIR1<6> are reserved on the PIC16C65/65A/R65, always maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 0											
00h ⁽¹⁾	INDF	Addressing	this location	uses conter	ts of FSR to	address data	a memory (n	ot a physica	register)	0000 0000	0000 0000
01h	TMR0	Timer0 mod	lule's registe	r						xxxx xxxx	uuuu uuuu
02h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signif	icant Byte					0000 0000	0000 0000
03h ⁽¹⁾	STATUS	IRP	RP1	RP0	TO	PD	z	DC	С	0001 1xxx	000q quuu
04h ⁽¹⁾	FSR	Indirect data	a memory ad	Idress pointe	r		I.			xxxx xxxx	uuuu uuuu
05h	PORTA	-	_	PORTA Dat	a Latch wher	written: PO	RTA pins wh	en read		xx xxxx	uu uuuu
06h	PORTB	PORTB Dat	a Latch whe	n written: PC	ORTB pins wh	nen read				xxxx xxxx	uuuu uuuu
07h	PORTC	PORTC Dat	a Latch whe	n written: PC	ORTC pins wi	hen read				xxxx xxxx	uuuu uuuu
08h ⁽⁵⁾	PORTD	PORTD Dat	ORTD Data Latch when written: PORTD pins when read								uuuu uuuu
09h ⁽⁵⁾	PORTE		_	_	_	—	RE2	RE1	RE0	xxx	uuu
0Ah ^(1,2)	PCLATH	-	Write Buffer for the upper 5 bits of the Program Counter							0 0000	0 0000
0Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽⁶⁾	(4)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh	PIR2		_	-		_	—	_	CCP2IF	0	0
0Eh	TMR1L	Holding reg	ister for the L	east Signific	ant Byte of t	he 16-bit TM	R1 register			xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding reg	ister for the M	Most Signific	ant Byte of th	e 16-bit TMF	R1 register			xxxx xxxx	uuuu uuuu
10h	T1CON	-		T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00 0000	uu uuuu
11h	TMR2	Timer2 mod	lule's registe	r						0000 0000	0000 0000
12h	T2CON	I	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h	SSPBUF	Synchronou	is Serial Port	t Receive Bu	ffer/Transmit	Register				xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
15h	CCPR1L	Capture/Co	mpare/PWM	1 (LSB)						xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Co	mpare/PWM	1 (MSB)						xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	_	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
19h	TXREG	USART Trai	nsmit Data R	legister						0000 0000	0000 0000
1Ah	RCREG	USART Red	eive Data R	egister						0000 0000	0000 0000
1Bh	CCPR2L	Capture/Co	mpare/PWM	2 (LSB)						xxxx xxxx	uuuu uuuu
1Ch	CCPR2H	Capture/Co	mpare/PWM	2 (MSB)						xxxx xxxx	uuuu uuuu
1Dh	CCP2CON	—	_	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	00 0000	00 0000
1Eh-1Fh	_	Unimpleme	nted	-						—	—

TABLE 4-6: SPECIAL FUNCTION REGISTERS FOR THE PIC16C66/67

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register contents are transferred to the upper byte of the program counter. (PC<12:8>)
 Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.
 PIE1<6> and PIR1<6> are reserved on the PIC16C66/67, always maintain these bits clear.
 PORTD, PORTE, TRISD, and TRISE are not implemented on the PIC16C66, read as '0'.
 PORTD, PORTE, TRISD, and TRISE are not implemented on the PIC16C66, read as '0'.

6: PSPIF (PIR1<7>) and PSPIE (PIE1<7>) are reserved on the PIC16C66, maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 1											
80h ⁽¹⁾	INDF	Addressing	0000 0000	0000 0000							
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Sig	nificant Byte					0000 0000	0000 0000
83h ⁽¹⁾	STATUS	IRP	RP1	RP0	TO	PD	Z	DC	С	0001 1xxx	000g quuu
84h ⁽¹⁾	FSR	Indirect data	a memory ac	Idress point	er		1	1		xxxx xxxx	uuuu uuuu
85h	TRISA	_	_	PORTA Da	ta Direction R	egister				11 1111	11 1111
86h	TRISB	PORTB Dat	a Direction I	Register						1111 1111	1111 1111
87h	TRISC	PORTC Dat	ta Direction I	Register						1111 1111	1111 1111
88h ⁽⁵⁾	TRISD	PORTD Da	ta Direction I	Register						1111 1111	1111 1111
89h ⁽⁵⁾	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Dat	ta Direction I	Bits	0000 -111	0000 -111
8Ah ^(1,2)	PCLATH	_	—	-	Write Buffer	for the uppe	er 5 bits of the	e Program C	ounter	0 0000	0 0000
8Bh(1)	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 0000
8Ch	PIE1	PSPIE ⁽⁶⁾	(4)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh	PIE2	-	—	-	_	-	_	—	CCP2IE	0	(
8Eh	PCON	_	_		_		_	POR	BOR	dd	uu
8Fh	_	Unimpleme	nted							_	_
90h	_	Unimpleme	nted							_	_
91h	_	Unimpleme	nted							_	_
92h	PR2	Timer2 Peri	od Register							1111 1111	1111 1111
93h	SSPADD	Synchronou	is Serial Por	t (I ² C mode)	Address Reg	ister				0000 0000	0000 0000
94h	SSPSTAT	SMP	CKE	D/A	Р	S	R/W	UA	BF	0000 0000	0000 0000
95h	_	Unimpleme	nted							_	_
96h	_	Unimpleme	nted							_	_
97h	_	Unimpleme	nted							_	_
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register									0000 0000
9Ah	_	Unimplemented								-	—
9Bh	_	Unimpleme	nted							-	—
9Ch	_	Unimpleme	nted							-	—
9Dh	_	Unimpleme	nted							-	—
9Eh	_	Unimpleme	nted							-	—
9Fh	_	Unimpleme	nted							_	_

TABLE 4-6: SPECIAL FUNCTION REGISTERS FOR THE PIC16C66/67 (Cont.'d)

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose Content are transferred to the upper byte of the program counter. (PC-12:8-)
 Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.
 PIE1<6> and PIR1<6> are reserved on the PIC16C66/67, always maintain these bits clear.

5: PORTD, PORTE, TRISD, and TRISE are not implemented on the PIC16C66, read as '0'.
 6: PSPIF (PIR1<7>) and PSPIE (PIE1<7>) are reserved on the PIC16C66, maintain these bits clear.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 2											
100h ⁽¹⁾	INDF Addressing this location uses contents of FSR to address data memory (not a physical register)										0000 0000
101h	TMR0	Timer0 module's register									uuuu uuuu
102h ⁽¹⁾	PCL	Program Counter's (PC) Least Significant Byte									0000 0000
103h ⁽¹⁾	STATUS	IRP RP1 RP0 TO PD Z DC C									000q quuu
104h ⁽¹⁾	FSR	Indirect dat	a memory ac	Idress pointe	ər					xxxx xxxx	uuuu uuuu
105h	_	Unimpleme	nted							_	—
106h	PORTB	PORTB Da	ta Latch whe	n written: PC	ORTB pins wh	nen read				xxxx xxxx	uuuu uuuu
107h	—	Unimpleme	nted							—	—
108h	_	Unimpleme	nted							_	—
109h	—	Unimpleme	nted							-	—
10Ah ^(1,2)	PCLATH	—	—		Write Buffer	for the uppe	r 5 bits of the	e Program C	ounter	0 0000	0 0000
10Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
10Ch- 10Fh	-	Unimplemented									—
Bank 3											
180h ⁽¹⁾	INDF	Addressing	this location	uses conter	nts of FSR to	address data	a memory (n	ot a physica	l register)	0000 0000	0000 0000
181h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
182h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Sigr	nificant Byte					0000 0000	0000 0000
183h ⁽¹⁾	STATUS	IRP	RP1	RP0	TO	PD	z	DC	С	0001 1xxx	000q quuu
184h ⁽¹⁾	FSR	Indirect dat	a memory ac	Idress pointe	ər					xxxx xxxx	uuuu uuuu
185h	_	Unimpleme	nted							-	—
186h	TRISB	SB PORTB Data Direction Register								1111 1111	1111 1111
187h	_	- Unimplemented								-	—
188h	—	- Unimplemented								—	—
189h	—	Unimplemented								_	—
18Ah ^(1,2)	PCLATH	-	-	-	Write Buffer	for the uppe	r 5 bits of the	e Program C	ounter	0 0000	0 0000
18Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
18Ch- 19Fh	—	Unimpleme	nted			·				-	—

TABLE 4-6: SPECIAL FUNCTION REGISTERS FOR THE PIC16C66/67 (Cont.'d)

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose The upper byte of the Program Counter (PC) is not uncertify accessible. PCLR1 is a holding register contents are transferred to the upper byte of the program counter. (PC<12:8>)
 Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.
 PIE1<6> and PIR1<6> are reserved on the PIC16C66/67, always maintain these bits clear.
 PORTD, PORTE, TRISD, and TRISE are not implemented on the PIC16C66, read as '0'.
 PSPIF (PIR1<7>) and PSPIE (PIE1<7>) are reserved on the PIC16C66, maintain these bits clear.

4.2.2.1 STATUS REGISTER

R/W-0

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The STATUS register, shown in Figure 4-9, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the TO and PD bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper-three bits and set the Z bit. This leaves the STATUS register as 000u uluu (where u = unchanged).

R/W-0 R/W-0 R-1

FIGURE 4-9: STATUS REGISTER (ADDRESS 03h, 83h, 103h, 183h)

R-1

It is recommended, therefore, that only ${\tt BCF}\,,\ {\tt BSF}\,,$ SWAPF and MOVWF instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions, not affecting any status bits, see the "Instruction Set Summary."

- Note 1: For those devices that do not use bits IRP and RP1 (STATUS<7:6>), maintain these bits clear to ensure upward compatibility with future products.
- Note 2: The C and DC bits operate as a borrow and digit borrow bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

IRP	RP1	RP0	TO	PD	Z	DC	С	R = Readable bit
bit7							bit0	W = Writable bit - n = Value at POR x = unknown
bit 7:	IRP : RegIs 1 = Bank 2 0 = Bank 0	, 3 (100h -	1FFh)	ed for indire	ect addressin	ıg)		
bit 6-5:	11 = Bank 10 = Bank 01 = Bank	3 (180h - 1 2 (100h - 1	FFh) 7Fh) h)	bits (used fo	or direct addr	essing)		

		 n = Value at POR reset
		x = unknown
bit 7:	IRP: Register Bank Select bit (used for indirect addressing) 1 = Bank 2, 3 (100h - 1FFh) 0 = Bank 0, 1 (00h - FFh)	
bit 6-5:	RP1:RP0 : Register Bank Select bits (used for direct addressing) 11 = Bank 3 (180h - 1FFh) 10 = Bank 2 (100h - 17Fh) 01 = Bank 1 (80h - FFh) 00 = Bank 0 (00h - 7Fh) Each bank is 128 bytes.	
bit 4:	TO: Time-out bit 1 = After power-up, CLRWDT instruction, or SLEEP instruction 0 = A WDT time-out occurred	
bit 3:	PD : Power-down bit 1 = After power-up or by the CLRWDT instruction 0 = By execution of the SLEEP instruction	
bit 2:	 Z: Zero bit 1 = The result of an arithmetic or logic operation is zero 0 = The result of an arithmetic or logic operation is not zero 	
bit 1:	DC: Digit carry/borrow bit (for ADDWF, ADDLW, SUBLW, and SUBWF instructions) (For 1 = A carry-out from the 4th low order bit of the result occurred 0 = No carry-out from the 4th low order bit of the result	or borrow the polarity is reversed).
bit 0:	C: Carry/borrow bit (for ADDWF, ADDLW, SUBLW, and SUBWF instructions)(For bor 1 = A carry-out from the most significant bit of the result occurred 0 = No carry-out from the most significant bit of the result Note: a subtraction is executed by adding the two's complement of the second ope For rotate (RRF, RLF) instructions, this bit is loaded with either the high or low	rand.

R/W-x R/W-x R/W-x

4.2.2.2 **OPTION REGISTER**

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

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The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external INT interrupt, TMR0, and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for TMR0 register, assign the prescaler to the Watchdog Timer.

FIGURE 4-10: OPTION REGISTER (ADDRESS 81h, 181h)

R/W-1 RBPU	R/W-1 INTEDG	R/W-1 T0CS	R/W-1 T0SE	R/W-1 PSA	R/W-1 PS2	R/W-1 PS1	R/W-1 PS0	R = Readable bit				
it7		1000	1002	TOA	1 02	101	bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset				
oit 7:	RBPU : POF 1 = PORTB 0 = PORTB	pull-ups ar	e disabled		al port latch	values						
bit 6:	INTEDG: In 1 = Interrup 0 = Interrup	t on rising	edge of RE	80/INT pin								
bit 5:	TOCS : TMR 1 = Transitio 0 = Internal	on on RA4/	T0CKI pin)							
bit 4:	1 = Increme	T0SE : TMR0 Source Edge Select bit 1 = Increment on high-to-low transition on RA4/T0CKI pin 0 = Increment on low-to-high transition on RA4/T0CKI pin										
bit 3:	1 = Prescal	PSA : Prescaler Assignment bit 1 = Prescaler is assigned to the WDT 0 = Prescaler is assigned to the Timer0 module										
bit 2-0:	PS2:PS0: Prescaler Rate Select bits											
	Bit Value	TMR0 R	ate WD	Rate								
	000 001 010 011 100 101	1 : 2 1 : 4 1 : 8 1 : 16 1 : 32 1 : 64	1:	2 4 8 16 32								
	110 111	1:12		64 128								

4.2.2.3 INTCON REGISTER

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The INTCON Register is a readable and writable register which contains the various enable and flag bits for the TMR0 register overflow, RB port change and external RB0/INT pin interrupts. Note: Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

FIGURE 4-11: INTCON REGISTER (ADDRESS 0Bh, 8Bh, 10Bh 18Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	B/W-x	
GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTE	BBIF	B = Beadable bit
bit7				HBIL	101		bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset x = unknown
bit 7:	GIE: ⁽¹⁾ Glo 1 = Enable 0 = Disable	s all un-ma	sked interr					
bit 6:	PEIE: ⁽²⁾ Pe 1 = Enable 0 = Disable	s all un-ma	sked peripl	neral interru	pts			
bit 5:	TOIE: TMR 1 = Enable 0 = Disable	s the TMR) overflow i	nterrupt				
bit 4:	INTE: RB0 1 = Enable 0 = Disable	s the RB0/	INT externa					
bit 3:	RBIE: RB 1 = Enable 0 = Disable	s the RB p	ort change	interrupt				
bit 2:	TOIF: TMR 1 = TMR0 0 = TMR0	register ove	erflowed (m	ust be clear	red in softwa	re)		
bit 1:		30/INT exte	rnal interru		(must be cle	ared in soft	ware)	
bit 0:		t one of the	RB7:RB4		ed state (see d state	Section 5.2	2 to clear the	interrupt)
	be re-enab description	led by the 1	RETFIE ins	truction in t		errupt Servi		ed, the GIE bit may unintentionally Refer to Section 13.5 for a detailed
globa		GIE (INTC						corresponding enable bit or the rupt flag bits are clear prior to

4.2.2.4 PIE1 REGISTER

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Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 This register contains the individual enable bits for the peripheral interrupts. Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

FIGURE 4-12: PIE1 REGISTER FOR PIC16C62/62A/R62 (ADDRESS 8Ch)

RW-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	
_	—	_		SSPIE	CCP1IE	TMR2IE	TMR1IE	R = Readable bit
bit7 bit 7-6:	Reserved:	Always ma	intain these	e bits clear.			bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 5-4:	Unimpleme	ented: Rea	id as '0'					
bit 3:	SSPIE : Syr 1 = Enables 0 = Disable	s the SSP i	nterrupt	Interrupt Er	nable bit			
bit 2:	CCP1IE : Co 1 = Enables 0 = Disable	s the CCP1	interrupt	oit				
bit 1:	TMR2IE: TI 1 = Enables 0 = Disable	s the TMR2	to PR2 ma	atch interru	pt			
bit 0:	TMR1IE : TI 1 = Enables 0 = Disable	s the TMR1	overflow i	nterrupt	t			

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FIGURE 4-13: PIE1 REGISTER FOR PIC16C63/R63/66 (ADDRESS 8Ch)

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R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
—	—	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	R = Readable bit
bit7							bit0	 W = Writable bit U = Unimplemented bit, read as '0' n = Value at POR reset
bit 7-6:	Reserved:	Always ma	aintain thes	e bits clear.				
bit 5:	RCIE: USA 1 = Enable 0 = Disable	s the USAF	RT receive i	nterrupt				
bit 4:	TXIE: USA 1 = Enable 0 = Disable	s the USAF	RT transmit	interrupt				
bit 3:	SSPIE : Syn 1 = Enable 0 = Disable	s the SSP i	nterrupt	Interrupt Er	able bit			
bit 2:	CCP1IE : C 1 = Enable 0 = Disable	s the CCP1	interrupt	bit				
bit 1:	TMR2IE: T 1 = Enable 0 = Disable	s the TMR2	2 to PR2 m	atch interru	ot			
bit 0:	TMR1IE : T 1 = Enable 0 = Disable	s the TMR1	l overflow i	nterrupt	t			

FIGURE 4-14: PIE1 REGISTER FOR PIC16C64/64A/R64 (ADDRESS 8Ch)

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	
PSPIE	_	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	R = Readable bit
bit7							bit0	 W = Writable bit U = Unimplemented bit, read as '0' n = Value at POR reset
bit 7:	PSPIE: Par 1 = Enables 0 = Disable	s the PSP i	read/write i	nterrupt	upt Enable b	it		
bit 6:	Reserved:	Always ma	intain this I	oit clear.				
bit 5-4:	Unimplem	ented: Rea	ad as '0'					
bit 3:	SSPIE: Syr 1 = Enables 0 = Disable	s the SSP i	nterrupt	Interrupt Er	able bit			
bit 2:	CCP1IE : C 1 = Enables 0 = Disable	s the CCP1	interrupt	oit				
bit 1:	TMR2IE : T 1 = Enables 0 = Disable	s the TMR2	2 to PR2 ma	atch interrup	ot			
bit 0:	TMR1IE : T 1 = Enables 0 = Disable	s the TMR1	l overflow i	nterrupt	t			

FIGURE 4-15: PIE1 REGISTER FOR PIC16C65/65A/R65/67 (ADDRESS 8Ch)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
PSPIE	_	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	R = Readable bit
bit7							bit0	 W = Writable bit U = Unimplemented bit, read as '0' n = Value at POR reset
bit 7:	PSPIE: Par 1 = Enable 0 = Disable	s the PSP r	ead/write i	nterrupt	upt Enable b	it		
bit 6:	Reserved:	Always ma	aintain this I	oit clear.				
bit 5:	RCIE: USA 1 = Enable 0 = Disable	s the USAF	RT receive i	nterrupt				
bit 4:	TXIE: USA 1 = Enable 0 = Disable	s the USAF	RT transmit	interrupt				
bit 3:	SSPIE: Syr 1 = Enable 0 = Disable	s the SSP i	nterrupt	Interrupt Er	hable bit			
bit 2:	CCP1IE : C 1 = Enables 0 = Disable	s the CCP1	interrupt	bit				
bit 1:	TMR2IE : T 1 = Enable 0 = Disable	s the TMR2	2 to PR2 ma	atch interru	pt			
bit 0:	TMR1IE: T 1 = Enable: 0 = Disable	s the TMR1	l overflow i	nterrupt	t			

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4.2.2.5 PIR1 REGISTER

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

This register contains the individual flag bits for the peripheral interrupts.

Note: Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 4-16: PIR1 REGISTER FOR PIC16C62/62A/R62 (ADDRESS 0Ch)

nimplemer	,		SSPIF	CCP1IF	TMR2IF	TMR1IF bit0	R = Readable bit W = Writable bit U = Unimplemented bit,
nimplemer	,	ntain these					read as '0' - n = Value at POR reset
•			e bits clear.				
	nted: Rea	d as '0'					
= The trans	mission/r	eception is	nterrupt Fla complete (ag bit must be clea	ared in softw	vare)	
apture Mod = A TMR1 = No TMR1 ompare Mo = A TMR1 = No TMR1 <u>WM Mode</u>	<u>e</u> register ca l register d <u>de</u> register co l register d	apture occi capture occi ompare ma	curred	d (must be c		oftware)	
= TMR2 to	PR2 mate	h occurred	d (must be c		ftware)		
= TMR1 reg	gister ove	rflow occur	red (must b	e cleared in	software)		
= C ar = = = = = = = = = = = = = = = = = =	Waiting to PIIF: CCI boture Mod A TMR1 No TMR1 mpare Mod A TMR1 No TMR1 Mode used in thi R2IF: TMI TMR2 to No TMR2 R1IF: TMI TMR1 rep No TMR1 ag bits ge	Waiting to transmit PIIF: CCP1 Interrup ture Mode A TMR1 register or No TMR1 register or Mode A TMR1 register or Mode used in this mode R2IF: TMR2 to PR2 mato No TMR2 to PR2 mato No TMR2 to PR2 mato No TMR1 register or MR1 register or MR1 register or Mo TMR1 register or MA State of the	Waiting to transmit/receive PIIF: CCP1 Interrupt Flag bit <u>bure Mode</u> A TMR1 register capture occu No TMR1 register capture occu mpare Mode A TMR1 register compare ma No TMR1 register compare ma Mode used in this mode R2IF: TMR2 to PR2 Match Int TMR2 to PR2 match occurred No TMR2 to PR2 match occurred No TMR2 to PR2 match occurred No TMR2 to PR2 match occurred No TMR1 register overflow occur TMR1 register overflow occur No TMR1 register overflow occur	Waiting to transmit/receive PIIF: CCP1 Interrupt Flag bit bure Mode A TMR1 register capture occurred (must No TMR1 register capture occurred mpare Mode A TMR1 register compare match occurred No TMR1 register compare match occurred Mode used in this mode R2IF: TMR2 to PR2 Match Interrupt Flag TMR2 to PR2 match occurred (must be of No TMR2 to PR2 match occurred R1IF: TMR1 Overflow Interrupt Flag bit TMR1 register overflow occurred must bit No TMR1 register overflow occurred ag bits get set when an interrupt condition	Waiting to transmit/receive PIIF: CCP1 Interrupt Flag bit bure Mode A TMR1 register capture occurred (must be cleared i No TMR1 register capture occurred mpare Mode A TMR1 register compare match occurred (must be c No TMR1 register compare match occurred <u>M Mode</u> used in this mode R2IF: TMR2 to PR2 Match Interrupt Flag bit TMR2 to PR2 match occurred R1IF: TMR1 Overflow Interrupt Flag bit TMR1 register overflow occurred R1IF: TMR1 Overflow Interrupt Flag bit TMR1 register overflow occurred must be cleared in No TMR1 register overflow occurred ag bits get set when an interrupt condition occurs rega	Waiting to transmit/receive PIIF: CCP1 Interrupt Flag bit bure Mode A TMR1 register capture occurred (must be cleared in software) No TMR1 register capture occurred mpare Mode A TMR1 register compare match occurred (must be cleared in so No TMR1 register compare match occurred M Mode used in this mode R2IF: TMR2 to PR2 Match Interrupt Flag bit TMR2 to PR2 match occurred (must be cleared in software) No TMR2 to PR2 match occurred R1IF: TMR1 Overflow Interrupt Flag bit TMR1 register overflow occurred mMR1 register overflow occurred ag bits get set when an interrupt condition occurs regardless of th	Waiting to transmit/receive PIIF: CCP1 Interrupt Flag bit bure Mode A TMR1 register capture occurred (must be cleared in software) No TMR1 register compare match occurred (must be cleared in software) No TMR1 register compare match occurred (must be cleared in software) No TMR1 register compare match occurred <u>M Mode</u> used in this mode R2IF: TMR2 to PR2 Match Interrupt Flag bit TMR2 to PR2 match occurred (must be cleared in software) No TMR2 to PR2 match occurred R1IF: TMR1 Overflow Interrupt Flag bit TMR1 register overflow occurred (must be cleared in software) No TMR1 register overflow occurred R1IF: TMR1 Overflow Interrupt Flag bit TMR1 register overflow occurred ag bits get set when an interrupt condition occurs regardless of the state of its

FIGURE 4-17: PIR1 REGISTER FOR PIC16C63/R63/66 (ADDRESS 0Ch)

R/W-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	
	_	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF bit0	R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
it 7-6:	Reserved:	Always ma	aintain thes	e bits clear.				
oit 5:	RCIF: USA 1 = The US 0 = The US	SART receiv	/e buffer is	full (cleared	d by reading	RCREG)		
bit 4:	TXIF: USA 1 = The US 0 = The US	SART transi	nit buffer is	empty (cle	ared by writi	ng to TXRE	G)	
bit 3:	SSPIF : Syr 1 = The tra 0 = Waiting	nsmission/	reception is		ag bit (must be clea	ared in softw	vare)	
bit 2:	0 = No TMI <u>Compare N</u>	ode 1 register c R1 register <u>Mode</u> 1 register c R1 register <u>2</u>	apture occ capture oc ompare ma	urred (must curred atch occurre	be cleared i ed (must be c red		oftware)	
bit 1:	TMR2IF : T 1 = TMR2 t 0 = No TMI	to PR2 mat	ch occurre	d (must be	bit cleared in so	ftware)		
bit 0:		register ove		rred (must b	be cleared in	software)		

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FIGURE 4-18: PIR1 REGISTER FOR PIC16C64/64A/R64 (ADDRESS 0Ch)

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	
PSPIF pit7	-	_	_	SSPIF	CCP1IF	TMR2IF	TMR1IF bit0	R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 7:	PSPIF: Par 1 = A read 0 = No read	or a write c	peration ha	as taken pla	ce (must be	cleared in s	oftware)	
bit 6:	Reserved:	Always ma	intain this l	bit clear.				
bit 5-4:	Unimplem	ented: Rea	id as '0'					
bit 3:	SSPIF : Syr 1 = The tra 0 = Waiting	nsmission/i	reception is		ag bit must be clea	ured in softw	vare)	
bit 2:	0 = No TMP Compare N	ode 1 register c R1 register <u>Mode</u> 1 register c R1 register <u>₽</u>	apture occ capture oc ompare ma	urred (must curred atch occurre	be cleared in ed (must be c red		oftware)	
bit 1:	TMR2IF : TI 1 = TMR2 t 0 = No TMF	o PR2 mat	ch occurre	d (must be o	bit cleared in so	ftware)		
bit 0:	TMR1IF : TI 1 = TMR1 r 0 = No TMF	register ove	rflow occu		e cleared in	software)		
global		GIE (INTCO						corresponding enable bit or the rrupt flag bits are clear prior to

FIGURE 4-19: PIR1 REGISTER FOR PIC16C65/65A/R65/67 (ADDRESS 0Ch)

R/W-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	
PSPIF pit7	_	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF bit0	R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 7:	PSPIF: Par 1 = A read 0 = No read	or a write c	peration h	as taken pla	ace (must be ce	cleared in s	oftware)	
bit 6:	Reserved:	Always ma	intain this	bit clear.				
bit 5:	RCIF: USA 1 = The US 0 = The US	SART receiv	/e buffer is	full (cleared	d by reading	RCREG)		
bit 4:	TXIF: USA 1 = The US 0 = The US	SART trans	nit buffer is	s empty (cle	eared by writ	ing to TXRE	:G)	
bit 3:	SSPIF : Syr 1 = The tra 0 = Waiting	nsmission/i	reception is		ag bit (must be clea	ared in softw	/are)	
bit 2:	0 = No TM Compare N	ode 1 register c R1 register <u>Mode</u> 1 register c R1 register <u>2</u>	apture occ capture oc ompare ma	urred (must curred atch occurre	be cleared i ed (must be o red	,	oftware)	
bit 1:	TMR2IF : T 1 = TMR2 1 0 = No TM	to PR2 mat	ch occurre	d (must be	bit cleared in so	ftware)		
bit 0:		register ove		rred (must b	be cleared in	software)		

4.2.2.6 PIE2 REGISTER

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Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 This register contains the CCP2 interrupt enable bit.

FIGURE 4-20: PIE2 REGISTER (ADDRESS 8Dh)

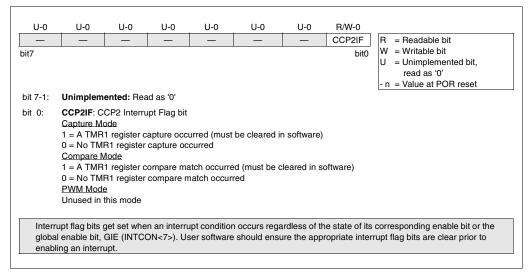
U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	
_	_	_	_	_	_	_	CCP2IE	R = Readable bit
bit7		I	I		I	I	bit0	 W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 7-1:	Unimplem	ented: Rea	ad as '0'					
bit 0:	CCP2IE : C 1 = Enable: 0 = Disable	s the CCP2	interrupt	oit				

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4.2.2.7 PIR2 REGISTER

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 This register contains the CCP2 interrupt flag bit. Note: Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 4-21: PIR2 REGISTER (ADDRESS 0Dh)



4.2.2.8 PCON REGISTER

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The Power Control register (PCON) contains a flag bit to allow differentiation between a Power-on Reset to an external MCLR reset or WDT reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset condition from a Poweron Reset condition. Note: BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if BOR is clear, indicating a brown-out has occurred. The BOR status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

FIGURE 4-22: PCON REGISTER FOR PIC16C62/64/65 (ADDRESS 8Eh)

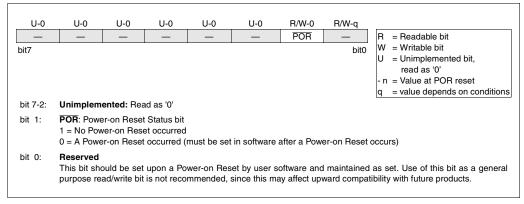
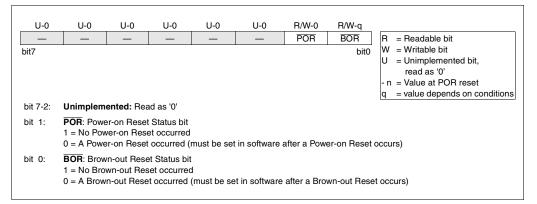


FIGURE 4-23: PCON REGISTER FOR PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67 (ADDRESS 8Eh)

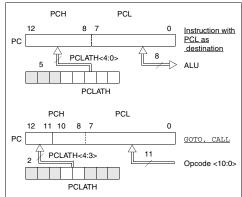


4.3 PCL and PCLATH

Applicable Devices

[61]62]62A R62[63]R63[64]64A R64[65]65A R65[66]67 The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The upper bits (PC<12:8>) are not readable, but are indirectly writable through the PCLATH register. On any reset, the upper bits of the PC will be cleared. Figure 4-24 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 4-24: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 word block). Refer to the application note "Implementing a Table Read" (AN556).

4.3.2 STACK

The PIC16CXX family has an 8 deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or a POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

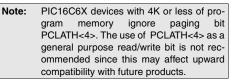
- Note 1: There are no status bits to indicate stack overflows or stack underflow conditions.
- Note 2: There are no instructions mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW, and RETFIE instructions, or the vectoring to an interrupt address

4.4 Program Memory Paging

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

PIC16C6X devices are capable of addressing a continuous 8K word block of program memory. The CALL and GOTO instructions provide only 11 bits of address to allow branching within any 2K program memory page. When doing a CALL or GOTO instruction the upper two bits of the address are provided by PCLATH<4:3>. When doing a CALL or GOTO instruction, the user must ensure that the page select bits are programmed so that the desired program memory page is addressed. If a return from a CALL instruction (or interrupt) is executed, the entire 13-bit PC is pushed onto the stack. Therefore, manipulation of the PCLATH<4:3> bits are not required for the return instructions (which POPs the address from the stack).



Example 4-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that the PCLATH is saved and restored by the interrupt service routine (if interrupts are used).

EXAMPLE 4-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

ORG 0x!	500	
BSF	PCLATH,3	;Select page 1 (800h-FFFh)
BCF	PCLATH,4	;Only on >4K devices
CALL	SUB1_P1	;Call subroutine in
	:	;page 1 (800h-FFFh)
	:	
	:	
ORG 0x	900	
SUB1_P	1:	;called subroutine
	:	;page 1 (800h-FFFh)
	:	
RETURN		;return to Call subroutine
		;in page 0 (000h-7FFh)

4.5 Indirect Addressing, INDF and FSR Registers

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Applicable Devices
61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67
The INDF register is not a physical register. Address- ing the INDF register will cause indirect addressing.
Indirect addressing is possible by using the INDF reg- ister. Any instruction using the INDF register actually accesses the register pointed to by the File Select Reg- ister, FSR. Reading the INDF register itself indirectly (FSR = '0') will produce 00h. Writing to the INDF regis- ter indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-25.

A simple program to clear RAM location 20h-2Fh using indirect addressing is shown in Example 4-2.

EXAMPLE 4-2: INDIRECT ADDRESSING

NEXT	movlw movwf clrf incf btfss	0x20 FSR INDF FSR,F FSR,4	<pre>;initialize pointer ; to RAM ;clear INDF register ;inc pointer ;all done?</pre>
	goto	NEXT	;NO, clear next
CONTINUE			
	:		;YES, continue

Direct Addressing Indirect Addressing RP1: RP0 6 0 IRP 7 FSR 0 from opcode bank select bank select location select location select ▶ 00 01 10 11 -00h 80h 100h 180h Data Memory 7Fh FFh 17Fh 1FFh Bank 0 Bank 1 Bank 3 Bank 2 For memory map detail see Figure 4-5, Figure 4-6, Figure 4-7, and Figure 4-8.

FIGURE 4-25: DIRECT/INDIRECT ADDRESSING

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NOTES:

5.0 I/O PORTS

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Some pins for these I/O ports are multiplexed with an alternate function(s) for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Register

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

All devices have a 6-bit wide PORTA, except for the PIC16C61 which has a 5-bit wide PORTA.

Pin RA4/T0CKI is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers) which can configure these pins as output or input.

Setting a bit in the TRISA register puts the corresponding output driver in a hi-impedance mode. Clearing a bit in the TRISA register puts the contents of the output latch on the selected pin.

Reading PORTA register reads the status of the pins whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified, and then written to the port data latch.

Pin RA4 is multiplexed with Timer0 module clock input to become the RA4/T0CKI pin.

EXAMPLE 5-1: INITIALIZING PORTA

BCF	STATUS,	RP0	;	
BCF	STATUS,	RP1	;	PIC16C66/67 only
CLRF	PORTA		;	Initialize PORTA by
			;	clearing output
			;	data latches
BSF	STATUS,	RP0	;	Select Bank 1
MOVLW	0xCF		;	Value used to
			;	initialize data
			;	direction
MOVWF	TRISA		;	Set RA<3:0> as inputs
			;	RA<5:4> as outputs
			;	TRISA<7:6> are always
			;	read as '0'.

FIGURE 5-1: BLOCK DIAGRAM OF THE RA3:RA0 PINS AND THE RA5

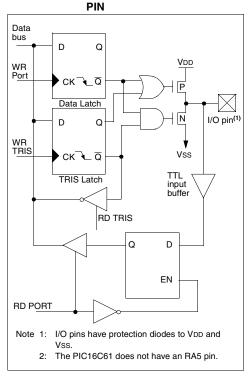
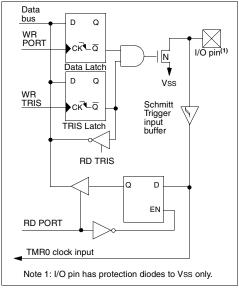


FIGURE 5-2: BLOCK DIAGRAM OF THE RA4/T0CKI PIN



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Name	Bit#	Buffer Type	Function
RA0	bit0	TTL	Input/output
RA1	bit1	TTL	Input/output
RA2	bit2	TTL	Input/output
RA3	bit3	TTL	Input/output
RA4/T0CKI	bit4	ST	Input/output or external clock input for Timer0. Output is open drain type.
RA5/SS (1)	bit5	TTL	Input/output or slave select input for synchronous serial port.

TABLE 5-1: PORTA FUNCTIONS

Legend: TTL = TTL input, ST = Schmitt Trigger input

Note 1: The PIC16C61 does not have PORTA<5> or TRISA<5>, read as '0'.

TABLE 5-2: REGISTERS/BITS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
05h	PORTA	—	—	RA5 ⁽¹⁾	RA4	RA3	RA2	RA1	RA0	xx xxxx	uu uuuu
85h	TRISA		—	PORTA Data	Direction Re	11 1111	11 1111				

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTA. Note 1: PORTA<5> and TRISA<5> are not implemented on the PIC16C61, read as '0'.

5.2 PORTB and TRISB Register

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. Setting a bit in the TRISB register puts the corresponding output driver in a hi-impedance mode. Clearing a bit in the TRISB register puts the contents of the output latch on the selected pin(s).

EXAMPLE 5-2: INITIALIZING PORTB

BCF	STATUS,	RP0	;
CLRF	PORTB		; Initialize PORTB by
			; clearing output
			; data latches
BSF	STATUS,	RP0	; Select Bank 1
MOVLW	0xCF		; Value used to
			; initialize data
			; direction
MOVWF	TRISB		; Set RB<3:0> as inputs
			; RB<5:4> as outputs
			; RB<7:6> as inputs

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overrightarrow{\mathsf{RBPU}}$ (OPTION<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are also disabled on a Power-on Reset.

Four of PORTB's pins, RB7:RB4, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB port change interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

- a) Any read or write of PORTB. This will end the mismatch condition.
- b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition, and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a keypad and make it possible for wake-up on key-depression. Refer to the Embedded Control Handbook, Application Note, *"Implementing Wake-up on Key Stroke"* (AN552).

Note:	For PIC16C61/62/64/65, if a change on the
	I/O pin should occur when a read operation
	is being executed (start of the Q2 cycle),
	then interrupt flag bit RBIF may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 5-3: BLOCK DIAGRAM OF THE RB7:RB4 PINS FOR PIC16C61/62/64/65

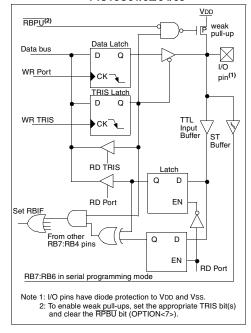
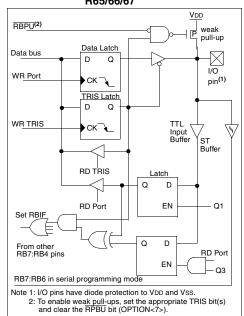


FIGURE 5-4: BLOCK DIAGRAM OF THE RB7:RB4 PINS FOR PIC16C62A/63/R63/64A/65A/ R65/66/67



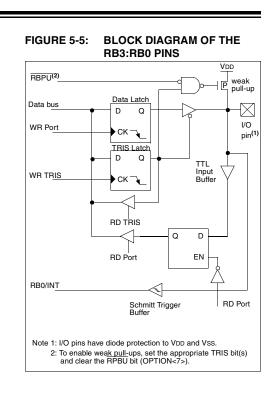


TABLE 5-3: PORTB FUNCTIONS Name Bit# **Buffer Type** Function RB0/INT Input/output pin or external interrupt input. Internal software programmable bit0 TTL/ST(1) weak pull-up. Input/output pin. Internal software programmable weak pull-up. RB1 bit1 TTL RB2 bit2 TTL Input/output pin. Internal software programmable weak pull-up. RB3 TTL Input/output pin. Internal software programmable weak pull-up. bit3 RB4 TTL Input/output pin (with interrupt on change). Internal software programmable bit4 weak pull-up. RB5 bit5 TTL Input/output pin (with interrupt on change). Internal software programmable weak pull-up. RB6 bit6 Input/output pin (with interrupt on change). Internal software programmable TTL/ST(2) weak pull-up. Serial programming clock. RB7 bit7 Input/output pin (with interrupt on change). Internal software programmable TTL/ST(2) weak pull-up. Serial programming data.

Legend: TTL = TTL input, ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in serial programming mode.

TABLE 5-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets	
06h, 106h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuuu	
86h, 186h	TRISB	PORTB D	ata Directior	n Register						1111 1111	1111 1111	
81h, 181h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111	
Legend: 2	egend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.											

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5.3 PORTC and TRISC Register

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

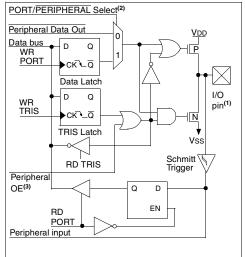
PORTC is an 8-bit wide bi-directional port. Each pin is individually configurable as an input or output through the TRISC register. PORTC is multiplexed with several peripheral functions (Table 5-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modifywrite instructions (BSF, BCF, XORWF) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

EXAMPLE 5-3: INITIALIZING PORTC

BCF	STATUS,	RP0	;	
BCF	STATUS,	RP1	;	PIC16C66/67 only
CLRF	PORTC		;	Initialize PORTC by
			;	clearing output
			;	data latches
BSF	STATUS,	RP0	;	Select Bank 1
MOVLW	0xCF		;	Value used to
			;	initialize data
			;	direction
MOVWF	TRISC		;	Set RC<3:0> as inputs
			;	RC<5:4> as outputs
			;	RC<7:6> as inputs

FIGURE 5-6: PORTC BLOCK DIAGRAM



- Note 1: I/O pins have diode protection to VDD and Vss.
 2: Port/Peripheral select signal selects between port data and peripheral output.
 - 3: Peripheral OE (output enable) is only activated if peripheral select is active.

TABLE 5-5: PORTC FUNCTIONS FOR PIC16C62/64 Name Bit# Buffer Type Function Function

Name	DIL#	Buller Type	Function
RC0/T1OSI/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator input or Timer1 clock input
RC1/T1OSO	bit1	ST	Input/output port pin or Timer1 oscillator output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I ² C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).
RC5/SDO	bit5	ST	Input/output port pin or synchronous serial port data output
RC6	bit6	ST	Input/output port pin
RC7	bit7	ST	Input/output port pin

Legend: ST = Schmitt Trigger input

TABLE 5-6: PORTC FUNCTIONS FOR PIC16C62A/R62/64A/R64

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output or Timer1 clock input
RC1/T1OSI	bit1	ST	Input/output port pin or Timer1 oscillator input
RC2/CCP1	bit2	ST	Input/output port pin or Capture input/Compare output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode).
RC5/SDO	bit5	ST	Input/output port pin or synchronous serial port data output
RC6	bit6	ST	Input/output port pin
RC7	bit7	ST	Input/output port pin

Legend: ST = Schmitt Trigger input

TABLE 5-7: PORTC FUNCTIONS FOR PIC16C63/R63/65/65A/R65/66/67

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output or Timer1 clock input
RC1/T1OSI/CCP2	bit1	ST	Input/output port pin or Timer1 oscillator input or Capture2 input/Compare2 output/PWM2 output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I ² C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode).
RC5/SDO	bit5	ST	Input/output port pin or synchronous serial port data output
RC6/TX/CK	bit6	ST	Input/output port pin or USART Asynchronous Transmit, or USART Syn- chronous Clock
RC7/RX/DT	bit7	ST	Input/output port pin or USART Asynchronous Receive, or USART Syn- chronous Data

Legend: ST = Schmitt Trigger input

TABLE 5-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
07h	PORTC	RC7	RC6	xxxx xxxx	uuuu uuuu						
87h	TRISC	PORTC D	Data Direct	1111 1111	1111 1111						

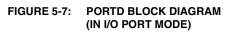
Legend: x = unknown, u = unchanged.

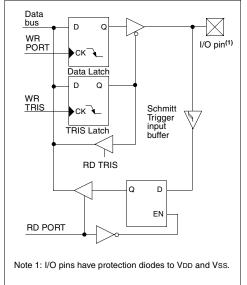
5.4 PORTD and TRISD Register

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

PORTD is an 8-bit port with Schmitt Trigger input buffers. Each pin is individually configurable as input or output.

PORTD can be configured as an 8-bit wide microprocessor port (parallel slave port) by setting control bit PSPMODE (TRISE<4>). In this mode, the input buffers are TTL.





Name	Bit#	Buffer Type	Function
RD0/PSP0	bit0	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit0
RD1/PSP1	bit1	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit1
RD2/PSP2	bit2	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit2
RD3/PSP3	bit3	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit3
RD4/PSP4	bit4	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit4
RD5/PSP5	bit5	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit5
RD6/PSP6	bit6	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit6
RD7/PSP7	bit7	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit7

TABLE 5-9: PORTD FUNCTIONS

Legend: ST = Schmitt Trigger input, TTL = TTL input Note 1: Buffer is a Schmitt Trigger when in I/O mode, and a TTL buffer when in Parallel Slave Port mode.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
08h	PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	uuuu uuuu
88h	TRISD	D PORTD Data Direction Register									1111 1111
89h	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Da	ata Directio	n Bits	0000 -111	0000 -111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTD.

5.5 PORTE and TRISE Register

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

PORTE has three pins, RE2/CS, RE1/WR, and RE0/RD which are individually configurable as inputs or outputs. These pins have Schmitt Trigger input buffers.

I/O PORTE becomes control inputs for the microprocessor port when bit PSPMODE (TRISE<4>) is set. In this mode, the user must make sure that the TRISE<2:0> bits are set (pins are configured as digital inputs). In this mode the input buffers are TTL.

Figure 5-9 shows the TRISE register, which controls the parallel slave port operation and also controls the direction of the PORTE pins.

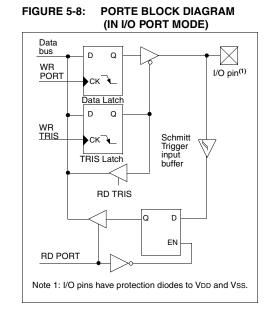


FIGURE 5-9: TRISE REGISTER (ADDRESS 89h)

R-0	R-0	R/W-0	R/W-0	U-0	R/W-1	R/W-1	R/W-1					
IBF	OBF	IBOV	PSPMODE		bit2	bit1	bit0	R = Readable bit				
bit7							bit0	W = Writable bit				
								U = Unimplemented bit, read as '0'				
								- n = Value at POR reset				
bit 7 :	IBF: Input	Buffer Full	Status bit									
	1 = A word 0 = No wor		received and n received	is waiting t	o be read by	the CPU						
bit 6:	OBF: Output Buffer Full Status bit											
5.1 0.	1 = The output buffer still holds a previously written word											
	0 = The output buffer has been read											
bit 5:	IBOV: Input Buffer Overflow Detect bit (in microprocessor mode)											
				usly input v	vord has not	been read	(must be clea	ared in software)				
	0 = No overflow occurred											
bit 4:	1 = Paralle		Slave Port Mo	de Select b	oit							
	0 = Genera											
bit 3:	Unimplem	• •										
bit 0.	•		ction Bits									
bit 2:	-											
DIL 2.	1 = Input	tion Contro	ol bit for pin RI	2/03								
	0 = Output											
bit 1:	Bit1: Direc	tion Contro	ol bit for pin RI	E1/WR								
	1 = Input											
	0 = Output											
bit 0:		tion Contro	ol bit for pin R	E0/RD								
	1 = Input											
	0 = Output											

TABLE 5-11:	PORTE FUNCTIONS

Name	Bit#	Buffer Type	Function
RE0/RD	bit0	ST/TTL ⁽¹⁾	Input/output port pin or Read control input in parallel slave port mode. RD 1 = Not a read operation 0 = Read operation. The system reads the PORTD register (if chip selected)
RE1/WR	bit1	ST/TTL ⁽¹⁾	Input/output port pin or Write control input in parallel slave port mode. WR 1 = Not a write operation 0 = Write operation. The system writes to the PORTD register (if chip selected)
RE2/CS	bit2	ST/TTL ⁽¹⁾	Input/output port pin or Chip select control input in parallel slave port mode. CS 1 = Device is not selected 0 = Device is selected

Legend: ST = Schmitt Trigger input, TTL = TTL input Note 1: Buffer is a Schmitt Trigger when in I/O mode, and a TTL buffer when in Parallel Slave Port (PSP) mode.

TABLE 5-12: SUMMARY OF REGISTERS ASSOCIATED WITH PORTE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
09h	PORTE		—		—		RE2	RE1	RE0	xxx	uuu
89h	TRISE	IBF	OBF	IBOV	PSPMODE		PORTE Data Direction Bits		0000 -111	0000 -111	

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells not used by PORTE.

5.6 I/O Programming Considerations

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

5.6.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (e.g., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-4 shows the effect of two sequential read-modify-write instructions on an I/O port.

FIGURE 5-10: SUCCESSIVE I/O OPERATION

EXAMPLE 5-4: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

;Initial PORT settings: PORTB<7:4> Inputs ; PORTB<3:0> Outputs ;PORTB<7:6> have external pull-ups and are ;not connected to other circuitry

;					PORT	latch	PORT	pins
;								
	BCF	PORTB,	7	;	01pp	pppp	11pp	pppp
	BCF	PORTB,	6	;	10pp	pppp	11pp	pppp
	BSF	STATUS,	RP0	;				
	BCF	TRISB,	7	;	10pp	pppp	11pp	pppp
	BCF	TRISB,	6	;	10pp	pppp	10pp	pppp

;Note that the user may have expected the ;pin values to be 00pp pppp. The 2nd BCF ;caused RB7 to be latched as the pin value ;(high).

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

5.6.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-10). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that fille to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 ' Note: This example shows a write to PORTB PC + 1 PC PC + 2 PC + 3 PC) Instruction fetched followed by a read from PORTB. MOVWF PORTB MOVF PORTB,W NOP write to PORTB NOP Note that: data setup time = (0.25TCY - TPD) RB7:RB0 where $T_{CY} = instruction cycle$ Port pin TPD = propagation delay sampled here Therefore, at higher clock frequencies, Instruction NOP executed a write followed by a read may be prob-MOVWF PORTB MOVF PORTB,W lematic. write to PORTB

5.7 Parallel Slave Port

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

PORTD operates as an 8-bit wide parallel slave port (microprocessor port) when control bit PSPMODE (TRISE<4>) is set. In slave mode it is asynchronously readable and writable by the external world through RD control input (RE0/RD) and WR control input pin (RE1/WR).

It can directly interface to an 8-bit microprocessor data bus. The external microprocessor can read or write the PORTD latch as an 8-bit latch. Setting PSPMODE enables port pin RE0/RD to be the RD input, RE1/WR to be the WR input and RE2/CS to be the CS (chip select) input. For this functionality, the corresponding data direction bits of the TRISE register (TRISE<2:0>) must be configured as inputs (set).

There are actually two 8-bit latches, one for data-out (from the PIC16/17) and one for data input. The user writes 8-bit data to PORTD data latch and reads data from the port pin latch (note that they have the same address). In this mode, the TRISD register is ignored since the microprocessor is controlling the direction of data flow.

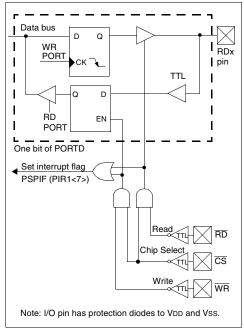
A write to the PSP occurs when both the \overline{CS} and \overline{WR} lines are first detected low. When either the \overline{CS} or \overline{WR} lines become high (level triggered), then the Input Buffer Full status flag bit IBF (TRISE<7>) is set on the Q4 clock cycle, following the next Q2 cycle, to signal the write is complete (Figure 5-12). The interrupt flag bit PSPIF (PIR1<7>) is also set on the same Q4 clock cycle. IBF can only be cleared by reading the PORTD input latch. The input Buffer Overflow status flag bit IBOV (TRISE<5>) is set if a second write to the Parallel Slave Port is attempted when the previous byte has not been read out of the buffer.

A read from the PSP occurs when both the \overline{CS} and \overline{RD} lines are first detected low. The Output Buffer Full status flag bit OBF (TRISE<6>) is cleared immediately (Figure 5-13) indicating that the PORTD latch is waiting to be read by the external bus. When either the \overline{CS} or \overline{RD} pin becomes high (level triggered), the interrupt flag bit PSPIF is set on the Q4 clock cycle, following the next Q2 cycle, indicating that the read is complete. OBF remains low until data is written to PORTD by the user firmware.

When not in Parallel Slave Port mode, the IBF and OBF bits are held clear. However, if flag bit IBOV was previously set, it must be cleared in firmware.

An interrupt is generated and latched into flag bit PSPIF when a read or write operation is completed. PSPIF must be cleared by the user in firmware and the interrupt can be disabled by clearing the interrupt enable bit PSPIE (PIE1<7>).

FIGURE 5-11: PORTD AND PORTE AS A PARALLEL SLAVE PORT



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FIGURE 5-12: PARALLEL SLAVE PORT WRITE WAVEFORMS

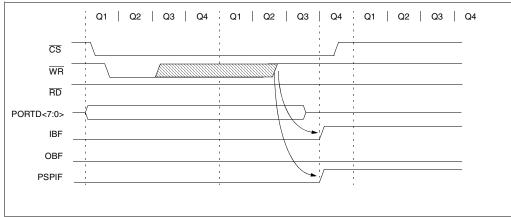


FIGURE 5-13: PARALLEL SLAVE PORT READ WAVEFORMS

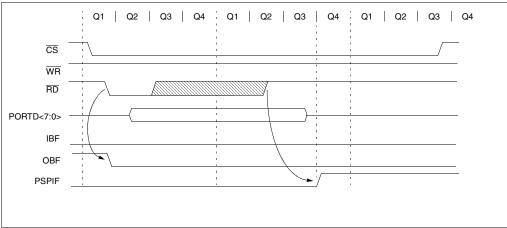


TABLE 5-13: REGISTERS ASSOCIATED WITH PARALLEL SLAVE PORT

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
08h	PORTD	PSP7	PSP6	PSP5	PSP4	PSP3	PSP2	PSP1	PSP0	xxxx xxxx	uuuu uuuu
09h	PORTE		_		_	_	RE2	RE1	RE0	xxx	uuu
89h	TRISE	IBF	OBF	IBOV	PSPMODE	_	PORTE D	ata Directior	Bits	0000 -111	0000 -111
0Ch	PIR1	PSPIF	(1)	RCIF ⁽²⁾	TXIF ⁽²⁾	SSPIF	CCP1IF	TMR2IF	TRM1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE	(1)	RCIE ⁽²⁾	TXIE ⁽²⁾	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by the PSP.

Note 1: These bits are reserved, always maintain these bits clear.

2: These bits are implemented on the PIC16C65/65A/R65/67 only.

6.0 OVERVIEW OF TIMER MODULES

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

All PIC16C6X devices have three timer modules except for the PIC16C61, which has one timer module. Each module can generate an interrupt to indicate that an event has occurred (i.e., timer overflow). Each of these modules are detailed in the following sections. The timer modules are:

- Timer0 module (Section 7.0)
- Timer1 module (Section 8.0)
- Timer2 module (Section 9.0)

6.1 <u>Timer0 Overview</u>

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The Timer0 module is a simple 8-bit overflow counter. The clock source can be either the internal system clock (Fosc/4) or an external clock. When the clock source is an external clock, the Timer0 module can be selected to increment on either the rising or falling edge.

The Timer0 module also has a programmable prescaler option. This prescaler can be assigned to either the Timer0 module or the Watchdog Timer. Bit PSA (OPTION<3>) assigns the prescaler, and bits PS2:PS0 (OPTION<2:0>) determine the prescaler value. TMR0 can increment at the following rates: 1:1 when the prescaler is assigned to Watchdog Timer, 1:2, 1:4, 1:8, 1:16, 1:32, 1:64, 1:128, and 1:256.

Synchronization of the external clock occurs after the prescaler. When the prescaler is used, the external clock frequency may be higher then the device's frequency. The maximum frequency is 50 MHz, given the high and low time requirements of the clock.

6.2 <u>Timer1 Overview</u>

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Timer1 is a 16-bit timer/counter. The clock source can be either the internal system clock (Fosc/4), an external clock, or an external crystal. Timer1 can operate as either a timer or a counter. When operating as a counter (external clock source), the counter can either operate synchronized to the device or asynchronously to the device. Asynchronous operation allows Timer1 to operate during sleep, which is useful for applications that require a real-time clock as well as the power savings of SLEEP mode.

TImer1 also has a prescaler option which allows TMR1 to increment at the following rates: 1:1, 1:2, 1:4, and 1:8. TMR1 can be used in conjunction with the Capture/Compare/PWM module. When used with a CCP module, Timer1 is the time-base for 16-bit capture or 16-bit compare and must be synchronized to the device.

6.3 <u>Timer2 Overview</u>

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Timer2 is an 8-bit timer with a programmable prescaler and a programmable postscaler, as well as an 8-bit Period Register (PR2). Timer2 can be used with the CCP module (in PWM mode) as well as the Baud Rate Generator for the Synchronous Serial Port (SSP). The prescaler option allows Timer2 to increment at the following rates: 1:1, 1:4, and 1:16.

The postscaler allows TMR2 register to match the period register (PR2) a programmable number of times before generating an interrupt. The postscaler can be programmed from 1:1 to 1:16 (inclusive).

6.4 CCP Overview

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The CCP module(s) can operate in one of three modes: 16-bit capture, 16-bit compare, or up to 10-bit Pulse Width Modulation (PWM).

Capture mode captures the 16-bit value of TMR1 into the CCPRxH:CCPRxL register pair. The capture event can be programmed for either the falling edge, rising edge, fourth rising edge, or sixteenth rising edge of the CCPx pin.

Compare mode compares the TMR1H:TMR1L register pair to the CCPRxH:CCPRxL register pair. When a match occurs, an interrupt can be generated and the output pin CCPx can be forced to a given state (High or Low) and Timer1 can be reset. This depends on control bits CCPxM3:CCPxM0.

PWM mode compares the TMR2 register to a 10-bit duty cycle register (CCPRxH:CCPRxL<5:4>) as well as to an 8-bit period register (PR2). When the TMR2 register = Duty Cycle register, the CCPx pin will be forced low. When TMR2 = PR2, TMR2 is cleared to 00h, an interrupt can be generated, and the CCPx pin (if an output) will be forced high.

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NOTES:

7.0 TIMER0 MODULE

 Applicable Devices

 61
 62
 62
 R62
 63
 R63
 64
 64
 R64
 65
 65
 R65
 66
 67

The Timer0 module has the following features:

- 8-bit timer/counter register, TMR0
 - Read and write capability
- Interrupt on overflow from FFh to 00h
- 8-bit software programmable prescaler
- Internal or external clock select
 - Edge select for external clock

Figure 7-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing bit TOCS (OPTION<5>). In timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 register is written, the increment is inhibited for the following two instruction cycles (Figure 7-2 and Figure 7-3). The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting bit T0CS. In this mode, Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge select bit T0SE

FIGURE 7-1: TIMER0 BLOCK DIAGRAM

(OPTION<4>). Clearing bit T0SE selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 7.2.

The prescaler is mutually exclusively shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by control bit PSA (OPTION<3>). Clearing bit PSA will assign the prescaler to the Timer0 module. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4, ..., 1:256 are selectable. Section 7.3 details the operation of the prescaler.

7.1 TMR0 Interrupt

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The TMR0 interrupt is generated when the register (TMR0) overflows from FFh to 00h. This overflow sets interrupt flag bit T0IF (INTCON<2>). The interrupt can be masked by clearing enable bit T0IE (INTCON<5>). Flag bit T0IF must be cleared in software by the TImer0 interrupt service routine before re-enabling this interrupt. The TMR0 interrupt cannot wake the processor from SLEEP since the timer is shut off during SLEEP. Figure 7-4 displays the Timer0 interrupt timing.

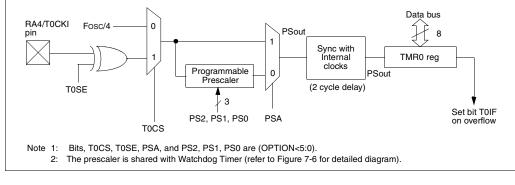


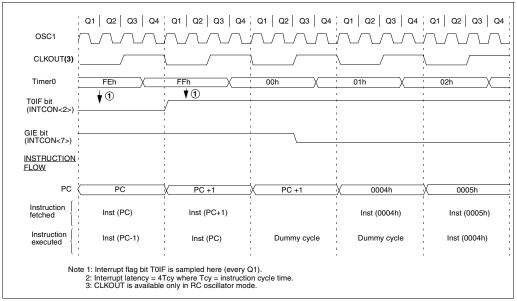
FIGURE 7-2: TIMER0 TIMING: INTERNAL CLOCK/NO PRESCALER

(Program	1	1	1	1	1	1	i i	
Counter)	PC-1) PC) PC+1	PC+2) PC+3	(PC+4	PC+5)	PC+6
Instruction Fetch		MOVWF TMR0	MOVF TMR0,W	MOVF TMR0,W	MOVF TMR0,W	MOVF TMR0,W	MOVF TMR0,W	
TMR0	χ	Τ0+1 χ	Τ0+2 χ	ΝΤΟ Χ	ΝΤΟ Χ		NT0+1 χ	NT0+2 χ
Instruction	1	1 1 1		4		. ▲	4	4
Executed			Write TMR0	Read TMR0 reads NT0	Read TMR0 reads NT0	Read TMR0 reads NT0	Read TMR0 reads NT0 + 1	Read TMR0 reads NT0 + 2

FIGURE 7-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2

Program Sounter)	PC-1	¥ PC	Y PC+1	Q1 Q2 Q3 Q4	PC+3	PC+4	PC+5	PC+6
struction		MOVWF TMR0	i	î	1	1	MOVF TMR0,W	
MR0	το χ	T0+1	X	1 1 1	NT0	 		NT0+1)(
struction xecute	1 1 1	1 1 1	Write TMR0 executed	Read TMR0 reads NT0 + 1				

FIGURE 7-4: TMR0 INTERRUPT TIMING



7.2 Using Timer0 with External Clock

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (Tosc). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

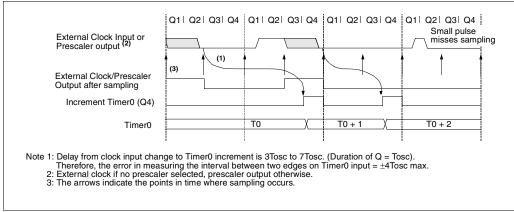
7.2.1 EXTERNAL CLOCK SYNCHRONIZATION

When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 7-5). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device. When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for TOCKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on TOCKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

7.2.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 7-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 7-5: TIMER0 TIMING WITH EXTERNAL CLOCK



7.3 Prescaler

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

An 8-bit counter is available as a prescaler for the Timer0 module or as a postscaler for the Watchdog Timer (WDT), respectively (Figure 7-6). For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that the prescaler may be used by either the Timer0 module or the Watchdog Timer, but not both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer, and vice-versa.

The PSA and PS2:PS0 bits (OPTION<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g. CLRF TMR0, MOVWF TMR0, BSF TMR0, bitx) will clear the prescaler count. When assigned to the Watchdog Timer, a CLRWDT instruction will clear the Watchdog Timer and the prescaler count. The prescaler is not readable or writable.

Note: Writing to TMR0 when the prescaler is assigned to Timer0 will clear the prescaler count, but will not change the prescaler assignment.

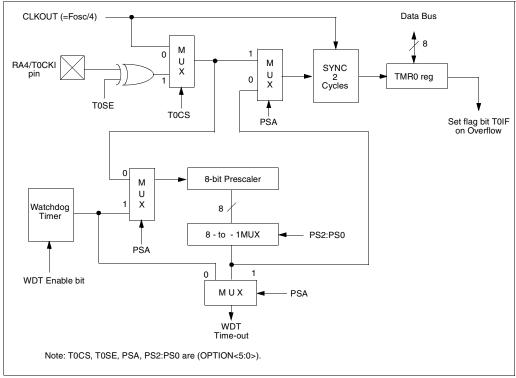


FIGURE 7-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER

7.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control, i.e., it can be changed "on the fly" during program execution.

Note:	To avoid an unintended device RESET, the
	following instruction sequence (shown in
	Example 7-1) must be executed when
	changing the prescaler assignment from
	Timer0 to the WDT. This precaution must
	be followed even if the WDT is disabled.

EXAMPLE 7-1: CHANGING PRESCALER (TIMER0 \rightarrow WDT)

	1)	BSF	STATUS, RPO	;Bank 1			
Lines 2 and 3 do NOT have to be included if the final desired prescale value is other than 1:1. If 1:1 is final desired value, then a temporary prescale value is set in lines 2 and 3 and the final prescale value will be set in lines 10 and 11.	2)	MOVLW	b'xx0x0xxx'	;Select clock source and prescale value of			
	3)	MOVWF	OPTION_REG	;other than 1:1			
	4)	BCF	STATUS, RPO	;Bank 0			
	5)	CLRF	TMR0	;Clear TMR0 and prescaler			
	6)	BSF	STATUS, RP1	;Bank 1			
	7)	MOVLW	b'xxxx1xxx'	;Select WDT, do not change prescale value			
	8)	MOVWF	OPTION_REG	;			
	9)	CLRWDT		;Clears WDT and prescaler			
	10)	MOVLW	b'xxxx1xxx'	;Select new prescale value and WDT			
	11)	MOVWF	OPTION_REG	;			
	12)	BCF	STATUS, RPO	;Bank 0			

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 7-2.

EXAMPLE 7-2: CHANGING PRESCALER (WDT→TIMER0)

CLRWDT		;Clear WDT and prescaler				
BSF	STATUS, RPO	;Bank 1				
MOVLW	b'xxxx0xxx'	;Select TMR0, new prescale value and clock source				
MOVWF	OPTION_REG	;				
BCF	STATUS, RPO	;Bank 0				

TABLE 7-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h, 101h	TMR0	Timer0	Timer0 module's register						xxxx xxxx	uuuu uuuu	
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE ⁽¹⁾	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
81h, 181h	OPTION	RBPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	_	_	PORTA Data Direction Register ⁽¹⁾				11 1111	11 1111		

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

Note 1: TRISA<5> and bit PEIE are not implemented on the PIC16C61, read as '0'.

NOTES:

8.0 TIMER1 MODULE

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Timer1 is a 16-bit timer/counter consisting of two 8-bit registers (TMR1H and TMR1L) which are readable and writable. Register TMR1 (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 Interrupt, if enabled, is generated on overflow which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing the TMR1 interrupt enable bit TMR1IE (PIE1<0>).

Timer1 can operate in one of two modes:

As a timer

· As a counter

The operating mode is determined by clock select bit, TMR1CS (T1CON<1>) (Figure 8-2).

In timer mode, Timer1 increments every instruction cycle. In counter mode, it increments on every rising edge of the external clock input.

Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Timer1 also has an internal "reset input". This reset can be generated by CCP1 or CCP2 (Capture/Compare/ PWM) module. See Section 10.0 for details. Figure 8-1 shows the Timer1 control register.

For the PIC16C62A/R62/63/R63/64A/R64/65A/R65/ R66/67, when the Timer1 oscillator is enabled (T10SCEN is set), the RC1 and RC0 pins become inputs. That is, the TRISC<1:0> value is ignored.

For the PIC16C62/64/65, when the Timer1 oscillator is enabled (T1OSCEN is set), RC1 pin becomes an input, however the RC0 pin will have to be configured as an input by setting the TRISC<0> bit.

The Timer1 module also has a software programmable prescaler.

U-0 U-0 R/W-0 R/W-0 R/W-0 **R/W-0** R/W-0 R/W-0 TMR1CS TMR1ON T1CKPS1 T1CKPS0 T1OSCEN T1SYNC R = Readable bit w = Writable bit bit7 bit0 11 = Unimplemented bit, read as '0' n = Value at POR reset Unimplemented: Read as '0' bit 7-6: T1CKPS1:T1CKPS0: Timer1 Input Clock Prescale Select bits bit 5-4: 11 = 1:8 Prescale value 10 = 1:4 Prescale value 01 = 1:2 Prescale value 00 = 1:1 Prescale value T1OSCEN: Timer1 Oscillator Enable Control bit bit 3: 1 = Oscillator is enabled 0 = Oscillator is shut off Note: The oscillator inverter and feedback resistor are turned off to eliminate power drain. bit 2: TISYNC: Timer1 External Clock Input Synchronization Control bit TMR1CS = 11 = Do not synchronize external clock input 0 = Synchronize external clock input TMR1CS = 0This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0. TMR1CS: Timer1 Clock Source Select bit bit 1: 1 = External clock from T1OSI (on the rising edge) (See pinouts for pin with T1OSI function) 0 = Internal clock (Fosc/4) bit 0: TMR10N: Timer1 On bit 1 = Enables Timer1 0 = Stops Timer1

FIGURE 8-1: T1CON: TIMER1 CONTROL REGISTER (ADDRESS 10h)

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8.1 Timer1 Operation in Timer Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Timer mode is selected by clearing bit TMR1CS (T1CON<1>). In this mode, the input clock to the timer is Fosc/4. The synchronize control bit T1SYNC (T1CON<2>) has no effect since the internal clock is always in sync.

8.2 <u>Timer1 Operation in Synchronized</u> Counter Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Counter mode is selected by setting bit TMR1CS. In this mode the timer increments on every rising edge of clock input on T1OSI when enable bit T1OSCEN is set or pin with T1CKI when bit T1OSCEN is cleared.

Note:	The T1OSI function is multiplexed to differ-
	ent pins, depending on the device. See the
	pinout descriptions to see which pin has
	the T1OSI function.

If T1SYNC is cleared, then the external clock input is synchronized with internal phase clocks. The synchronization is done after the prescaler stage. The prescaler stage is an asynchronous ripple counter.

In this configuration, during SLEEP mode, Timer1 will not increment even if an external clock is present, since the synchronization circuit is shut off. The prescaler, however, will continue to increment.

8.2.1 EXTERNAL CLOCK INPUT TIMING FOR SYNCHRONIZED COUNTER MODE

When an external clock input is used for Timer1 in synchronized counter mode, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of TMR1 after synchronization.

When the prescaler is 1:1, the external clock input is the same as the prescaler output. The synchronization of T1CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks. Therefore, it is necessary for T1CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to appropriate electrical specification section, parameters 45, 46, and 47.

When a prescaler other than 1:1 is used, the external clock input is divided by the asynchronous ripple-counter type prescaler so that the prescaler output is symmetrical. In order for the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T1CKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T1CKI high and low time is that they do not violate the minimum pulse width requirements of 10 ns). Refer to applicable electrical specification section, parameters 40, 42, 45, 46, and 47.

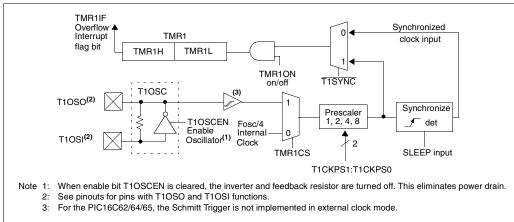


FIGURE 8-2: TIMER1 BLOCK DIAGRAM

8.3 <u>Timer1 Operation in Asynchronous</u> <u>Counter Mode</u>

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

If control bit $\overline{T1SYNC}$ (T1CON<2>) is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during SLEEP and generate an interrupt on overflow which will wake the processor. However, special precautions in software are needed to read-from or write-to the Timer1 register pair, TMR1L and TMR1H (Section 8.3.2).

In asynchronous counter mode, Timer1 cannot be used as a time-base for capture or compare operations.

8.3.1 EXTERNAL CLOCK INPUT TIMING WITH UNSYNCHRONIZED CLOCK

If control bit $\overline{T1SYNC}$ is set, the timer will increment completely asynchronously. The input clock must meet certain minimum high time and low time requirements, as specified in timing parameters (45 - 47).

8.3.2 READING AND WRITING TMR1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L, while the timer is running from an external asynchronous clock, will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself poses certain problems since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. Example 8-1 is an example routine to read the 16-bit timer value. This is useful if the timer cannot be stopped.

EXAMPLE 8-1: READING A 16-BIT FREE-RUNNING TIMER

;	All Int	errupts	are	disabled
	MOVF	TMR1H,	W	;Read high byte
	MOVWF	TMPH		;
	MOVF	TMR1L,	W	;Read low byte
	MOVWF	TMPL		;
	MOVF	TMR1H,	W	;Read high byte
	SUBWF	TMPH,	W	;Sub 1st read
				;with 2nd read
	BTFSC	STATUS	, Z	;is result = 0
	GOTO	CONTIN	UE	;Good 16-bit read
;	TMR1L may	y have r	olle	d over between the read
;	of the h	igh and	low	bytes. Reading the high
;	and low	bytes no	ow wa	ill read a good value.
	MOVF	TMR1H,	W	;Read high byte
	MOVWF	TMPH		;
	MOVF	TMR1L,	W	;Read low byte
	MOVWF	TMPL		;
;	Re-enal	ble Inte	errup	ot (if required)
C	ONTINUE			;Continue with
	:			;your code

8.4 Timer1 Oscillator

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

A crystal oscillator circuit is built in-between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low power oscillator rated up to 200 kHz. It will continue to run during SLEEP. It is primarily intended for a 32 kHz crystal. Table 8-1 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is identical to the LP oscillator. The user must allow a software time delay to ensure proper oscillator start-up.

TABLE 8-1: CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR

Osc Type	è	Freq	C1	C2					
LP		32 kHz	33 pF	33 pF					
		100 kHz	15 pF	15 pF					
	200 kHz 15 pF 15 pF								
These values are for design guidance only.									
Crystals Tested:									
32.768 kH	2.768 kHz Epson C-001R32.768K-A ± 20 PF								
100 kHz		Epson C-2 1	00.00 KC-P	\pm 20 PPM					
200 kHz		STD XTL 20	0.000 kHz	\pm 20 PPM					
o ti 2: S c	Higher capacitance increases the stability of oscillator but also increases the start-up time. Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropri-								

8.5 <u>Resetting Timer1 using a CCP Trigger</u> Output

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

CCP2 is implemented on the PIC16C63/R63/65/65A/ R65/66/67 only.

If CCP1 or CCP2 module is configured in Compare mode to generate a "special event trigger" (CCPxM3:CCPxM0 = 1011), this signal will reset Timer1.

Note:	The "special		event	trigger"	from	the	
	CCP1 and CCP2 modules will not set inter-						
	rupt flag bit TMR1IF(PIR1<0>).						

Timer1 must be configured for either timer or synchronized counter mode to take advantage of this feature. If the Timer1 is running in asynchronous counter mode, this reset operation may not work.

In the event that a write to Timer1 coincides with a special event trigger from CCP1 or CCP2, the write will take precedence.

In this mode of operation, the CCPRxH:CCPRxL registers pair effectively becomes the period register for the Timer1 module.

8.6 <u>Resetting of TMR1 Register Pair</u> (TMR1H:TMR1L)

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The TMR1H and TMR1L registers are not reset to 00h on a POR or any other reset except by the CCP1 or CCP2 special event trigger.

The T1CON register is reset to 00h on a Power-on Reset or a Brown-out Reset, which shuts off the timer and leaves a 1:1 prescaler. In all other resets, the register is unaffected.

8.7 <u>Timer1 Prescaler</u>

	Ap	pli	cable	e Dev	/ice	es								
--	----	-----	-------	-------	------	----	--	--	--	--	--	--	--	--

616262A R6263 R636464A R646565A R656667 The prescaler counter is cleared on writes to the TMR1H or TMR1L registers.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	PC	e on:)R,)R	all c	e on other sets
0Bh,8Bh 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000	000x	0000	000u
0Ch	PIR1	PSPIF ⁽²⁾	(3)	RCIF ⁽¹⁾	TXIF ⁽¹⁾	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000	0000	0000	0000
8Ch	PIE1	PSPIE ⁽²⁾	(3)	RCIE ⁽¹⁾	TXIE ⁽¹⁾	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000	0000	0000	0000
0Eh	TMR1L	Holding re	lolding register for the Least Significant Byte of the 16-bit TMR1 register									uuuu	
0Fh	TMR1H	Holding re	olding register for the Most Significant Byte of the 16-bit TMR1 register										
10h	T1CON	_	_	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00	0000	uu	uuuu

TABLE 8-2: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by the Timer1 module.

Note 1: The USART is implemented on the PIC16C63/R63/65/65A/R65/66/67 only.

2: Bits PSPIE and PSPIF are reserved on the PIC16C62/62A/R62/63/R63/66, always maintain these bits clear.

3: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

9.0 TIMER2 MODULE

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Timer2 is an 8-bit timer with a prescaler and a postscaler. It is especially suitable as PWM time-base for PWM mode of CCP module(s). TMR2 is a readable and writable register, and is cleared on any device reset.

The input clock (FOSC/4) has a prescale option of 1:1, 1:4 or 1:16, selected by control bits T2CKPS1:T2CKPS0 (T2CON<1:0>).

The Timer2 module has an 8-bit period register, PR2. Timer2 increments from 00h until it matches PR2 and then resets to 00h on the next increment cycle. PR2 is a readable and writable register. The PR2 register is initialized to FFh upon reset.

The match output of the TMR2 register goes through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling, inclusive) to generate a TMR2 interrupt (latched in flag bit TMR2IF (PIR1<1>)).

The Timer2 module can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 9-2 shows the Timer2 control register. T2CON is cleared upon reset which initializes Timer2 as shut off with the prescaler and postscaler at a 1:1 value.

9.1 <u>Timer2 Prescaler and Postscaler</u> Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- · a write to the T2CON register
- any device reset (POR, BOR, MCLR Reset, or WDT Reset).
- TMR2 is not cleared when T2CON is written.

9.2 Output of TMR2

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The output of TMR2 (before the postscaler) is fed to the Synchronous Serial Port module which optionally uses it to generate shift clock.

FIGURE 9-1: TIMER2 BLOCK DIAGRAM

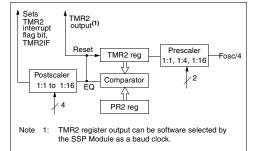


FIGURE 9-2: T2CON: TIMER2 CONTROL REGISTER (ADDRESS 12h)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	R = Readable bit
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 7:	Unimplem	ented: Rea	d as '0'					
bit 6-3:	TOUTPS3: 0000 = 1:1 0001 = 1:2 1111 = 1:1	postscale postscale		tput Postsc	ale Select bi	ts		
bit 2:	TMR2ON : 1 1 = Timer2 0 = Timer2	is on	bit					
bit 1-0:	T2CKPS1: 00 = 1:1 pr 01 = 1:4 pr 1x = 1:16 p	escale escale	Timer2 Clo	ick Prescale	e Select bits			

TABLE 9-1:	REGISTERS ASSOCIATED WITH TIMER2 AS A TIMER/COUNTER	

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	PC	e on: DR, DR		e on other sets
0Bh,8Bh 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000	000x	0000	000u
0Ch	PIR1	PSPIF ⁽²⁾	(3)	RCIF ⁽¹⁾	TXIF ⁽¹⁾	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000	0000	0000	0000
8Ch	PIE1	PSPIE ⁽²⁾	(3)	RCIE ⁽¹⁾	TXIE ⁽¹⁾	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000	0000	0000	0000
11h	TMR2	Timer2 m	imer2 module's register 0000 0000 0000 0000									0000	
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000	0000	-000	0000
92h	PR2	Timer2 P	ner2 Period register 1111 1111 1111 1111										

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer2. Note 1: The USART is implemented on the PIC16C63/R63/65/65A/R65/66/67 only. 2: Bits PSPIE and PSPIF are reserved on the PIC16C62/62A/R62/63/R63/66, always maintain these bits clear.

3: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

10.0 CAPTURE/COMPARE/PWM (CCP) MODULE(s)

Applicable Devices

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CCP1 module:

Capture/Compare/PWM Register1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. All are readable and writable.

CCP2 module:

Capture/Compare/PWM Register2 (CCPR2) is comprised of two 8-bit registers: CCPR2L (low byte) and CCPR2H (high byte). The CCP2CON register controls the operation of CCP2. All are readable and writable.

For use of the CCP modules, refer to the *Embedded Control Handbook*, "Using the CCP Modules" (AN594).

TABLE 10-1: CCP MODE - TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

TABLE 10-2: INTERACTION OF TWO CCP MODULES

CCPx Mode	CCPy Mode	Interaction
Capture	Capture	Same TMR1 time-base.
Capture	Compare	The compare should be configured for the special event trigger, which clears TMR1.
Compare	Compare	The compare(s) should be configured for the special event trigger, which clears TMR1.
PWM	PWM	The PWMs will have the same frequency, and update rate (TMR2 interrupt).
PWM	Capture	None
PWM	Compare	None

FIGURE 10-1: CCP1CON REGISTER (ADDRESS 17h) / CCP2CON REGISTER (ADDRESS 1Dh)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
—	—	CCPxX	CCPxY	CCPxM3	CCPxM2	CCPxM1	CCPxM0	R = Readable bit		
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n =Value at POR reset		
bit 7-6:	Unim	plemente	d: Read a	ıs '0'						
bit 5-4:	bit 5-4: CCPxY: PWM Least Significant bits <u>Capture Mode</u> Unused <u>Compare Mode</u> Unused <u>PWM Mode</u> These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.									
bit 3-0:	 3-0: CCPxM3:CCPxM0: CCPx Mode Select bits 0000 = Capture/Compare/PWM off (resets CCPx module) 0100 = Capture mode, every falling edge 0101 = Capture mode, every 4th rising edge 0111 = Capture mode, every 16th rising edge 1000 = Compare mode, set output on match (bit CCPxIF is set) 1001 = Compare mode, clear output on match (bit CCPxIF is set) 1010 = Compare mode, generate software interrupt on match (bit CCPxIF is set, CCPx pin is unaffected) 1011 = Compare mode, trigger special event (CCPxIF bit is set; CCP1 resets TMR1; CCP2 resets TMR1) 11xx = PWM mode 									

10.1 Capture Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RC2/CCP1 (Figure 10-2). An event is defined as:

- · Every falling edge
- · Every rising edge
- · Every 4th rising edge
- · Every 16th rising edge

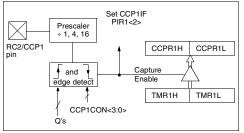
An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

10.1.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1 pin should be configured as an input by setting the TRISC<2> bit.

Note: If the RC2/CCP1 pin is configured as an output, a write to PORTC can cause a capture condition.

FIGURE 10-2: CAPTURE MODE OPERATION BLOCK DIAGRAM



10.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work consistently.

10.1.3 SOFTWARE INTERRUPT

When the Capture event is changed, a false capture interrupt may be generated. The user should clear enable bit CCP1IE (PIE1<2>) to avoid false interrupts and should clear flag bit CCP1IF following any such change in operating mode.

10.1.4 CCP PRESCALER

There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore the first capture may be from a non-zero prescaler. Example 10-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the "false" interrupt.

EXAMPLE 10-1: CHANGING BETWEEN CAPTURE PRESCALERS

CLRF	CCP1CON	;	Turn CCP module off
MOVLW	NEW_CAPT_PS	;	Load the W reg with
		;	the new prescaler
		;	mode value and CCP ON
MOVWF	CCP1CON	;	Load CCP1CON with
; this	value		

10.2 Compare Mode

Applicable Devices

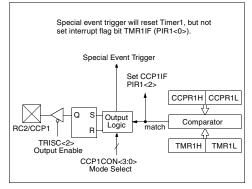
61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the RC2/CCP1 pin is:

- Driven High
- Driven Low
- · Remains Unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). At the same time interrupt flag bit CCP1IF is set.

FIGURE 10-3: COMPARE MODE OPERATION BLOCK DIAGRAM



10.2.1 CCP PIN CONFIGURATION

The user must configure the RC2/CCP1 pin as an output by clearing the TRISC<2> bit.

Note:	Clearing the CCP1CON register will force
	the RC2/CCP1 compare output latch to the
	default low level. This is not the data latch.

10.2.1 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

10.2.2 SOFTWARE INTERRUPT MODE

When Generate Software Interrupt is chosen, the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

10.2.3 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated which may be used to initiate an action.

The special event trigger output of CCP1 and CCP2 resets the TMR1 register pair. This allows the CCPR1H:CCPR1L and CCPR2H:CCPR2L registers to effectively be 16-bit programmable period register(s) for Timer1.

For compatibility issues, the special event trigger output of CCP1 (<u>PIC16C72</u>) and CCP2 (all other <u>PIC16C7X</u> devices) also starts an A/D conversion.

Note:	The	"special	event	trigger"	from	the				
	CCP1and CCP2 modules will not set inte									
	rupt flag bit TMR1IF (PIR1<0>).									

10.3 PWM Mode

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

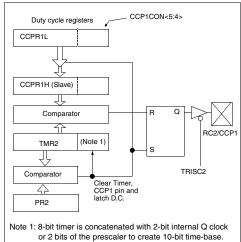
In Pulse Width Modulation (PWM) mode, the CCP1 pin produces up to a 10-bit resolution PWM output. Since the CCP1 pin is multiplexed with the PORTC data latch, the TRISC<2> bit must be cleared to make the CCP1 pin an output.

Note: Clearing the CCP1CON register will force the CCP1 PWM output latch to the default low level. This is not the PORTC I/O data latch.

Figure 10-4 shows a simplified block diagram of the CCP module in PWM mode.

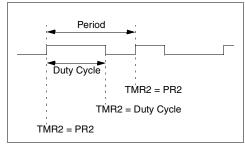
For a step by step procedure on how to set up the CCP module for PWM operation, see Section 10.3.3.

FIGURE 10-4: SIMPLIFIED PWM BLOCK DIAGRAM



A PWM output (Figure 10-5) has a time base (period) and a time that the output stays high (duty cycle). The frequency of the PWM is the inverse of the period (1/period).

FIGURE 10-5: PWM OUTPUT



10.3.1 PWM PERIOD

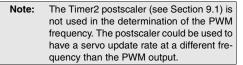
The PWM period is specified by writing to the PR2 register. The PWM period can be calculated using the following formula:

PWM period = [(PR2) + 1] • 4 • TOSC • (TMR2 prescale value)

PWM frequency is defined as 1 / [PWM period].

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The PWM duty cycle is latched from CCPR1L into CCPR1H
- The CCP1 pin is set (exception: if PWM duty cycle = 0%, the CCP1 pin will not be set)



10.3.2 PWM DUTY CYCLE

The PWM duty cycle is specified by writing to the CCPR1L register and to the CCP1CON<5:4> bits. Up to 10-bit resolution is available: the CCPR1L contains the eight MSbs and the CCP1CON<5:4> contains the two LSbs. This 10-bit value is represented by CCPR1L:CCP1CON<5:4>. The following equation is used to calculate the PWM duty cycle in time:

PWM duty cycle = (CCPR1L:CCP1CON<5:4>) • Tosc • (TMR2 prescale value)

CCPR1L and CCP1CON<5:4> can be written to at any time, but the duty cycle value is not latched into CCPR1H until after a match between PR2 and TMR2 occurs (i.e., the period is complete). In PWM mode, CCPR1H is a read-only register.

The CCPR1H register and a 2-bit internal latch are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

When the CCPR1H and 2-bit latch match TMR2 concatenated with an internal 2-bit Q clock or 2 bits of the TMR2 prescaler, the CCP1 pin is cleared.

Maximum PWM resolution (bits) for a given PWM frequency:

$$= \frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log(2)} \quad \text{bits}$$

Note: If the PWM duty cycle value is longer than the PWM period the CCP1 pin will not be forced to the low level.

EXAMPLE 10-2: PWM PERIOD AND DUTY CYCLE CALCULATION

Desired PWM frequency is 78.125 kHz, Fosc = 20 MHz TMR2 prescale = 1

 $1/78.125 \text{ kHz} = [(PR2) + 1] \cdot 4 \cdot 1/20 \text{ MHz} \cdot 1$

12.8 μ s = [(PR2) + 1] • 4 • 50 ns • 1

PR2 = 63

Find the maximum resolution of the duty cycle that can be used with a 78.125 kHz frequency and 20 MHz oscillator:

1/78.125 kHz	$= 2^{\text{PWM RESOLUTION}} \bullet 1/20 \text{ MHz} \bullet 1$
12.8 µs	= $2^{\text{PWM RESOLUTION}} \bullet 50 \text{ ns} \bullet 1$
256	$= 2^{\text{PWM RESOLUTION}}$
log(256)	= (PWM Resolution) • $log(2)$
8.0	= PWM Resolution

At most, an 8-bit resolution duty cycle can be obtained from a 78.125 kHz frequency and a 20 MHz oscillator, i.e., $0 \leq$ CCPR1L:CCP1CON<5:4> \leq 255. Any value greater than 255 will result in a 100% duty cycle.

In order to achieve higher resolution, the PWM frequency must be decreased. In order to achieve higher PWM frequency, the resolution must be decreased.

Table 10-3 lists example PWM frequencies and resolutions for Fosc = 20 MHz. The TMR2 prescaler and PR2 values are also shown.

10.3.3 SET-UP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

- 1. Set the PWM period by writing to the PR2 register.
- 2. Set the PWM duty cycle by writing to the CCPR1L register and CCP1CON<5:4> bits.
- 3. Make the CCP1 pin an output by clearing the TRISC<2> bit.
- 4. Set the TMR2 prescale value and enable Timer2 by writing to T2CON.
- 5. Configure the CCP1 module for PWM operation.

TABLE 10-3: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 20 MHz

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	5.5

TABLE 10-4: REGISTERS ASSOCIATED WITH TIMER1, CAPTURE AND COMPARE

Add	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	PC	e on: DR, DR	all c	e on other sets
0Bh,8Bh 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000	000x	0000	000u
0Ch	PIR1	PSPIF ⁽²⁾	(3)	RCIF ⁽¹⁾	TXIF ⁽¹⁾	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000	0000	0000	0000
0Dh ⁽⁴⁾	PIR2	_		_		—	—	—	CCP2IF		0		0
8Ch	PIE1	PSPIE ⁽²⁾	(3)	RCIE ⁽¹⁾	TXIE ⁽¹⁾	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000	0000	0000	0000
8Dh ⁽⁴⁾	PIE2	_	-	_		_	_	_	CCP2IE		0		0
87h	TRISC	PORTC D	Data Dire	ction registe	ər					1111	1111	1111	1111
0Eh	TMR1L	Holding re	egister fo	r the Least	Significant	Byte of the	16-bit TM	R1 register		xxxx	xxxx	uuuu	uuuu
0Fh	TMR1H	Holding re	egister fo	r the Most	Significant	Byte of the '	16-bit TMF	1 register		xxxx	xxxx	uuuu	uuuu
10h	T1CON	_	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00	0000	uu	uuuu
15h	CCPR1L	Capture/0	Compare/	PWM1 (LS	B)					xxxx	xxxx	uuuu	uuuu
16h	CCPR1H	Capture/0	Compare/	PWM1 (MS	SB)					xxxx	xxxx	uuuu	uuuu
17h	CCP1CON	_	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00	0000	00	0000
1Bh ⁽⁴⁾	CCPR2L	Capture/0	Capture/Compare/PWM2 (LSB)									uuuu	uuuu
1Ch ⁽⁴⁾	CCPR2H	Capture/0	Compare/		xxxx	xxxx	uuuu	uuuu					
1Dh ⁽⁴⁾	CCP2CON	—	_	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	00	0000	00	0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used in these modes.

Note 1: These bits are associated with the USART module, which is implemented on the PIC16C63/R63/65/65A/R65/66/67 only. 2: Bits PSPIE and PSPIF are reserved on the PIC16C62/62A/R62/63/R63/66, always maintain these bits clear.

3: The PIR1<6> and PIE1<6> bits are reserved, always maintain these bits clear.

4: These registers are associated with the CCP2 module, which is only implemented on the PIC16C63/R63/65/65A/R65/66/67.

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Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh,8Bh 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽²⁾	(3)	RCIF ⁽¹⁾	TXIF ⁽¹⁾	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000	0000
0Dh ⁽⁴⁾	PIR2	—	_	_	_	_	_	_	CCP2IF		
8Ch	PIE1	PSPIE ⁽²⁾	(3)	RCIE ⁽¹⁾	TXIE ⁽¹⁾	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000	0000
8Dh ⁽⁴⁾	PIE2	_	_	_		_	_	_	CCP2IE		
87h	TRISC	PORTC [Data Directio	on register			1			1111 1111	1111 1111
11h	TMR2	Timer2 m	iodule's regi		0000	0000					
92h	PR2	Timer2 m	odule's Per	iod register						1111 1111	1111 1111
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/0	Compare/P\	VM1 (LSB)		I	1			xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/0	Compare/P\	WM1 (MSB)					xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	_	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
1Bh ⁽⁴⁾	CCPR2L	Capture/0	Compare/P\	VM2 (LSB)		1	1			xxxx xxxx	uuuu uuuu
1Ch ⁽⁴⁾	CCPR2H	Capture/0	Capture/Compare/PWM2 (MSB)								
1Dh ⁽⁴⁾	CCP2CON	-	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	00 0000	00 0000

TABLE 10-5: REGISTERS ASSOCIATED WITH PWM AND TIMER2

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used in this mode. Note 1: These bits are associated with the USART module, which is implemented on the PIC16C63/R63/65/65A/R65/66/67 only.

These bits are associated with the USART module, which is implemented on the PIC16C63/R63/65/65A/R65/66/67 only.
 Bits PSPIE and PSPIF are reserved on the PIC16C62/62A/R62/63/R63/66, always maintain these bits clear.

3: The PIR1<6> and PIE1<6> bits are reserved, always maintain these bits clear.

4: These registers are associated with the CCP2 module, which is only implemented on the PIC16C63/R63/65/65A/R65/66/67.

11.0 SYNCHRONOUS SERIAL PORT (SSP) MODULE

11.1 SSP Module Overview

The Synchronous Serial Port (SSP) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be Serial EEPROMs, shift registers, display drivers, A/D converters, etc. The SSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I²C)

The SSP module in I^2C mode works the same in all PIC16C6X devices that have an SSP module. However the SSP Module in SPI mode has differences between the PIC16C66/67 and the other PIC16C6X devices.

The register definitions and operational description of SPI mode has been split into two sections because of the differences between the PIC16C66/67 and the other PIC16C6X devices. The default reset values of both the SPI modules is the same regardless of the device:

11.2 SPI Mode for PIC16C62/62A/R62/	63/R63/64/
64A/R64/65/65A/R65	
11.3 SPI Mode for PIC16C66/67	89
11.4 I ² C [™] Overview	
11.5 SSP I ² C Operation	

Refer to Application Note AN578, "Use of the SSP Module in the l^2C Multi-Master Environment."

PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

11.2 <u>SPI Mode for PIC16C62/62A/R62/63/</u> R63/64/64A/R64/65/65A/R65

This section contains register definitions and operational characteristics of the SPI module for the PIC16C62, PIC16C62A, PIC16CR62, PIC16C63, PIC16CR63, PIC16C64A, PIC16CR64A, PIC16CR64, PIC16C655, PIC16C65A, PIC16CR65.

FIGURE 11-1: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS 94h)

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0						
—	—	D/A	Р	S	R/W	UA	BF	R = Readable bit					
bit7							bit0	 W = Writable bit U = Unimplemented bit, read as '0' - n =Value at POR reset 					
bit 7-6:	bit 7-6: Unimplemented: Read as '0'												
bit 5:	 bit 5: D/Ā: Data/Address bit (l²C mode only) 1 = Indicates that the last byte received or transmitted was data 0 = Indicates that the last byte received or transmitted was address 												
bit 4:	 P: Stop bit (I²C mode only. This bit is cleared when the SSP module is disabled, SSPEN is cleared) 1 = Indicates that a stop bit has been detected last (this bit is '0' on RESET) 0 = Stop bit was not detected last 												
bit 3:	 S: Start bit (I²C mode only. This bit is cleared when the SSP module is disabled, SSPEN is cleared) 1 = Indicates that a start bit has been detected last (this bit is '0' on RESET) 0 = Start bit was not detected last 												
bit 2:	This bit	holds the o the next ad	R/W bit in	ation (I ² C n nformation stop bit, or 1	following the	e last addre	ss match. T	his bit is valid from the address					
bit 1:	1 = Indi	cates that	the user r	t I ² C mode needs to up to be upda	date the add	dress in the	SSPADD re	egister					
bit 0:	BF: Buf	fer Full St	atus bit										
	<u>Receive</u> (SPI and I ² C modes) 1 = Receive complete, SSPBUF is full 0 = Receive not complete, SSPBUF is empty												
	1 = Trar		ogress, S	SPBUF is f 'BUF is err									

FIGURE 11-2: SSPCON: SYNC SERIAL PORT CONTROL REGISTER (ADDRESS 14h)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0						
WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	R = Readable bit					
bit7			-				bit0	W = Writable bit U = Unimplemented bit, read as '0' - n =Value at POR reset					
bit 7:	WCOL: W $1 = \text{The S}^2$ (must be c 0 = No col	SPBUF reg	gister is w		e it is still tr	ansmitting	g the previou	<u>.</u>					
bit 6:	SSPOV: Receive Overflow Detect bit												
	In SPI mode 1 = A new byte is received while the SSPBUF register is still holding the previous data. In case of overflow, the data in SSPSR register is lost. Overflow can only occur in slave mode. The user must read the SSP- BUF, even if only transmitting data, to avoid setting overflow. In master mode the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPBUF register. 0 = No overflow												
	In l^2 C mode 1 = A byte is received while the SSPBUF register is still holding the previous byte. SSPOV is a "don't care" in transmit mode. SSPOV must be cleared in software in either mode. 0 = No overflow												
bit 5:	SSPEN: S	ynchronou	is Serial F	ort Enable	e bit								
	SSPEN : Synchronous Serial Port Enable bit <u>In SPI mode</u> 1 = Enables serial port and configures SCK, SDO, and SDI as serial port pins 0 = Disables serial port and configures these pins as I/O port pins												
	0 = Disabl	es the seria es serial p	ort and co	nfigures th	nese pins a	as I/O port	•	al port pins s input or output.					
bit 4:	CKP: Cloc	k Polarity	Select bit										
		ate for cloc						receive on rising edge. ceive on falling edge.					
	$\frac{\ln l^2 C \mod SCK}{SCK}$ relea	se control e clock											
bit 3-0:	$0110 = ^{2}(0)$ $0111 = ^{2}(0)$ $1011 = ^{2}(0)$ $1110 = ^{2}(0)$	SPM0: Syr PI master r PI master r PI master r PI slave mo C slave mo C slave mo C slave mo C slave mo	nchronous node, cloc node, cloc node, clock ode, clock ode, clock ode, 7-bit a de, 10-bit controllec ode, 7-bit a	Serial Po k = Fosc/2 k = Fosc/2 k = Fosc/2 k = TMR2 = SCK pir address address d Master M address wi	rt Mode Se 1 16 54 output/2 n. SS pin c n. SS pin c 10de (slave th start an	elect bits ontrol ena ontrol disa e idle) d stop bit i	bled.	n be used as I/O pin. nabled enabled					

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

11.2.1 OPERATION OF SSP MODULE IN SPI MODE

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO)
- · Serial Data In (SDI)
- Serial Clock (SCK)

Additionally a fourth pin may be used when in a slave mode of operation:

Slave Select (SS)

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON register (SSPCON<5:0>). These control bits allow the following to be specified:

- Master Mode (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Output/Input data on the Rising/ Falling edge of SCK)
- · Clock Rate (Master mode only)
- Slave Select Mode (Slave mode only)

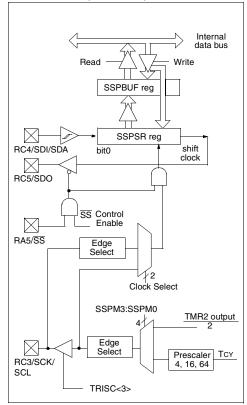
The SSP consists of a transmit/receive Shift Register (SSPSR) and a Buffer register (SSPBUF). The SSPSR shifts the data in and out of the device. MSb first. The SSPBUF holds the data that was written to the SSPSR, until the received data is ready. Once the 8-bits of data have been received, that byte is moved to the SSPBUF register. Then the Buffer Full bit, BF (SSPSTAT<0>) and flag bit SSPIF are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit, WCOL (SSPCON<7>) will be set. User software must clear bit WCOL so that it can be determined if the following write(s) to the SSPBUF completed successfully. When the application software is expecting to receive valid data, the SSPBUF register should be read before the next byte of data to transfer is written to the SSPBUF register. The Buffer Full bit BF (SSPSTAT<0>) indicates when the SSPBUF register has been loaded with the received data (transmission is complete). When the SSPBUF is read, bit BF is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally the SSP Interrupt is used to determine when the transmission/reception has completed. The SSPBUF register must be read and/or written. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur. Example 11-1 shows the loading of the SSPBUF (SSPSR) register for data transmission. The shaded instruction is only required if the received data is meaningful.

EXAMPLE 11-1: LOADING THE SSPBUF (SSPSR) REGISTER

	BSF	STATUS,	RP0	;Specify Bank 1
LOOP	BTFSS	SSPSTAT,	BF	;Has data been
				;received
				;(transmit
				;complete)?
	GOTO	LOOP		;No
	BCF	STATUS,	RP0	;Specify Bank 0
	MOVF	SSPBUF,	W	;W reg = contents
				;of SSPBUF
	MOVWF	RXDATA		;Save in user RAM
	MOVF	TXDATA,	W	;W reg = contents
				; of TXDATA
	MOVWF	SSPBUF		;New data to xmit

The block diagram of the SSP module, when in SPI mode (Figure 11-3), shows that the SSPSR register is not directly readable or writable, and can only be accessed from addressing the SSPBUF register. Additionally, the SSP status register (SSPSTAT) indicates the various status conditions.

FIGURE 11-3: SSP BLOCK DIAGRAM (SPI MODE)



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PIC16C6X

To enable the serial port, SSP enable bit SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear enable bit SSPEN, re-initialize SSPCON register, and then set enable bit SSPEN. This configures the SDI, SDO, SCK, and \overline{SS} pins as serial port pins. For the pins to behave as the serial port function, they must have their data direction bits (in the TRIS register) appropriately programmed. That is:

- SDI must have TRISC<4> set
- SDO must have TRISC<5> cleared
- SCK (Master mode) must have TRISC<3> cleared
- SCK (Slave mode) must have TRISC<3> set
- SS must have TRISA<5> set (if implemented)

Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value. An example would be in master mode where you are only sending data (to a display driver), then both SDI and SS could be used as general purpose outputs by clearing their corresponding TRIS register bits.

Figure 11-4 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCK signal. Data is shifted out of both shift registers on their programmed clock edge, and latched on the opposite edge of the clock. Both processors should be programmed to the same Clock Polarity (CKP), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application software. This leads to three scenarios for data transmission:

- Master sends data Slave sends dummy data
- Master sends data Slave sends data
- · Master sends dummy data Slave sends data

FIGURE 11-4: SPI MASTER/SLAVE CONNECTION

The master can initiate the data transfer at any time because it controls the SCK. The master determines when the slave (Processor 2) is to broadcast data by the software protocol.

In master mode the data is transmitted/received as soon as the SSPBUF register is written to. If the SPI is only going to receive, the SCK output could be disabled (programmed as an input). The SSPSR register will continue to shift in the signal present on the SDI pin at the programmed clock rate. As each byte is received, it will be loaded into the SSPBUF register as if a normal received byte (interrupts and status bits appropriately set). This could be useful in receiver applications as a "line activity monitor" mode.

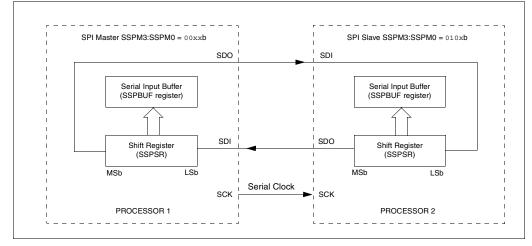
In slave mode, the data is transmitted and received as the external clock pulses appear on SCK. When the last bit is latched interrupt flag bit SSPIF (PIR1<3>) is set.

The clock polarity is selected by appropriately programming bit CKP (SSPCON<4>). This then would give waveforms for SPI communication as shown in Figure 11-5 and Figure 11-6 where the MSB is transmitted first. In master mode, the SPI clock rate (bit rate) is user programmable to be one of the following:

- Fosc/4 (or TCY)
- Fosc/16 (or 4 TCY)
- Fosc/64 (or 16 TCY)
- Timer2 output/2

This allows a maximum bit clock frequency (at 20 MHz) of 5 MHz. When in slave mode the external clock must meet the minimum high and low times.

In sleep mode, the slave can transmit and receive data and wake the device from sleep.



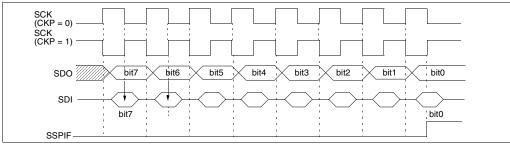
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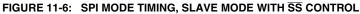
The \overline{SS} pin allows a synchronous slave mode. The SPI must be in slave mode (SSPCON<3:0> = 04h) and the TRISA<5> bit must be set the for synchronous slave mode to be enabled. When the \overline{SS} pin is low, transmission and reception are enabled and the SDO pin is driven. When the \overline{SS} pin goes high, the SDO pin is no longer driven, even if in the middle of a transmitted byte, and becomes a floating output. If the \overline{SS} pin is taken low without resetting SPI mode, the transmission will continue from the

point at which it was taken high. External pull-up/ pull-down resistors may be desirable, depending on the application.

To emulate two-wire communication, the SDO pin can be connected to the SDI pin. When the SPI needs to operate as a receiver the SDO pin can be configured as an input. This disables transmissions from the SDO. The SDI can always be left as an input (SDI function) since it cannot create a bus conflict.

FIGURE 11-5: SPI MODE TIMING, MASTER MODE OR SLAVE MODE W/O SS CONTROL





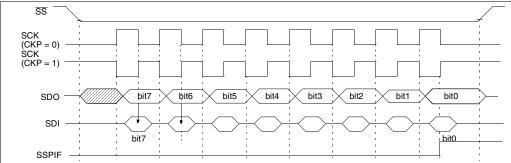


TABLE 11-1: REGISTERS ASSOCIATED WITH SPI OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽²⁾	(3)	RCIF ⁽¹⁾	TXIF ⁽¹⁾	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽²⁾	(3)	RCIE ⁽¹⁾	TXIE ⁽¹⁾	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
13h	SSPBUF	Synchrono	ous Serial	Port Rece	ive Buffer	/Transmit	Register			xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
85h	TRISA	_	_	PORTA Da	ta Directior	Register				11 1111	11 1111
87h	TRISC	PORTC D	PORTC Data Direction Register								1111 1111
94h	SSPSTAT	—	—	D/A	Р	BF	00 0000	00 0000			

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by SSP module in SPI mode.

Note 1: These bits are associated with the USART which is implemented on the PIC16C63/R63/65/65A/R65 only.

2: PSPIF and PSPIE are reserved on the PIC16C62/62A/R62/63/R63, always maintain these bits clear.

3: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

11.3 SPI Mode for PIC16C66/67

This section contains register definitions and operational characterisitics of the SPI module on the PIC16C66 and PIC16C67 only.

FIGURE 11-7: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS 94h)(PIC16C66/67)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0						
SMP	CKE	D/A	P	S	B/W	UA	BF	R = Readable bit					
bit7	ONL	Dirt				<u> </u>	bitO	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset					
bit 7:	SPI Master Mode 1 = Input data sampled at end of data output time 0 = Input data sampled at middle of data output time <u>SPI Slave Mode</u> SMP must be cleared when SPI is used in slave mode												
bit 6:													
bit 5:	 D/A: Data/Address bit (I²C mode only) 1 = Indicates that the last byte received or transmitted was data 0 = Indicates that the last byte received or transmitted was address 												
bit 4:	detected 1 = Indic	l last, SS cates tha	SPEN is cle	eared) t has been	cleared whe			lisabled, or when the Start bit is ET)					
bit 3:	detected 1 = Indic	l last, SS cates tha	SPEN is cle	eared) t has been	cleared whe			disabled, or when the Stop bit is ET)					
bit 2:	This bit	holds th match to d	e R/W bit	informatio	mode only) n following t op bit, or AC		dress match	. This bit is only valid from the					
bit 1:	1 = Indic	cates tha	t the user	it I ² C mode needs to u I to be upd	pdate the ad	dress in the	e SSPADD r	egister					
bit 0:	 BF: Buffer Full Status bit <u>Receive</u> (SPI and I²C modes) 1 = Receive complete, SSPBUF is full 0 = Receive not complete, SSPBUF is empty 												
	1 = Tran	smit in p		SPBUF is PBUF is er									

Γ

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FIGURE 11-8: SSPCON: SYNC SERIAL PORT CONTROL REGISTER (ADDRESS 14h)(PIC16C66/67)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	R = Readable bit W = Writable bit
bit7							bit0	U = Unimplemented bit, read as '0'
								- n =Value at POR reset
bit 7:	WCOL : W 1 = The SS (must be c 0 = No col	SPBUF reg	gister is wi		e it is still tr	ansmitting	the previo	us word
bit 6:	SSPOV: R	eceive Ov	erflow Indi	cator bit				
	the data in if only tran	byte is rece SSPSR is smitting da tion (and t	lost. Over ata, to avo	rflow can o bid setting	only occur i overflow. I	n slave mo n master r	de. The us	revious data. In case of overflow er must read the SSPBUF, eve verflow bit is not set since eac egister.
	$\frac{\ln I^2 C \mod}{1 = A \text{ byte}}$ in transmit 0 = No over	is received mode. SS						us byte. SSPOV is a "don't care
bit 5:	SSPEN: S	ynchronou	is Serial P	ort Enable	bit			
	$\frac{\text{In SPI mod}}{1 = \text{Enable}}$ $0 = \text{Disable}$	es serial po					s serial poi pins	rt pins
	0 = Disable	es the seria es serial p	ort and co	nfigures th	nese pins a	as I/O port	pins	rial port pins s input or output.
bit 4:	CKP : Cloc In SPI mod 1 = Idle sta0 = Idle staIn I2C modSCK relea1 = Enable0 = Holds	de ate for cloc ate for cloc de se control e clock	k is a high k is a low	level	to ensure	data setu	p time)	
bit 3-0:	$0110 = I^{2}(0)$ $0111 = I^{2}(0)$ $1011 = I^{2}(0)$	PI master r PI master r PI master r PI master r PI slave mo CI slave mo CI slave mo CI slave mo CI slave mo CI slave mo	node, cloc node, cloc node, cloc ode, clock ode, clock de, 7-bit a de, 10-bit controllec de, 7-bit a	k = Fosc/4 k = Fosc/7 k = Fosc/7 k = TMR2 = SCK pin address address d master m address wi	4 64 output/2 n. <u>SS</u> pin c n. <u>SS</u> pin c node (slave th start an	ontrol enal ontrol disa e idle) d stop bit i	bled. SS c	

11.3.1 SSP MODULE IN SPI MODE FOR PIC16C66/67

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO) RC5/SDO
- Serial Data In (SDI) RC4/SDI/SDA
- Serial Clock (SCK) RC3/SCK/SCL

Additionally a fourth pin may be used when in a slave mode of operation:

Slave Select (SS) RA5/SS

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON register (SSPCON<5:0>) and SSPSTAT<7:6>. These control bits allow the following to be specified:

- · Master Mode (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Clock edge (output data on rising/falling edge of SCK)
- · Clock Rate (Master mode only)
- · Slave Select Mode (Slave mode only)

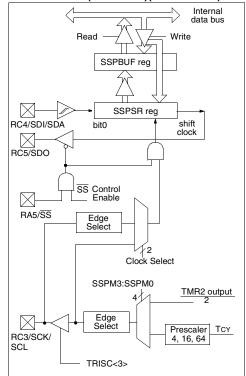
The SSP consists of a transmit/receive Shift Register (SSPSR) and a buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR until the received data is ready. Once the 8-bits of data have been received, that byte is moved to the SSPBUF register. Then the buffer full detect bit BF (SSPSTAT<0>) and interrupt flag bit SSPIF (PIR1<3>) are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit WCOL (SSPCON<7>) will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully. When the application software is expecting to receive valid data, the SSPBUF should be read before the next byte of data to transfer is written to the SSPBUF. Buffer full bit BF (SSPSTAT<0>) indicates when SSPBUF has been loaded with the received data (transmission is complete). When the SSPBUF is read, bit BF is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally the SSP Interrupt is used to determine when the transmission/reception has completed. The SSPBUF must be read and/or written. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur. Example 11-2 shows the loading of the SSPBUF (SSPSR) for data transmission. The shaded instruction is only required if the received data is meaningful.

EXAMPLE 11-2: LOADING THE SSPBUF (SSPSR) REGISTER (PIC16C66/67)

BCF	STATUS, RP1	;Specify Bank 1
BSF	STATUS, RPO	;
LOOP BTFSS	SSPSTAT, BF	;Has data been
		;received
		;(transmit
		;complete)?
GOTO	LOOP	;No
BCF	STATUS, RPO	;Specify Bank 0
MOVF	SSPBUF, W	;W reg = contents
		; of SSPBUF
MOVWF	RXDATA	;Save in user RAM
MOVF	TXDATA, W	;W reg = contents
		; of TXDATA
MOVWF	SSPBUF	;New data to xmit

The block diagram of the SSP module, when in SPI mode (Figure 11-9), shows that the SSPSR is not directly readable or writable, and can only be accessed from addressing the SSPBUF register. Additionally, the SSP status register (SSPSTAT) indicates the various status conditions.

FIGURE 11-9: SSP BLOCK DIAGRAM (SPI MODE)(PIC16C66/67)



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To enable the serial port, SSP Enable bit, SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear bit SSPEN, re-initialize the SSPCON register, and then set bit SSPEN. This configures the SDI, SDO, SCK, and \overline{SS} pins as serial port pins. For the pins to behave as the serial port function, they must have their data direction bits (in the TRISC register) appropriately programmed. That is:

- SDI must have TRISC<4> set
- SDO must have TRISC<5> cleared
- SCK (Master mode) must have TRISC<3> cleared
- SCK (Slave mode) must have TRISC<3> set
- SS must have TRISA<5> set

Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value. An example would be in master mode where you are only sending data (to a display driver), then both SDI and \overline{SS} could be used as general purpose outputs by clearing their corresponding TRIS register bits.

Figure 11-10 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCK signal. Data is shifted out of both shift registers on their programmed clock edge, and latched on the opposite edge of the clock. Both processors should be programmed to same Clock Polarity (CKP), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application firmware. This leads to three scenarios for data transmission:

- Master sends data Slave sends dummy data
- Master sends data Slave sends data
- Master sends dummy data Slave sends data

The master can initiate the data transfer at any time because it controls the SCK. The master determines when the slave (Processor 2) is to broadcast data by the firmware protocol.

In master mode the data is transmitted/received as soon as the SSPBUF register is written to. If the SPI is only going to receive, the SCK output could be disabled (programmed as an input). The SSPSR register will continue to shift in the signal present on the SDI pin at the programmed clock rate. As each byte is received, it will be loaded into the SSPBUF register as if a normal received byte (interrupts and status bits appropriately set). This could be useful in receiver applications as a "line activity monitor" mode.

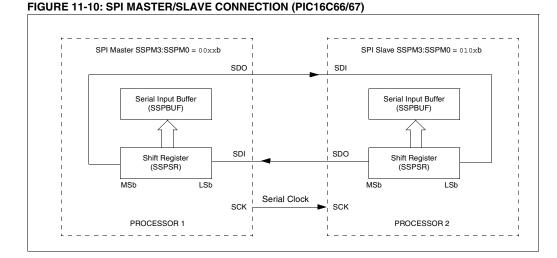
In slave mode, the data is transmitted and received as the external clock pulses appear on SCK. When the last bit is latched the interrupt flag bit SSPIF (PIR1<3>) is set.

The clock polarity is selected by appropriately programming bit CKP (SSPCON<4>). This then would give waveforms for SPI communication as shown in Figure 11-11, Figure 11-12, and Figure 11-13 where the MSB is transmitted first. In master mode, the SPI clock rate (bit rate) is user programmable to be one of the following:

- Fosc/4 (or Tcy)
- Fosc/16 (or 4 Tcy)
- Fosc/64 (or 16 Tcy)
- Timer2 output/2

This allows a maximum bit clock frequency (at 20 MHz) of 5 MHz. When in slave mode the external clock must meet the minimum high and low times.

In sleep mode, the slave can transmit and receive data and wake the device from sleep.



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The \overline{SS} pin allows a synchronous slave mode. The SPI must be in slave mode (SSPCON<3:0> = 04h) and the TRISA<5> bit must be set for the synchronous slave mode to be enabled. When the \overline{SS} pin is low, transmission and reception are enabled and the SDO pin is driven. When the \overline{SS} pin goes high, the SDO pin is no longer driven, even if in the middle of a transmitted byte, and becomes a floating output. If the \overline{SS} pin is taken low without resetting SPI mode, the transmission will continue from the point at which it was taken high. External pull-up/ pull-down resistors may be desirable, depending on the application.

- **Note:** When the SPI is in Slave Mode with \overline{SS} pin control enabled, (SSPCON<3:0> = 0100) the SPI module will reset if the \overline{SS} pin is set to VDD.
- Note: If the SPI is used in Slave Mode with CKE = '1', then the SS pin control must be enabled.

To emulate two-wire communication, the SDO pin can be connected to the SDI pin. When the SPI needs to operate as a receiver the SDO pin can be configured as an input. This disables transmissions from the SDO. The SDI can always be left as an input (SDI function) since it cannot create a bus conflict.

FIGURE 11-11: SPI MODE TIMING, MASTER MODE (PIC16C66/67)

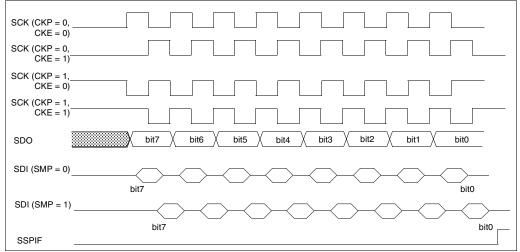
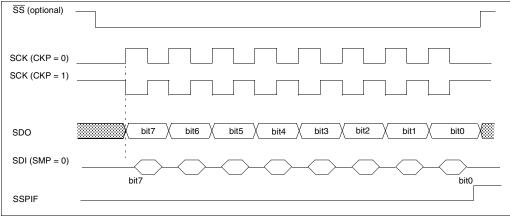


FIGURE 11-12: SPI MODE TIMING (SLAVE MODE WITH CKE = 0) (PIC16C66/67)



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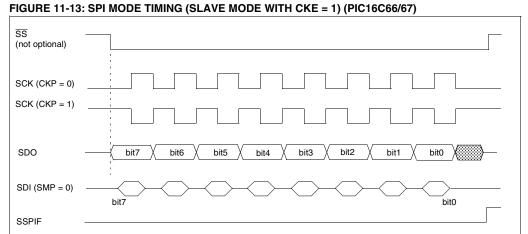


TABLE 11-2: REGISTERS ASSOCIATED WITH SPI OPERATION (PIC16C66/67)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Pow	e on er-on set		on all resets
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000	000x	0000	000u
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000	0000	0000	0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000	0000	0000	0000
13h	SSPBUF	Synchron	ous Serial	Port Rece	eive Buffe	r/Transmit	Register			xxxx	xxxx	uuuu	uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000	0000	0000	0000
85h	TRISA	— — PORTA Data Direction register									1111	11	1111
87h	TRISC	PORTC Data Direction register									1111	1111	1111
94h	SSPSTAT	SMP	CKE	D/Ā	Р	S	R/W	UA	BF	0000	0000	0000	0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'.

Shaded cells are not used by SSP module in SPI mode.

Note 1: PSPIF and PSPIE are reserved on the PIC16C66, always maintain these bits clear.

2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

11.4 I²C[™] Overview

This section provides an overview of the Inter-Integrated Circuit (I^2C) bus, with Section 11.5 discussing the operation of the SSP module in I^2C mode.

The I²C bus is a two-wire serial interface developed by the Philips[®] Corporation. The original specification, or standard mode, was for data transfers of up to 100 Kbps. The enhanced specification (fast mode) is also supported. This device will communicate with both standard and fast mode devices if attached to the same bus. The clock will determine the data rate.

The I²C interface employs a comprehensive protocol to ensure reliable transmission and reception of data. When transmitting data, one device is the "master" which initiates transfer on the bus and generates the clock signals to permit that transfer, while the other device(s) acts as the "slave." All portions of the slave protocol are implemented in the SSP module's hardware, except general call support, while portions of the master protocol need to be addressed in the PIC16CXX software. Table 11-3 defines some of the I²C bus terminology. For additional information on the I²C interface specification, refer to the Philips document "*The I²C bus and how to use it.*"#939839340011, which can be obtained from the Philips Corporation.

In the I²C interface protocol each device has an address. When a master wishes to initiate a data transfer, it first transmits the address of the device that it wishes to "talk" to. All devices "listen" to see if this is their address. Within this address, a bit specifies if the master wishes to read-from/write-to the slave device. The master and slave are always in opposite modes (transmitter/receiver) of operation during a data transfer. That is they can be thought of as operating in either of these two relations:

- · Master-transmitter and Slave-receiver
- Slave-transmitter and Master-receiver

Term	Description
Transmitter	The device that sends the data to the bus.
Receiver	The device that receives the data from the bus.
Master	The device which initiates the transfer, generates the clock and terminates the transfer.
Slave	The device addressed by a master.
Multi-master	More than one master device in a system. These masters can attempt to control the bus at the same time without corrupting the message.
Arbitration	Procedure that ensures that only one of the master devices will control the bus. This ensure that the transfer data does not get corrupted.
Synchronization	Procedure where the clock signals of two or more devices are synchronized.

TABLE 11-3: I²C BUS TERMINOLOGY

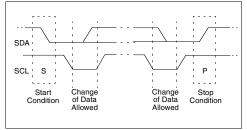
In both cases the master generates the clock signal.

The output stages of the clock (SCL) and data (SDA) lines must have an open-drain or open-collector in order to perform the wired-AND function of the bus. External pull-up resistors are used to ensure a high level when no device is pulling the line down. The number of devices that may be attached to the l^2C bus is limited only by the maximum bus loading specification of 400 pF.

11.4.1 INITIATING AND TERMINATING DATA TRANSFER

During times of no data transfer (idle time), both the clock line (SCL) and the data line (SDA) are pulled high through the external pull-up resistors. The START and STOP conditions determine the start and stop of data transmission. The START condition is defined as a high to low transition of the SDA when the SCL is high. The STOP condition is defined as a low to high transition of the SDA when the SCL is high. The START and STOP conditions. The master generates these conditions for starting and terminating data transfer. Due to the definition of the START and STOP conditions, when data is being transmitted, the SDA line can only change state when the SCL line is low.

FIGURE 11-14: START AND STOP CONDITIONS



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11.4.2 ADDRESSING I²C DEVICES

There are two address formats. The simplest is the 7-bit address format with a R/ \overline{W} bit (Figure 11-15). The more complex is the 10-bit address with a R/ \overline{W} bit (Figure 11-16). For 10-bit address format, two bytes must be transmitted with the first five bits specifying this to be a 10-bit address.

FIGURE 11-15: 7-BIT ADDRESS FORMAT

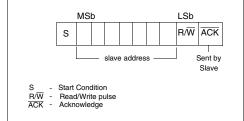
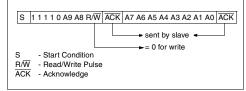


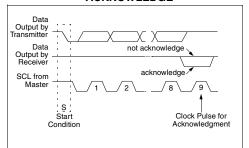
FIGURE 11-16: I²C 10-BIT ADDRESS FORMAT



11.4.3 TRANSFER ACKNOWLEDGE

All data must be transmitted per byte, with no limit to the number of bytes transmitted per data transfer. After each byte, the slave-receiver generates an acknowledge bit (\overline{ACK}) (Figure 11-17). When a slave-receiver doesn't acknowledge the slave address or received data, the master must abort the transfer. The slave must leave SDA high so that the master can generate the STOP condition (Figure 11-14).

FIGURE 11-17: SLAVE-RECEIVER ACKNOWLEDGE



If the master is receiving the data (master-receiver), it generates an acknowledge signal for each received byte of data, except for the last byte. To signal the end of data to the slave-transmitter, the master does not generate an acknowledge (not acknowledge). The slave then releases the SDA line so the master can generate the STOP condition. The master can also generate the STOP condition during the acknowledge pulse for valid termination of data transfer.

If the slave needs to delay the transmission of the next byte, holding the SCL line low will force the master into a wait state. Data transfer continues when the slave releases the SCL line. This allows the slave to move the received data or fetch the data it needs to transfer before allowing the clock to start. This wait state technique can also be implemented at the bit level, Figure 11-18. The slave will inherently stretch the clock, when it is a transmitter, but will not when it is a receiver. The slave will have to clear the SSPCON<4> bit to enable clock stretching when it is a receiver.

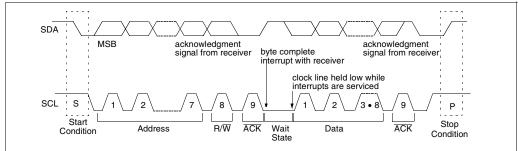


FIGURE 11-18: DATA TRANSFER WAIT STATE

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

PIC16C6X

Figure 11-19 and Figure 11-20 show Master-transmitter and Master-receiver data transfer sequences.

When a master does not wish to relinquish the bus (by generating a STOP condition), a repeated START condition (Sr) must be generated. This condition is identical to the start condition (SDA goes high-to-low while

SCL is high), but occurs after a data transfer acknowledge pulse (not the bus-free state). This allows a master to send "commands" to the slave and then receive the requested information or to address a different slave device. This sequence is shown in Figure 11-21.

FIGURE 11-19: MASTER-TRANSMITTER SEQUENCE

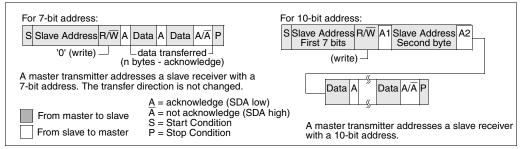


FIGURE 11-20: MASTER-RECEIVER SEQUENCE

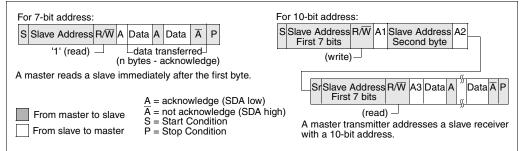


FIGURE 11-21: COMBINED FORMAT

(read or write)									
S Slave Address R/W A Data A/A Sr Slave Address R/W A Data A/A P									
(read) Sr = repeated (write) \Box Direction of transfer Start Condition may change at this point									
Transfer direction of data and acknowledgment bits depends on R/\overline{W} bits.									
Combined format:	"								
Sr Slave Address R/W A Slave Address A Data A & Data A & Data A/A Sr Slave Address R/W A E Second byte	Data A Data A P								
(write) (read)))								
Combined format - A master addresses a slave with a 10-bit address, then transmits data to this slave and reads data from this slave.									
From master to slave A = acknowledge (SDA low) From slave to master A = not acknowledge (SDA high) S = Start Condition P = Stop Condition									

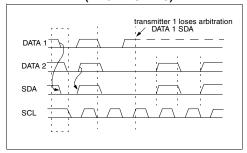
11.4.4 MULTI-MASTER

The I²C protocol allows a system to have more than one master. This is called multi-master. When two or more masters try to transfer data at the same time, arbitration and synchronization occur.

11.4.4.1 ARBITRATION

Arbitration takes place on the SDA line, while the SCL line is high. The master which transmits a high when the other master transmits a low loses arbitration (Figure 11-22), and turns off its data output stage. A master which lost arbitration can generate clock pulses until the end of the data byte where it lost arbitration. When the master devices are addressing the same device, arbitration continues into the data.

FIGURE 11-22: MULTI-MASTER ARBITRATION (TWO MASTERS)



Masters that also incorporate the slave function, and have lost arbitration must immediately switch over to slave-receiver mode. This is because the winning master-transmitter may be addressing it.

Arbitration is not allowed between:

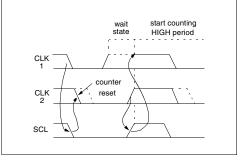
- A repeated START condition
- A STOP condition and a data bit
- A repeated START condition and a STOP condition

Care needs to be taken to ensure that these conditions do not occur.

11.2.4.2 Clock Synchronization

Clock synchronization occurs after the devices have started arbitration. This is performed using a wired-AND connection to the SCL line. A high to low transition on the SCL line causes the concerned devices to start counting off their low period. Once a device clock has gone low, it will hold the SCL line low until its SCL high state is reached. The low to high transition of this clock may not change the state of the SCL line, if another device clock is still within its low period. The SCL line is held low by the device with the longest low period. Devices with shorter low periods enter a high waitstate, until the SCL line comes high. When the SCL line comes high, all devices start counting off their high periods. The first device to complete its high period will pull the SCL line low. The SCL line high time is determined by the device with the shortest high period, Figure 11-23.

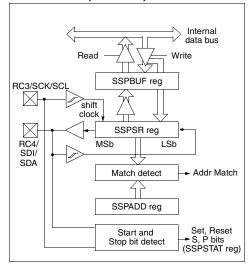
FIGURE 11-23: CLOCK SYNCHRONIZATION



11.5 SSP I²C Operation

The SSP module in I^2C mode fully implements all slave functions, except general call support, and provides interrupts on start and stop bits in hardware to facilitate firmware implementations of the master functions. The SSP module implements the standard mode specifications as well as 7-bit and 10-bit addressing. Two pins are used for data transfer. These are the RC3/SCK/SCL pin, which is the clock (SCL), and the RC4/SDI/SDA pin, which is the data (SDA). The user must configure these pins as inputs or outputs through the TRISC<4:3> bits. The SSP module functions are enabled by setting SSP Enable bit SSPEN (SSP-CON<5>).

FIGURE 11-24: SSP BLOCK DIAGRAM (I²C MODE)



The SSP module has five registers for $\mathsf{I}^2\mathsf{C}$ operation. These are the:

- SSP Control Register (SSPCON)
- SSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift Register (SSPSR) Not directly accessible
- SSP Address Register (SSPADD)

The SSPCON register allows control of the I²C operation. Four mode selection bits (SSPCON<3:0>) allow one of the following I²C modes to be selected:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Slave mode (7-bit address), with start and stop bit interrupts enabled
- I²C Slave mode (10-bit address), with start and stop bit interrupts enabled
- I²C Firmware controlled Master Mode, slave is idle

Selection of any I²C mode, with the SSPEN bit set, forces the SCL and SDA pins to be open drain, provided these pins are programmed to inputs by setting the appropriate TRISC bits.

The SSPSTAT register gives the status of the data transfer. This information includes detection of a START or STOP bit, specifies if the received byte was data or address if the next byte is the completion of 10-bit address, and if this will be a read or write data transfer. The SSPSTAT register is read only.

The SSPBUF is the register to which transfer data is written to or read from. The SSPSR register shifts the data in or out of the device. In receive operations, the SSPBUF and SSPSR create a doubled buffered receiver. This allows reception of the next byte to begin before reading the last byte of received data. When the complete byte is received, it is transferred to the SSPBUF register and flag bit SSPIF is set. If another complete byte is received before the SSPBUF register is read, a receiver overflow has occurred and bit SSPOV (SSPCON<6>) is set and the byte in the SSPSR is lost.

The SSPADD register holds the slave address. In 10-bit mode, the user first needs to write the high byte of the address (1111 0 A9 A8 0). Following the high byte address match, the low byte of the address needs to be loaded (A7:A0).

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

11.5.1 SLAVE MODE

In slave mode, the SCL and SDA pins must be configured as inputs (TRISC<4:3> set). The SSP module will override the input state with the output data when required (slave-transmitter).

When an address is matched or the data transfer after an address match is received, the hardware automatically will generate the acknowledge (\overline{ACK}) pulse, and then load the SSPBUF register with the received value currently in the SSPSR register.

There are certain conditions that will cause the SSP module not to give this ACK pulse. These are if either (or both):

- a) The buffer full bit BF (SSPSTAT<0>) was set before the transfer was received.
- b) The overflow bit SSPOV (SSPCON<6>) was set before the transfer was received.

In this case, the SSPSR register value is not loaded into the SSPBUF, but bit SSPIF (PIR1<3>) is set. Table 11-4 shows what happens when a data transfer byte is received, given the status of bits BF and SSPOV. The shaded cells show the condition where user software did not properly clear the overflow condition. Flag bit BF is cleared by reading the SSPBUF register while bit SSPOV is cleared through software.

The SCL clock input must have a minimum high and low for proper operation. The high and low times of the I^2C specification as well as the requirement of the SSP module is shown in timing parameter #100 and parameter #101.

11.5.1.1 ADDRESSING

Once the SSP module has been enabled, it waits for a START condition to occur. Following the START condition, the 8-bits are shifted into the SSPSR register. All incoming bits are sampled with the rising edge of the clock (SCL) line. The value of register SSPSR<7:1> is compared to the value of the SSPADD register. The

address is compared on the falling edge of the eighth clock (SCL) pulse. If the addresses match, and the BF and SSPOV bits are clear, the following events occur:

- a) The SSPSR register value is loaded into the SSPBUF register.
- b) The buffer full bit, BF is set.
- c) An \overline{ACK} pulse is generated.
- d) SSP interrupt flag bit, SSPIF (PIR1<3>) is set (interrupt is generated if enabled) - on the falling edge of the ninth SCL pulse.

In 10-bit address mode, two address bytes need to be received by the slave (Figure 11-16). The five Most Significant bits (MSbs) of the first address byte specify if this is a 10-bit address. Bit R/\overline{W} (SSPSTAT<2>) must specify a write so the slave device will receive the second address byte. For a 10-bit address the first byte would equal '1111 0 A9 A8 0', where A9 and A8 are the two MSbs of the address. The sequence of events for 10-bit address is as follows, with steps 7-9 for slave-transmitter:

- 1. Receive first (high) byte of Address (bits SSPIF, BF, and bit UA (SSPSTAT<1>) are set).
- 2. Update the SSPADD register with second (low) byte of Address (clears bit UA and releases the SCL line).
- 3. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.
- 4. Receive second (low) byte of Address (bits SSPIF, BF, and UA are set).
- 5. Update the SSPADD register with the first (high) byte of Address, if match releases SCL line, this will clear bit UA.
- 6. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.
- 7. Receive repeated START condition.
- 8. Receive first (high) byte of Address (bits SSPIF and BF are set).
- 9. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.

TABLE 11-4: DATA TRANSFER RECEIVED BYTE ACTIONS

	ts as Data s Received		a . 	Set bit SSPIF
BF	SSPOV	$SSPSR \to SSPBUF$	Generate ACK Pulse	(SSP Interrupt occurs if enabled)
0	0	Yes	Yes	Yes
1	0	No	No	Yes
1	1	No	No	Yes
0	1	No	No	Yes

An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF (PIR1<3>) must be cleared in soft-

ware. The SSPSTAT register is used to determine the

status of the byte.

11.5.1.2 RECEPTION

When the R/ \overline{W} bit of the address byte is clear and an address match occurs, the R/ \overline{W} bit of the SSPSTAT register is cleared. The received address is loaded into the SSPBUF register.

When the address byte overflow condition exists, then no acknowledge (\overline{ACK}) pulse is given. An overflow condition is defined as either bit BF (SSPSTAT<0>) is set or bit SSPOV (SSPCON<6>) is set.

FIGURE 11-25: I ² C WAVEFORMS FOR	RECEPTION (7-BIT ADDRESS)
--	----------------------------------

Receiving Address R/W=0_Receiving Data ACK Receiving Data SDA/A7_XA6XA5XA4XA3XA2XA1XACK D7XD6XD5XD4XD3XD2XD1XD0X_/D7XD6XD5XD4XD3XD2XD1X		
	/8 \ _/9\	∫ ! p! •
SSPIF (PIR1<3>) Cleared in software	 	Bus Master terminates transfer
BF (SSPSTAT<0>) - SSPBUF register is read	 	
SSPOV (SSPCON<6>)		
Bit SSPOV is set because the SSPBUF register is still full.	_	
ACK is not sent		

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

11.5.1.3 TRANSMISSION

When the R/\overline{W} bit of the incoming address byte is set and an address match occurs, the R/\overline{W} bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The \overline{ACK} pulse will be sent on the ninth bit, and pin RC3/SCK/SCL is held low. The transmit data must be loaded into the SSP-BUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP (SSPCON<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 11-26). An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF must be cleared in software, and the SSPSTAT register is used to determine the status of the byte. Flag bit SSPIF is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the \overline{ACK} pulse from the masterreceiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not \overline{ACK}), then the data transfer is complete. When the \overline{ACK} is latched by the slave, the slave logic is reset (resets SSPSTAT register) and the slave then monitors for another occurrence of the START bit. If the SDA line was low (\overline{ACK}), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP.

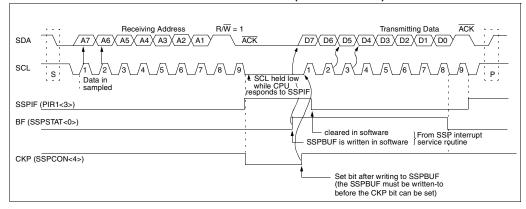


FIGURE 11-26: I²C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)

11.5.2 MASTER MODE

Master mode of operation is supported in firmware using interrupt generation on the detection of the START and STOP conditions. The STOP (P) and START (S) bits are cleared from a reset or when the SSP module is disabled. The STOP (P) and START (S) bits will toggle based on the START and STOP conditions. Control of the l^2C bus may be taken when the P bit is set, or the bus is idle and both the S and P bits are clear.

In master mode the SCL and SDA lines are manipulated by clearing the corresponding TRISC<4:3> bit(s). The output level is always low, irrespective of the value(s) in PORTC<4:3>. So when transmitting data, a '1' data bit must have the TRISC<4> bit set (input) and a '0' data bit must have the TRISC<4> bit set (output). The same scenario is true for the SCL line with the TRISC<3> bit.

The following events will cause SSP Interrupt Flag bit, SSPIF, to be set (SSP Interrupt if enabled):

- START condition
- STOP condition
- Data transfer byte transmitted/received

Master mode of operation can be done with either the slave mode idle (SSPM3:SSPM0 = 1011) or with the slave active. When both master and slave modes are enabled, the software needs to differentiate the source(s) of the interrupt.

11.5.3 MULTI-MASTER MODE

In multi-master mode, the interrupt generation on the detection of the START and STOP conditions allows the determination of when the bus is free. The STOP (P) and START (S) bits are cleared from a reset or when the SSP module is disabled. The STOP (P) and START (S) bits will toggle based on the START and STOP conditions. Control of the 1^2 C bus may be taken when bit P (SSPSTAT<4>) is set, or the bus is idle and both the S and P bits clear. When the bus is busy, enabling the SSP Interrupt will generate the interrupt when the STOP condition occurs.

In multi-master operation, the SDA line must be monitored to see if the signal level is the expected output level. This check only needs to be done when a high level is output. If a high level is expected and a low level is present, the device needs to release the SDA and SCL lines (set TRISC<4:3>). There are two stages where this arbitration can be lost, these are:

- · Address Transfer
- Data Transfer

When the slave logic is enabled, the slave continues to receive. If arbitration was lost during the address transfer stage, communication to the device may be in progress. If addressed an ACK pulse will be generated. If arbitration was lost during the data transfer stage, the device will need to re-transfer the data at a later time.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other resets
0Bh, 8Bh, 10Bh, 18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
13h	SSPBUF	Synchrono	us Serial	Port Rece	ive Buffe	r/Transmit	Register			xxxx xxxx	uuuu uuuu
93h	SSPADD	Synchrono	us Serial	Port (I ² C ı	mode) Ad	ldress Re	gister			0000 0000	0000 0000
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
94h	SSPSTAT	SMP ⁽³⁾	CKE ⁽³⁾	D/A	Р	S	R/W	UA	BF	0000 0000	0000 0000
87h	TRISC	1111 1111	1111 1111								

TABLE 11-5: REGISTERS ASSOCIATED WITH I²C OPERATION

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'.

Shaded cells are not used by SSP module in SPI mode.

Note 1: PSPIF and PSPIE are reserved on the PIC16C66, always maintain these bits clear.

2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

3: The SMP and CKE bits are implemented on the PIC16C66/67 only. All other PIC16C6X devices have these two bits unimplemented, read as '0'.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 11-27: OPERATION OF THE I²C MODULE IN IDLE_MODE, RCV_MODE OR XMIT_MODE

IDLE_MODE (7-bit): if (Addr_match) { Set interrupt; if (R/W = 1) { Send ACK = 0; set XMIT_MODE; }
else if ($R/\overline{W} = 0$) set RCV_MODE;
RCV_MODE:
if ((SSPBUF=Full) OR (SSPOV = 1))
{ Set SSPOV;
Do not acknowledge;
}
else { transfer SSPSR \rightarrow SSPBUF;
send ACK = 0;
Receive 8-bits in SSPSR;
Set interrupt; XMIT MODE:
XMIT_MODE: While ((SSPBUF = Empty) AND (CKP=0)) Hold SCL Low;
Send byte;
Set interrupt;
if (ACK Received = 1) { End of transmission;
Go back to IDLE_MODE;
}
else if (\overline{ACK} Received = 0) Go back to XMIT_MODE;
IDLE_MODE (10-Bit):
If (High_byte_addr_match AND (R/W = 0))
{ PRIOR_ADDR_MATCH = FALSE;
Set interrupt;
if ((SSPBUF = Full) OR ((SSPOV = 1))
{ Set SSPOV;
Do not acknowledge;
} else { Set UA = 1;
Send $\overline{ACK} = 0;$
While (SSPADD not updated) Hold SCL low;
Clear UA = 0;
Receive Low_addr_byte;
Set interrupt;
Set UA = 1;
If (Low_byte_addr_match)
{ PRIOR_ADDR_MATCH = TRUE;
Send $\overline{ACK} = 0;$
while (SSPADD not updated) Hold SCL low;
Clear UA = 0;
Set RCV_MODE;
}
}
}
else if (High_byte_addr_match AND ($R/\overline{W} = 1$)
{ if (PRIOR_ADDR_MATCH)
$\{$ send $\overline{ACK} = 0;$
set XMIT_MODE;
}
ر else PRIOR_ADDR_MATCH = FALSE;
}

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12.0 UNIVERSAL SYNCHRONOUS ASYNCHRONOUS RECEIVER TRANSMITTER (USART) MODULE

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The Universal Synchronous Asynchronous Receiver Transmitter (USART) module is one of the two serial I/O modules. (USART is also known as a Serial Communications Interface or SCI) The USART can be configured as a full duplex asynchronous system that can communicate with peripheral devices such as CRT terminals and personal computers, or it can be configured as a half duplex synchronous system that can communicate with peripheral devices such as A/D or D/A integrated circuits, Serial EEPROMs etc.

The USART can be configured in the following modes:

- Asynchronous (full duplex)
- · Synchronous Master (half duplex)
- Synchronous Slave (half duplex)

Bit SPEN (RCSTA<7>) and bits TRISC<7:6> have to be set in order to configure pins RC6/TX/CK and RC7/RX/DT as the Universal Synchronous Asynchronous Receiver Transmitter.

FIGURE 12-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER (ADDRESS 98h)

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R-1	R/W-0	
CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	R = Readable bit
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n =Value at POR reset
bit 7:	CSRC: Clo	ck Source	Select bit					
	Asynchron Don't care	ous mode						
	Synchrono 1 = Master 0 = Slave r	mode (Clo				G)		
bit 6:	TX9 : 9-bit 1 = Selects 0 = Selects	9-bit trans	smission					
bit 5:	TXEN : Tran 1 = Transm 0 = Transm Note: SRE	iit enabled iit disabled		(EN in SYI	NC mode.			
bit 4:	SYNC: US 1 = Synchr 0 = Asynch	onous mod	de					
bit 3:	Unimplem	ented: Re	ad as '0'					
bit 2:	BRGH: Hig	h Baud Ra	ate Select b	oit				
	Asynchron 1 = High sp							
	Note:	For the P experience higher ba	e a high ra	ite of rece n BRGH =	ive errors. = 0 can sup	t is recom	mended tha	eed mode (BRGH = 1) may t BRGH = 0. If you desire a se errata for additional infor-
	0 = Low sp	eed						
	Synchrono Unused in							
bit 1:	TRMT : Tran 1 = TSR er 0 = TSR fu	npty	Register S	tatus bit				
bit 0:	TX9D : 9th	bit of trans	mit data. C	an be pari	ty bit.			

FIGURE 12-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER (ADDRESS 18h)

R/W-0 SPEN	R/W-0 BX9	R/W-0 SREN	R/W-0 CREN	U-0	R-0 FERR	R-0 OERR	R-x RX9D	R = Readable bit
bit7		UNLIN	ONLIN			OLINI	bitO	 W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR rese x = unknown
bit 7:	SPEN: Ser (Configures 1 = Serial p 0 = Serial p	s RC7/RX/ port enable	DT and RC d	:6/TX/CK p	oins as seri	al port pins	when bits	TRISC<7:6> are set)
bit 6:	RX9 : 9-bit 1 = Selects 0 = Selects	9-bit rece	ption					
bit 5:	SREN: Sin	gle Receiv	e Enable b	it				
	Asynchron Don't care	ous mode						
	$\frac{Synchrono}{1 = Enable} \\ 0 = Disable \\ This bit is c$	s single re s single re	ceive ceive	ı is comple	ete.			
	Synchrono Unused in		<u>slave</u>					
bit 4:	CREN: Co	ntinuous R	eceive Ena	ble bit				
	$\frac{\text{Asynchron}}{1 = \text{Enable}}$ $0 = \text{Disable}$	s continuo						
	$\frac{\text{Synchrono}}{1 = \text{Enable}}$ $0 = \text{Disable}$	s continuo		until enabl	e bit CREN	l is cleared	(CREN ov	errides SREN)
bit 3:	Unimplem	ented: Re	ad as '0'					
bit 2:	FERR: Fran 1 = Framin 0 = No fran	g error (Ca		ed by read	ling RCRE	G register	and receive	e next valid byte)
bit 1:	OERR : Over 1 = Overrue 0 = No over	n error (Ca		ed by clear	ing bit CRI	EN)		
bit 0:	RX9D : 9th			on he nee				

12.1 USART Baud Rate Generator (BRG) Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In asynchronous mode bit BRGH (TXSTA-2>) also controls the baud rate. In synchronous mode bit BRGH is ignored. Table 12-1 shows the formula for computation of the baud rate for different USART modes which only apply in master mode (internal clock).

Given the desired baud rate and Fosc, the nearest integer value for the SPBRG register can be calculated using the formula in Table 12-1. From this, the error in baud rate can be determined.

Example 12-1 shows the calculation of the baud rate error for the following conditions:

Fosc = 16 MHz Desired Baud Rate = 9600 BRGH = 0 SYNC = 0

EXAMPLE 12-1: CALCULATING BAUD RATE ERROR

Desired Baud rate = Fosc / (64 (X + 1))

9600	=	16000000 /(64 (X + 1))

 $X = \lfloor 25.042 \rfloor = 25$

Calculated Baud Rate=16000000 / (64 (25 + 1))

= 9615

Error = (Calculated Baud Rate - Desired Baud Rate) Desired Baud Rate

= (9615 - 9600) / 9600

= 0.16%

It may be advantageous to use the high baud rate (BRGH = 1) even for slower baud clocks. This is because the FOSC/(16(X + 1)) equation can reduce the baud rate error in some cases.

Writing a new value to the SPBRG register, causes the BRG timer to be reset (or cleared), this ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

TABLE 12-1: BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = FOSC/(64(X+1))	Baud Rate = Fosc/(16(X+1))
1	(Synchronous) Baud Rate = Fosc/(4(X+1))	N/A

X = value in SPBRG (0 to 255)

TABLE 12-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
99h	SPBRG	Baud Rat	te Genera	0000 0000	0000 0000						

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used by the BRG.

Note: For the PIC16C63/R63/65/65A/R65 the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information or use the PIC16C66/67.

TABLE 12-3: BAUD RATES FOR SYNCHRONOUS MODE

BAUD	FOSC = 20 MHz		SPBRG	16 MHz		SPBRG	10 MHz		SPBRG	7.15909 I	MHz	SPBRG
RATE (K)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)
0.3	NA	-		NA	-	-	NA	-	-	NA	-	-
1.2	NA	-	-	NA	-	-	NA	-	-	NA	-	-
2.4	NA	-	-	NA	-	-	NA	-	-	NA	-	-
9.6	NA	-	-	NA	-	-	9.766	+1.73	255	9.622	+0.23	185
19.2	19.53	+1.73	255	19.23	+0.16	207	19.23	+0.16	129	19.24	+0.23	92
76.8	76.92	+0.16	64	76.92	+0.16	51	75.76	-1.36	32	77.82	+1.32	22
96	96.15	+0.16	51	95.24	-0.79	41	96.15	+0.16	25	94.20	-1.88	18
300	294.1	-1.96	16	307.69	+2.56	12	312.5	+4.17	7	298.3	-0.57	5
500	500	0	9	500	0	7	500	0	4	NA	-	-
HIGH	5000	-	0	4000	-	0	2500	-	0	1789.8	-	0
LOW	19.53	-	255	15.625	-	255	9.766	-	255	6.991	-	255

	Fosc =	5.0688 MH	Ηz	4 MHz			3.579545	5 MHz		1 MHz			32.768 kHz		
BAUD RATE (K)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-	0.303	+1.14	26
1.2	NA	-	-	NA	-	-	NA	-	-	1.202	+0.16	207	1.170	-2.48	6
2.4	NA	-	-	NA	-	-	NA	-	-	2.404	+0.16	103	NA	-	-
9.6	9.6	0	131	9.615	+0.16	103	9.622	+0.23	92	9.615	+0.16	25	NA	-	-
19.2	19.2	0	65	19.231	+0.16	51	19.04	-0.83	46	19.24	+0.16	12	NA	-	-
76.8	79.2	+3.13	15	76.923	+0.16	12	74.57	-2.90	11	83.34	+8.51	2	NA	-	-
96	97.48	+1.54	12	1000	+4.17	9	99.43	+3.57	8	NA	-	-	NA	-	-
300	316.8	+5.60	3	NA	-	-	298.3	-0.57	2	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	1267	-	0	100	-	0	894.9	-	0	250	-	0	8.192	-	0
LOW	4.950	-	255	3.906	-	255	3.496	-	255	0.9766	-	255	0.032	-	255

TABLE 12-4: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

BAUD	Fosc = 20 MHz S		SPBRG	16 MHz		SPBRG	10 MHz		SPBRG	7.15909	MHz	SPBRG
RATE (K)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1.2	1.221	+1.73	255	1.202	+0.16	207	1.202	+0.16	129	1.203	+0.23	92
2.4	2.404	+0.16	129	2.404	+0.16	103	2.404	+0.16	64	2.380	-0.83	46
9.6	9.469	-1.36	32	9.615	+0.16	25	9.766	+1.73	15	9.322	-2.90	11
19.2	19.53	+1.73	15	19.23	+0.16	12	19.53	+1.73	7	18.64	-2.90	5
76.8	78.13	+1.73	3	83.33	+8.51	2	78.13	+1.73	1	NA	-	-
96	104.2	+8.51	2	NA	-	-	NA	-	-	NA	-	-
300	312.5	+4.17	0	NA	-	-	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	312.5	-	0	250	-	0	156.3	-	0	111.9	-	0
LOW	1.221	-	255	0.977	-	255	0.6104	-	255	0.437	-	255

	FOSC = 5.0688 MHz 4 MHz						3.57954	5 MHz		1 MHz			32.768 kHz		
BAUD RATE (K)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	0.31	+3.13	255	0.3005	-0.17	207	0.301	+0.23	185	0.300	+0.16	51	0.256	-14.67	1
1.2	1.2	0	65	1.202	+1.67	51	1.190	-0.83	46	1.202	+0.16	12	NA	-	-
2.4	2.4	0	32	2.404	+1.67	25	2.432	+1.32	22	2.232	-6.99	6	NA	-	-
9.6	9.9	+3.13	7	NA	-	-	9.322	-2.90	5	NA	-	-	NA	-	-
19.2	19.8	+3.13	3	NA	-	-	18.64	-2.90	2	NA	-	-	NA	-	-
76.8	79.2	+3.13	0	NA	-	-	NA	-	-	NA	-	-	NA	-	-
96	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
300	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	79.2	-	0	62.500	-	0	55.93	-	0	15.63	-	0	0.512	-	0
LOW	0.3094	-	255	3.906	-	255	0.2185	-	255	0.0610	-	255	0.0020	-	255

TABLE 12-5: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 1)

BAUD RATE (K)	Fosc = 2 KBAUD	20 MHz % ERROR	SPBRG value (decimal)	16 MHz KBAUD	% ERROR	SPBRG value (decimal)	10 MHz KBAUD	% ERROR	SPBRG value (decimal)	7.16 MH: KBAUD	z RROR	SPBRG value (decimal)
9.6	9.615	+0.16	129	9.615	+0.16	103	9.615	+0.16	64	9.520	-0.83	46
19.2	19.230	+0.16	64	19.230	+0.16	51	18.939	-1.36	32	19.454	+1.32	22
38.4	37.878	-1.36	32	38.461	+0.16	25	39.062	+1.7	15	37.286	-2.90	11
57.6	56.818	-1.36	21	58.823	+2.12	16	56.818	-1.36	10	55.930	-2.90	7
115.2	113.636	-1.36	10	111.111	-3.55	8	125	+8.51	4	111.860	-2.90	3
250	250	0	4	250	0	3	NA	-	-	NA	-	-
625	625	0	1	NA	-	-	625	0	0	NA	-	-
1250	1250	0	0	NA	-	-	NA	-	-	NA	-	-

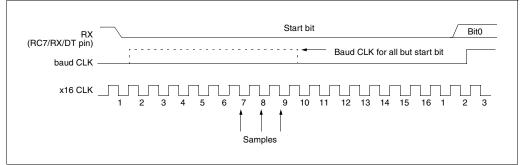
BAUD	Fosc = 5	.068 MHz	SPBRG	4 MHz		SPBRG	3.579 Mł	lz	SPBRG	1 MHz		SPBRG	32.768	кНz	SPBRG
RATE		%	value		%	value		%	value		%	value		%	value
(K)	KBAUD	ERROR	(decimal)	KBAUD	ERROR	(decimal)	KBAUD	ERROR	(decimal)	KBAUD	ERROR	(decimal)	KBAUD	ERROR	(decimal)
9.6	9.6	0	32	NA	-	-	9.727	+1.32	22	8.928	-6.99	6	NA	-	-
19.2	18.645	-2.94	16	1.202	+0.17	207	18.643	-2.90	11	20.833	+8.51	2	NA	-	-
38.4	39.6	+3.12	7	2.403	+0.13	103	37.286	-2.90	5	31.25	-18.61	1	NA	-	-
57.6	52.8	-8.33	5	9.615	+0.16	25	55.930	-2.90	3	62.5	+8.51	0	NA	-	-
115.2	105.6	-8.33	2	19.231	+0.16	12	111.860	-2.90	1	NA	-	-	NA	-	-
250	NA	-	-	NA	-	-	223.721	-10.51	0	NA	-	-	NA	-	-
625	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1250	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-

Note: For the PIC16C63/R63/65/65A/R65 the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information or use the PIC16C66/67.

12.1.1 SAMPLING

The data on the RC7/RX/DT pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin. If bit BRGH (TXSTA<2>) is clear (i.e., at the low baud rates), the sampling is done on the seventh, eighth and ninth falling edges of a x16 clock (Figure 12-3). If bit BRGH is set (i.e., at the high baud rates), the sampling is done on the 3 clock edges preceding the second rising edge after the first falling edge of a x4 clock (Figure 12-4 and Figure 12-5).







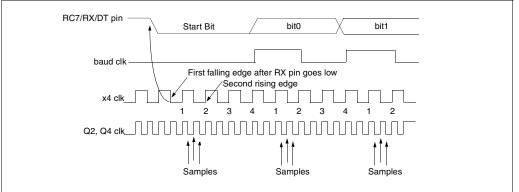
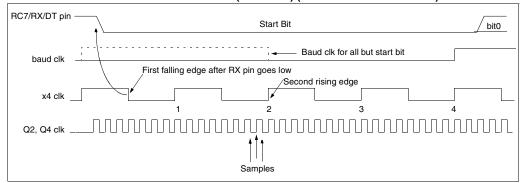


FIGURE 12-5: RX PIN SAMPLING SCHEME (BRGH = 1) (PIC16C63/R63/65/65A/R65)



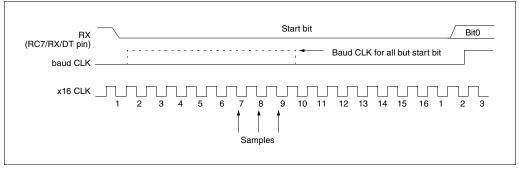


FIGURE 12-6: RX PIN SAMPLING SCHEME (BRGH = 0 OR = 1) (PIC16C66/67)

12.2 USART Asynchronous Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 In this mode, the USART uses standard nonreturn-tozero (NRZ) format (one start bit, eight or nine data bits and one stop bit). The most common data format is 8-bits. An on-chip dedicated 8-bit baud rate generator can be used to derive standard baud rate frequencies from the oscillator. The USART transmits and receives the LSb first. The USART's transmitter and receiver are functionally independent but use the same data format and baud rate. The baud rate generator produces a clock either x16 or x64 of the bit shift rate, depending on bit BRGH (TXSTA<2>). Parity is not supported by the hardware, but can be implemented in software (and stored as the ninth data bit). Asynchronous mode is stopped during SLEEP.

Asynchronous mode is selected by clearing bit SYNC (TXSTA<4>).

The USART Asynchronous module consists of the following important elements:

- · Baud Rate Generator
- Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver

12.2.1 USART ASYNCHRONOUS TRANSMITTER

The USART transmitter block diagram is shown in Figure 12-7. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the STOP bit has been transmitted from the previous load. As soon as the STOP bit is transmitted, the TSR is loaded with new data from the TXREG (if available). Once the TXREG register transfers the data to the TSR register (occurs in one Tcv) the TXREG register is empty and flag bit TXIF (PIR1<4>) is set. This interrupt is enabled/dis

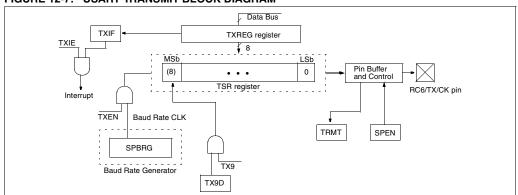
FIGURE 12-7: USART TRANSMIT BLOCK DIAGRAM

abled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit, TRMT (TXSTA<1>) shows the status of the TSR register. Status bit TRMT is a read only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty.

Note 1:	The TSR register is not mapped in data memory so it is not available to the user.
Note 2:	Flag bit TXIF is set when enable bit TXEN is set.

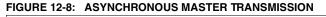
Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data and the baud rate generator (BRG) has produced a shift clock (Figure 12-7). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN. Normally when transmission is first started, the TSR register is empty, so a transfer to the TXREG register will result in an immediate transfer to TSR register resulting in an empty TXREG register. A back-to-back transfer is thus possible (Figure 12-9). Clearing enable bit TXEN during a transmission will cause the transmission to be aborted and will revert to hi-impedance.

In order to select 9-bit transmission, transmit bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to bit TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). In such a case, an incorrect ninth data bit maybe loaded in the TSR register.



Steps to follow when setting up an Asynchronous Transmission:

- 1. Initialize the SPBRG register for the appropriate baud rate. If a high speed baud rate is desired, then set bit BRGH. (Section 12.1).
- 2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
- 3. If interrupts are desired, then set enable bit TXIE.
- 4. If 9-bit transmission is desired, then set transmit bit TX9.
- 5. Enable the transmission by setting bit TXEN, which will also set bit TXIF.
- 6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
- 7. Load data to the TXREG register (starts transmission).



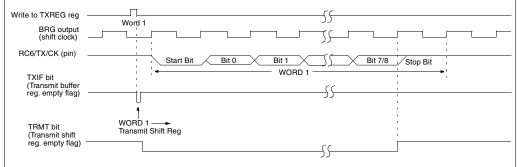


FIGURE 12-9: ASYNCHRONOUS MASTER TRANSMISSION (BACK TO BACK)

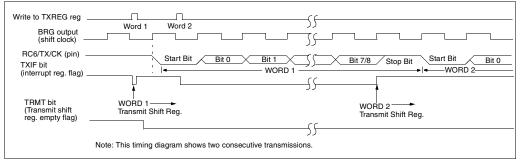


TABLE 12-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN		FERR	OERR	RX9D	0000 -00x	0000 -00x
19h	TXREG	USART Tra	ansmit R	egister						0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC		BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate	Generat	tor Registe	ər					0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Transmission.

Note 1: PSPIF and PSPIE are reserved on the PIC16C63/R63/66, always maintain these bits clear.

2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

12.2.2 USART ASYNCHRONOUS RECEIVER

The receiver block diagram is shown in Figure 12-10. The data comes in the RC7/RX/DT pin and drives the data recovery block. The data recovery block is actually a high speed shifter operating at x16 times the baud rate, whereas the main receive serial shifter operates at the bit rate or at FOSC.

Once Asynchronous mode is selected, reception is enabled by setting bit CREN (RCSTA<4>).

The heart of the receiver is the receive (serial) shift register (RSR). After sampling the STOP bit, the received data in the RSR is transferred to the RCREG register (if it is empty). If the transfer is complete, flag bit RCIF (PIR1<5>) is set. The actual interrupt can be enabled/disabled by setting/clearing enable bit RCIE (PIE1<5>). Flag bit RCIF is a read only bit which is cleared by the hardware. It is cleared when the RCREG register has been read and is empty. The RCREG is double buffered register, i.e., it is a two deep FIFO. It is

FIGURE 12-10: USART RECEIVE BLOCK DIAGRAM

possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte begin shifting to the RSR register. On the detection of the STOP bit of the third byte, if the RCREG is still full, then the overrun error bit, OERR (RCSTA<1>) will be set. The word in the RSR register will be lost. The RCREG register can be read twice to retrieve the two bytes in the FIFO. Overrun bit OERR has to be cleared in software. This is done by resetting the receive logic (CREN is cleared and then set). If bit OERR is set, transfers from the RSR register to the RCREG register are inhibited, so it is essential to clear overrun bit OERR if it is set. Framing error bit FERR (RCSTA<2>) is set if a stop bit is detected as clear. Error bit FERR and the 9th receive bit are buffered the same way as the receive data. Reading the RCREG register will load bits RX9D and FERR with new values. Therefore it is essential for the user to read the RCSTA register before reading RCREG in order not to lose the old FERR and RX9D information.

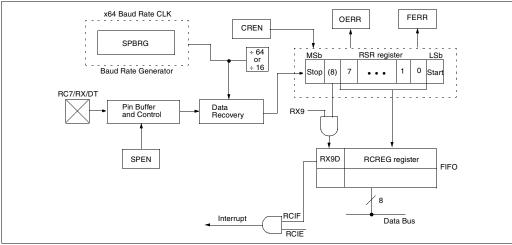
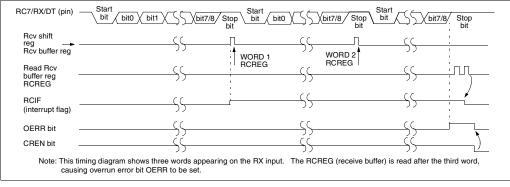


FIGURE 12-11: ASYNCHRONOUS RECEPTION



Steps to follow when setting up an Asynchronous Reception:

- 1. Initialize the SPBRG register for the appropriate baud rate. If a high speed baud rate is desired, set bit BRGH (Section 12.1).
- 2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
- 3. If interrupts are desired, then set enable bit RCIE.
- 4. If 9-bit reception is desired, then set bit RX9.
- 5. Enable the reception by setting enable bit CREN.
- Flag bit RCIF will be set when reception is complete, and an interrupt will be generated if enable bit RCIE was set.
- 7. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
- 8. Read the 8-bit received data by reading the RCREG register.
- 9. If any error occurred, clear the error by clearing enable bit CREN.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
1Ah	RCREG	USART Re	eceive Re	egister						0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate	Generat	tor Regist	ər					0000 0000	0000 0000

TABLE 12-7: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Reception.

Note 1: PSPIE and PSPIF are reserved on the PIC16C63/R63/66, always maintain these bits clear.

2: PIE1<6> and PIR1<6> are reserved, always maintain these bits clear.

12.3 USART Synchronous Master Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

In Synchronous Master mode the data is transmitted in a half-duplex manner i.e., transmission and reception do not occur at the same time. When transmitting data the reception is inhibited and vice versa. Synchronous mode is entered by setting bit SYNC (TXSTA<4>). In addition enable bit SPEN (RCSTA<7>) is set in order to configure the RC6 and RC7 I/O pins to CK (clock) and DT (data) lines respectively. The Master mode indicates that the processor transmits the master clock on the CK line. The Master mode is entered by setting bit CSRC (TXSTA<7>).

12.3.1 USART SYNCHRONOUS MASTER TRANSMISSION

The USART transmitter block diagram is shown in Figure 12-7. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer register. TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the last bit has been transmitted from the previous load. As soon as the last bit is transmitted, the TSR register is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register (occurs in one Tcycle), the TXREG register is empty and interrupt flag bit TXIF (PIR1<4>) is set. This interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the status of enable bit TXIE and cannot be cleared in software. It will clear only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit, TRMT (TXSTA<1>), shows the status of the TSR register. Status bit TRMT is a read only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty. The TSR register is not mapped in data memory so it is not available to the user.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data. The first data bit will be shifted out on the next available rising edge of the clock on the CK line. Data out is stable around the falling edge of the synchronous clock (Figure 12-12). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN (Figure 12-13). This is advantageous when slow baud rates are selected, since the BRG is kept in reset when bits TXEN, CREN, and SREN are clear. Setting enable bit TXEN will start the BRG, creating a shift clock immediately. Normally when transmission is first started, the TSR register is empty, so a transfer to the TXREG register will result in an immediate transfer to TSR resulting in an empty TXREG register. Back-to-back transfers are possible.

Clearing enable bit TXEN, during a transmission, will cause the transmission to be aborted and will reset the transmitter. The DT and CK pins will revert to hi-impedance. If, during a transmission, either bit CREN or bit SREN is set the transmission is aborted and the DT pin reverts to a hi-impedance state (for a reception). The CK pin will remain an output if bit CSRC is set (internal clock). The transmitter logic however, is not reset although it is disconnected from the pins. In order to reset the transmitter, the user has to clear enable bit TXEN. If enable bit SREN is set (to interrupt an on going transmission and receive a single word), then after the single word is received, enable bit SREN will be cleared, and the serial port will revert back to transmitting since enable bit TXEN is still set. The DT line will immediately switch from hi-impedance receive mode to transmit and start driving. To avoid this, enable bit TXEN should be cleared.

In order to select 9-bit transmission, bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to bit TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). If the TSR register was empty and the TXREG register was written before writing the "new" TX9D, the "present" value of bit TX9D is loaded.

Steps to follow when setting up a Synchronous Master Transmission:

- 1. Initialize the SPBRG register for the appropriate baud rate (Section 12.1).
- 2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
- 3. If interrupts are desired, then set enable bit $\ensuremath{\mathsf{TXIE}}$.
- 4. If 9-bit transmission is desired, then set bit TX9.
- 5. Enable the transmission by setting enable bit TXEN.
- 6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
- 7. Start transmission by loading data to the TXREG register.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	x00- 0000	x00- 0000
19h	TXREG	USART Tra	ansmit Re	egister						0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate	Generat	or Regist	ter					0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Synchronous Master Transmission. Note 1: PSPIE and PSPIF are reserved on the PIC16C63/R63/66, always maintain these bits clear. 2: PIE1<6> and PIR1<6> are reserved, always maintain these bits clear.

FIGURE 12-12: SYNCHRONOUS TRANSMISSION

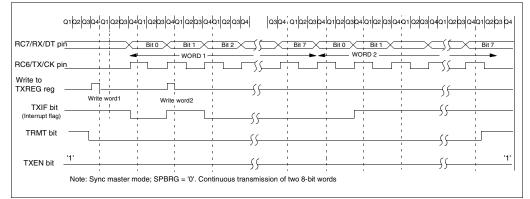
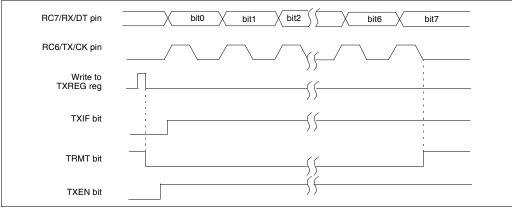


FIGURE 12-13: SYNCHRONOUS TRANSMISSION THROUGH TXEN



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12.3.2 USART SYNCHRONOUS MASTER RECEPTION

Once Synchronous Mode is selected, reception is enabled by setting either enable bit SREN (RCSTA<5>) bit or enable bit CREN (RCSTA<4>). Data is sampled on the DT pin on the falling edge of the clock. If enable bit SREN is set, then only a single word is received. If enable bit CREN is set, the reception is continuous until bit CREN is cleared. If both the bits are set then bit CREN takes precedence. After clocking the last bit, the received data in the Receive Shift Register (RSR) is transferred to the RCREG register (if it is empty). When the transfer is complete, interrupt bit RCIF (PIR1<5>) is set. The actual interrupt can be enabled/disabled by setting/clearing enable bit RCIE (PIE1<5>). Flag bit RCIF is a read only bit which is reset by the hardware. In this case, it is reset when the RCREG register has been read and is empty. The RCREG is a double buffered register, i.e., it is a two deep FIFO. It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte to begin shifting into the RSR register. On the clocking of the last bit of the third byte, if the RCREG register is still full, then overrun error bit, OERR (RCSTA<1>) is set. The word in the RSR register will be lost. The RCREG register can be read twice to retrieve the two bytes in the FIFO. Overrun error bit OERR has to be cleared in software (by clearing bit CREN). If bit OERR is set, transfers from the RSR to the RCREG are inhibited, so it is essential to clear bit OERR if it is set. The 9th receive bit is buffered the same way as the receive data. Reading the RCREG register will load bit RX9D with a new value. Therefore it is essential for the user to read the RCSTA register before reading the RCREG register in order not to lose the old RX9D bit information.

Steps to follow when setting up Synchronous Master Reception:

- 1. Initialize the SPBRG register for the appropriate baud rate (Section 12.1).
- 2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
- 3. Ensure bits CREN and SREN are clear.
- 4. If interrupts are desired, then set enable bit $\ensuremath{\mathsf{RCIE}}$.
- 5. If 9-bit reception is desired, then set bit RX9.
- If a single reception is required, set enable bit SREN. For continuous reception set enable bit CREN.
- Flag bit RCIF will be set when reception is complete and an interrupt will be generated if enable bit RCIE was set.
- Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
- 9. Read the 8-bit received data by reading the RCREG register.
- 10. If any error occurred, clear the error by clearing enable bit CREN.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	_	FERR	OERR	RX9D	0000 -00x	0000 -00x
1Ah	RCREG	USART Re	ceive Re	gister						0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate	Generat	or Regis	ter					0000 0000	0000 0000

TABLE 12-9: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Synchronous Master Reception. Note 1: PSPIF and PSPIE are reserved on the PIC16C63/R63/66, always maintain these bits clear.

2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

13/04/01/0	2 Q3 Q4 Q1 Q2	Q3Q4Q1Q2	Q3Q4Q1Q2	23 04 01 02	030401020	1304010203	Q4Q1Q2Q3Q	40102030	401020304
t t t	bit0	bit1	, bit2	, bit3	bit4	bit5	bit6	bit7	1 1 1
1 1 1						<u> </u>			1 1 1
			1 1 1 1	1 1 1 1	1 1 1 1		1 1 1	t t t t	
	1	1	1	t t	r r	1 1 1	1		1
)' '	1	1	1	t t	t t	1	1	t t	'0'
t t t	1 1 1	1 1 1	1 1 1	1 1 1	1 1 1	 	1 1 1		
t t	1	1	1 1 1	t t	t t	1 1 1	1	t t	
			bito bit1		bito bit1 bit2 bit3	bit0 bit1 bit2 bit3 bit4		bit0 bit1 bit2 bit3 bit4 bit5 bit6	

FIGURE 12-14: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)

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12.4 USART Synchronous Slave Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Synchronous Slave Mode differs from Master Mode in the fact that the shift clock is supplied externally at the CK pin (instead of being supplied internally in master mode). This allows the device to transfer or receive data while in SLEEP mode. Slave mode is entered by clearing bit CSRC (TXSTA<7>).

12.4.1 USART SYNCHRONOUS SLAVE TRANSMIT

The operation of the synchronous master and slave modes are identical except in the case of the SLEEP mode.

If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

- a) The first word will immediately transfer to the TSR register and transmit.
- b) The second word will remain in TXREG register.
- c) Flag bit TXIF will not be set.
- d) When the first word has been shifted out of TSR, the TXREG register will transfer the second word to the TSR and flag bit TXIF will now be set.
- e) If enable bit TXIE is set, the interrupt will wake the chip from SLEEP and if the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

Steps to follow when setting up Synchronous Slave Transmission:

- 1. Enable the synchronous slave serial port by setting bits SYNC and SPEN, and clearing bit CSRC.
- 2. Clear bits CREN and SREN.
- 3. If interrupts are desired, then set enable bit TXIE.
- 4. If 9-bit transmission is desired, then set bit TX9.
- 5. Enable the transmission by setting bit TXEN.
- 6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
- 7. Start transmission by loading data to the TXREG register.

12.4.2 USART SYNCHRONOUS SLAVE RECEPTION

The operation of the synchronous master and slave modes is identical except in the case of the SLEEP mode. Also, enable bit SREN is a don't care in slave mode.

If receive is enabled by setting bit CREN prior to the SLEEP instruction, then a word may be received during SLEEP. On completely receiving the word, the RSR register will transfer the data to the RCREG register and if enable bit RCIE is set, the interrupt generated will wake the chip from SLEEP. If the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

Steps to follow when setting up a Synchronous Slave Reception:

- Enable the synchronous master serial port by setting bits SYNC and SPEN, and clearing bit CSRC.
- 2. If interrupts are desired, then set enable bit RCIE.
- 3. If 9-bit reception is desired, then set bit RX9.
- 4. To enable reception, set enable bit CREN.
- Flag bit RCIF will be set when reception is complete, and an interrupt will be generated if enable bit RCIE was set.
- Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
- 7. Read the 8-bit received data by reading the RCREG register.
- 8. If any error occurred, clear the error by clearing enable bit CREN.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	_	FERR	OERR	RX9D	0000 -00x	0000 -00x
19h	TXREG	USART Tra	ansmit R	egister						0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate	Generat	or Registe	ər		•			0000 0000	0000 0000

TABLE 12-10: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Synchronous Slave Transmission. Note 1: PSPIF and PSPIE are reserved on the PIC16C63/R63/66, always maintain these bits clear.

2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

TABLE 12-11: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
1Ah	RCREG	USART Re	eceive Re	egister						0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate	Generat	or Regist	ter					0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Synchronous Slave Reception.

Note 1: PSPIF and PSPIE are reserved on the PIC16C63/R63/66, always maintain these bits clear.

2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

NOTES:

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13.0 SPECIAL FEATURES OF THE CPU

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

What sets a microcontroller apart from other processors are special circuits to deal with the needs of realtime applications. The PIC16CXX family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These are:

- Oscillator selection
- Reset
- Power-on Reset (POR)
- Power-up Timer (PWRT)
- Oscillator Start-up Timer (OST)
- Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- SLEEP mode
- · Code protection
- ID locations
- In-circuit serial programming

The PIC16CXX has a Watchdog Timer which can be shut off only through configuration bits. It runs off its own RC oscillator for added reliability. There are two

timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in reset while the power supply stabilizes. With these two timers on-chip, most applications need no external reset circuitry.

SLEEP mode is designed to offer a very low current power-down mode. The user can wake from SLEEP through external reset, Watchdog Timer Wake-up or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

13.1 Configuration Bits

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h - 3FFFh), which can be accessed only during programming.

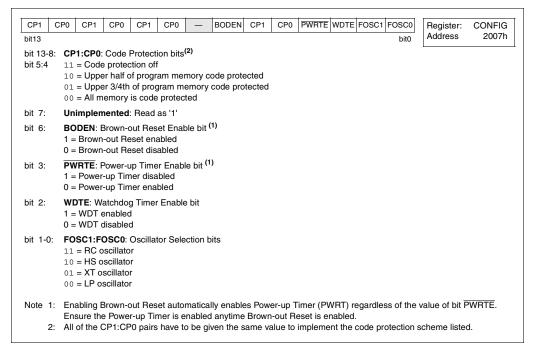
FIGURE 13-1: CONFIGURATION WORD FOR PIC16C61

— bit13	- -	_	—	-	_	_	-	CP0	PWRTE	WDTE	FOSC1	FOSC0 bit0	Register: Address	CONFIG 2007h
bit 13-5:	Unimpler	nented	Read a	as '1'										
bit 4:	CP0 : Cod 1 = Code 0 = All me	protecti	on off		d, but ()0h - 3l	=h is wi	ritable						
bit 3:	PWRTE : 1 = Power 0 = Power	r-up Tim	ier enat	oled	e bit									
bit 2:	WDTE : W 1 = WDT 0 = WDT	enabled		Enable	bit									
bit 1-0:	FOSC1:F 11 = RC (10 = HS (01 = XT (00 = LP (oscillato oscillato oscillato	r r	or Sele	ction bi	ts								

FIGURE 13-2: CONFIGURATION WORD FOR PIC16C62/64/65

		_	_	—	_	_	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0	Register:	CONFIG
bit13												bit0	Address	2007h
bit 13-6:	Unimpler	nented	Read	as '1'										
bit 5-4:	CP1:CP0 11 = Code 10 = Uppe 01 = Uppe 00 = All m	e protec er half c er 3/4th	tion off f progra of prog	am men Iram me	mory c									
bit 3:	1 = Power	PWRTE: Power-up Timer Enable bit 1 = Power-up Timer enabled 0 = Power-up Timer disabled												
bit 2:	1 = WDT	WDTE: Watchdog Timer Enable bit 1 = WDT enabled 0 = WDT disabled												
bit 1-0:	FOSC1:F 11 = RC (10 = HS (01 = XT (00 = LP (oscillato oscillato	r r	or Selee	ction bi	ts								

FIGURE 13-3: CONFIGURATION WORD FOR PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67



13.2 Oscillator Configurations

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

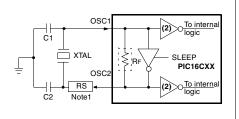
13.2.1 OSCILLATOR TYPES

The PIC16CXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor
- 13.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In LP, XT, or HS modes a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 13-4). The PIC16CXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in LP, XT, or HS modes, the device can have an external clock source to drive the OSC1/ CLKIN pin (Figure 13-5).

FIGURE 13-4: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



See Table 13-1, Table 13-3, Table 13-2 and Table 13-4 for recommended values of C1 and C2.

- Note 1: A series resistor may be required for AT strip cut crystals.
 - 2: For the PIC16C61 the buffer is on the OSC2 pin, all other devices have the buffer on the OSC1 pin.

FIGURE 13-5: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

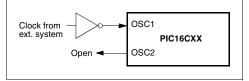


TABLE 13-1: CERAMIC RESONATORS PIC16C61

Ranges Te	Ranges Tested:									
Mode	Freq	OSC2								
ХТ	455 kHz 2.0 MHz 4.0 MHz	47 - 100 pF 15 - 68 pF 15 - 68 pF	47 - 100 pF 15 - 68 pF 15 - 68 pF							
HS	8.0 MHz 16.0 MHz	15 - 68 pF 10 - 47 pF	15 - 68 pF 10 - 47 pF							
	se values are for s at bottom of page		nce only. See							
Resonator	s Used:									
455 kHz	Panasonic EF	D-A455K04B	± 0.3%							
2.0 MHz	Murata Erie CS	SA2.00MG	± 0.5%							
4.0 MHz	Murata Erie CSA4.00MG ± 0.5%									
8.0 MHz	Murata Erie CS	Murata Erie CSA8.00MT ± 0.5%								
16.0 MHz	Murata Erie CS	SA16.00MX	$\pm 0.5\%$							

TABLE 13-2: CERAMIC RESONATORS PIC16C62/62A/R62/63/R63/64/ 64A/R64/65/65A/R65/66/67

All resonators used did not have built-in capacitors.

Ranges Tested:								
Mode	Freq	OSC2						
XT	455 kHz	68 - 100 pF	68 - 100 pF					
	2.0 MHz	15 - 68 pF	15 - 68 pF					
	4.0 MHz	15 - 68 pF	15 - 68 pF					
HS	8.0 MHz	10 - 68 pF	10 - 68 pF					
16.0 MHz 10 - 22 pF 10 - 22 pF								
	se values are f es at bottom of p	or design guidar bage.	nce only. See					
Resonator	rs Used:							
455 kHz	Panasonic E	FO-A455K04B	± 0.3%					
2.0 MHz	Murata Erie	CSA2.00MG	$\pm 0.5\%$					
4.0 MHz	Murata Erie	CSA4.00MG	$\pm 0.5\%$					
8.0 MHz	Murata Erie	CSA8.00MT	$\pm 0.5\%$					
16.0 MHz	Murata Erie	CSA16.00MX	$\pm 0.5\%$					
All reso	onators used did	d not have built-in	capacitors.					

TABLE 13-3: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR FOR PIC16C61

Mode	Freq	OSC1	OSC2				
LP	32 kHz	33 - 68 pF	33 - 68 pF				
	200 kHz	15 - 47 pF	15 - 47 pF				
XT	100 kHz	47 - 100 pF	47 - 100 pF				
	500 kHz	20 - 68 pF	20 - 68 pF				
	1 MHz	15 - 68 pF	15 - 68 pF				
	2 MHz	15 - 47 pF	15 - 47 pF				
	4 MHz	15 - 33 pF	15 - 33 pF				
HS	8 MHz	15 - 47 pF	15 - 47 pF				
	20 MHz	15 - 47 pF	15 - 47 pF				
	These values are for design guidance only. See notes at bottom of page.						

TABLE 13-4:CAPACITOR SELECTION FOR
CRYSTAL OSCILLATOR FOR
PIC16C62/62A/R62/63/R63/64/
64A/R64/65/65A/R65/66/67

Оѕс Туре	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
	e values are at bottom of	for design guidanc page.	e only. See
	Crys	atals Used	
32 kHz	Epson C-00	01R32.768K-A	± 20 PPM
200 kHz	STD XTL 2	00.000KHz	± 20 PPM
1 MHz	ECS ECS-	± 50 PPM	
4 MHz	ECS ECS-4	± 50 PPM	
8 MHz	EPSON CA	A-301 8.000M-C	± 30 PPM
20 MHz	EPSON CA	-301 20.000M-C	± 30 PPM

Note 1: Recommended values of C1 and C2 are identical to the ranges tested Table 13-1 and Table 13-2.

2: Higher capacitance increases the stability of oscillator but also increases the start-up time.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

4: Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification.

13.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance, or one with parallel resonance.

Figure 13-6 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 k Ω resistor provides the negative feedback for stability. The 10 k Ω potentioometer biases the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 13-6: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

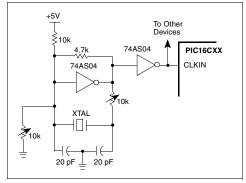
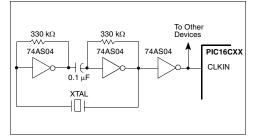


Figure 13-7 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 k Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 13-7: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



13.2.4 RC OSCILLATOR

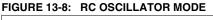
For timing insensitive applications the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 13-8 shows how the RC combination is connected to the PIC16CXX. For Rext values below 2.2 kΩ, the oscillator operation may become unstable or stop completely. For very high Rext values (e.g. 1 M Ω), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping Rext between 3 k Ω and 100 k Ω .

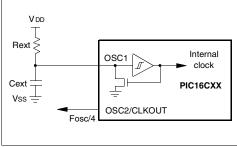
Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See characterization data for desired device for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See characterization data for desired device for variation of oscillator frequency due to VDD for given Rext/ Cext values as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic (see Figure 3-5 for waveform).





13.3 <u>Reset</u>

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 The PIC16CXX differentiates between various kinds of

reset:

- Power-on Reset (POR)
- MCLR reset during normal operation
- MCLR reset during SLEEP
- WDT Reset (normal operation)
- Brown-out Reset (BOR) Not on PIC16C61/62/ 64/65

Some registers are not affected in any reset condition, their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a "reset state" on Power-on Reset (POR), on $\overline{\text{MCLR}}$ or $\overline{\text{WDT}}$ Reset, on $\overline{\text{MCLR}}$ reset during SLEEP, and on Brownout Reset (BOR). They are not affected by a WDT Wake-up, which is viewed as the resumption of normal operation.

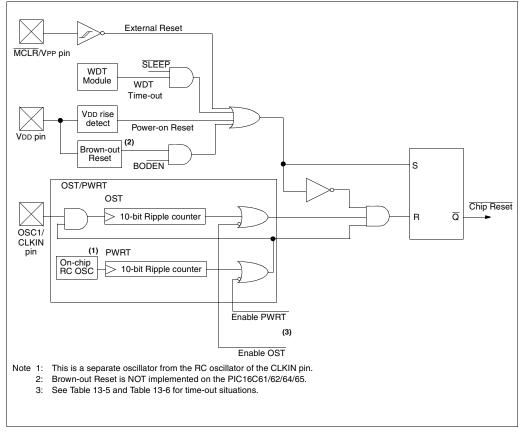
The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different reset situations as indicated in Table 13-7, Table 13-8, and Table 13-9. These bits are used in software to determine the nature of the reset. See Table 13-12 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 13-9.

On the PIC16C62A/R62/63/R63/64A/R64/65A/R65/ 66/67, the MCLR reset path has a noise filter to detect and ignore small pulses. See parameter #34 for pulse width specifications.

It should be noted that a WDT Reset does not drive the $\overline{\text{MCLR}}$ pin low.

FIGURE 13-9: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



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13.4 <u>Power-on Reset (POR), Power-up</u> <u>Timer (PWRT), Oscillator Start-up</u> <u>Timer (OST) and Brown-out Reset</u> (BOR)

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

13.4.1 POWER-ON RESET (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the POR, just tie the \overline{MCLR}/VPP pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is required. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

For additional information, refer to Application Note AN607, "Power-up Trouble Shooting."

13.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

13.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

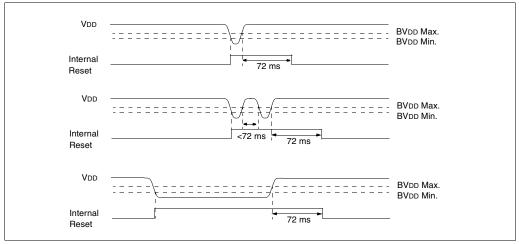
13.4.4 BROWN-OUT RESET (BOR)

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (parameter D005 in Electrical Specification section) for greater than parameter #34 (see Electrical Specification section), the brown-out situation will reset the chip. A reset may not occur if VDD falls below 4.0V for less than parameter #34. The chip will remain in Brown-out Reset until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms. If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms time delay. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 13-10 shows typical brown-out situations.

FIGURE 13-10: BROWN-OUT SITUATIONS



13.4.5 TIME-OUT SEQUENCE

On power-up the time-out sequence is as follows: First a PWRT time-out is invoked after the POR time delay has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode, with the PWRT disabled, there will be no time-out at all. Figure 13-11, Figure 13-12, and Figure 13-13 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if the $\overline{\text{MCLR}}/\text{VPP}$ pin is kept low long enough, the time-outs will expire. Then bringing the $\overline{\text{MCLR}}/\text{VPP}$ pin high will begin execution immediately (Figure 13-14). This is useful for testing purposes or to synchronize more than one PIC16CXX device operating in parallel.

Table 13-10 and Table 13-11 show the reset conditions for some special function registers, while Table 13-12 shows the reset conditions for all the registers.

13.4.6 POWER CONTROL/STATUS REGISTER (PCON)

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The Power Control/Status Register, PCON has up to two bits, depending upon the device. Bit0 is not implemented on the PIC16C62/64/65.

Bit0 is BOR (Brown-out Reset Status bit). BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if BOR cleared, indicating that a brown-out has occurred. The BOR status bit is a "Don't Care" and is not necessarily predictable if the Brown-out Reset circuitry is disabled (by clearing bit BODEN in the Configuration Word).

Bit1 is POR (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 13-5: TIME-OUT IN VARIOUS SITUATIONS, PIC16C61/62/64/65

Oscillator Configuration	Powe	r-up	Wake-up from SLEEP
	PWRTE = 1	PWRTE = 0	
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	1024 Tosc
RC	72 ms	—	—

TABLE 13-6: TIME-OUT IN VARIOUS SITUATIONS, PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67

Oscillator Configuration	Power	-up	Brown-out	Wake up from	
	PWRTE = 0 PWRTE = 1		Brown-out	SLEEP	
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	72 ms + 1024Tosc	1024 Tosc	
RC	72 ms		72 ms	—	

TABLE 13-7: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C61

TO	PD	
1	1	Power-on Reset or MCLR reset during normal operation
0	1	WDT Reset
0	0	WDT Wake-up
1	0	MCLR reset during SLEEP or interrupt wake-up from SLEEP

TABLE 13-8: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C62/64/65

POR	то	PD	
0	1	1	Power-on Reset
0	0	х	Illegal, TO is set on a Power-on Reset
0	x	0	Illegal, PD is set on a Power-on Reset
1	0	1	WDT Reset
1	0	0	WDT Wake-up
1	u	u	MCLR reset during normal operation
1	1	0	MCLR reset during SLEEP or interrupt wake-up from SLEEP

Legend: x = unknown, u = unchanged

TABLE 13-9: STATUS BITS AND THEIR SIGNIFICANCE FOR PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67

POR	BOR	то	PD	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, TO is set on a Power-on Reset
0	x	x	0	Illegal, PD is set on a Power-on Reset
1	0	x	x	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	MCLR reset during normal operation
1	1	1	0	MCLR reset during SLEEP or interrupt wake-up from SLEEP

Legend: x = unknown, u = unchanged

TABLE 13-10: RESET CONDITION FOR SPECIAL REGISTERS ON PIC16C61/62/64/65

	Program Counter	STATUS	PCON ⁽²⁾
Power-on Reset	000h	0001 1xxx	0 -
MCLR reset during normal operation	000h	000u uuuu	u-
MCLR reset during SLEEP	000h	0001 0uuu	u-
WDT Reset	000h	0000 luuu	u-
WDT Wake-up	PC + 1	uuu0 0uuu	u-
Interrupt wake-up from SLEEP	PC + 1 ⁽¹⁾	uuul 0uuu	u-

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC+1.

2: The PCON register is not implemented on the PIC16C61.

TABLE 13-11: RESET CONDITION FOR SPECIAL REGISTERS ON PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67

	Program Counter	STATUS	PCON
Power-on Reset	000h	0001 1xxx	0x
MCLR reset during normal operation	000h	000u uuuu	uu
MCLR reset during SLEEP	000h	0001 0uuu	uu
WDT Reset	000h	0000 luuu	uu
Brown-out Reset	000h	0001 luuu	u0
WDT Wake-up	PC + 1	uuu0 0uuu	uu
Interrupt wake-up from SLEEP	PC + 1 ⁽¹⁾	uuul 0uuu	uu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC+1.

Register	Applicable Devices			Power-or Browr Res	n-out	MCLR Reset during: – normal operation – SLEEP WDT Reset		Wake-up via interrupt or WDT Wake-up												
W	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
INDF	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	N/	A	N	I/A	N/A	۹.
TMR0	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
PCL	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	000	0h	0.0	00h	PC +	1 (2)
STATUS	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0001	1xxx	000q	quuu (3)	uuuq q	uuu (3)
FSR	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	
DODTA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	x	xxxx	u	uuuu	u ı	uuuu
PORTA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xx	xxxx	uu	uuuu	uu ı	uuuu
PORTB	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
PORTC	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
PORTD	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
PORTE	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		-xxx		-uuu		-uuu
PCLATH	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0	0000	0	0000	u ı	uuuu
INTCON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000	000x	0000	000u	uuuu u	uuu (1)
PIR1	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	00	0000	00	0000	uu u	uuu(1)
	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000	0000	0000	0000	uuuu u	uuu (1)
PIR2	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		0		0		
TMR1L	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu u	uuuu
TMR1H	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
T1CON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	00	0000	uu	uuuu	uu ı	uuuu
TMR2	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000	0000	0000	0000	uuuu i	uuuu
T2CON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	-000	0000	- 0 0 0	0000	-uuu i	uuuu
SSPBUF	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
SSPCON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000	0000	0000	0000	uuuu i	uuuu
CCPR1L	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
CCPR1H	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
CCP1CON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0 0	0000	0 0	0000	uu ı	uuuu
RCSTA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000	-00x	0000	-00x	uuuu ·	-uuu
TXREG	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000	0000	0000	0000	uuuu ı	uuuu
RCREG	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000	0000	0000	0000	uuuu ı	uuuu
CCPR2L	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	uuuu i	uuuu
CCPR2H	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx	xxxx	uuuu	uuuu	սսսս ւ	uuuu
CCP2CON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000	0000	0000	0000	uuuu i	uuuu
OPTION	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111	1111	1111	1111	uuuu ı	uuuu
TRISA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1	1111	1	1111	u ı	uuuu
INISA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	11	1111	11	1111	uu ı	uuuu
TRISB	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111	1111	1111	1111	սսսս ւ	uuuu
TRISC	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111	1111	1111	1111	uuuu ı	uuuu

TABLE 13-12: INITIALIZATION CONDITIONS FOR ALL REGISTERS

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0', q = value depends on condition.
Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).
2: When the wake-up is due to an interrupt and the global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC + 1.
3: See Table 13-10 and Table 13-11 for reset value for specific conditions.

TABLE 13-12: INITIALIZATION CONDITIONS FOR ALL REGISTERS (Cont.'d)

Register										Power-on Brown- Rese	-out	MCLR Rese – normal oj – SLEEP WDT Reset	Wake-up via interrupt or WDT Wake-up						
TRISD	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111 1	.111	1111	1111	uuuu uuuu
TRISE	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 -	111	0000	-111	uuuu -uuu
PIE1	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	000	000	00	0000	uu uuuu
	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0	000	0000	0000	uuuu uuuu
PIE2	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		0		0	u
PCON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		-0u		uu	uu
PCON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		- 0 -		u-	u-
PR2	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111 1	.111	1111	1111	1111 1111
SSPADD	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	00000	000	0000	0000	uuuu uuuu
SSPSTAT	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	00 0	000	0 0	0000	uu uuuu
TXSTA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 -	010	0000	-010	uuuu -uuu
SPBRG	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0	000	0000	0000	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0', q = value depends on condition.
Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).
2: When the wake-up is due to an interrupt and the global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

3: See Table 13-10 and Table 13-11 for reset value for specific conditions.

FIGURE 13-11: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 1

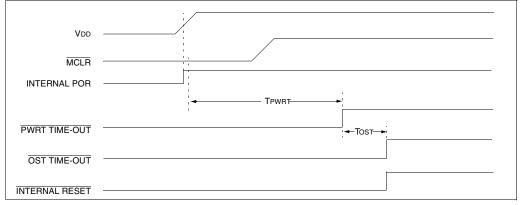


FIGURE 13-12: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2

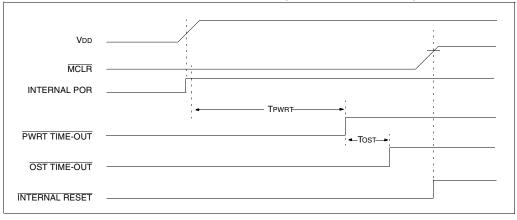
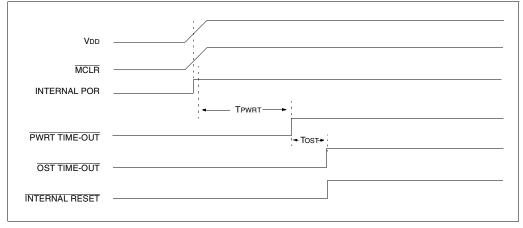
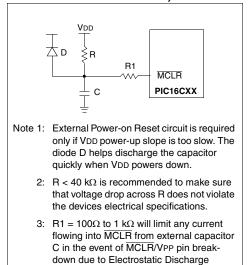


FIGURE 13-13: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)

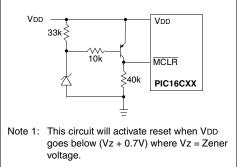


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FIGURE 13-14: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



(ESD) or Electrostatic Overstress (EOS).

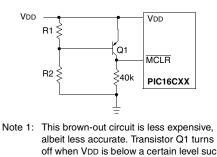


PROTECTION CIRCUIT 1

FIGURE 13-15: EXTERNAL BROWN-OUT

- 2: Internal brown-out detection on the PIC16C62A/R62/63/R63/64A/R64/65A/ R65/66/67 should be disabled when using this circuit.
- 3: Resistors should be adjusted for the characteristics of the transistors.

FIGURE 13-16: EXTERNAL BROWN-OUT **PROTECTION CIRCUIT 2**

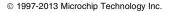


off when VDD is below a certain level such that:

$$r_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

ν

- 2: Internal brown-out detection on the PIC16C62A/R62/63/R63/64A/R64/65A/ R65/66/67 should be disabled when using this circuit.
- 3: Resistors should be adjusted for the characteristics of the transistors.



13.5 Interrupts

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The PIC16C6X family has up to 11 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or global enable bit, GIE.

Global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in the INTCON register. GIE is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine as well as sets the GIE bit, which re-enable interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flag bits are contained in the INTCON register.

The peripheral interrupt flag bits are contained in special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2 and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, bit GIE is cleared to disable any further interrupts, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the RB0/INT pin or RB port change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 13-19). The latency is the same for one or two cycle instructions. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid infinite interrupt requests. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

- Note: For the PIC16C61/62/64/65, if an interrupt occurs while the Global Interrupt Enable bit, GIE is being cleared, bit GIE may unintentionally be re-enabled by the user's Interrupt Service Routine (the RETFIE instruction). The events that would cause this to occur are:
 - 1. An instruction clears the GIE bit while an interrupt is acknowledged
 - 2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
 - The Interrupt Service Routine completes with the execution of the RET-FIE instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.
 - 4. Perform the following to ensure that interrupts are globally disabled.

LOOP	BCF IN	NTCON,GIE	;Disable Global
			;Interrupt bit
	BTFSC	INTCON,GIE	;Global Interrupt
			;Disabled?
	GOTO	LOOP	;NO, try again
	:		;Yes, continue
			;with program flow

FIGURE 13-17: INTERRUPT LOGIC FOR PIC16C61

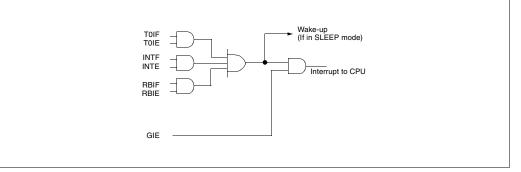
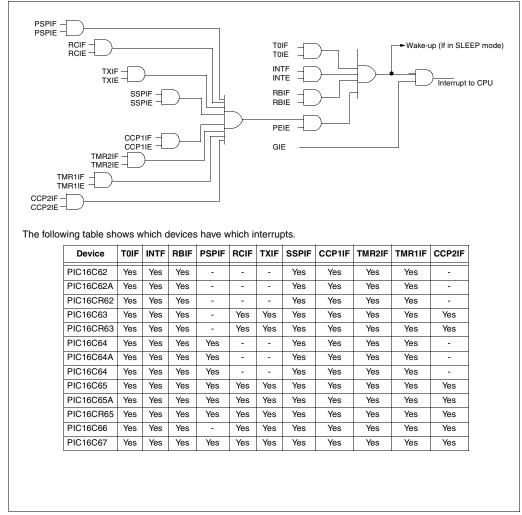


FIGURE 13-18: INTERRUPT LOGIC FOR PIC16C6X



13.5.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if edge select bit INTEDG (OPTION<6>) is set, or falling, if bit INTEDG is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake the processor from SLEEP. The status of global enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 13.8 for details on SLEEP mode.

13.5.2 TMR0 INTERRUPT

An overflow (FFh \rightarrow 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>) (Section 7.0).

13.5.3 PORTB INTERRUPT ON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>) (Section 5.2).

Note: For the PIC16C61/62/64/65, if a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then flag bit RBIF may not get set.

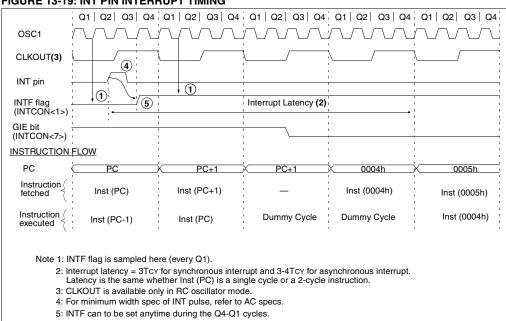


FIGURE 13-19: INT PIN INTERRUPT TIMING

13.6 Context Saving During Interrupts

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt i.e., W register and STATUS register. This will have to be implemented in software.

Example 13-1 stores and restores the STATUS and W registers. Example 13-2 stores and restores the STATUS, W, and PCLATH registers (Devices with paged program memory). For all PIC16C6X devices with greater than 1K of program memory (all devices except PIC16C61), the register, W_TEMP, must be

defined in all banks and must be defined at the same offset from the bank base address (i.e., if W_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1, 0x120 in bank 2, and 0x1A0 in bank 3).

The examples:

- a) Stores the W register
- b) Stores the STATUS register in bank 0
- c) Stores PCLATH
- d) Executes ISR code
- e) Restores PCLATH
- f) Restores STATUS register (and bank select bit)
- g) Restores W register

EXAMPLE 13-1: SAVING STATUS AND W REGISTERS IN RAM (PIC16C61)

MOVWF	W_TEMP	;Copy W to TEMP register, could be bank one or zero
SWAPF	STATUS,W	;Swap status to be saved into W
MOVWF	STATUS_TEMP	;Save status to bank zero STATUS_TEMP register
:		
:(ISR)		
:		
SWAPF	STATUS_TEMP,W	;Swap STATUS_TEMP register into W
		;(sets bank to original state)
MOVWF	STATUS	;Move W into STATUS register
SWAPF	W_TEMP,F	;Swap W_TEMP
SWAPF	W_TEMP,W	;Swap W_TEMP into W
	—	_
: SWAPF MOVWF SWAPF	 STATUS W_TEMP,F	;(sets bank to original state) ;Move W into STATUS register ;Swap W_TEMP

EXAMPLE 13-2: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM (ALL OTHER PIC16C6X DEVICES)

MOVWF	W_TEMP	;Copy W to TEMP register, could be bank one or zero
SWAPF	STATUS,W	;Swap status to be saved into W
CLRF	STATUS	;bank 0, regardless of current bank, Clears IRP,RP1,RP0
MOVWF	STATUS_TEMP	;Save status to bank zero STATUS_TEMP register
MOVF	PCLATH, W	;Only required if using pages 1, 2 and/or 3
MOVWF	PCLATH_TEMP	;Save PCLATH into W
CLRF	PCLATH	;Page zero, regardless of current page
BCF	STATUS, IRP	;Return to Bank 0
MOVF	FSR, W	;Copy FSR to W
MOVWF	FSR_TEMP	;Copy FSR from W to FSR_TEMP
:(ISR)		
:		
MOVF	PCLATH_TEMP, W	;Restore PCLATH
MOVWF	PCLATH	;Move W into PCLATH
SWAPF	STATUS_TEMP,W	;Swap STATUS_TEMP register into W
		;(sets bank to original state)
MOVWF	STATUS	;Move W into STATUS register
SWAPF	W_TEMP,F	;Swap W_TEMP
SWAPF	W_TEMP,W	;Swap W_TEMP into W

13.7 Watchdog Timer (WDT)

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 The Watchdog Timer is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/ CLKOUT pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time-out generates a device reset. If the device is in SLEEP mode, a WDT time-out causes the device to wake-up and continue with normal operation (WDT Wake-up). The WDT can be permanently disabled by clearing configuration bit WDTE (Section 13.1).

13.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be

FIGURE 13-20: WATCHDOG TIMER BLOCK DIAGRAM

assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device RESET condition.

The $\overline{\text{TO}}$ bit in the STATUS register will be cleared upon a WDT time-out.

13.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken in account that under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler) it may take several seconds before a WDT time-out occurs.

Note: When a CLRWDT instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed.

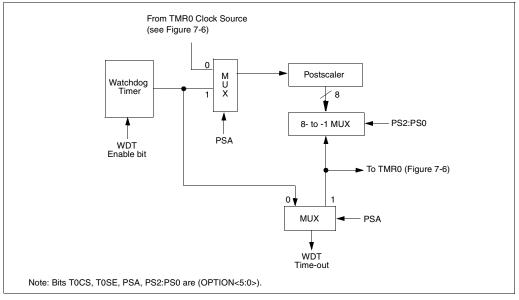


FIGURE 13-21: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	(1)	BODEN ⁽¹⁾	CP1	CP0	PWRTE ⁽¹⁾	WDTE	FOSC1	FOSC0
81h,181h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer.

Note 1: See Figure 13-1, Figure 13-2, and Figure 13-3 for details of these bits for the specific device.

13.8 Power-down Mode (SLEEP)

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Power-down mode is entered by executing a $\ensuremath{\mathtt{SLEEP}}$ instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, status bit \overline{PD} (STATUS<3>) is cleared, status bit \overline{TO} (STATUS<4>) is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either VDD, or VSS, ensure no external circuitry is drawing current from the I/O pin, and disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should also be at VDD or VSS for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The MCLR/VPP pin must be at a logic high level (VIHMC).

13.8.1 WAKE-UP FROM SLEEP

The device can wake from SLEEP through one of the following events:

- 1. External reset input on MCLR/VPP pin.
- 2. Watchdog Timer Wake-up (if WDT was enabled).
- 3. Interrupt from RB0/INT pin, RB port change, or some peripheral interrupts.

External $\overline{\text{MCLR}}$ Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register can be used to determine the cause of device reset. The $\overline{\text{PD}}$ bit, which is set on power-up is cleared when SLEEP is invoked. The $\overline{\text{TO}}$ bit is cleared if WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from SLEEP:

- 1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
- 2. SSP (Start/Stop) bit detect interrupt.
- 3. SSP transmit or receive in slave mode (SPI/I²C).
- 4. CCP capture mode interrupt.
- 5. Parallel Slave Port read or write.
- 6. USART TX or RX (synchronous slave mode).

Other peripherals can not generate interrupts since during SLEEP, no on-chip Q clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction after the sLEEP instruction after the subset (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

13.8.2 WAKE-UP USING INTERRUPTS

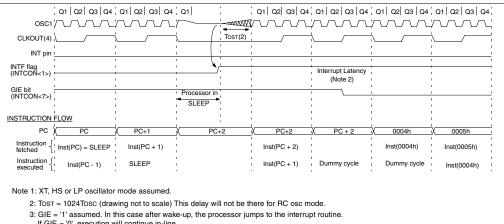
When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs before the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the TO bit will not be set and PD bits will not be cleared.
- If the interrupt occurs during or after the execution of a SLEEP instruction, the device will immediately wake up from sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the TO bit will be set and the PD bit will be cleared.

Even if the flag bits were checked before executing a $_{SLEEP}$ instruction, it may be possible for flag bits to become set before the $_{SLEEP}$ instruction completes. To determine whether a $_{SLEEP}$ instruction executed, test the \overline{PD} bit. If the \overline{PD} bit is set, the $_{SLEEP}$ instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

FIGURE 13-22: WAKE-UP FROM SLEEP THROUGH INTERRUPT



If GIE = '0', execution will continue in-line.

4: CLKOUT is not available in these osc modes, but shown here for timing reference.

13.9 **Program Verification/Code Protection**

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Microchip does not recommend code pro-Note: tecting windowed devices.

13.10 ID Locations

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Four memory locations (2000h - 2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. It is recommended that only the 4 least significant bits of the ID location are used.

For ROM devices, these values are submitted along with the ROM code.

13.11 In-Circuit Serial Programming

Applicable Devices

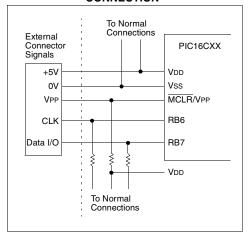
61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The PIC16CXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding pins RB6 and RB7 low while raising the MCLR (VPP) pin from VIL to VIHH (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After reset, to place the device in program/verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X Programming Specifications (Literature #DS30228).

FIGURE 13-23: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



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14.0 INSTRUCTION SET SUMMARY

Each PIC16CXX instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CXX instruction set summary in Table 14-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 14-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 14-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with $x = 0$. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; $d = 0$: store result in W, d = 1: store result in file register f. Default is $d = 1$
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination either the W register or the specified register file location
[]	Options
()	Contents
\rightarrow	Assigned to
<>	Register bit field
∈	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- Byte-oriented operations
- Bit-oriented operations
- · Literal and control operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μ s. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μ s.

Table 14-2 lists the instructions recognized by the MPASM assembler.

Figure 14-1 shows the general formats that the instructions can have.

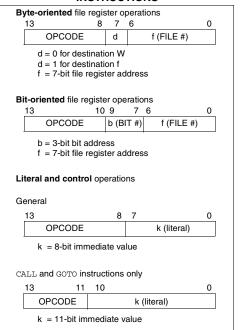
Note: To maintain upward compatibility with future PIC16CXX products, <u>do not use</u> the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 14-1: GENERAL FORMAT FOR INSTRUCTIONS



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IABLE 14-2:	PIC16CXX INSTRUCTION SET

Mnemonic, Operands		Description	Cycles		14-Bit	Status	Notes		
				MSb			LSb	Affected	
BYTE-ORIE	NTED	FILE REGISTER OPERATIONS							
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	С	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	С	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENT	ED FIL	E REGISTER OPERATIONS							
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL A	ND CO	NTROL OPERATIONS							
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO,PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	TO,PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11		kkkk		z	1

Note 1: When an I/O register is modified as a function of itself (e.g., MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

14.1 Instruction Descriptions

ADDLW	Add Literal and W	ANDLW	AND Literal with W
Syntax:	[<i>label</i>] ADDLW k	Syntax:	[<i>label</i>] ANDLW k
Operands:	$0 \le k \le 255$	Operands:	$0 \le k \le 255$
Operation:	$(W) + k \rightarrow (W)$	Operation:	(W) .AND. (k) \rightarrow (W)
Status Affected:	C, DC, Z	Status Affected:	Z
Encoding:	11 111x kkkk kkkk	Encoding:	11 1001 kkkk kkkk
Description:	The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.	Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1	Words:	1
Cycles:	1	Cycles:	1
Q Cycle Activity:	Q1 Q2 Q3 Q4	Q Cycle Activity:	Q1 Q2 Q3 Q4
	Decode Read literal 'k' Process data Write to W		Decode Read Process Write to data W
Example:	ADDLW 0x15	Example	ANDLW 0x5F
Example:	Before Instruction		Before Instruction
	W = 0x10		W = 0xA3
	After Instruction W = 0x25		After Instruction W = 0x03
ADDWF	Add W and f	ANDWF	AND W with f
Syntax:	[<i>label</i>] ADDWF f,d	Syntax:	[<i>label</i>] ANDWF f,d
Syntax: Operands:		Syntax: Operands:	
2	$0 \le f \le 127$	-	0 ≤ f ≤ 127
Operands:	$ \begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array} $	Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operands: Operation:	$\begin{array}{l} 0\leq f\leq 127\\ d\in [0,1]\\ (W)+(f)\rightarrow (destination) \end{array}$	Operands: Operation:	$0 \le f \le 127$ $d \in [0,1]$ (W) .AND. (f) \rightarrow (destination)
Operands: Operation: Status Affected:	$\begin{array}{l} 0\leq f\leq 127\\ d\in [0,1]\\ (W)+(f)\rightarrow (destination)\\ C, DC, Z \end{array}$	Operands: Operation: Status Affected:	$0 \le f \le 127$ $d \in [0,1]$ (W) .AND. (f) \rightarrow (destination) Z
Operands: Operation: Status Affected: Encoding:	$\begin{split} 0 &\leq f \leq 127 \\ d &\in [0,1] \\ (W) + (f) \rightarrow (destination) \\ C, DC, Z \\ \hline 00 0111 dfff ffff \\ Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is \\ \end{split}$	Operands: Operation: Status Affected: Encoding:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. \ (f) \rightarrow (destination) \\ Z \\ \hline \hline 00 & 0101 & dfff & ffff \\ AND \ the W \ register \ with \ register \ 'f'. \ If \ 'd' \\ is 0 \ the \ result \ is \ stored \ in \ the \ W \ register \ W \ register \ with \ register \ with \ register \ W \ register \ W \ register \ with \ register \ W \ register \ W \ register \ with \ register \ W \ register \ r$
Operands: Operation: Status Affected: Encoding: Description:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) + (f) \rightarrow (destination) \\ C, DC, Z \\ \hline \hline 00 0111 dfff ffff \\ Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. \end{array}$	Operands: Operation: Status Affected: Encoding: Description:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. \ (f) \rightarrow (destination) \\ \hline Z \\ \hline \hline 00 \ 0101 \ dfff \ ffff \\ \hline AND \ the \ W \ register \ with \ register \ 'f. \ If \ 'd' \\ is \ 0 \ the \ result \ is \ stored \ in \ the \ W \ register \ 'f. \\ \end{array}$
Operands: Operation: Status Affected: Encoding: Description: Words:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) + (f) \rightarrow (destination) \\ C, DC, Z \\ \hline 00 0111 dfff ffff \\ Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. 1 \\ \end{array}$	Operands: Operation: Status Affected: Encoding: Description: Words:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. \ (f) \rightarrow (destination) \\ \hline Z \\ \hline \hline 00 & 0101 & dfff & ffff \\ \hline AND the W register with register 'f'. If 'd' \\ is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. \\ 1 \end{array}$
Operands: Operation: Status Affected: Encoding: Description: Words: Cycles:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) + (f) \rightarrow (destination) \\ C, DC, Z \\ \hline 00 0111 dfff ffff \\ Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. \\ 1 \\ 1 \end{array}$	Operands: Operation: Status Affected: Encoding: Description: Words: Cycles:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. \ (f) \rightarrow (destination) \\ Z \\ \hline \hline 00 0101 dfff ffff \\ AND the W register with register 'f'. If 'd' \\ is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. \\ 1 \\ 1 \end{array}$
Operands: Operation: Status Affected: Encoding: Description: Words: Cycles:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) + (f) \rightarrow (destination) \\ C, DC, Z \\ \hline \hline 00 0111 dfff ffff \\ Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. 1 \\ 1 \\ \hline Q1 Q2 Q3 Q4 \\ \hline \hline Decode \hline Read \\ register Process Write to \\ destination \\ \hline \end{array}$	Operands: Operation: Status Affected: Encoding: Description: Words: Cycles:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. (f) \rightarrow (destination) \\ \hline Z \\ \hline \hline 00 & 0101 & dfff & ffff \\ \hline AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. \\ 1 \\ 1 \\ \hline Q1 & Q2 & Q3 & Q4 \\ \hline \hline Decode & Read & Process & Write to \\ register & data & destination \\ \hline \end{array}$
Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Q Cycle Activity:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) + (f) \rightarrow (destination) \\ C, DC, Z \\ \hline \hline 00 0111 dfff ffff \\ \end{tabular} \\ Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. 1 \\ 1 \\ \hline Q1 Q2 Q3 Q4 \\ \hline \hline \ Pecode \end{tabular} \\ \hline \ \ Q1 \end{tabular} \\ \hline \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Q Cycle Activity:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. (f) \rightarrow (destination) \\ \hline Z \\ \hline \hline 00 & 0101 & dfff & ffff \\ \hline AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. \\ 1 \\ 1 \\ \hline Q1 & Q2 & Q3 & Q4 \\ \hline \hline Decode & Read & Process & Write to \\ register 'f' & data & destination \\ \hline \end{array}$
Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Q Cycle Activity:	$0 \le f \le 127$ $d \in [0,1]$ (W) + (f) \rightarrow (destination) C, DC, Z 00 0111 dfff ffff Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. 1 1 2 Q1 Q2 Q3 Q4 $Q1 Q2 Q3 Q4$ $Decode Read \\ register \\ 'f' \qquad data \qquad Write to \\ destination \qquad destinatio$	Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Q Cycle Activity:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. (f) \rightarrow (destination) \\ Z \\ \hline \hline 00 0101 dfff ffff \\ AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f. \\ 1 \\ 1 \\ \hline Q1 Q2 Q3 Q4 \\ \hline \hline Decode Read \\ register \\ rgister \\ r \\ Hata \\ \hline Decode FSR, 1 \\ Before Instruction \\ W = 0x17 \\ \end{array}$
Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Q Cycle Activity:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) + (f) \rightarrow (destination) \\ C, DC, Z \\ \hline 00 0111 dfff ffff \\ Add the contents of the W register with register 'f. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. \\ 1 \\ 1 \\ \hline 2 \\ Q1 Q2 Q3 Q4 \\ \hline \hline Decode Read \\ register \\ r' \\ f' \end{array} \begin{array}{c} Process \\ Or easy \\ Or e$	Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Q Cycle Activity:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. \ (f) \rightarrow (destination) \\ Z \\ \hline \hline 00 0101 dfff ffff \\ AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. \\ 1 \\ 1 \\ \hline 01 Q2 Q3 Q4 \\ \hline \hline Decode Read \\ register \\ register \\ register \\ register \\ register \\ Read \\ register \\ Read \\ register \\ Read \\ register $
Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Q Cycle Activity:	$0 \le f \le 127$ $d \in [0,1]$ (W) + (f) \rightarrow (destination) C, DC, Z 00 0111 dfff ffff Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. 1 1 2 Q1 Q2 Q3 Q4 $Q1 Q2 Q3 Q4$ $Decode Read \\ register \\ 'f' \qquad data \qquad Write to \\ destination \qquad destinatio$	Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Q Cycle Activity:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \\ (W) \ .AND. (f) \rightarrow (destination) \\ Z \\ \hline \hline 00 0101 dfff ffff \\ AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f. \\ 1 \\ 1 \\ \hline Q1 Q2 Q3 Q4 \\ \hline \hline Decode Read \\ register \\ rgister \\ r \\ Hata \\ \hline Decode FSR, 1 \\ Before Instruction \\ W = 0x17 \\ \end{array}$

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BCF	Bit Clear	r f			BTFS		
Syntax:	[<i>label</i>] BCF f,b Synta						
Operands:		$0 \le f \le 127$ Operating $0 \le b \le 7$					
Operation:							
-		>)			Opera		
Status Affected:	None 01	oobb	hfff	6666	Statu		
Encoding:		00bb	bfff	ffff	Encoo		
Description:	Bit 'b' in re	egister i is	s cleared.		Desci		
Words:	1 1						
Cycles:		00	02	04			
Q Cycle Activity:	Q1	Q2	Q3	Q4 Write	1		
	Decode	Read register	Process data	register 'f'	Word		
		'f'			Cycle		
Example	BCF	FLAG	REG, 7		Q Cyc		
	Before In	_					
		FLAG_RE	EG = 0xC7	,			
	After Inst		EG = 0x47				
			_0 _ 0,47				
					Exam		
BSF	Bit Set f						
Syntax:	[<i>label</i>] BS	SF f,b					
Operands:	$0 \le f \le 12$						
o	0 ≤ b ≤ 7						
Operation:	$1 \rightarrow (f < b)$	>)					
Status Affected:	None		1		1		
Encoding:	01	01bb	bfff	ffff			
Description:	Bit 'b' in re	egister 'f' is	s set.				
Words:	1						
Cycles:	1						
Q Cycle Activity:	Q1	Q2	Q3	Q4	-		
	Decode	Read register	Process data	Write register 'f'			
		f	uata	.09/3(6) 1			
Example	BSF	FLAG_F	REG, 7				
	Before In						
	DOIDIG III		EG = 0x0/	4			
	After Inst	ruction					
		FLAG RE	EG = 0x8/	4			

BTFSC		Skip if Cl	ear			
Syntax:	[<i>label</i>] BTFSC f,b					
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$					
Operation:	skip if (f) = 0					
Status Affected:	None					
Encoding:	01	10bb	bfff	ffff		
Description:	If bit 'b' in register 'f' is '1' then the next instruction is executed. If bit 'b', in register 'f', is '0' then the next instruction is discarded, and a NOP is executed instead, making this a 2Tcy instruction.					
Words:	1					
Cycles:	1(2)					
Q Cycle Activity:	Q1	Q2	Q3	Q4		
	Decode	Read register 'f'	Process data	No- Operation		
If Skip:	(2nd Cyc	le)				
	Q1	Q2	Q3	Q4		
	No- Operation	No- Operation	No- Operation	No- Operation		
Example	HERE FALSE TRUE		FLAG,1 PROCESS	_CODE		
	Before Instruction PC = address HERE After Instruction if FLAG<1> = 0, PC = address TRUE if FLAG<1>=1,					

PC =

address FALSE

 $FLAG_REG = 0x8A$

BTFSS	Bit Test	f, Skip if S	Set		CALL	Call Sub	routine		
Syntax:	[<i>label</i>] BT	FSS f,b			Syntax:	[label]	CALL k		
Operands:	$0 \le f \le 12$	27			Operands:	$0 \le k \le 2047$			
	0 ≤ b < 7	0 ≤ b < 7			Operation:	(PC)+ 1-	→ TOS,		
Operation:	skip if (f) = 1			$k \rightarrow PC < 10:0>,$					
Status Affected:	None			$(PCLATH{<}4:3{>}) \rightarrow PC{<}12:11{>}$			11>		
Encoding:	01 11bb bfff ffff		Status Affected:	None	1	1			
Description:		register 'f' i		ne next	Encoding:	10	0kkk	kkkk	kkkk
Words:	instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2Tcy instruction.		Description:	Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loadd into PC bits <10:0>. The upper bits o the PC are loaded from PCLATH. CA		k. The s loaded bits of			
Cycles:	1(2)					is a two cy	cle instruc	ction.	
-		00	00	04	Words:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4	Cycles:	2			
	Decode	Read register 'f'	Process data	No- Operation	Q Cycle Activity:	Q1	Q2	Q3	Q4
If Skip:	(2nd Cyc	le)			1st Cycle	Decode	Read literal 'k',	Process data	Write to PC
	Q1	Q2	Q3	Q4			Push PC to Stack		
	No- Operation	No- Operation	No- Operation	No- Operation	2nd Cycle	No- Operation	No- Operation	No- Operation	No- Operation
Example	HERE FALSE	BTFSC GOTO	FLAG,1 PROCESS	CODE	Example	HERE	CALL	THERE	
	TRUE	•				Before Ir			
		•				After Inst		ddress HE	RE
	Defere In	otruction						ddress TH	ERE
	Before In		address H	TTTT				ddress HE	
	After Inst								
		if FLAG<1:	> = 0,						
			address F	ALSE					
		if FLAG<1: PC =	> = 1, address TI	aus					

	Clear f	CLRW
Syntax:	[<i>label</i>] CLRF f	Syntax:
Operands:	$0 \leq f \leq 127$	Operands:
Operation:	$\begin{array}{l} \text{O0h} \rightarrow (\text{f}) \\ 1 \rightarrow \text{Z} \end{array}$	Operation:
Status Affected:	Z	Status Affect
Encoding:	00 0001 1fff ffff	Encoding:
Description:	The contents of register 'f' are cleared and the Z bit is set.	Description:
Words:	1	Words:
Cycles:	1	Cycles:
Q Cycle Activity:	Q1 Q2 Q3 Q4	Q Cycle Acti
	Decode Read register data Vite register 'f'	
Example	CLRF FLAG_REG	Example
	Before Instruction	
	FLAG_REG = 0x5A After Instruction	
	FLAG_REG = 0x00	
	Z = 1	
		CLRWDT
		Syntax:
		Operands:
		Operation:
		Status Affect Encoding:
		Description:
		Words:
		Cycles:
		Q Cycle Acti
		,

CLRW	Clear W	
Syntax:	[label] CLRW	
Operands:	None	
Operation:	$\begin{array}{l} 00h \rightarrow (W) \\ 1 \rightarrow Z \end{array}$	
Status Affected:	Z	
Encoding:	00 0001 0xxx xx	xx
Description:	W register is cleared. Zero bit (Z) is set.	8
Words:	1	
Cycles:	1	
Q Cycle Activity:	Q1 Q2 Q3 (Q 4
		rite to W
Example	CLRW	
	Before Instruction W = 0x5A	
	After Instruction W = 0x00 Z = 1	
CLRWDT	Clear Watchdog Timer	
Syntax:	[label] CLRWDT	
Operands:	None	
Operation:	$\begin{array}{l} 00h \rightarrow WDT \\ 0 \rightarrow WDT \mbox{ prescaler}, \\ 1 \rightarrow \overline{TO} \\ 1 \rightarrow \overline{PD} \end{array}$	
Status Affected:	TO, PD	
Encoding:	00 0000 0110 01	00
Description:	CLRWDT instruction resets the Wate dog Timer. It also resets the presc of the WDT. Status bits TO and PD set.	aler
Words:	1	
Cycles:	1	
Q Cycle Activity:	Q1 Q2 Q3 (Q 4
	Operation data W	lear /DT unter
Example	CLRWDT	
	Before Instruction	
	WDT counter = ?	
	After Instruction WDT counter = 0x00	n

Ξ

COMF	Complement f	DECFSZ	Decrement f, Skip if 0
Syntax:	[label] COMF f,d	Syntax:	[label] DECFSZ f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$	Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	$(\overline{f}) \rightarrow (destination)$	Operation:	(f) - 1 \rightarrow (destination);
Status Affected:	Z		skip if result = 0
Encoding:	00 1001 dfff ffff	Status Affected:	None
Description:	The contents of register 'f' are comple- mented. If 'd' is 0 the result is stored in W. If 'd' is 1 the result is stored back in register 'f'.	Encoding: Description:	00 1011 dfff ffff The contents of register 'f' are decremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed in the the result is placed in the W register. If 'd' is 1 the result is placed
Words:	1		back in register 'f'. If the result is 1, the next instruction, is
Cycles:	1		executed. If the result is 0, then a NOP is executed instead making it a 2Tcy instruc-
Q Cycle Activity:	Q1 Q2 Q3 Q4		tion.
	Decode Read Process Write to register data destination	Words:	1
	"" data destination	Cycles:	1(2)
English	2017 P.201 A	Q Cycle Activity:	Q1 Q2 Q3 Q4
Example	COMF REG1, 0 Before Instruction		Decode Read Process Write to register 'f' data destination
	REG1 = 0x13	If Skip:	(2nd Cycle)
	After Instruction REG1 = 0x13		Q1 Q2 Q3 Q4
	W = 0xEC		No- No- No- No- Operation Operation Operation
DECF	Decrement f	E	
Syntax:	[<i>label</i>] DECF f,d	Example	HERE DECFSZ CNT, 1 GOTO LOOP
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]		CONTINUE •
Operation:	(f) - 1 \rightarrow (destination)		Before Instruction
Status Affected:	Z		PC = address HERE
Encoding:	00 0011 dfff ffff		After Instruction CNT = CNT - 1
Description:	Decrement register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.		if CNT = 0, PC = address CONTINUE
Words:	1		if $CNT \neq 0$, PC = address HERE+1
Cycles:	1		
-	Q1 Q2 Q3 Q4		
Q Cycle Activity:			
Q Cycle Activity:	Decode Read register f		
Q Cycle Activity: Example	register data destination		
	register data destination		

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GOTO	Uncondi	tional Br	anch		INCF	Increme	nt f		
Syntax:	[label]	GOTO	k		Syntax:	[label]	INCF	f,d	
Operands:	$0 \le k \le 2047$			Operands:	$0 \leq f \leq 127$				
Operation:	$k \rightarrow PC<10:0>$ PCLATH<4:3> \rightarrow PC<12:11>			Operation:	$d \in [0,1]$ (f) + 1 \rightarrow (destination)				
Status Affected:	None	<4.32 → 1	0<12.11	-	Status Affected:	(I) + I → Z	(uestine	luon	
Encoding:	10	1kkk	kkkk	kkkk	Encoding:	00	1010	dfff	ffff
Description:	GOTO is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:>. GOTO is a two cycle instruction.		Description:	The contents of register 'f' are incre- mented. If 'd' is 0 the result is placed i the W register. If 'd' is 1 the result is placed back in register 'f'.		placed in			
Words:	1				Words:	1			
Cycles:	2				Cycles:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4	Q Cycle Activity:	Q1	Q2	Q3	Q4
1st Cycle	Decode	Read literal 'k'	Process data	Write to PC		Decode	Read register 'f'	Process data	Write to destination
2nd Cycle	No- Operation	No- Operation	No- Operation	No- Operation	Evenale	INCF	CNT,	1	
Example	GOTO TI	JEDE			Example	Before In			
Example	After Inst	ruction	Address	THERE		After Inst	CNT Z	= 0xF = 0 = 0x0 = 1	-

INCFSZ	Increment f, Skip if 0	IORLW	Inclusive OR Literal with W
Syntax:	[label] INCFSZ f,d	Syntax:	[<i>label</i>] IORLW k
Operands:	$0 \le f \le 127$	Operands:	$0 \leq k \leq 255$
	d ∈ [0,1]	Operation:	(W) .OR. $k \rightarrow$ (W)
Operation:	(f) + 1 \rightarrow (destination), skip if result = 0	Status Affected:	Z
Status Affected:	None	Encoding:	11 1000 kkkk kkkk
Encoding: Description:	00 1111 dfff ffff The contents of register 'f' are incre- """"""""""""""""""""""""""""""""""""	Description:	The contents of the W register is OR'ed with the eight bit literal 'k'. The result is placed in the W register.
Description.	mented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is	Words:	1
	placed back in register 'f'.	Cycles:	1
	If the result is 1, the next instruction is executed. If the result is 0, a NOP is exe- cuted instead making it a 2Tcy instruc-	Q Cycle Activity:	Q1 Q2 Q3 Q4
Words:	tion. 1		Decode Read Process Write to literal 'k' data W
Cycles:	1(2)	Evenuela	
Q Cycle Activity:	Q1 Q2 Q3 Q4	Example	IORLW 0x35
	Decode Read register 'f' Process Write to destination		Before Instruction W = 0x9A After Instruction
If Skip:	(2nd Cycle)		W = 0xBF
	Q1 Q2 Q3 Q4		Z = 1
	No- OperationNo- OperationNo- OperationOperationOperation		
Example	HERE INCFSZ CNT, 1 GOTO LOOP CONTINUE • •		
	$\begin{array}{rcl} Before \mbox{ Instruction} & PC & = & address \mbox{ HERE} \\ After \mbox{ Instruction} & & \\ CNT & = & CNT + 1 & \\ \mbox{if } CNT = & 0, & \\ PC & = & address \mbox{ continue} & \\ \mbox{if } CNT \neq & 0, & \\ PC & = & address \mbox{ HERE} \ +1 & \\ \end{array}$		

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	Inclusive	ORW	with f		MOVLW
Syntax:	[label]	IORWF	f,d		Syntax:
Operands:	$0 \le f \le 12$	27			Operands
o	d ∈ [0,1]	<i>(</i>) <i>(</i>)		,	Operation
Operation:	(W) .OR.	$(f) \rightarrow (d)$	estinatior	1)	Status Aff
Status Affected:	Z		1		Encoding
Encoding:	00	0100	dfff	ffff	Descriptio
Description:	Inclusive (ter 'f'. If 'd' W register back in reg	is 0 the re . If 'd' is 1	esult is place	ced in the	Words:
Words:	1				Cycles:
Cycles:	1				Q Cycle A
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read register 'f'	Process data	Write to destination	Example
Example	After Inst	RESULT W	= 0x13 = 0x91	3	
MOVF	Move f				MOVWF
MOVF Syntax:	Move f	MOVF	f,d		MOVWF Syntax:
-	[<i>label</i>] 0 ≤ f ≤ 12		f,d		-
Syntax: Operands:	[<i>label</i>] 0 ≤ f ≤ 12 d ∈ [0,1]	7	,		Syntax: Operands
Syntax: Operands: Operation:	$\begin{bmatrix} label \end{bmatrix}$ $0 \le f \le 12$ $d \in [0,1]$ $(f) \rightarrow (decomposition of the set of $	7	,		Syntax:
Syntax: Operands: Operation: Status Affected:	$\begin{bmatrix} label \end{bmatrix}$ $0 \le f \le 12$ $d \in [0,1]$ $(f) \rightarrow (dex)$ Z	7 stination)		Syntax: Operands Operatior Status Afl
Syntax: Operands: Operation: Status Affected: Encoding:	$\begin{bmatrix} label \end{bmatrix}$ $0 \le f \le 12$ $d \in [0,1]$ $(f) \rightarrow (dezzet)$ Z 00	tination) dfff	ffff	Syntax: Operands Operation
Syntax: Operands: Operation: Status Affected:	$\begin{bmatrix} label \\ 0 \le f \le 12 \\ d \in [0,1] \\ (f) \rightarrow (de: Z \\ \hline 00 \\ \hline The content \\ \end{bmatrix}$	27 stination 1000 nts of reg) dfff ister f is m	oved to a	Syntax: Operands Operation Status Aff Encoding Descriptio
Syntax: Operands: Operation: Status Affected: Encoding:	$[label]$ $0 \le f \le 12$ $d \in [0,1]$ $(f) \rightarrow (dez)$ Z $\boxed{00}$ The content destination of d. If d =	1000 nts of reg o, destina) dfff ister f is me ant upon th attion is W r	oved to a ne status egister. If	Syntax: Operands Operatior Status Afi Encoding Description Words:
Syntax: Operands: Operation: Status Affected: Encoding:	$[label]$ $0 \le f \le 12$ $d \in [0,1]$ $(f) \rightarrow (dez)$ Z $\boxed{00}$ The content destination	27 stination 1000 nts of reg n dependa 0, destination 1 is usefu) ister f is m ant upon th ation is W r on is file rea I to test a f	oved to a ne status egister. If gister f ile regis-	Syntax: Operands Operation Status Aff Encoding Descriptio
Syntax: Operands: Operation: Status Affected: Encoding:	$\begin{bmatrix} label \\ 0 \le f \le 12 \\ d \in [0,1] \\ (f) \rightarrow (dex Z \\ \hline 00 \\ The context \\ destination \\ of d. If d = \\ d = 1, the \\ itself. d = 1 \end{bmatrix}$	27 stination 1000 nts of reg n dependa 0, destination 1 is usefu) ister f is m ant upon th ation is W r on is file rea I to test a f	oved to a ne status egister. If gister f ile regis-	Syntax: Operands Operation Status Aff Encoding Descriptic Words: Cycles:
Syntax: Operands: Operation: Status Affected: Encoding: Description:	$\begin{bmatrix} label \\ 0 \le f \le 12 \\ d \in [0,1] \\ (f) \rightarrow (de: Z \\ \hline 0 0 \\ The conter \\ destination \\ of d. If d = \\ d = 1, the \\ itself. d = 7 \\ ter since s \end{bmatrix}$	27 stination 1000 nts of reg n dependa 0, destination 1 is usefu) ister f is m ant upon th ation is W r on is file rea I to test a f	oved to a ne status egister. If gister f ile regis-	Syntax: Operands Operation Status Aff Encoding Descriptio Words: Cycles:
Syntax: Operands: Operation: Status Affected: Encoding: Description: Words: Cycles:	$\begin{bmatrix} label \\ 0 \le f \le 12 \\ d \in [0,1] \\ (f) \rightarrow (der Z) \\ \hline 0 \\ \hline C \\ The context destination of d. If d = d = 1, the itself, d = 1 \\ ter since s \\ 1 \end{bmatrix}$	27 stination 1000 nts of reg n dependa 0, destination 1 is usefu) ister f is m ant upon th ation is W r on is file rea I to test a f	oved to a ne status egister. If gister f ile regis-	Syntax: Operands Operation Status Aff Encoding Descriptio Words: Cycles: Q Cycle A
Syntax: Operands: Operation: Status Affected: Encoding: Description: Words:	$\begin{bmatrix} label \\ 0 \le f \le 12 \\ d \in [0,1] \\ (f) \rightarrow (dez Z \\ \hline 00 \\ \hline The conteres destination of d. If d = d = 1, the itself. d = 1 \\ ter since s \\ 1 \\ 1 \\ \end{bmatrix}$	1000 nts of reg dependa 0, destination 1 is usefu tatus flag	dfff ister f is m ant upon th ttion is W r n is file ree I to test a f Z is affect	oved to a ne status egister. If gister f ile regis- red.	Syntax: Operands Operation Status Aff Encoding Descriptic Words: Cycles:
Syntax: Operands: Operation: Status Affected: Encoding: Description: Words: Cycles:	$\begin{bmatrix} label \\ 0 \le f \le 12 \\ d \in [0,1] \\ (f) \to (de: Z) \\ \hline 00 \\ \hline The content destination of d. If d = d = 1, the itself. d = 1 \\ ter since s \\ 1 \\ 1 \\ Q1 \\ \hline Q1 \\ \hline \end{tabular}$	1000 1000 nts of reg n dependa 0, destination destination tis usefu tatus flag Q2 Read register 'f'	dfff ister f is m ant upon th tition is W r n is file re- I to test a f Z is affect Q3 Process	oved to a ne status egister. If gister f ile regis- ed. Q4 Write to	Syntax: Operands Operation Status Aff Encoding Descriptio Words: Cycles: Q Cycle A

MOVLW	Move Lit	eral to V	v	
Syntax:	[label]	MOVLW	/ k	
Operands:	$0 \le k \le 2\xi$	55		
Operation:	$k \to (W)$			
Status Affected:	None			
Encoding:	11	00xx	kkkk	kkkk
Description:	The eight l register. Th as 0's.			
Words:	1			
Cycles:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read literal 'k'	Process data	Write to W
Example	MOVLW	0x5A		
	After Inst	ruction W =	0x5A	

MOVWF	Move W	to f			
Syntax:	[label]	MOVW	= f		
Operands:	$0 \leq f \leq 12$	7			
Operation:	$(W) \to (f)$				
Status Affected:	None				
Encoding:	00	0000	lfff	ffff	
Description:	Move data 'f'.	from W r	egister to	register	
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read register 'f'	Process data	Write register 'f'	
Example	MOVWF	OPTIC	DN_REG		
	Before Instruction OPTION = 0xFF W = 0x4F				
		ruction OPTION W	= 0x4F = 0x4F		

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IOP	No Oper	ation		
Syntax:	[label]	NOP		
)perands:	None			
peration:	No opera	ition		
tatus Affected:	None			
incoding:	00	0000	0xx0	0000
escription:	No operat	ion.		
/ords:	1			
ycles:	1			
Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	No- Operation	No- Operation	No- Operation

RETFIE	Return fi	rom Inter	rupt	
Syntax:	[label]	RETFIE		
Operands:	None			
Operation:	$\begin{array}{l} TOS \rightarrow F \\ 1 \rightarrow GIE \end{array}$	PC,		
Status Affected:	None			
Encoding:	00	0000	0000	1001
Words:	and Top of PC. Interru Global Inte (INTCON< instruction	upts are er errupt Ena (7>). This i	habled by s ble bit, GIE	setting E
Cycles:	2			
Q Cycle Activity:	Q1	Q2	Q3	Q4
1st Cycle	Decode	No- Operation	Set the GIE bit	Pop from the Stack
2nd Cycle	No- Operation	No- Operation	No- Operation	No- Operation
Example	RETFIE	rrupt		

After Interrupt PC = TOS GIE = 1

OPTION	Load Op	tion Reg	gister		
Syntax:	[label] OPTION				
Operands:	None				
Operation:	$(W) \rightarrow O$	PTION			
Status Affected:	None				
Encoding:	00	0000	0110	0010	
Description:	The conter loaded in t instruction patibility w Since OPT register, th it.	he OPTIC is suppor ith PIC16 ION is a	DN registe rted for co C5X produ readable/v	r. This de com- ucts. vritable	
	1				
Cycles:	1				
Example	To maint		-	tibility	
		re PIC16	rd compa CXX production.		

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RETLW	Return w	ith Liter	al in W		
Syntax:	[label]	RETLW	k		
Operands:	$0 \le k \le 255$				
Operation:	$k \rightarrow (W);$ TOS $\rightarrow PC$				
Status Affected:	None				
Encoding:	11	01xx	kkkk	kkkk	
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two cycle instruction.				
Words:	1				
Cycles:	2				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
1st Cycle	Decode	Read literal 'k'	No- Operation	Write to W, Pop from the Stack	
2nd Cycle	No- Operation	No- Operation	No- Operation	No- Operation	
Example	CALL TABL	;offse	tains tabl t value has table		
TABLE	ADDWF PC RETLW k1 RETLW k2	;W = 0 ;Begin ;			
	RETLW kn	; End	of table		
	Before In				
	After Inst		0x07		
			value of k8	3	

RETURN	Return fi	rom Sub	routine	
Syntax:	[label]	RETURI	N	
Operands:	None			
Operation:	$\text{TOS} \to \text{F}$	о С		
Status Affected:	None			
Encoding:	0.0	0000	0000	1000
Description:	Return fro POPed an is loaded in is a two cy	d the top on to the pro	of the stack gram coun	(TOS)
Words:	1			
Cycles:	2			
Q Cycle Activity:	Q1	Q2	Q3	Q4
1st Cycle	Decode	No- Operation	No- Operation	Pop from the Stack
2nd Cycle	No- Operation	No- Operation	No- Operation	No- Operation
Example	RETURN After Inte	•	TOS	

RLF	Rotate Left f through Carry	RRF	Rotate Right f through Carry
Syntax:	[<i>label</i>] RLF f,d	Syntax:	[<i>label</i>] RRF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$	Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	See description below	Operation:	See description below
Status Affected:	С	Status Affected:	С
Encoding:	00 1101 dfff ffff	Encoding:	00 1100 dfff ffff
Description:	The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.	Description:	The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
Words:	1	Words:	1
Cycles:	1	Cycles:	1
Q Cycle Activity:	Q1 Q2 Q3 Q4	Q Cycle Activity:	Q1 Q2 Q3 Q4
	Decode Read register tr		Decode Read register 'f' Vite to destination
Example	RLF REG1,0	Example	RRF REG1,0
	Before Instruction REG1 = 1110 0110 C = 0 After Instruction		Before Instruction REG1 = 1110 0110 C = 0 After Instruction
	REG1 = 1110 0110 W = 1100 1100 C = 1		$\begin{array}{rcl} REG1 & = & 1110 & 0110 \\ W & = & 0111 & 0011 \\ C & = & 0 \end{array}$

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SLEEP

Syntax:	[label]	SLEEP			
Operands:	None				
Operation:	$\begin{array}{l} 00h \rightarrow WDT, \\ 0 \rightarrow WDT \ prescaler, \\ 1 \rightarrow \overline{TO}, \\ 0 \rightarrow \overline{PD} \end{array}$				
Status Affected:	TO, PD				
Encoding:	00	0000	0110	0011	
Description:	cleared. T set. Watc caler are The proce mode with	er-down sta Time-out st hdog Time cleared. essor is pu n the oscilla 3.8 for mo	tatus bit, T er and its p it into SLE ator stoppe	O is eres- EP	
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	No- Operation	No- Operation	Go to Sleep	
Example:	SLEEP				

SUBLW	Subtract	W from I	iteral		
Syntax:	[label]	SUBLW	k		
Operands:	$0 \le k \le 255$				
Operation:	k - (W) \rightarrow	(W)			
Status Affected:	C, DC, Z				
Encoding:	11	110x	kkkk	kkkk	
Description:	ment meth	od) from th	tracted (2's ne eight bit n the W reg	literal 'k'.	
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read literal 'k'	Process data	Write to W	
Example 1:	SUBLW	0x02			
	Before Instruction				
		W = C = Z =	1 ? ?		
	After Inst	ruction			
		W = C = Z =	1 1; result is 0	positive	
Example 2:	Before In:	struction			
		W = C = Z =	2 ? ?		
	After Inst	ruction			
		W = C = Z =	0 1; result i 1	s zero	
Example 3:	Before Ins	struction			
		W = C = Z =	3 ? ?		
	After Insti	ruction			
		W = C = Z =	0xFF 0; result is 0	negative	

SUBWF	Subtract W 1	trom f	SWAPF	Swap Nibbles in f
Syntax:	[label] SI	UBWF f,d	Syntax:	[label] SWAPF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$		Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(f) - (W) \rightarrow (d	lestination)	Operation:	$(f<3:0>) \rightarrow (destination<7:4>),$
Status Affected:	C, DC, Z			$(f < 7:4 >) \rightarrow (destination < 3:0 >)$
Encoding:	00 0	010 dfff ffff	Status Affected:	None
Description:		omplement method) W reg-	Encoding:	00 1110 dfff ffff
	stored in the W	ster 'f'. If 'd' is 0 the result is V register. If 'd' is 1 the I back in register 'f'.	Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.
Words:	1		Words:	1
Cycles:	1			1
Q Cycle Activity:	Q1	Q2 Q3 Q4	Cycles:	
		Read Process Write to gister 'f' data destination	Q Cycle Activity:	Q1 Q2 Q3 Q4 Decode Read Process Write to
Example 1:	SUBWF RI	EG1,1		register 'f' data destination
	Before Instru		Example	SWAPF REG, 0
	REG1	= 3		Before Instruction
	W	= 2		REG1 = 0xA5
	C Z	= ? = ?		After Instruction
	After Instruct	-		REG1 = 0xA5
	REG1 W C Z	= 1 = 2 = 1; result is positive = 0		W = 0x5A
Example 2:	Before Instru	ction	TRIS	Load TRIS Register
	REG1	= 2	Syntax:	[<i>label</i>] TRIS f
	W C	= 2 = ?	Operands:	$5 \le f \le 7$
	z	= ?	Operation:	(W) \rightarrow TRIS register f;
	After Instruct	ion	Status Affected	None
	REG1	= 0	Encoding:	00 0000 0110 0fff
	W C	= 2 = 1; result is zero	Description:	The instruction is supported for code
	Z	= 1		compatibility with the PIC16C5X prod- ucts. Since TRIS registers are read-
Example 3:	Before Instru	ction		able and writable, the user can directly address them.
	REG1	= 1	Words:	1
	W C	= 2 = ?	Cycles:	1
	z	= ?	Example	
	After Instruct	ion		To maintain upward compatibility
	REG1	= 0xFF		with future PIC16CXX products, do
	W C	= 2 - 0: result is pegative		not use this instruction.
	U	 0; result is negative 		

XORLW	Exclusive OR Literal with W	XORWF	Exclusive OR W with f
Syntax:	[<i>label</i>] XORLW k	Syntax:	[<i>label</i>] XORWF f,d
Operands:	$0 \le k \le 255$	Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation: Status Affected: Encoding: Description:		Operation: Status Affected: Encoding:	(W) .XOR. (f) \rightarrow (destination) Z 00 0110 dfff ffff Exclusive QB the contents of the W
	XOR'ed with the eight bit literal 'k'. The result is placed in the W regis- ter.	Description:	register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.
Words:	1	Words:	1
Cycles:	1	Cycles:	1
Q Cycle Activity:	Q1 Q2 Q3 Q4	Q Cycle Activity:	Q1 Q2 Q3 Q4
	Decode Read Process Write to data W	Q Oyole Activity.	Decode Read rejeter data destination
Example:	XORLW 0xAF		
	Before Instruction	Example	XORWF REG 1
	W = 0xB5		Before Instruction
	After Instruction W = 0x1A		REG = 0xAF W = 0xB5
			After Instruction
			$\begin{array}{rcl} REG &=& 0x1A\\ W &=& 0xB5 \end{array}$

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15.0 ELECTRICAL CHARACTERISTICS FOR PIC16C61

Absolute	Maximum	Ratings 1	t i

Ambient temperature under bias	55°C to +125°C
Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD, MCLR, and RA4)	
Voltage on VDD with respect to VSS	-0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0V to +14V
Voltage on RA4 pin with respect to Vss	0V to +14V
Total power dissipation (Note 1)	800 mW
Maximum current out of Vss pin	150 mA
Maximum current into VDD pin	100 mA
Input clamp current, IiK (VI < 0 or VI > VDD)	± 20 mA
Output clamp current, Ioк (Vo < 0 or Vo > VDD)	± 20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	20 mA
Maximum current sunk by PORTA	80 mA
Maximum current sourced by PORTA	50 mA
Maximum current sunk by PORTB	150 mA
Maximum current sourced by PORTB	100 mA
Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - \sum IOH} + \sum {(VD	D-VOH) x IOH} + Σ (VOI x IOL)

Note 2: Voltage spikes below Vss at the MCLR pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the MCLR pin rather than pulling this pin directly to Vss.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 15-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C61-04	PIC16C61-20	PIC16LC61-04	JW Devices
RC	VDD: 4.0V to 6.0V	VDD: 4.5V to 5.5V	VDD: 3.0V to 6.0V	VDD: 4.0V to 6.0V
	IDD: 3.3 mA max. at 5.5V	IDD: 1.8 mA typ. at 5.5V	IDD: 1.4 mA typ. at 3.0V	IDD: 3.3 mA max. at 5.5V
	IPD: 14 μA max. at 4V	IPD: 1.0 μA typ. at 4V	IPD: 0.6 μA typ. at 3V	IPD: 14 μA max. at 4V
	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V	VDD: 4.5V to 5.5V	VDD: 3.0V to 6.0V	VDD: 4.0V to 6.0V
	IDD: 3.3 mA max. at 5.5V	IDD: 1.8 mA typ. at 5.5V	IDD: 1.4 mA typ. at 3.0V	IDD: 3.3 mA max. at 5.5V
	IPD: 14 μA max. at 4V	IPD: 1.0 μA typ. at 4V	IPD: 0.6 μA typ. at 3V	IPD: 14 μA max. at 4V
	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V	VDD: 4.5V to 5.5V		VDD: 4.5V to 5.5V
	IDD: 13.5 mA typ. at 5.5V	IDD: 30 mA max. at 5.5V	Not recommended for use in	IDD: 30 mA max. at 5.5V
	IPD: 1.0 µA typ. at 4.5V	IPD: 1.0 μA typ. at 4.5V	HS mode	IPD: 1.0 μA typ. at 4.5V
	Freq: 4 MHz max.	Freq: 20 MHz max.		Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V		VDD: 3.0V to 6.0V	VDD: 3.0V to 6.0V
	IDD: 15 μA typ. at 32 kHz,	Not recommended for	IDD: 32 μA max. at 32 kHz,	IDD: 32 μA max. at 32 kHz,
	4.0V	use in LP mode	3.0V	3.0V
	IPD: 0.6 μA typ. at 4.0V	use in LP mode	IPD: 9 μA max. at 3.0V	IPD: 9 μA max. at 3.0V
	Freq: 200 kHz max.		Freq: 200 kHz max.	Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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15.1 DC Characteristics: PIC16C61-04 (Commercial, Industrial, Extended) PIC16C61-20 (Commercial, Industrial, Extended)

		Standa	rd Opei	rating	Condi	tions (ı	unless otherwise stated)
	ACTERISTICS	Operatir	ng temp	erature	e -40)°C ≤	\leq TA \leq +125°C for extended,
DC CHAR	ACTERISTICS				-40)°C ≤	\leq TA \leq +85°C for industrial and
					0°0	C ≤	$\leq TA \leq +70^{\circ}C$ for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
	Current Vielte ere	Vaa	4.0		<u> </u>	v	XT DC and LD and configuration
D001	Supply Voltage	VDD	4.0	-	6.0		XT, RC and LP osc configuration
D001A			4.5	-	5.5	V	HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power- on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2)	IDD	-	1.8	3.3	mA	Fosc = 4 MHz, VDD = 5.5V (Note 4)
D013			-	13.5	30	mA	HS osc configuration Fosc = 20 MHz, VDD = 5.5V
D020	Power-down Current	IPD	-	7	28	μA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021	(Note 3)		-	1.0	14	μA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.0	16	μA	$VDD = 4.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$
D021B			-	1.0	20	μA	$V_{DD} = 4.0V$, WDT disabled, -40°C to +125°C
* TI	and noromotors are abor						

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

 $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

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15.2 DC Characteristics: PIC16LC61-04 (Commercial, Industrial)

DC CHA	ARACTERISTICS	Standa Operatir		•		°C ≤	Inless otherwise stated) TA ≤ +85°C for industrial and TA ≤ +70°C for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage	Vdd	3.0	-	6.0	V	XT, RC, and LP osc configuration
D002*	RAM Data Retention Volt- age (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2)	Idd	-	1.4	2.5	mA	Fosc = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	15	32	μA	Fosc = 32 kHz, VDD = 3.0V, WDT disabled, LP osc configuration
D020	Power-down Current	IPD	-	5	20	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021	(Note 3)		-	0.6	9	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.6	12	μA	VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

 $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

^{4:} For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

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15.3 DC Characteristics: PIC16C61-04 (Commercial, Industrial, Extended) PIC16C61-20 (Commercial, Industrial, Extended) PIC16LC61-04 (Commercial, Industrial)

DC CHA			rd Operat		onditions -40°C -40°C 0°C	Ì ≤ TA ≤ TA	so otherwise stated) $\Delta \le +125^{\circ}$ C for extended, $\Delta \le +85^{\circ}$ C for industrial and $\Delta \le +70^{\circ}$ C for commercial
		Operatii Section		Vdd r			ed in DC spec Section 15.1 and
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
	Input Low Voltage						
	I/O ports	VIL					
D030 D030A	with TTL buffer		Vss Vss	-	0.15VDD 0.8V	V V	For entire VDD range 4.5V ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		Vss	-	0.2VDD	V	
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3Vdd	V	Note1
	Input High Voltage						
	I/O ports	Vін		-			
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \le V$ DD $\le 5.5V$
D040A			0.25VDD + 0.8V	-	Vdd	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.85Vdd	-	Vdd	v	For entire VDD range
D042	MCLR		0.85VDD	-	Vdd	V	
D042A	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	Vdd	V	
D070	PORTB weak pull-up current	IPURB	50	250	† 400	μA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	lı∟	-	-	±1	μA	$Vss \leq VPIN \leq VDD, Pin at hi-impedance$
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \leq V PIN \leq V DD$
D063	OSC1		-	-	±5	μA	Vss \leq VPIN \leq VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	v	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
D083A			-	-	0.6	v	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C

The parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 Standard Operating Conditions (unless otherwise stated) \leq TA \leq +125°C for extended, -40°C Operating temperature \leq TA \leq +85°C for industrial and -40°C DC CHARACTERISTICS 0°C \leq TA \leq +70°C for commercial Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2. Param Characteristic Sym Min Typ† Max Units Conditions No. Output High Voltage I/O ports (Note 3) D090 νон VDD-0.7 _ v IOH = -3.0 mA, $VDD = 4.5V, -40^{\circ}C \text{ to } +85^{\circ}C$ D090A IOH = -2.5 mA, VDD-0.7 V VDD = 4.5V, -40°C to +125°C D092 OSC2/CLKOUT (RC osc config) VDD-0.7 IOH = -1.3 mA, v -VDD = 4.5V, -40°C to +85°C D092A VDD-0.7 V IOH = -1.0 mA, $VDD = 4.5V, -40^{\circ}C \text{ to } +125^{\circ}C$ D150* **Open-Drain High Voltage** Vod 14 V RA4 pin --**Capacitive Loading Specs on Output Pins** D100 OSC2 pin Cosc₂ 15 pF In XT, HS and LP modes when external clock is used to drive OSC1. D101 All I/O pins and OSC2 (in RC mode) CIO 50 pF

The parameters are characterized but not tested.

t Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages

3: Negative current is defined as current sourced by the pin.

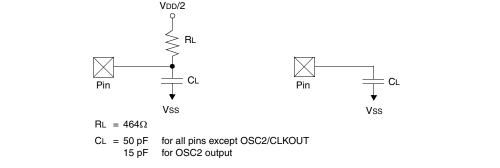
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15.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

1. TppS2p	pS	3. TCC:ST	(I ² C specifications only)
2. TppS		4. Ts	(I ² C specifications only)
т			
F	Frequency	т	Time
Lowerca	ase letters (pp) and their meanings:		
рр			
СС	CCP1	OSC	OSC1
ck	CLKOUT	rd	RD
CS	CS	rw	RD or WR
di	SDI	SC	SCK
do	SDO	SS	SS
dt	Data in	tO	TOCKI
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR
Upperca	ase letters and their meanings:		
S	~		
F	Fall	Р	Period
н	High	R	Rise
I	Invalid (Hi-impedance)	v	Valid
L	Low	z	Hi-impedance
I ² C only			
AA	output access	High	High
BUF	Bus free	Low	Low
TCC:ST ((I ² C specifications only)	1	
CC	· · · · ·		
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		
FIGURE 1	5-1: LOAD CONDITIONS FOR DEVIC	E TIMING SF	PECIFICATIONS
	Load condition 1		Load condition 2
	VDD/2		
	Ĭ		
	< _		



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15.5 <u>Timing Diagrams and Specifications</u>

FIGURE 15-2: EXTERNAL CLOCK TIMING

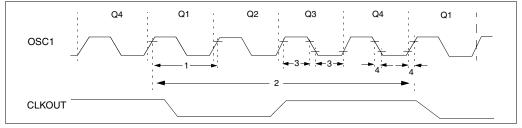


TABLE 15-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
	Fosc	External CLKIN Frequency	DC	_	4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	_	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			1	_	4	MHz	HS osc mode (-04)
			1	_	20	MHz	HS osc mode (-20)
1	Tosc	External CLKIN Period	250	_	—	ns	XT and RC osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			50	_	—	ns	HS osc mode (-20)
			5	_	—	μs	LP osc mode
		Oscillator Period	250	—	—	ns	RC osc mode
		(Note 1)	250	—	10,000	ns	XT osc mode
			250	_	1,000	ns	HS osc mode (-04)
			50	_	1,000	ns	HS osc mode (-20)
			5	_	_	μS	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	1.0	Тсү	DC	μs	TCY = 4/Fosc
3	TosL,	External Clock in (OSC1) High or	50	_	_	ns	XT oscillator
	TosH	Low Time	2.5	_	—	μS	LP oscillator
			10	_	_	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise or	25	_	—	ns	XT oscillator
	TosF	Fall Time	50	_	—	ns	LP oscillator
			15	_	_	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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FIGURE 15-3: CLKOUT AND I/O TIMING

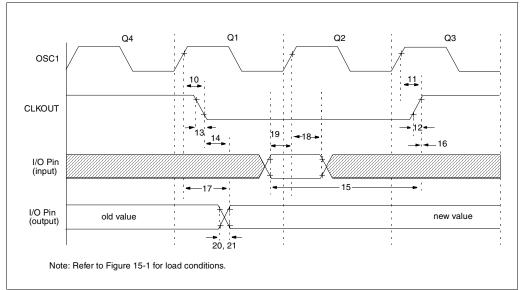


TABLE 15-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Мах	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		—	15	30	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		—	15	30	ns	Note 1
12*	TckR	CLKOUT rise time		_	5	15	ns	Note 1
13*	TckF	CLKOUT fall time		_	5	15	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out va	alid	_		0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKC)UT ↑	0.25Tcy + 25		_	ns	Note 1
16*	TckH2iol	Port in hold after CLKOU	T ↑	0		_	ns	Note 1
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Po	rt out valid	_		80 - 100	ns	
18*	TosH2iol	OSC1 [↑] (Q2 cycle) to Po (I/O in hold time)	rt input invalid	TBD		_	ns	
19*	TioV2osH	Port input valid to OSC1 time)	↑ (I/O in setup	TBD		_	ns	
20*	TioR	Port output rise time	PIC16 C 61	_	10	25	ns	
			PIC16 LC 61	_		60	ns	
21*	TioF	Port output fall time	PIC16 C 61	—	10	25	ns	
			PIC16LC61	_		60	ns	
22††*	Tinp	RB0/INT pin high or low	time	20	-	_	ns	
23††*	Trbp	RB7:RB4 change int hig	n or low time	20	_	_	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

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FIGURE 15-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

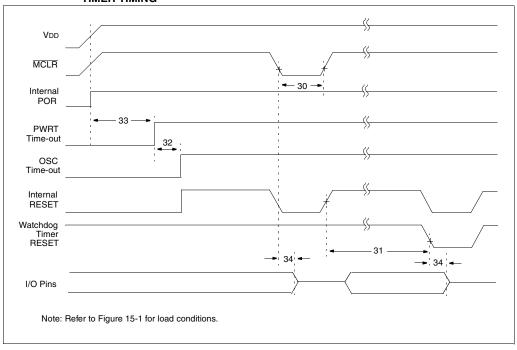


TABLE 15-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30*	TmcL	MCLR Pulse Width (low)	200	—		ns	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period		1024Tosc			TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34*	Tioz	I/O Hi-impedance from MCLR Low		—	100	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62 63 R63 64 644 R64 65 65A R65 66 67

FIGURE 15-5: TIMER0 EXTERNAL CLOCK TIMINGS

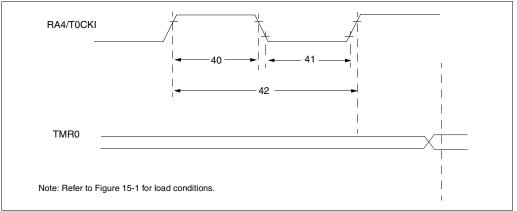


TABLE 15-5: TIMER0 EXTERNAL CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5Tcy + 20	-	_	ns	Must also meet
			With Prescaler	10	_	—	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5TCY + 20	_		ns	Must also meet
			With Prescaler	10	—		ns	parameter 42
42*	Tt0P	T0CKI Period	No Prescaler	Tcy + 40	_		ns	N = prescale value
			With Prescaler	Greater of: 20 ns or <u>TCY + 40</u> N	_		ns	(2, 4,, 256)

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C61

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables the data presented are outside specified operating range (i.e., outside specified VDD range). This is for information only and devices are guaranteed to operate properly only within the specified range. Note: The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution while 'max' or 'min' represents (mean $+3\sigma$) and (mean -3σ) respectively where σ is standard deviation.

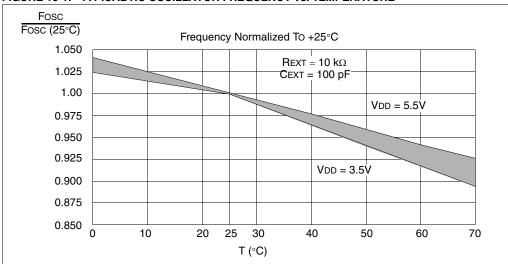


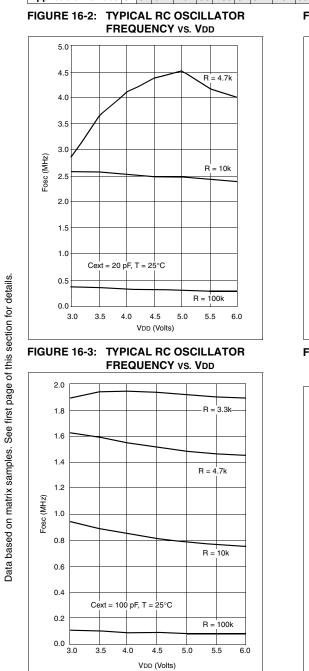
FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

TABLE 16-1: RC OSCILLATOR FREQUENCIE

Cext	Rext	Average Fosc @ 5V, 25°C	
20 pF	4.7k	4.52 MHz	± 17.35%
	10k	2.47 MHz	± 10.10%
	100k	290.86 kHz	± 11.90%
100 pF	3.3k	1.92 MHz	± 9.43%
	4.7k	1.48 MHz	± 9.83%
	10k	788.77 kHz	± 10.92%
	100k	88.11 kHz	± 16.03%
300 pF	3.3k	726.89 kHz	± 10.97%
	4.7k	573.95 kHz	± 10.14%
	10k	307.31 kHz	± 10.43%
	100k	33.82 kHz	± 11.24%

The percentage variation indicated here is part to part variation due to normal process distribution. The variation indicated is ± 3 standard deviation from average value for VDD = 5V.

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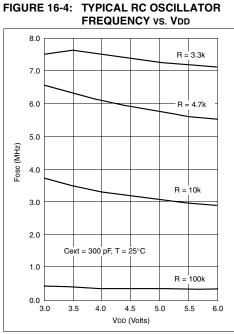
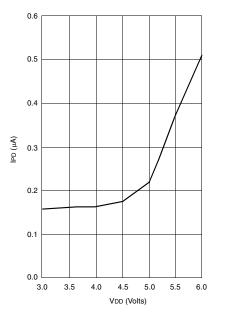
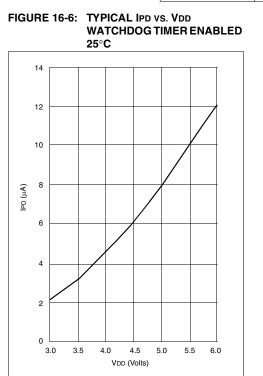
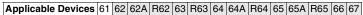
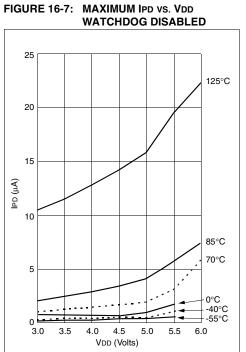


FIGURE 16-5: TYPICAL IPD vs. VDD WATCHDOG TIMER DISABLED 25°C



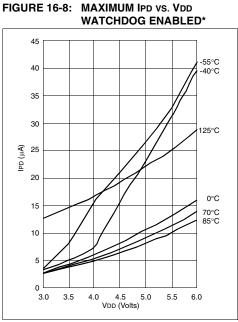




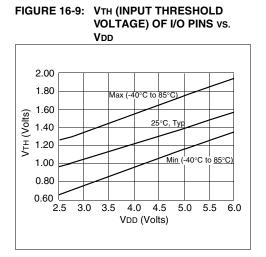


Data based on matrix samples. See first page of this section for details.

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*IPD, with Watchdog Timer enabled, has two components: The leakage current which increases with higher temperature and the operating current of the Watchdog Timer logic which increases with lower temperature. At -40°C, the latter dominates explaining the apparently anomalous behavior.



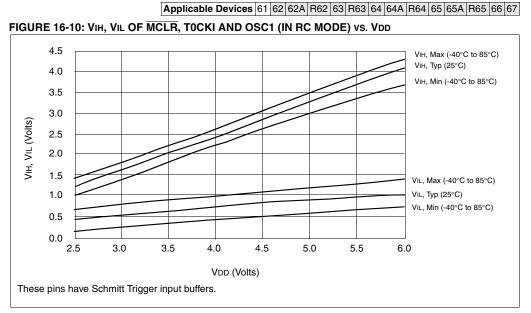
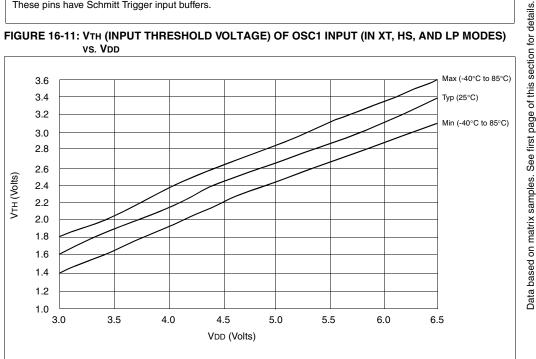
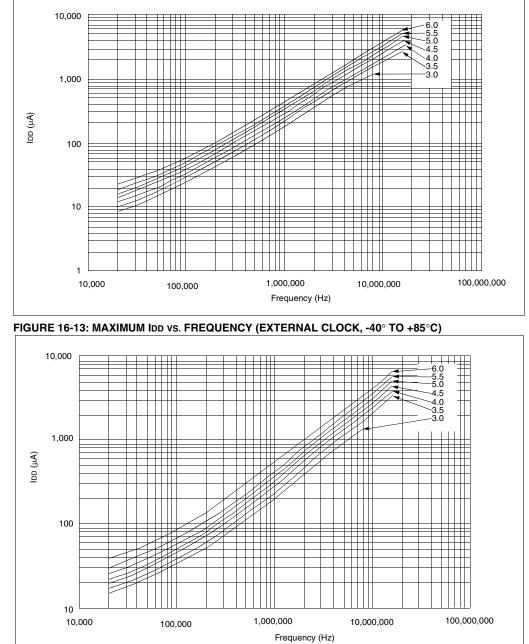


FIGURE 16-11: VTH (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (IN XT, HS, AND LP MODES) vs. Vdd



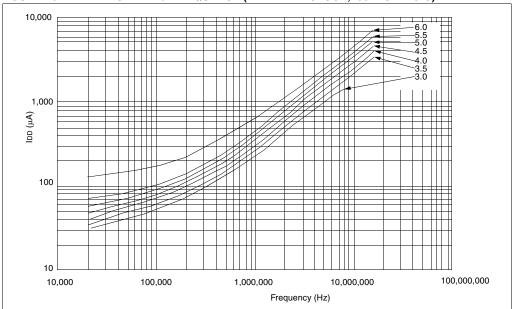
Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



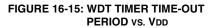


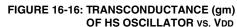
Data based on matrix samples. See first page of this section for details.

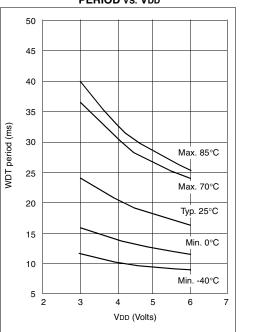


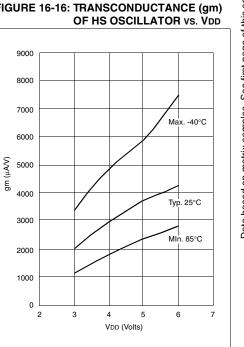








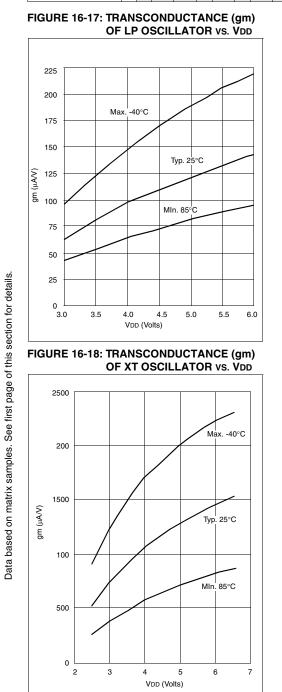






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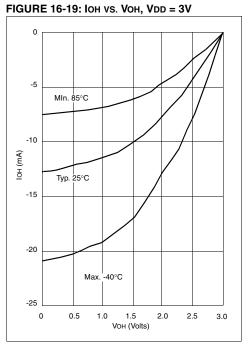
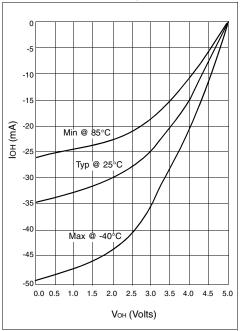
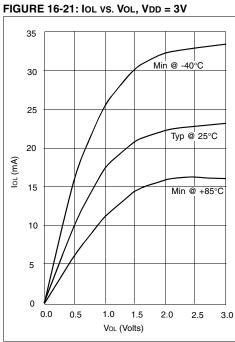
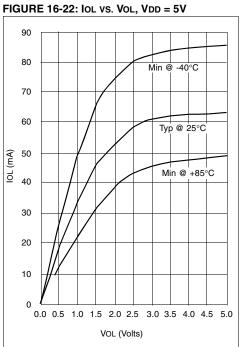


FIGURE 16-20: IOH VS. VOH, VDD = 5V





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VDD = 3V FIGURE 16-2

TABLE 16-2: INPUT CAPACITANCE*

Pin Name	Typical Capacitance (pF)					
	18L PDIP	18L SOIC				
RA port	5.0	4.3				
RB port	5.0	4.3				
MCLR	17.0	17.0				
OSC1/CLKIN	4.0	3.5				
OSC2/CLKOUT	4.3	3.5				
TOCKI	3.2	2.8				

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NOTES:

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17.0 ELECTRICAL CHARACTERISTICS FOR PIC16C62/64

Absolute Maximum Ratings †

Ambient temperature under bias	55°C to +85°C
Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD, MCLR, and RA4)	
Voltage on VDD with respect to VSS	0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	
Voltage on RA4 with respect to Vss	0V to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of Vss pin	
Maximum current into VDD pin	250 mA
Input clamp current, Iк (Vi < 0 or Vi > VDD)	±20 mA
Output clamp current, loк (Vo < 0 or Vo > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE* (combined)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE* (combined)	200 mA
Maximum current sunk by PORTC and PORTD* (combined)	200 mA
Maximum current sourced by PORTC and PORTD* (combined)	200 mA
* PORTD and PORTE not available on the PIC16C62.	

Note 1: Power dissipation is calculated as follows: Pdis = VDD x { $IDD - \sum IOH$ } + $\sum {(VDD-VOH) x IOH} + \sum (VOI x IOL)$

Note 2: Voltage spikes below Vss at the MCLR pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the MCLR pin rather than pulling this pin directly to Vss.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 17-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C62-04 PIC16C64-04	PIC16C62-10 PIC16C64-10	PIC16C62-20 PIC16C64-20	PIC16LC62-04 PIC16LC64-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 3.8 mA max. at 5.5V IPD: 21 μA max. at 4V Freq:4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq:4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq:4 MHz max.	VDD: 3.0V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 13.5 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.8 mA max. at 5.5V IPD: 21 μA max. at 4V Freq:4 MHz max.
ХТ	VDD: 4.0V to 6.0V IDD: 3.8 mA max. at 5.5V IPD: 21 μA max. at 4V Freq:4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq:4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq:4 MHz max.	VDD: 3.0V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 13.5 μA max. at 3.0V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.8 mA max. at 5.5V IPD: 21 μA max. at 4V Freq:4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq:4 MHz max.	VDD: 4.5V to 5.5V IDD: 15 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 10 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq:200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 13.5 μA max. at 3.0V Freq:200 kHz max.	VDD: 3.0V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD:13.5 μA max. at 3.0V Freq:200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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17.1 DC Characteristics: PIC16C62/64-04 (Commercial, Industrial) PIC16C62/64-10 (Commercial, Industrial) PIC16C62/64-20 (Commercial, Industrial)

DC CHARACTERISTICSStandard Operating Conditions (unless otherwise stated)Operating temperature -40° C $\leq TA \leq +85^{\circ}$ C for industrial and 0° C $\leq TA \leq +70^{\circ}$ C for commercial							
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001 D001A	Supply Voltage	Vdd	4.0 4.5	-	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power- on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5.0	mA	XT, RC, osc configuration Fosc = 4 MHz, VDD = 5.5V (Note 4)
D013			-	13.5	30	mA	HS osc configuration Fosc = 20 MHz, VDD = 5.5V
D020 D021 D021A	Power-down Current (Note 3, 5)	IPD	- - -	10.5 1.5 1.5	42 21 24	μΑ μΑ μΑ	$\label{eq:VDD} \begin{array}{l} VDD = 4.0V, WDT \text{ enabled}, -40^\circC \text{ to } +85^\circC \\ VDD = 4.0V, WDT \text{ disabled}, -0^\circC \text{ to } +70^\circC \\ VDD = 4.0V, WDT \text{ disabled}, -40^\circC \text{ to } +85^\circC \end{array}$

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSs.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

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17.2 DC Characteristics: PIC16LC62/64-04 (Commercial, Industrial)

		Standa	rd Ope	rating (Condi	tions (u	Inless otherwise stated)
DC CHA	RACTERISTICS	Operatir	ng temp	erature	-40	°C ≤	TA \leq +85°C for industrial and
					0°C	; ≤	$TA \le +70^{\circ}C$ for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage	Vdd	3.0	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power- on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021	(Note 3, 5)		-	0.9	13.5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	18	μA	VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

- 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
 - The test conditions for all IDD measurements in active operation mode are:
 - OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
 - $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.
- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSs.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

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17.3 DC Characteristics: PIC16C62/64-04 (Commercial, Industrial) PIC16C62/64-10 (Commercial, Industrial) PIC16C62/64-20 (Commercial, Industrial) PIC16LC62/64-04 (Commercial, Industrial)

			rd Operations temperations temperations to the second seco		-40°C	≤ T/	ss otherwise stated) $A \le +85^{\circ}$ C for industrial and
DC CHA	ARACTERISTICS	•	ng voltage tion 17.2	Vdd	0°C range as o		$A \le +70^{\circ}C$ for commercial ed in DC spec Section 17.1
Param No.	Characteristic	Sym	Min	тур †	Мах	Units	Conditions
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		Vss	-	0.15Vdd	V	For entire VDD range
D030A			Vss	-	0.8V	V	$4.5V \le VDD \le 5.5V$
D031	with Schmitt Trigger buffer		Vss	-	0.2Vdd	V	
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2Vdd	V	
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3Vdd	V	Note1
	Input High Voltage						
	I/O ports	VIH					
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \le VDD \le 5.5V$
D040A			0.25VDD	-	Vdd	V	For entire VDD range
			+ 0.8V				
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd		For entire VDD range
D042	MCLR		0.8VDD	-	Vdd	V	
D042A	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1
D043	OSC1 (in RC mode)		0.9Vdd	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	200	400	μΑ	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	lı∟	-	-	±1	μA	Vss \leq VPIN \leq VDD, Pin at hi- impedance
D061	MCLR, RA4/T0CKI		-	-	±5	μA	\dot{V} ss \leq VPIN \leq VDD
D063	OSC1		-	-	±5	μA	Vss \leq VPIN \leq VDD, XT, HS and
							LP osc configuration
	Output Low Voltage						
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	v	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D150*	Open-Drain High Voltage	VOD	-	-	14	V	RA4 pin

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
 Negative current is defined as current sourced by the pin.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C \leq TA \leq +85°C for industrial and 0°C DC CHARACTERISTICS \leq TA \leq +70°C for commercial Operating voltage VDD range as described in DC spec Section 17.1 and Section 17.2 Param Characteristic Sym Min Max Units Conditions Тур No. t **Capacitive Loading Specs on Output** Pins pF D100 OSC2 pin Cosc₂ In XT, HS and LP modes _ 15 when external clock is used to drive OSC1. D101 All I/O pins and OSC2 (in RC mode) CIO 50 pF D102 Cb 400 pF SCL, SDA in I²C mode _

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

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17.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

1. TppS2p	ppS	3. Tcc:st	(I ² C specifications only)
2. TppS		4. Ts	(I ² C specifications only)
Т		4.13	(i o specifications only)
F	Frequency	т	Time
	ase letters (pp) and their meanings:		-
рр			
cc	CCP1	OSC	OSC1
ck	CLKOUT	rd	RD
CS	CS	rw	RD or WR
di	SDI	SC	SCK
do	SDO	SS	SS
dt	Data in	tO	TOCKI
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR
Upperca	ase letters and their meanings:		
S			
F	Fall	Р	Period
н	High	R	Rise
I.	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I ² C only			
AA	output access	High	High
BUF	Bus free	Low	Low
TCC:ST ((I ² C specifications only)		
CC	· · · · ·		
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		
FIGURE 1	17-1: LOAD CONDITIONS FOR DEVICE	TIMING SP	PECIFICATIONS
	Load condition 1 VDD/2		Load condition 2
	9		
	< _		
	\geq RL		
		F	
			★
			Vss
	▼ Vss		
RL = 46		No	ote 1: PORTD and PORTE are not imple-
			mented on the PIC16C62.
CL = 50	0 pF for all pins except OSC2/CLKOUT but including D and E outputs as ports		
	but moluting D and L outputs as poins		

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15 pF for OSC2 output

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17.5 <u>Timing Diagrams and Specifications</u>

FIGURE 17-2: EXTERNAL CLOCK TIMING

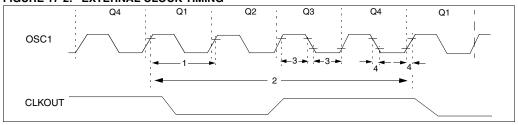


TABLE 17-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC		4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC		4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250		_	ns	XT and RC osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
		Oscillator Period	250		_	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	_	250	ns	HS osc mode (-04)
			100	_	250	ns	HS osc mode (-10)
			50	_	1,000	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	200	Тсү	DC	ns	Tcy = 4/Fosc
3	TosL,	External Clock in (OSC1) High	100	-	—	ns	XT oscillator
	TosH	or Low Time	2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise	—	_	25	ns	XT oscillator
	TosF	or Fall Time	—	—	50	ns	LP oscillator
			_	_	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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FIGURE 17-3: CLKOUT AND I/O TIMING

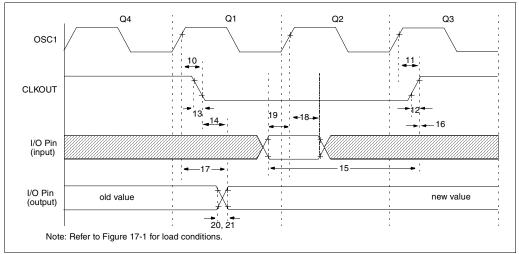


TABLE 17-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameters	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		—	75	200	ns	Note 1
11*	TosH2ckH	OSC1 [↑] to CLKOUT [↑]		—	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid	—		0.5TCY + 20	ns	Note 1	
15*	TioV2ckH	Port in valid before CLKOUT	↑	Tosc + 200	_	—	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑	0		—	ns	Note 1	
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out	—	50	150	ns		
18*	TosH2iol	OSC1 [↑] (Q2 cycle) to Port	PIC16 C 62/64	100		_	ns	
		input invalid (I/O in hold time)	PIC16 LC 62/64	200		_	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)		0		—	ns	
20*	TioR	Port output rise time	PIC16 C 62/64	_	10	40	ns	
			PIC16 LC 62/64	_		80	ns	
21*	TioF	Port output fall time	PIC16 C 62/64	—	10	40	ns	
			PIC16 LC 62/64	—	_	80	ns	
22††*	Tinp	INT pin high or low time		Тсү	—	_	ns	
23††*	Trbp	RB7:RB4 change INT high or	low time	Тсү	—	_	ns	

* These parameters are characterized but not tested.

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

These parameters are asynchronous events not related to any internal clock edge.
 Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

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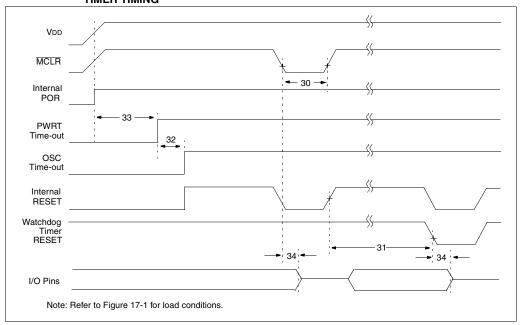


TABLE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30*	TmcL	MCLR Pulse Width (low)	100	—	l	ns	$VDD = 5V$, $-40^{\circ}C$ to $+85^{\circ}C$
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024Tosc	-	-	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +85°C
34*	Tıoz	I/O Hi-impedance from MCLR Low	_	—	100	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 17-5: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

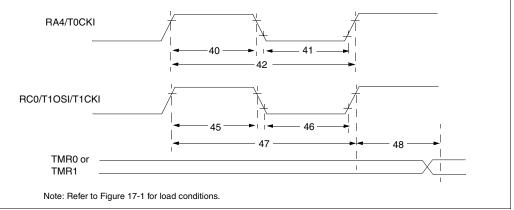


TABLE 17-5:	TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS
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Param No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse V	Vidth	No Prescaler	0.5TCY + 20	-	—	ns	Must also meet
				With Prescaler	10	_	_	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse W	/idth	No Prescaler	0.5TCY + 20	_	—	ns	Must also meet
				With Prescaler	10	—	_	ns	parameter 42
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
				With Prescaler	Greater of: 20 or <u>Tcy + 40</u> N	-	—	ns	N = prescale value (2, 4,, 256)
45*	Tt1H	T1CKI High Time	Synchronous, P	Prescaler = 1	0.5TCY + 20		_	ns	Must also meet
		-	Synchronous,	PIC16 C 6X	15	_	—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	—	—	ns	+
			Asynchronous	PIC16 C 6X	30	—	—	ns	
				PIC16 LC 6X	50	—	—	ns	Ť
46*	Tt1L	T1CKI Low Time	Synchronous, P	rescaler = 1	0.5TCY + 20	—	—	ns	Must also meet
			Synchronous,	PIC16 C 6X	15	—	—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	—	_	ns	
			Asynchronous	PIC16 C 6X	30	—	—	ns	
				PIC16 LC 6X	50	—	—	ns	Ī
47*	Tt1P	T1CKI input period	Synchronous	PIC16 C 6X	<u>Greater of:</u> 30 OR <u>TCY + 40</u> N	-	—	ns	N = prescale value (1, 2, 4, 8)
				PIC16 LC 6X	<u>Greater of:</u> 50 OR <u>TCY + 40</u> N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16 C 6X	60	—	—	ns	
				PIC16 LC 6X	100	—	—	ns	
	Ft1	Timer1 oscillator inp (oscillator enabled b			DC	-	200	kHz	
48	TCKEZtmr1	Delay from external	clock edge to tin	ner increment	2Tosc	—	7Tosc	_	

These parameters are characterized but not tested.

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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FIGURE 17-6: CAPTURE/COMPARE/PWM TIMINGS (CCP1)

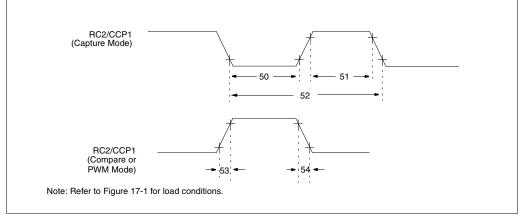


TABLE 17-6:	CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1)

Parameter No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
50*	TccL	CCP1	No Prescaler		0.5TCY + 20	-	-	ns	
		input low time	With Prescaler	PIC16 C 62/64	10	_		ns	
				PIC16 LC 62/64	20	—	_	ns	
51*			No Prescaler		0.5Tcy + 20	_		ns	
	input high time	With Prescaler	PIC16 C 62/64	10	-		ns		
				PIC16 LC 62/64	20	_	_	ns	
52*	TccP	CCP1 input period			<u>3Tcy + 40</u> N	-	Ι	ns	N = prescale value (1,4 or 16)
53	TccR	CCP1 output rise time	9	PIC16 C 62/64	_	10	25	ns	
				PIC16 LC 62/64	_	25	45	ns	
54	54 TccF CCP1 output fall time			PIC16 C 62/64	_	10	25	ns	
				PIC16LC62/64	_	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 17-7: PARALLEL SLAVE PORT TIMING (PIC16C64)

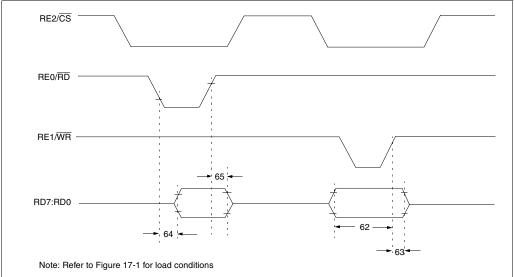


TABLE 17-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C64)

Parameter No.	Sym	Characteristic			Тур†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} (setup time)		20	_	_	ns	
63*	TwrH2dtl	\overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} to data–in invalid	PIC16 C 64	20	—	—	ns	
		(hold time)	PIC16 LC 64	35	—	—	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid		—	80	ns	
65	TrdH2dtl	$\overline{RD}\uparrow$ or $\overline{CS}\uparrow$ to data–out invalid	$\overline{D}\uparrow$ or $\overline{CS}\uparrow$ to data–out invalid		—	30	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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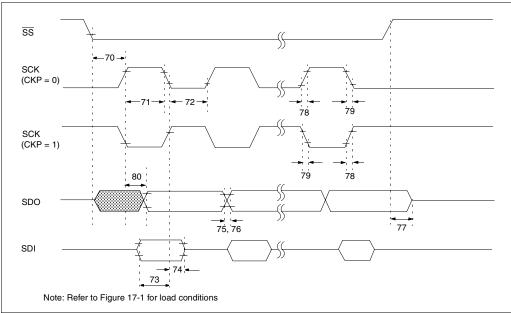


FIGURE 17-8: SPI MODE TIMING

TABLE 17-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK \downarrow or SCK \uparrow input	Тсү	—	—	ns	
71	TscH	SCK input high time (slave mode)	Tcy + 20	_	_	ns	
72	TscL	SCK input low time (slave mode)	Tcy + 20	_	_	ns	
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50		—	ns	
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	_	_	ns	
75	TdoR	SDO data output rise time	_	10	25	ns	
76	TdoF	SDO data output fall time	_	10	25	ns	
77	TssH2doZ	SS↑ to SDO output hi-impedance	10	—	50	ns	
78	TscR	SCK output rise time (master mode)		10	25	ns	
79	TscF	SCK output fall time (master mode)	_	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge	_	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 17-9: I²C BUS START/STOP BITS TIMING

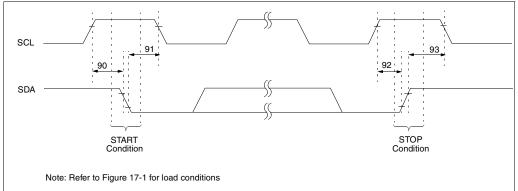


TABLE 17-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур	Max	Units	Conditions	
90	TSU:STA	START condition	100 kHz mode	4700	—	-		Only relevant for repeated START	
		Setup time	400 kHz mode	600	—	_	ns	condition	
91	THD:STA	START condition	100 kHz mode	4000	_	_		After this period the first clock	
		Hold time	400 kHz mode	600	—	_	ns	pulse is generated	
92	Tsu:sto	STOP condition	100 kHz mode	4700	_	_			
		Setup time	400 kHz mode	600	—	_	ns		
93	THD:STO	STOP condition	100 kHz mode	4000	—	-	-		
		Hold time	400 kHz mode	600	—	-	ns		

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FIGURE 17-10: I²C BUS DATA TIMING

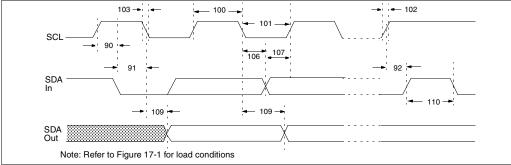


TABLE 17-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions	
100	Thigh	Clock high time	100 kHz mode	4.0	-	μS	Device must operate at a mini- mum of 1.5 MHz	
			400 kHz mode	0.6	_	μS	Device must operate at a mini mum of 10 MHz	
			SSP Module	1.5Tcy	—			
101	TLOW	Clock low time	100 kHz mode	4.7	_	μS	Device must operate at a mini mum of 1.5 MHz	
			400 kHz mode	1.3	—	μs	Device must operate at a mini mum of 10 MHz	
			SSP Module	1.5Tcy	—			
102	TR	SDA and SCL rise	100 kHz mode	_	1000	ns		
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF	
103	TF	SDA and SCL fall time	100 kHz mode	_	300	ns		
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF	
90	TSU:STA	START condition	100 kHz mode	4.7	—	μS	Only relevant for repeated	
		setup time	400 kHz mode	0.6	—	μS	START condition	
91	THD:STA	START condition hold	100 kHz mode	4.0	—	μS	After this period the first clock	
		time	400 kHz mode	0.6	—	μS	pulse is generated	
106	THD:DAT	Data input hold time	100 kHz mode	0	-	ns		
			400 kHz mode	0	0.9	μS		
107	TSU:DAT	Data input setup time	100 kHz mode	250	_	ns	Note 2	
			400 kHz mode	100	-	ns		
92	Tsu:sto	STOP condition setup	100 kHz mode	4.7	—	μS		
		time	400 kHz mode	0.6	—	μS		
109	ΤΑΑ	Output valid from	100 kHz mode	_	3500	ns	Note 1	
		clock	400 kHz mode	_	—	ns		
110	TBUF	Bus free time	100 kHz mode	4.7	—	μS	Time the bus must be free	
			400 kHz mode	1.3	—	μs	before a new transmission car start	
	Cb	Bus capacitive loading		—	400	pF		

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.
2: A fast-mode (400 kHz) l²C-bus device can be used in a standard-mode (100 kHz) l²C-bus system, but the requirement

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement tsu;DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max. + tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

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NOTES:

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18.0 ELECTRICAL CHARACTERISTICS FOR PIC16C62A/R62/64A/R64

Absolute Maximum Ratings †

Ambient temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to Vss (except VDD, MCLR, and RA4)	
Voltage on VDD with respect to VSS	0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	
Voltage on RA4 with respect to Vss	0V to +14V
Total power dissipation (Note 1)	
Maximum current out of Vss pin	
Maximum current into VDD pin	
Input clamp current, Iк (VI < 0 or VI > VDD)	
Output clamp current, loк (Vo < 0 or Vo > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	
Maximum current sunk by PORTA, PORTB, and PORTE (combined)	
Maximum current sourced by PORTA, PORTB, and PORTE (combined)	
Maximum current sunk by PORTC and PORTD (combined)	200 mA
Maximum current sourced by PORTC and PORTD (combined)	
Note 1 . Power dissination is calculated as follows: Pdis – VDD x (IDD - $\sum OH + \sum (V)$	$(V \cap H) \times (O H) + \Sigma (V \cap H \cap H)$

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - \sum IOH} + \sum {(VDD-VOH) x IOH} + \sum (VOI x IOL)

Note 2: Voltage spikes below Vss at the MCLR pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the MCLR pin rather than pulling this pin directly to Vss.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 18-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C62A-04 PIC16CR62-04 PIC16C64A-04 PIC16CR64-04	PIC16C62A-10 PIC16CR62-10 PIC16C64A-10 PIC16CR64-10	PIC16C62A-20 PIC16CR62-20 PIC16C64A-20 PIC16CR64-20	PIC16LC62A-04 PIC16LCR62-04 PIC16LC64A-04 PIC16LCR64-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq:4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq:4 MHz max.
ХТ	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 5 µA max. at 3.0V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.		VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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18.1 DC Characteristics: PIC16C62A/R62/64A/R64-04 (Commercial, Industrial, Extended) PIC16C62A/R62/64A/R64-10 (Commercial, Industrial, Extended) PIC16C62A/R62/64A/R64-20 (Commercial, Industrial, Extended)

DC CHA	RACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature -40° C \leq TA \leq +125°C for extended, -40° C \leq TA \leq +85°C for industrial and 0° C $<$ TA $<$ +70°C for commercial								
Param No.	Characteristic	Sym	Min	Тур†		 Units				
D001 D001A	Supply Voltage	Vdd	4.0 4.5	-	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration			
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V				
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details			
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details			
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN bit in configuration word enabled			
			3.7	4.0	4.4	V	Extended Range Only			
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5	mA	XT, RC, osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)			
D013			-	10	20	mA	HS osc configuration FOSC = 20 MHz, VDD = 5.5V			
D015*	Brown-out Reset Current (Note 6)	Δ Ibor	-	350	425	μA	BOR enabled, VDD = 5.0V			
D020	Power-down Current (Note	IPD	-	10.5	42	μA	VDD = 4.0V, WDT enabled, -40°C to +85°C			
D021	3, 5)		-	1.5	16	μA	$VDD = 4.0V$, WDT disabled, $-0^{\circ}C$ to $+70^{\circ}C$			
D021A			-	1.5	19	μA	VDD = $4.0V$, WDT disabled, -40° C to $+85^{\circ}$ C			
D021B			-	2.5	19	μA	VDD = $4.0V$, WDT disabled, $-40^{\circ}C$ to $+125^{\circ}C$			
D023*	Brown-out Reset Current (Note 6)	Δ Ibor	-	350	425	μA	BOR enabled, VDD = 5.0V			

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

 $\overline{MCLR} = VDD$; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSs.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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18.2 DC Characteristics: PIC16LC62A/R62/64A/R64-04 (Commercial, Industrial)

		Standa	rd Ope	rating (Condi	tions (u	Inless otherwise stated)
DC CHA	RACTERISTICS	Operatir	ng temp	perature			$TA \leq +85^{\circ}C$ for industrial and
					0°C	> ≤	$TA \le +70^{\circ}C$ for commercial
Param No.	Characteristic	Sym	Min	Тур†	Мах	Units	Conditions
D001	Supply Voltage	Vdd	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Volt- age (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021	(Note 3, 5)		-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD \overline{MCLR} = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

 The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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18.3 DC Characteristics: PIC16C62A/R62/64A/R64-04 (Commercial, Industrial, Extended) PIC16C62A/R62/64A/R64-10 (Commercial, Industrial, Extended) PIC16C62A/R62/64A/R64-20 (Commercial, Industrial, Extended) PIC16LC62A/R62/64A/R64-04 (Commercial, Industrial)

		Standard Operating Conditions (unless otherwise stated)Operating temperature -40° C \leq TA \leq +125°C for extended,								
		Operatio	ig temper	ature	-40°		TA \leq +85°C for industrial and			
DC CHA	ARACTERISTICS				0°C		TA \leq +70°C for commercial			
		Operating voltage VDD range as described in DC spec Section 18.1 and								
		Section			0		·			
Param	Characteristic				Max	Units	Conditions			
No.				†						
	Input Low Voltage									
	I/O ports	VIL								
D030	with TTL buffer		Vss	-	0.15VDD	V	For entire VDD range			
D030A			Vss	-	0.8V	V	$4.5V \le VDD \le 5.5V$			
D031	with Schmitt Trigger buffer		Vss	-	0.2Vdd	V				
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2Vdd	V				
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3Vdd	V	Note1			
	Input High Voltage									
	I/O ports	Vін		-						
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \le VDD \le 5.5V$			
D040A			0.25VDD	-	Vdd	V	For entire VDD range			
			+ 0.8V							
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd	V	For entire VDD range			
-	MCLR		0.8VDD	-	Vdd	V				
	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1			
	OSC1 (in RC mode)		0.9Vdd	-	Vdd	V				
	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS			
	Input Leakage Current (Notes 2, 3)									
D060	I/O ports	lı∟	-	-	±1	μA	Vss \leq VPIN \leq VDD, Pin at hi-imped-			
							ance			
	MCLR, RA4/T0CKI		-	-	± 5	μA	$Vss \le VPIN \le VDD$			
D063	OSC1		-	-	±5	μA	$Vss \le VPIN \le VDD$, XT, HS and LP			
	Outrout I and Malta and						osc configuration			
	Output Low Voltage	Ve			0.0	N N				
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C			
D080A			_	-	0.6	v	-40° C to $+85^{\circ}$ C IOL = 7.0 mA, VDD = 4.5V,			
DUOUA			-	-	0.0	v	-40°C to +125°C			
D083	OSC2/CLKOUT (RC osc config)		_	-	0.6	v	IOL = 1.6 mA, VDD = 4.5 V,			
2000			-	-	0.0	v	-40°C to +85°C			
D083A			-	_	0.6	v	IOL = 1.2 mA, VDD = 4.5 V,			
					0.0		-40°C to +125°C			

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

- 2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3: Negative current is defined as current sourced by the pin.

		Standa	rd Operat	ing (Conditior	ns (unle	ess otherwise stated)				
		Operatir	ng temper	ature	e -40°	C ≤	TA \leq +125°C for extended,				
	ARACTERISTICS	-40°C \leq TA \leq +85°C for industrial and									
	ARACIERISTICS	$0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial									
		Operating voltage VDD range as described in DC spec Section 18.1 and									
		Section 18.2									
Param	Characteristic	Sym	Min	Тур	Max	Units	Conditions				
No.				†							
	Output High Voltage										
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V,				
							-40°C to +85°C				
D090A			VDD-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V,				
							-40°C to +125°C				
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V,				
							-40°C to +85°C				
D092A			VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V,				
							-40°C to +125°C				
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin				
	Capacitive Loading Specs on Out-										
	put Pins										
D100	OSC2 pin	Cosc ₂	-	-	15	pF	In XT, HS and LP modes when				
							external clock is used to drive				
							OSC1.				
D101	All I/O pins and OSC2 (in RC mode)	Cio	-	-	50	pF					
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF					

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These parameters are characterized but not tested.

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and t are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
 Negative current is defined as current sourced by the pin.

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18.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

1. TppS2	ppS	3. Tcc:s	T (I ² C specifications only)
2. TppS		4. Ts	(I ² C specifications only)
т			
F	Frequency	Т	Time
Lowerc	case letters (pp) and their meanings:		
рр			
сс	CCP1	OSC	OSC1
ck	CLKOUT	rd	RD
CS	CS	rw	RD or WR
di	SDI	SC	SCK
do	SDO	SS	SS
dt	Data in	tO	TOCKI
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR
	case letters and their meanings:		
S			
F	Fall	P	Period
Н	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I ² C only			
AA	output access	High	High
BUF	Bus free	Low	Low
Tcc:st	(I ² C specifications only)		
CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		
	18-1: LOAD CONDITIONS FOR DE		SPECIFICATIONS
	Load condition 1		Load condition 2
	VDD/2		
	Ŷ		
	\leq RL		
	<		Pin U
	• • • • • • • • • • • • • • • • • • •		Vss
			100
	• • • • • •		
	Vss	D: 4040	
		$RL = 464\Omega$	
		CL = 50 pF	for all pins except OSC2/CLKOUT but including D and E outputs as ports
Note 1:	PORTD and PORTE are not	45 -5	• • •
	implemented on the PIC16C62A/R62.	15 pF	for OSC2 output

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18.5 <u>Timing Diagrams and Specifications</u>

FIGURE 18-2: EXTERNAL CLOCK TIMING

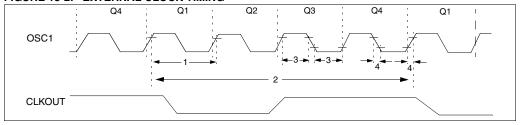


TABLE 18-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency					
		(Note 1)	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	_	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	_	_	ns	XT and RC osc mode
		(Note 1)	250	_		ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
		Oscillator Period	250	_	_	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	_	250	ns	HS osc mode (-04)
			100	_	250	ns	HS osc mode (-10)
			50	_	250	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	200	Тсү	DC	ns	Tcy = 4/Fosc
3	TosL,	External Clock in (OSC1) High or	100	_	_	ns	XT oscillator
	TosH	Low Time	2.5	_	_	μs	LP oscillator
			15	_	_	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise or	_	_	25	ns	XT oscillator
	TosF	Fall Time	_	_	50	ns	LP oscillator
			_	_	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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FIGURE 18-3: CLKOUT AND I/O TIMING

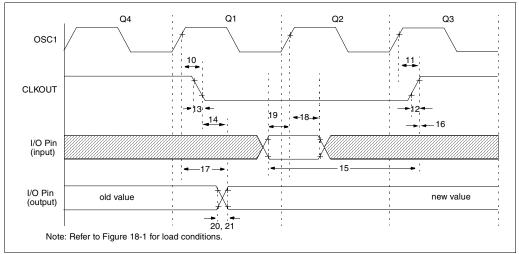


TABLE 18-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameters	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		—	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	—	75	200	ns	Note 1	
12*	TckR	CLKOUT rise time		—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		—	—	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT \uparrow		Tosc + 200	—	—	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT \uparrow		0	—	—	ns	Note 1
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out va	1↑ (Q1 cycle) to Port out valid			150	ns	
18*	TosH2iol	OSC1 [↑] (Q2 cycle) to Port input invalid (I/O in hold time)	PIC16 C 62A/ R62/64A/R64	100	-	—	ns	
			PIC16 LC 62A/ R62/64A/R64	200	—	—	ns	
19*	TioV2osH	Port input valid to OSC1 [↑] (I/O in	setup time)	0	_	_	ns	
20*	TioR	Port output rise time	PIC16 C 62A/ R62/64A/R64	—	10	40	ns	
			PIC16 LC 62A/ R62/64A/R64	—	—	80	ns	
21*	TioF	Port output fall time	PIC16 C 62A/ R62/64A/R64	—	10	40	ns	
			PIC16 LC 62A/ R62/64A/R64	—	_	80	ns	
22††*	Tinp	RB0/INT pin high or low time		Тсү	_	_	ns	
23††*	Trbp	RB7:RB4 change int high or low	time	Тсү	_	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

these parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

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FIGURE 18-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

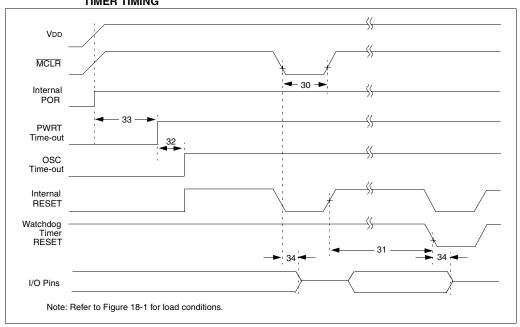






 TABLE 18-4:
 RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

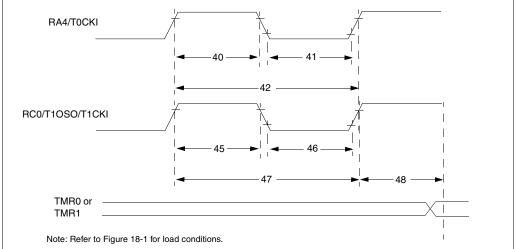
Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2	—	_	μs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	$VDD = 5V$, $-40^{\circ}C$ to $+125^{\circ}C$
32	Tost	Oscillation Start-up Timer Period	—	1024Tosc	—	-	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	Tioz	I/O Hi-impedance from MCLR Low or WDT Reset	—	—	2.1	μs	
35	TBOR	Brown-out Reset Pulse Width	100	—	—	μs	$VDD \le BVDD$ (param. D005)

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 18-6: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Param No.	Sym	Characteristic			Min		Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse V	Vidth	No Prescaler	0.5TCY + 20	-	—	ns	Must also meet
				With Prescaler	10	—	—	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse W	/idth	No Prescaler	0.5TCY + 20	-	-	ns	Must also meet
				With Prescaler	10	_		ns	parameter 42
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
		Wi		With Prescaler	Greater of: 20 or <u>Tcy + 40</u> N	-	_	ns	N = prescale value (2, 4,, 256)
45*	Tt1H	T1CKI High Time	Synchronous, P	rescaler = 1	0.5TCY + 20	-	—	ns	Must also meet
			Synchronous,	PIC16 C 6X	15	—	—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	—	_	ns	
			Asynchronous	PIC16 C 6X	30	_	—	ns	
			PIC16 LC 6X	50	—	—	ns		
46*	Tt1L	T1CKI Low Time	Synchronous, P		0.5TCY + 20	—	—	ns	Must also meet
			Synchronous,	PIC16 C 6X	15		—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	-	ns	
			Asynchronous	PIC16 C 6X	30	_	—	ns	
				PIC16 LC 6X	50		—	ns	-
47*	Tt1P	T1CKI input period	Synchronous	PIC16 C 6X	<u>Greater of:</u> 30 OR <u>TCY + 40</u> N	_	_	ns	N = prescale value (1, 2, 4, 8)
				PIC16 LC 6X	<u>Greater of:</u> 50 OR <u>TCY + 40</u> N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16 C 6X	60	-	_	ns	
				PIC16 LC 6X	100	-	_	ns	
	Ft1	Timer1 oscillator inp			DC	—	200	kHz	
40	TO//57	(oscillator enabled b		,					
48		Delay from external	U		2Tosc		7Tosc		

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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FIGURE 18-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1)

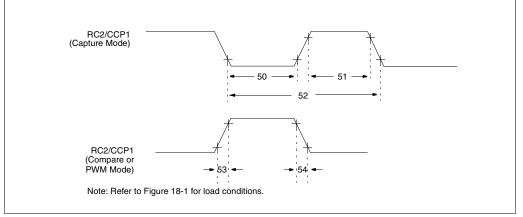


TABLE 18-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1)

Parameter No.			Min	Тур†	Max	Units	Conditions		
50*	TccL	CCP1	No Prescaler	0.5TCY + 20	_	_	ns		
		input low time	With Prescaler	PIC16 C 62A/R62/ 64A/R64	10	—		ns	
				PIC16 LC 62A/R62/ 64A/R64	20	—	I	ns	
51*	TccH	CCP1	No Prescaler	I	0.5TCY + 20	_	-	ns	
		input high time	With Prescaler	PIC16 C 62A/R62/ 64A/R64	10	—	I	ns	
				PIC16 LC 62A/R62/ 64A/R64	20	—		ns	
52*	TccP	CCP1 input period	1	1	<u>3Tcy + 40</u> N	_		ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 output rise	time	PIC16 C 62A/R62/ 64A/R64	_	10	25	ns	
				PIC16 LC 62A/R62/ 64A/R64	_	25	45	ns	
54*	TccF	CCP1 output fall time		PIC16 C 62A/R62/ 64A/R64	_	10	25	ns	
				PIC16 LC 62A/R62/ 64A/R64	_	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 18-8: PARALLEL SLAVE PORT TIMING (PIC16C64A/R64)

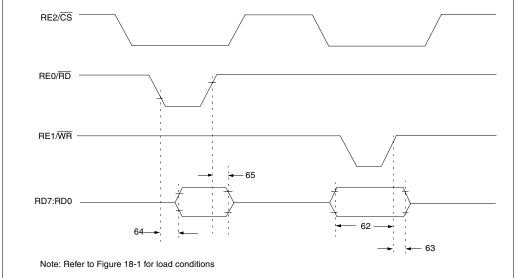


TABLE 18-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C64A/R64)

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions	
62	TdtV2wrH	Data in valid before $\overline{WR}{\uparrow}$ or $\overline{CS}{\uparrow}$ (set	20	-	—	ns		
					_	-	ns	Extended Range Only
63*	TwrH2dtI \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} to data-in invalid (hold		PIC16 C 64A/R64	20	_	—	ns	
		time)	PIC16LC64A.R64	35		—	ns	
64	TrdL2dtV	$\overline{\text{RD}}\downarrow$ and $\overline{\text{CS}}\downarrow$ to data–out valid				80	ns	
					—	90	ns	Extended Range Only
65*	TrdH2dtl	\overline{RD} or \overline{CS} to data-out invalid		10	-	30	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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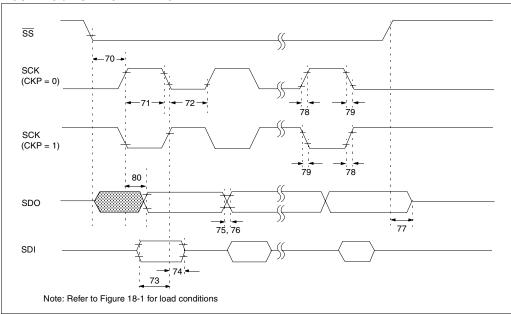


FIGURE 18-9: SPI MODE TIMING

TABLE 18-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK \downarrow or SCK \uparrow input	Тсү	—	—	ns	
71*	TscH	SCK input high time (slave mode)	Tcy + 20	_	_	ns	
72*	TscL	SCK input low time (slave mode)	Tcy + 20	_	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	_	_	ns	
75*	TdoR	SDO data output rise time	_	10	25	ns	
76*	TdoF	SDO data output fall time		10	25	ns	
77*	TssH2doZ	SS↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)		10	25	ns	
79*	TscF	SCK output fall time (master mode)	_	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	_	—	50	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

 Applicable Devices
 61
 62
 62A
 R62
 63
 R63
 64
 64A
 R64
 65
 65A
 R65
 66
 67

FIGURE 18-10: I²C BUS START/STOP BITS TIMING

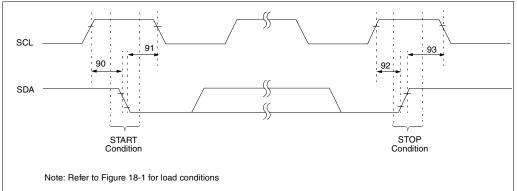


TABLE 18-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур	Max	Units	Conditions	
90*	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START	
		Setup time	400 kHz mode	600	—	_	110	condition	
91*	THD:STA	START condition	100 kHz mode	4000	—	_	ns	After this period the first clock pulse is generated	
		Hold time	400 kHz mode	600	—	_	115		
92*	TSU:STO	STOP condition	100 kHz mode	4700	—	_	ns		
		Setup time	400 kHz mode	600	—	—	115		
93*	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns		
		Hold time	400 kHz mode	600	—	—	115		

*These parameters are characterized but not tested.

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FIGURE 18-11: I²C BUS DATA TIMING

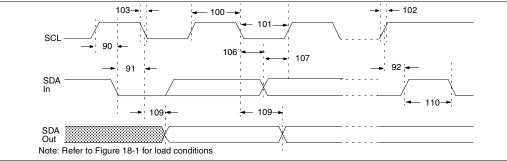


TABLE 18-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100*	Thigh	Clock high time	100 kHz mode	4.0	_	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY			
101*	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	—		
102*	TR	SDA and SCL rise	100 kHz mode	_	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	_	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90*	TSU:STA	START condition	100 kHz mode	4.7	—	μS	Only relevant for repeated
		setup time	400 kHz mode	0.6	_	μS	START condition
91*	THD:STA	START condition hold	100 kHz mode	4.0	—	μs	After this period the first clock
		time	400 kHz mode	0.6	_	μS	pulse is generated
106*	THD:DAT	Data input hold time	100 kHz mode	0		ns	
			400 kHz mode	0	0.9	μS	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92*	Tsu:sto	STOP condition setup	100 kHz mode	4.7	—	μs	
		time	400 kHz mode	0.6	—	μs	
109*	ΤΑΑ	Output valid from	100 kHz mode	—	3500	ns	Note 1
		clock	400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free
			400 kHz mode	1.3	—	μs	before a new transmission can start
	Cb	Bus capacitive loading		_	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.
2: A fast-mode (400 kHz) l²C-bus device can be used in a standard-mode (100 kHz) l²C-bus system, but the requirement

2: A fast-mode (400 kHz) l^2 C-bus device can be used in a standard-mode (100 kHz) l^2 C-bus system, but the requirement tsu;DAT \ge 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode l^2 C bus specification) before the SCL line is released.

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NOTES:

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19.0 ELECTRICAL CHARACTERISTICS FOR PIC16C65

Absolute Maximum Ratings †	
Ambient temperature under bias	55°C to +85°C
Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD, MCLR, and RA4)	0.3V to (VDD + 0.3V)
Voltage on VDD with respect to Vss	-0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0V to +14V
Voltage on RA4 with respect to Vss	0V to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of Vss pin	
Maximum current into VDD pin	250 mA
Input clamp current, Iк (VI < 0 or VI > VDD)	±20 mA
Output clamp current, loк (Vo < 0 or Vo > VDD)	
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined)	200 mA
Maximum current sunk by PORTC and PORTD (combined)	200 mA
Maximum current sourced by PORTC and PORTD (combined)	200 mA
Note 1. Power dissipation is calculated as follows: Pdis – VDD x $\{DD - \sum OH\} + \sum \{(VD - \sum OH) + \sum ((VD - \sum OH) + \sum ((V$	$\nabla - V(OH) \times [OH] + \Sigma(VO \times [OH))$

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - \sum IOH} + \sum {(VDD-VOH) x IOH} + \sum (VOI x IOL) **Note 2:** Voltage spikes below VSs at the MCLR pin, inducing currents greater than 80 mA, may cause latch-up. Thus,

a series resistor of 50-100Ω should be used when applying a "low" level to the MCLR pin rather than pulling this pin directly to Vss.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 19-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C65-04	PIC16C65-10	PIC16C65-20	PIC16LC65-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 3.8 mA max. at 3V IPD: 800 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 μA max. at 4V Freq: 4 MHz max.
ХТ	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 3.8 mA max. at 3V IPD: 800 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 μA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V	VDD: 4.5V to 5.5V VDD: 4.5V to 5.5V IDD: 15 mA max. at 5.5V IDD: 30 mA max. at 5.5V		Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V
	IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	IPD 1.0 μA typ. at 4.5V Freq: 10 MHz max.	IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.		IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 105 μA max. at 32 kHz, 3.0V IPD: 800 μA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 105 μA max. at 32 kHz, 3.0V IPD: 800 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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19.1 DC Characteristics: PIC16C65-04 (Commercial, Industrial) PIC16C65-10 (Commercial, Industrial) PIC16C65-20 (Commercial, Industrial)

		Standa	rd One	rating (Condi	tions (unless otherwise stated)				
DC CHA		Standard Operating Conditions (unless otherwise stated)Operating temperature -40° C \leq Ta \leq +85°C for industrial and 0° C \leq Ta \leq +70°C for commercial									
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions				
D001 D001A	Supply Voltage	Vdd	4.0 4.5		6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration				
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V					
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details				
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details				
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 5.5V (Note 4)				
D013			-	13.5	30	mA	HS osc configuration Fosc = 20 MHz, VDD = 5.5V				
D020 D021 D021A	Power-down Current (Note 3, 5)	IPD		10.5 1.5 1.5	800 800 800	μΑ μΑ μΑ	$\label{eq:VDD} \begin{array}{l} VDD=4.0V, WDT \text{ enabled}, -40^\circ C \text{ to } +85^\circ C \\ VDD=4.0V, WDT \text{ disabled}, -0^\circ C \text{ to } +70^\circ C \\ VDD=4.0V, WDT \text{ disabled}, -40^\circ C \text{ to } +85^\circ C \end{array}$				

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

19.2 DC Characteristics: PIC16LC65-04 (Commercial, Industrial)

DC CH		$\begin{array}{llllllllllllllllllllllllllllllllllll$									
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions				
D001	Supply Voltage	Vdd	3.0	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)				
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V					
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details				
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details				
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)				
D010A			-	22.5	105	μA	LP osc configuration Fosc = 32 kHz, VDD = 4.0V, WDT disabled				
D020	Power-down Current	IPD	-	7.5	800	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C				
D021	(Note 3, 5)		-	0.9	800	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C				
D021A			-	0.9	800	μA	VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$				

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

 $\overline{MCLR} = VDD$; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

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19.3 DC Characteristics: PIC16C65-04 (Commercial, Industrial) PIC16C65-10 (Commercial, Industrial) PIC16C65-20 (Commercial, Industrial) PIC16LC65-04 (Commercial, Industrial)

DC CHA	RACTERISTICS	Standard Operating Conditions (unless otherwise stated)Operating temperature -40° C \leq Ta \leq +85°C for industrial and 0° C \leq Ta \leq +70°C for commercialOperating voltage VDD range as described in DC spec Section 19.1 andSection 19.2									
Param No.	Characteristic	Sym	Min	Тур †	Max	Units	Conditions				
	Input Low Voltage										
	I/O ports	VIL									
D030	with TTL buffer		Vss	-	0.15VDD	V	For entire VDD range				
D030A			Vss	-	0.8V	V	$4.5V \le VDD \le 5.5V$				
D031	with Schmitt Trigger buffer		Vss	-	0.2VDD	V					
D032	MCLR, OSC1(in RC mode)		Vss	-	0.2Vdd	V					
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3Vdd	V	Note1				
	Input High Voltage										
	I/O ports	VIH		-							
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \leq V\text{DD} \leq 5.5V$				
D040A			0.25VDD+ 0.8V	-	Vdd	V	For entire VDD range				
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd		For entire VDD range				
D042	MCLR		0.8VDD	-	Vdd	V					
D042A	OSC1 (XT, HS and LP)		0.7 Vdd	-	Vdd	V	Note1				
D043	OSC1 (in RC mode)		0.9VDD	-	Vdd	V					
D070	PORTB weak pull-up current	IPURB	50	250	400	μΑ	VDD = 5V, VPIN = VSS				
	Input Leakage Current (Notes 2, 3)										
D060	I/O ports	lı∟	-	-	±1	μA	Vss \leq VPIN \leq VDD, Pin at hi- impedance				
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \le VPIN \le VDD$				
D063	OSC1		-	-	±5	μA	Vss \leq VPIN \leq VDD, XT, HS, and LP osc configuration				
	Output Low Voltage										
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C				
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C				
	Output High Voltage										
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°С to +85°С				
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°С to +85°С				
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin				

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

	Applicabl	e Device	s 61 62	62A F	R62 63 F	863 64	64A R64 65 65A R65 66 67	
	Standard Operating Conditions (unless otherwise stated)							
		Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for industrial and						
DC CHA	ARACTERISTICS	$0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial						
		Operating voltage VDD range as described in DC spec Section 19.1 and						
		Section	19.2					
Param	Characteristic	Sym	Min	Тур	Max	Units	Conditions	
No.				†				
	Capacitive Loading Specs on							
	Output Pins							
D100	OSC2 pin	Cosc ₂	-	-	15	pF	In XT, HS and LP modes when	
							external clock is used to drive	
1							OSC1.	
D101	All I/O pins and OSC2 (in RC mode)	Cio	-	-	50	pF		
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF		

These parameters are characterized but not tested.

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only t and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

 Applicable Devices
 61
 62
 62A
 R62
 63
 R63
 64
 AAA
 ABA
 ABA

19.4 **Timing Parameter Symbology**

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS		3. Tcc:st	(I ² C specifications only)					
2. TppS		4. Ts	(I ² C specifications only)					
т								
F	Frequency	т	Time					
Lowerca	ase letters (pp) and their meanings:							
рр								
сс	CCP1	osc	OSC1					
ck	CLKOUT	rd	RD					
CS	CS	rw	RD or WR					
di	SDI	SC	SCK					
do	SDO	SS	SS					
dt	Data in	tO	ТОСКІ					
io	I/O port	t1	T1CKI					
mc	MCLR	wr	WR					
Upperca	ase letters and their meanings:							
S								
F	Fall	Р	Period					
Н	High	R	Rise					
I	Invalid (Hi-impedance)	V	Valid					
L	Low	Z	Hi-impedance					
I ² C only								
AA	output access	High	High					
BUF	Bus free	Low	Low					
Tcc:st	(I ² C specifications only)							
CC								
HD	Hold	SU	Setup					
ST								
DAT	DATA input hold	STO	STOP condition					
STA	START condition							
FIGURE 19-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS								
	Load condition 1		Load condition 2					
	VDD/2							
	\ge RL	P						

CL

CL = 50 pF

Vss

Pin

* Vss $RL = 464\Omega$

> for all pins except OSC2/CLKOUT but including D and E outputs as ports 15 pF for OSC2 output

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19.5 <u>Timing Diagrams and Specifications</u>

FIGURE 19-2: EXTERNAL CLOCK TIMING

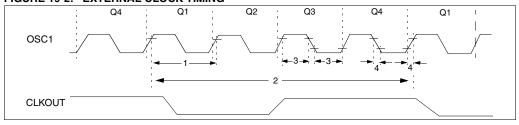


TABLE 19-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC	_	4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	_	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	—	_	ns	XT and RC osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	_	_	μS	LP osc mode
		Oscillator Period	250	_	_	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	_	250	ns	HS osc mode (-04)
			100	_	250	ns	HS osc mode (-10)
			50	_	250	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	200	TCY	DC	ns	Tcy = 4/Fosc
3	TosL,	External Clock in (OSC1) High or	50	_	—	ns	XT oscillator
	TosH	Low Time	2.5	_	—	μs	LP oscillator
			15	_	—	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise or	_	_	25	ns	XT oscillator
	TosF	Fall Time	—	_	50	ns	LP oscillator
			_	_	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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FIGURE 19-3: CLKOUT AND I/O TIMING

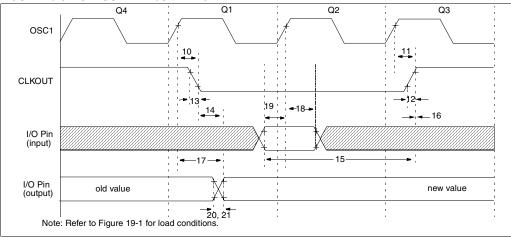


TABLE 19-3: CLROUT AND I/O TIMING REQUIREMENTS	TABLE 19-3:	CLKOUT AND I/O TIMING REQUIREMENTS
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Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
10*	TosH2ckL	OSC1 [↑] to CLKOUT↓		—	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		_	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		_	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		_	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		_		0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	rt in valid before CLKOUT 1 0.			_	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑	rt in hold after CLKOUT ↑			_	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		_	50	150	ns	
18*	TosH2iol		PIC16 C 65	100		_	ns	
		input invalid (I/O in hold time)	PIC16 LC 65	200		_	ns ns ns ns ns ns ns ns	
19*	TioV2osH	Port input valid to OSC1 [↑] (I/O	in setup time)	0		_	ns	
20*	TioR	Port output rise time	PIC16 C 65	_	10	25	ns	
			PIC16 LC 65	_		60	ns	
21*	TioF	Port output fall time	PIC16 C 65	—	10	25	ns	
			PIC16 LC 65	_		60	ns	
22††*	Tinp	RB0/INT pin high or low time	1	Тсү	-	_	ns	
23††*	Trbp	RB7:RB4 change int high or lo	w time	Тсү	-	_	ns	

These parameters are characterized but not tested.

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

These parameters are asynchronous events not related to any internal clock edge.
 Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

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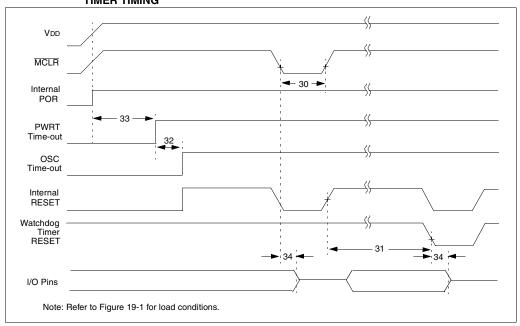


TABLE 19-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30*	TmcL	MCLR Pulse Width (low)	100	—		ns	VDD = 5V, -40°C to +85°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)		18	33	ms	VDD = 5V, -40°C to +85°C
32	Tost	Oscillation Start-up Timer Period		1024Tosc		—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period or WDT reset	28	72	132	ms	VDD = 5V, -40°C to +85°C
34	Tioz	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low		—	100	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 19-5: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

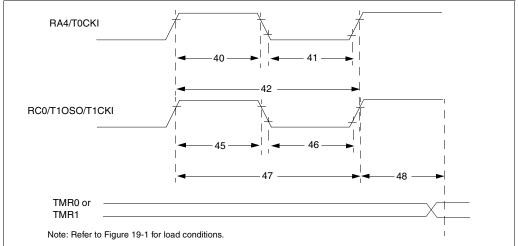


TABLE 19-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

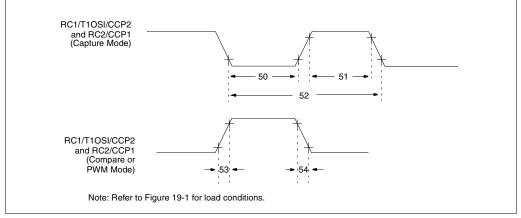
Param No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse V	Vidth	No Prescaler	0.5TCY + 20	-	—	ns	Must also meet
				With Prescaler	10	-	-	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse W	/idth	No Prescaler	0.5TCY + 20	_	—	ns	Must also meet
				With Prescaler	10		-	ns	parameter 42
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
		, v		With Prescaler	Greater of: 20 or <u>Tcy + 40</u> N	-	-	ns	N = prescale value (2, 4,, 256)
45*	Tt1H	T1CKI High Time	Synchronous, P	Prescaler = 1	0.5TCY + 20	_	_	ns	Must also meet
		-	Synchronous,	PIC16 C 6X	15	-	—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	—	ns	
			Asynchronous	PIC16 C 6X	30		-	ns	
				PIC16 LC 6X	50	_	—	ns	Ī
46*	Tt1L	T1CKI Low Time Synchronous, Pr			0.5TCY + 20	—		ns	Must also meet
			Synchronous,	PIC16 C 6X	15		-	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	_	ns	
			Asynchronous	PIC16 C 6X	30	-	—	ns	
				PIC16 LC 6X	50		-	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16 C 6X	<u>Greater of:</u> 30 OR <u>TCY + 40</u> N	_	_	ns	N = prescale value (1, 2, 4, 8)
				PIC16 LC 6X	<u>Greater of:</u> 50 OR <u>TCY + 40</u> N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16 C 6X	60	—	_	ns	
				PIC16 LC 6X	100	—	—	ns	
	Ft1	Timer1 oscillator inp (oscillator enabled b			DC	—	200	kHz	
48	TCKEZtmr1	Delay from external	clock edge to tir	ner increment	2Tosc	- 1	7Tosc	-	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 19-6: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)



Parameter No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2	No Prescaler		0.5Tcy + 20	_	_	ns	
		input low time	With Prescaler	PIC16 C 65	10	_		ns	
				PIC16 LC 65	20	—		ns	
51*	51* TccH CCP1 and 0		No Prescaler		0.5Tcy + 20	_		ns	
		input high time	With Prescaler	PIC16 C 65	10	_		ns	
				PIC16 LC 65	20	_		ns	
52*	TccP	CCP1 and CCP2 in	nput period		<u>3Tcy + 40</u> N	—	I		N = prescale value (1,4, or 16)
53	TccR	CCP1 and CCP2 c	output rise time	PIC16 C 65	—	10	25	ns	
				PIC16 LC 65		25	45	ns	
54	TccF	CCP1 and CCP2 output fall time		PIC16 C 65	—	10	25	ns	
				PIC16 LC 65	—	25	45	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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FIGURE 19-7: PARALLEL SLAVE PORT TIMING

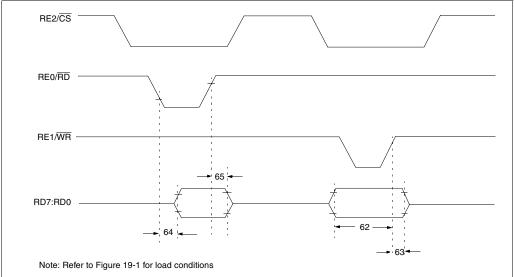
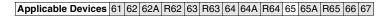


TABLE 19-7: PARALLEL SLAVE PORT REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} (setup time)			_	_	ns	
63*	TwrH2dtl	\overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} to data–in invalid (hold	PIC16 C 65	20		_	ns	
		me)	PIC16 LC 65	35		_	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid		—		80	ns	
65	TrdH2dtl	$\overline{RD}\uparrow$ or $\overline{CS}\uparrow$ to data–out invalid	\overline{RD}^{\uparrow} or \overline{CS}^{\uparrow} to data-out invalid		_	30	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.



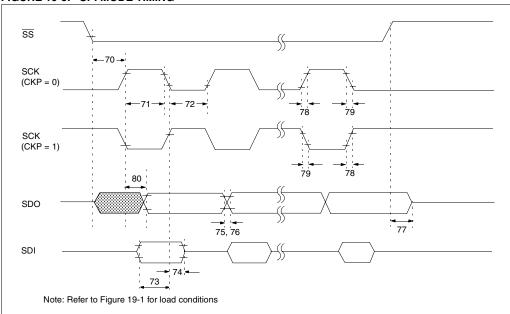


FIGURE 19-8: SPI MODE TIMING

TABLE 19-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
70	TssL2scH, TssL2scL	\overline{SS} ↓ to SCK↓ or SCK↑ input	Тсү	—	_	ns	
71	TscH	SCK input high time (slave mode)	TCY + 20	_	_	ns	
72	TscL SCK input low time (slave mode)		TCY + 20	_	—	ns	
73			50	—	—	ns	
74	74 TscH2diL, Hold time of SDI da TscL2diL edge		50	_	_	ns	
75	TdoR	SDO data output rise time	_	10	25	ns	
76	TdoF	SDO data output fall time	_	10	25	ns	
77	TssH2doZ	$\overline{\mathrm{SS}}^{\uparrow}$ to SDO output hi-impedance	10	_	50	ns	
78	TscR	SCK output rise time (master mode)	_	10	25	ns	
79	TscF	SCK output fall time (master mode)	_	10	25	ns	
80	80 TscH2doV, SDO data output valid after SCK TscL2doV edge		_	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 19-9: I²C BUS START/STOP BITS TIMING

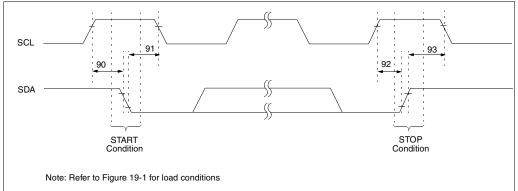


TABLE 19-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур	Max	Units	Conditions			
90	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START			
		Setup time	400 kHz mode	600	—	_	110	condition			
91	THD:STA	START condition	100 kHz mode	4000	—	_	ns	After this period the first clock			
		Hold time	400 kHz mode	600	—	_	115	pulse is generated			
92	TSU:STO	STOP condition	100 kHz mode	4700	—	—	ns				
		Setup time	400 kHz mode	600	—	—	113				
93	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns				
		Hold time	400 kHz mode	600	—	—	115				

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FIGURE 19-10: I²C BUS DATA TIMING

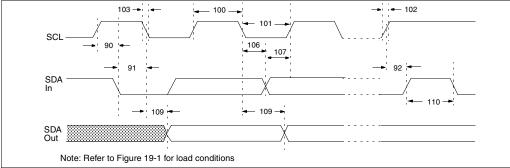


TABLE 19-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100	Тнідн	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Devce must operate at a mini- mum of 10 MHz
			SSP Module	1.5Tcy	—		
101	TLOW	Clock low time	100 kHz mode	4.7	-	μS	Device must operate at a mini mum of 1.5 MHz
			400 kHz mode	1.3	_	μs	Device must operate at a mini mum of 10 MHz
			SSP Module	1.5Tcy	_		
102	TR	SDA and SCL rise	100 kHz mode	—	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90	TSU:STA	START condition	100 kHz mode	4.7	_	μs	Only relevant for repeated
		setup time	400 kHz mode	0.6	—	μs	START condition
91	THD:STA	START condition hold	100 kHz mode	4.0		μs	After this period the first clock
		time	400 kHz mode	0.6		μs	pulse is generated
106	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92	Tsu:sto	STOP condition setup	100 kHz mode	4.7	—	μs	
		time	400 kHz mode	0.6		μs	
109	ΤΑΑ	Output valid from	100 kHz mode	—	3500	ns	Note 1
		clock	400 kHz mode	—	—	ns	
110	TBUF	Bus free time	100 kHz mode	4.7		μs	Time the bus must be free
			400 kHz mode	1.3	—	μs	before a new transmission car start
	Cb	Bus capacitive loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement tsu;DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

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FIGURE 19-11: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

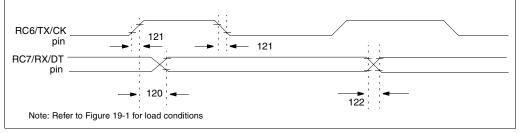


TABLE 19-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
No.								
120			PIC16 C 65	_	—	80	ns	
		Clock high to data out valid	PIC16 LC 65		—	100	ns	
121	121 Tckrf		PIC16 C 65	_	—	45	ns	
		(Master Mode)	PIC16 LC 65		—	50	ns ns	
122	Tdtrf	Data out rise time and fall time	PIC16 C 65		—	45	ns	
			PIC16 LC 65		—	50	ns	

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 19-12: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

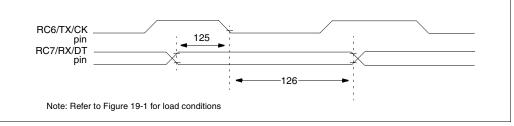


TABLE 19-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE)					
		Data setup before CK \downarrow (DT setup time)	15		—	ns	
126	TckL2dtl	Data hold after CK \downarrow (DT hold time)	15	—	-	ns	

t: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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20.0 ELECTRICAL CHARACTERISTICS FOR PIC16C63/65A

Absolute Maximum Ratings ^(†)	
Ambient temperature under bias	55°C to +125°C
Storage temperature	65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, MCLR, and RA4)	0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	
Voltage on RA4 with respect to Vss	0V to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of Vss pin	300 mA
Maximum current into VDD pin	250 mA
Input clamp current, Iικ (VI < 0 or VI > VDD)	±20 mA
Output clamp current, Iok (VO < 0 or VO > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (Note 3) (combined)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (Note 3) (combined)	200 mA
Maximum current sunk by PORTC and PORTD (Note 3) (combined)	200 mA
Maximum current sourced by PORTC and PORTD (Note 3) (combined)	200 mA
Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - \sum IOH} + \sum {(VDD-	VOH) x IOH} + Σ (VOI x IOL)

Note 1: Power dissipation is calculated as follows. Pdis = VDD X (IDD * 2 for f + 2 (VDD VOR) X IOF + 2(VDD VOR)

Note 3: PORTD and PORTE not available on the PIC16C63.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 20-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C63-04 PIC16C65A-04	PIC16C63-10 PIC16C65A-10	PIC16C63-20 PIC16C65A-20	PIC16LC63-04 PIC16LC65A-04	JW Devices	
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	
ХТ	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V	VDD: 4.5V to 5.5V IDD: 10 mA max. at 5.5V	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V	
		IPD 1.5 μA typ. at 4.5V	IPD: 1.5 μA typ. at 4.5V	use in HS mode	IPD: 1.5 μA typ. at 4.5V	
LP	Freq: 4 MHz max. VDD: 4.0V to 6.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Freq: 10 MHz max. Not recommended for use in LP mode	Freq: 20 MHz max. Not recommended for use in LP mode	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	Freq: 20 MHz max. VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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20.1 DC Characteristics: PIC16C63/65A-04 (Commercial, Industrial, Extended) PIC16C63/65A-10 (Commercial, Industrial, Extended) PIC16C63/65A-20 (Commercial, Industrial, Extended)

DC CH/		Standaı Operatir	unless otherwise stated) $\leq TA \leq +125^{\circ}C$ for extended, $\leq TA \leq +85^{\circ}C$ for industrial and $\leq TA \leq +70^{\circ}C$ for commercial				
Param No.	Characteristic	Sym	Min	Тур†	Мах	Units	Conditions
D001 D001A	Supply Voltage	Vdd	4.0 4.5		6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
			3.7	4.0	4.4	V	Extended Range Only
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5	mA	XT, RC, osc config Fosc = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	mA	HS osc config Fosc = 20 MHz, VDD = 5.5V
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current	IPD	-	10.5	42	μA	VDD = 4.0V, WDT enabled,-40°C to +85°C
D021	(Note 3, 5)		-	1.5	16	μA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A D021B			-	1.5 2.5	19 19	μ Α μ Α	VDD = 4.0V, WDT disabled,-40°C to +85°C VDD = 4.0V, WDT disabled,-40°C to +125°C
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

- 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
 - The test conditions for all IDD measurements in active operation mode are:
 - OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,
 - MCLR = VDD; WDT enabled/disabled as specified.
- 3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSs.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.
- 6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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20.2 DC Characteristics: PIC16LC63/65A-04 (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated)												
DC CHA	RACTERISTICS	Operatir	ng temp	perature			$TA \leq +85^{\circ}C$ for industrial and					
	1		i		0°C	; ≤	TA \leq +70°C for commercial					
Param No.	Characteristic	Sym	Min	Тур†	Мах	Units	Conditions					
D001	Supply Voltage	Vdd	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)					
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V						
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details					
D004*	VDD rise rate to ensure internal Power-on Reset signal	Svdd	0.05	-	-	V/ms	See section on Power-on Reset for details					
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	V	BODEN configuration bit is enabled					
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)					
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled					
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V					
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C					
D021	(Note 3, 5)		-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C					
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C					
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V					

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

 $\underline{OSC1} = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,$

 $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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20.3 DC Characteristics: PIC16C63/65A-04 (Commercial, Industrial, Extended) PIC16C63/65A-10 (Commercial, Industrial, Extended) PIC16C63/65A-20 (Commercial, Industrial, Extended) PIC16LC63/65A-04 (Commercial, Industrial)

							ss otherwise stated)
		Operatir	ng temper	ature	-40°C		$A \le +125^{\circ}C$ for extended, A $\le +85^{\circ}C$ for industrial and
DC CHA	RACTERISTICS				-40 C 0°C		$A \le +80^{\circ}$ C for industrial and $A \le +70^{\circ}$ C for commercial
		Oneratir	na voltane	Voo			ed in DC spec Section 20.1 and
		Section		100	runge us (
Param	Characteristic	Sym	Min	Тур	Мах	Units	Conditions
No.		- /		ť			
	Input Low Voltage						
	I/O ports	Vi∟					
D030	with TTL buffer		Vss	-	0.15VDD	V	For entire VDD range
D030A			Vss	-	0.8V	V	$4.5V \leq V \text{DD} \leq 5.5V$
D031	with Schmitt Trigger buffer		Vss	-	0.2Vdd	V	
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2Vdd	V	
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3Vdd	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \le VDD \le 5.5V$
D040A			0.25VDD	-	Vdd	V	For entire VDD range
			+ 0.8V				
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd	v	For entire VDD range
D042	MCLR		0.8VDD	-	VDD	V	_
D042A	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1
D043	OSC1 (in RC mode)		0.9Vdd	-	Vdd	V	
D070	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	lı∟	-	-	±1	μA	$Vss \le VPIN \le VDD$, Pin at hi-
							impedance
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \leq V PIN \leq V DD$
D063	OSC1		-	-	± 5	μA	$Vss \leq VPIN \leq VDD, XT, HS and$
							LP osc configuration
	Output Low Voltage						
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5 V,
D 0000						.,	-40°C to +85°C
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5 V,
Daga							-40°C to +125°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5 V,
					0.0		-40°C to +85°C
D083A			-	-	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C
			L				-40 0 10 +125 0

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

	Applicable	Device	s 61 62 6	2A F	R62 63 R	63 64	64A R64 65 65A R65 66 67				
-		0				- ()-					
		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended,									
		Operation	ig tempera	ature	-40 (-40°($A \le +125$ C for extended, $A \le +85^{\circ}$ C for industrial and				
DC CHA	RACTERISTICS		$0^{\circ}C$ < TA < +70^{\circ}C for commercial								
		Operatin Section		Vdd			ed in DC spec Section 20.1 and				
Param No.	Characteristic	Sym	Min	Тур †	Max	Units	Conditions				
	Output High Voltage										
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C				
D090A			VDD-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C				
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°С to +85°С				
D092A			VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, -40°С to +125°С				
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin				
	Capacitive Loading Specs on Out- put Pins										
D100	OSC2 pin	Cosc2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.				
D101	All I/O pins and OSC2 (in RC mode)	Сю	-	-	50	pF					
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF					

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

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20.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

1. TppS2p	pS		3. Tcc:st	(I ² C specifications only)
2. TppS			4. Ts	(I ² C specifications only)
т				
F	Frequency		т	Time
Lowerca	ase letters (pp) and their me	anings:		
рр				
CC	CCP1		osc	OSC1
ck	CLKOUT		rd	RD
CS	CS		rw	RD or WR
di	SDI		sc	SCK
do	SDO		SS	SS
dt	Data in		tO	TOCKI
io	I/O port		t1	T1CKI
mc	MCLR		wr	WR
Upperca	ase letters and their meanin	gs:	II.	
S		-		
F	Fall		Р	Period
Н	High		R	Rise
I	Invalid (Hi-impedance)		V	Valid
L	Low		Z	Hi-impedance
I ² C only				
AA	output access		High	High
BUF	Bus free		Low	Low
TCC:ST ((I ² C specifications only)			
cc				
HD	Hold		SU	Setup
ST				
DAT	DATA input hold		STO	STOP condition
STA	START condition			
-IGURE 2	20-1: LOAD CONDITIO	NS FOR DEVIC	E TIMING S	SPECIFICATIONS
	Load condition	on 1		Load condition 2
		VDD/2		
		φ Q	ſ	\bigtriangledown
		\geq RL		Pin CL
		\geq		*
		-• -		Vss
	Pin		RL = 464Ω	
		•		
			CL = 50 pF	for all pins except OSC2/CLKOUT
Note 1:	PORTD and PORTE are n	ot imple-		but including D and E outputs as ports

Note 1: PORTD and PORTE are not implemented on the PIC16C63.



15 pF for OSC2 output

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20.5 <u>Timing Diagrams and Specifications</u>

FIGURE 20-2: EXTERNAL CLOCK TIMING

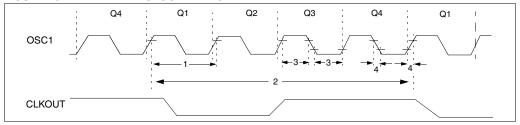


TABLE 20-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC	_	4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	—	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	_	_	ns	XT and RC osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period	250	—	—	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	200	Тсү	DC	ns	Tcy = 4/Fosc
3*	TosL,	External Clock in (OSC1) High or	100	_	_	ns	XT oscillator
	TosH	Low Time	2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR,	External Clock in (OSC1) Rise or	—	_	25	ns	XT oscillator
	TosF	Fall Time	—	—	50	ns	LP oscillator
			-	—	15	ns	HS oscillator

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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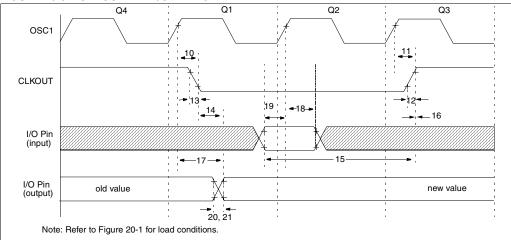


TABLE 20-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	_	75	200	ns	Note 1	
11*	TosH2ckH	OSC1↑ to CLKOUT↑	—	75	200	ns	Note 1	
12*	TckR	CLKOUT rise time	—	35	100	ns	Note 1	
13*	TckF	CLKOUT fall time	_	35	100	ns	Note 1	
14*	TckL2ioV	CLKOUT \downarrow to Port out valid	—	_	0.5TCY + 20	ns	Note 1	
15*	TioV2ckH	Port in valid before CLKOUT ↑	Tosc + 200		—	ns	Note 1	
16*	TckH2iol	Port in hold after CLKOUT 1	0	—	—	ns	Note 1	
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out val	lid	—	50	150	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port input	PIC16 C 63/65A	100	—	—	ns	
		invalid (I/O in hold time)	PIC16LC63/65A	200		—	ns	
19*	TioV2osH	Port input valid to OSC1 [↑] (I/O in	setup time)	0		_	ns	
20*	TioR	Port output rise time	PIC16 C 63/65A	—	10	40	ns	
			PIC16LC63/65A	_		80	ns	
21*	TioF	Port output fall time	PIC16 C 63/65A	—	10	40	ns	
			PIC16 LC 63/65A		_	80	ns	
22††*	Tinp	INT pin high or low time		Тсү	—	—	ns	
23††*	Trbp	RB7:RB4 change INT high or low	<i>i</i> time	Тсү	_	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

tt These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

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FIGURE 20-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP

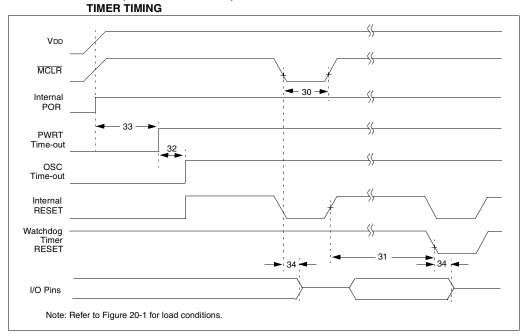






TABLE 20-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2	—		μs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	_	1024 Tosc		-	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	Tioz	I/O Hi-impedance from MCLR Low or WDT reset	—	_	2.1	μs	
35	TBOR	Brown-out Reset Pulse Width	100	—		μs	$VDD \le BVDD$ (D005)

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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FIGURE 20-6: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

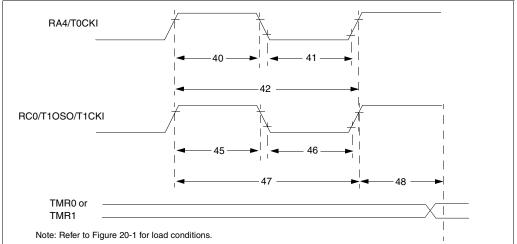


TABLE 20-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

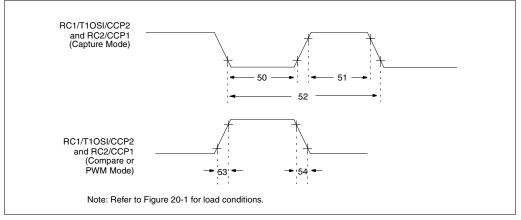
Param No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse V	Vidth	No Prescaler	0.5TCY + 20	-	—	ns	Must also meet
				With Prescaler	10	—	—	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse W	/idth	No Prescaler	0.5TCY + 20	—	_	ns	Must also meet
				With Prescaler	10		—	ns	parameter 42
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40		—	ns	
				With Prescaler	Greater of: 20 or <u>Tcy + 40</u> N	-	_	ns	N = prescale value (2, 4,, 256)
45*	Tt1H	T1CKI High Time	Synchronous, P	rescaler = 1	0.5TCY + 20	—	—	ns	Must also meet
	Synchrono Prescaler 2,4,8	Synchronous,	PIC16 C 6X	15	_	—	ns	parameter 47	
			PIC16 LC 6X	25	-	-	ns		
			Asynchronous	PIC16 C 6X	30	_	—	ns	
				PIC16 LC 6X	50		—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, P		0.5TCY + 20	—	—	ns	Must also meet
			Synchronous,	PIC16 C 6X	15		—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	-	ns	
			Asynchronous	PIC16 C 6X	30	—	—	ns	
				PIC16 LC 6X	50	—	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16 C 6X	<u>Greater of:</u> 30 OR <u>TCY + 40</u> N	-	_	ns	N = prescale value (1, 2, 4, 8)
				PIC16 LC 6X	<u>Greater of:</u> 50 OR <u>TCY + 40</u> N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16 C 6X	60	—	-	ns	
				PIC16 LC 6X	100	—	—	ns	
	Ft1	Timer1 oscillator inp (oscillator enabled b			DC	-	200	kHz	
48	TCKEZtmr1	Delay from external	clock edge to tin	ner increment	2Tosc	—	7Tosc	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 20-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)





Parameter No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
50*	50* TccL CCP1 and CCP2 No F		No Prescaler		0.5Tcy + 20	—	_	ns	
		input low time	With Prescaler	PIC16 C 63/65A	10	—	_	ns	
				PIC16LC63/65A	20	—	—	ns	
51*	TccH	CCP1 and CCP2	CP1 and CCP2 No Prescaler		0.5Tcy + 20	—	_	ns	
		input high time	With Prescaler	PIC16 C 63/65A	10	—	_	ns	
				PIC16 LC 63/65A	20	—	_	ns	
52*	TccP	CCP1 and CCP2 in	nput period		<u>3Tcy + 40</u> N	—	—	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 and CCP2 c	output rise time	PIC16 C 63/65A	_	10	25	ns	
				PIC16 LC 63/65A	_	25	45	ns	
54*	TccF	CCP1 and CCP2 c	output fall time	PIC16 C 63/65A	—	10	25	ns	
				PIC16LC63/65A	-	25	45	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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FIGURE 20-8: PARALLEL SLAVE PORT TIMING (PIC16C65A)

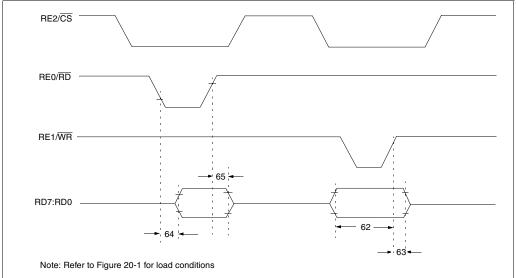


TABLE 20-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C65A)

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions	
62*	TdtV2wrH	Data in valid before $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ (setup time)		20	_	—	ns	
					_	-	ns	Extended Range Only
63*	TwrH2dtl	\overline{WR} or \overline{CS} to data–in invalid (hold	PIC16 C 65A	20	—	—	ns	
		time)	PIC16 LC 65A	35	_	—	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid		—	_	80	ns	
				-	_	90	ns	Extended Range Only
65*	TrdH2dtl	\overline{RD}^{\uparrow} or \overline{CS}^{\uparrow} to data–out invalid		10	—	30	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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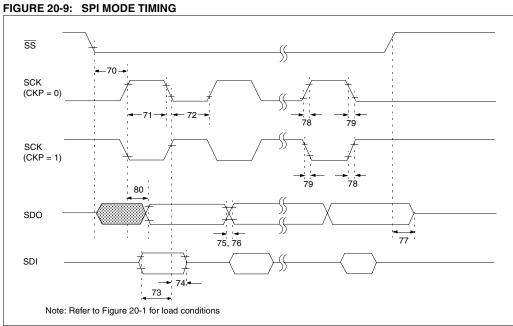


TABLE 20-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK \downarrow or SCK \uparrow input	Тсү	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	_	_	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	_	_	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	_	ns	
75*	TdoR	SDO data output rise time	_	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{\mathrm{SS}}$ to SDO output hi-impedance	10	_	50	ns	
78*	TscR	SCK output rise time (master mode)	_	10	25	ns	
79*	TscF	SCK output fall time (master mode)	_	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	_	_	50	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 20-10: I²C BUS START/STOP BITS TIMING

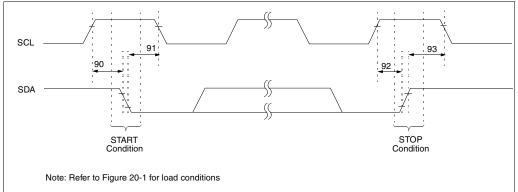


TABLE 20-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур	Max	Units	Conditions	
90*	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START	
		Setup time	400 kHz mode	600	—	—	113	condition	
91*	THD:STA	START condition	100 kHz mode	4000	—	—	ns	After this period the first clock	
		Hold time	400 kHz mode	600	—	_	115	pulse is generated	
92*	Tsu:sto	STOP condition	100 kHz mode	4700	—	_	ns		
		Setup time	400 kHz mode	600	—	—	115		
93	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns		
		Hold time	400 kHz mode	600	—	—	115		

* These parameters are characterized but not tested.

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FIGURE 20-11: I²C BUS DATA TIMING

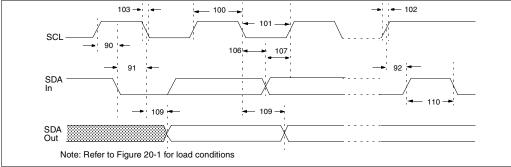


TABLE 20-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100*	Thigh	Clock high time	100 kHz mode	4.0	-	μS	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	_		
101*	TLOW	Clock low time	100 kHz mode	4.7	_	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	1.3	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	—		
102*	TR	SDA and SCL rise	100 kHz mode	—	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	_	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90*	TSU:STA	START condition	100 kHz mode	4.7	—	μS	Only relevant for repeated
		setup time	400 kHz mode	0.6	—	μs	START condition
91*	THD:STA	START condition hold	100 kHz mode	4.0	—	μS	After this period the first clock
		time	400 kHz mode	0.6	—	μS	pulse is generated
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μS	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92*	TSU:STO	STOP condition setup	100 kHz mode	4.7	—	μS	
		time	400 kHz mode	0.6	—	μS	
109*	ΤΑΑ	Output valid from	100 kHz mode	_	3500	ns	Note 1
		clock	400 kHz mode	_	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	-	μS	Time the bus must be free
			400 kHz mode	1.3	-	μs	before a new transmission can start
	Cb	Bus capacitive loading		_	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.
2: A fast-mode (400 kHz) l²C-bus device can be used in a standard-mode (100 kHz) l²C-bus system, but the requirement

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement Tsu:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

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FIGURE 20-12: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

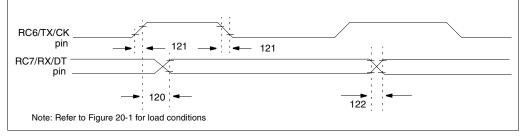


TABLE 20-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter No.	Sym	Characteristic	steristic				Units	Conditions
120*	* TckH2dtV <u>SYNC XMIT (MASTER & SLAVE)</u>		PIC16 C 63/65A	_	—	80	ns	
		Clock high to data out valid	PIC16 LC 63/65A	—	—	100	ns	
121*	Tckrf	Clock out rise time and fall time	PIC16 C 63/65A	_	—	45	ns	
		(Master Mode)	PIC16LC63/65A	—	—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16 C 63/65A	_	—	45	ns	
			PIC16LC63/65A	_	—	50	ns	

* These parameters are characterized but not tested.

+: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 20-13: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

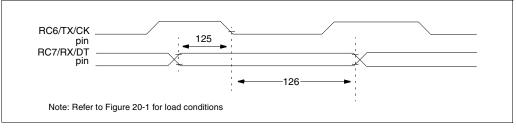


TABLE 20-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
125*	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK \downarrow (DT setup time)	15	_	_	ns	
126*	TckL2dtl	Data hold after CK \downarrow (DT hold time)	15	—	_	ns	

* These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested. Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

21.0 ELECTRICAL CHARACTERISTICS FOR PIC16CR63/R65

Absolute Maximum Ratings ^(†)	
Ambient temperature under bias	55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, MCLR, and RA4)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0V to +14V
Voltage on RA4 with respect to Vss	
Total power dissipation (Note 1)	1.0W
Maximum current out of Vss pin	
Maximum current into VDD pin	
Input clamp current, IIK (VI < 0 or VI > VDD)	
Output clamp current, Ioк (Vo < 0 or Vo > VDD)	±20 mA
Maximum output current sunk by any I/O pin	
Maximum output current sourced by any I/O pin Maximum current sunk by PORTA, PORTB, and PORTE (Note 3) (combined)	
Maximum current sourced by Forth X, Forth D, and Forth E (Note o) (combined).	200 11/1
Maximum current sunk by PORTC and PORTD (Note 3) (combined)	
Maximum current sourced by PORTC and PORTD (Note 3) (combined)	
	\ \

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {HDD - Σ [OH} + Σ {(VDD-VOH) x IOH} + Σ (VOI x IOL)

Note 2: Voltage spikes below Vss at the MCLR/VPP pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the MCLR/VPP pin rather than pulling this pin directly to Vss.

Note 3: PORTD and PORTE not available on the P(C16CR63).

† NOTICE: Stresses above those listed under "Absolute Maximum Patings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 21-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16CR63-04 PIC16CR65-04	PIC16CR63-10 PIC16CR65-10	PIC16CR63-20 PIC16CR65-20	PIC16LCR63-04 PIC16LCR65-04	JW Devices
RC	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IRD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 5.5V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.
ХТ	VDD: 4.0V to 5:5V IDD: 5 mA max. at 5.5V IPD: 16 JA max. at 4V Freq: 4 MHz max.	Vod: 4.5V to 5.5V Idd: 2.7 mA typ. at 5.5V Idd: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 5.5V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V	VDD: 4.5V to 5.5V IDD: 10 mA max. at 5.5V	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V
	IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	IPD 1.5 μA typ. at 4.5V Freq: 10 MHz max.	IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	use in no mode	IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 5.5V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 3.0V to 5.5V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 5.5V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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21.1 DC Characteristics: PIC16CR63/R65-04 (Commercial, Industrial) PIC16CR63/R65-10 (Commercial, Industrial) PIC16CR63/R65-20 (Commercial, Industrial)

		Standar	d Oper	rating	Condi	tions (ı	unless otherwise stated)
DC CHA	ARACTERISTICS	Operatir	ng temp	erature	e -40)°C ≤	\leq TA \leq +85°C for industrial and
					0°0	2 ≤	\leq TA \leq +70°C for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001 D001A	Supply Voltage	Vdd	4.0 4.5	-	5.5 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	V	BODEN contiguration bit is enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5	mA	XT, RC, osc config Fosc = 4 MHz, VDD = 5:5V (Note 4)
D013			-	10	20	mA	HS osc config Fosc = 20 MHz, VDD = 5.5V
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020 D021 D021A	Power-down Current (Note 3, 5)		-	10.5 1.5 1.5	42 16 19	μΑ μΑ μΑ	VDD = 4.0V, WDT enabled,-40°C to +85°C VDD = 4.0V, WDT disabled,-0°C to +70°C VDD = 4.0V, WDT disabled,-40°C to +85°C
D023*	Brown-out Reset Current (Note 6)		-	350	425	μA	BOR enabled, VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 50, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VoD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

 $MCLR \neq VDD$; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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21.2 DC Characteristics: PIC16LCR63/R65-04 (Commercial, Industrial)

		Standa	rd Ope	rating	Condi	tions (u	Inless otherwise stated)
DC CHA	RACTERISTICS	Operatir	ng temp	perature			$TA \le +85^{\circ}C$ for industrial and
					0°C	> ≤	$TA \le +70^{\circ}C$ for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage	Vdd	3.0	-	5.5	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	Svdd	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021	(Note 3, 5)		-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

 $\overline{MCLR} = VDD$; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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21.3 DC Characteristics: PIC16CR63/R65-04 (Commercial, Industrial) PIC16CR63/R65-10 (Commercial, Industrial) PIC16CR63/R65-20 (Commercial, Industrial) PIC16LCR63/R65-04 (Commercial, Industrial)

	RACTERISTICS		r d Operat ng temper			C` ≤ T	ss otherwise stated) $A \le +85^{\circ}C$ for industrial and $A \le +70^{\circ}C$ for commercial
2001		Operatin Section		Vdd			ed in DC spec Section 21.1 and
Param No.	Characteristic	Sym	Min	Тур †	Мах	Units	Conditions
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		Vss	-	0.15Vdd	V	For entire VDD range
D030A			Vss	-	0.8V	V	$4.5V \le VDD \le 5.5V$
D031	with Schmitt Trigger buffer		Vss	-	0.2Vdd	V	
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2Vdd	V	
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3Vdd	V	Note1
	Input High Voltage						
	I/O ports	Vін		-			
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \leq V \text{dd} \leq 5.5V$
D040A			0.25VDD	-	Vdd	V	For entire VDD range
			+ 0.8V				
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd	v	For entire VDD range
D042	MCLR		0.8VDD	-	Vdd	V	
D042A	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1
D043	OSC1 (in RC mode)		0.9Vdd	-	Vdd	V	
D070	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	lı∟	-	-	±1	μA	Vss \leq VPIN \leq VDD, Pin at hi- impedance
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \le VPIN \le VDD$
D063	OSC1		-	-	±5	μΑ	Vss \leq VPIN \leq VDD, XT, HS and LP osc configuration
	Output Low Voltage						LF OSC configuration
D080	I/O ports	Vol	-	-	0.6	v	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	v	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	v	IOH = -3.0 mA, VDD = 4.5V, -40°С to +85°С
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	v	IOH = -1.3 mA, VDD = 4.5V, -40°С to +85°С
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

	Applicable	Devices	61 62 6	62A F	R62 63 F	863 64	64A R64 65 65A R65 66 67				
		Standard Operating Conditions (unless otherwise stated)									
		Operating	g temper	ature	-40°	C ́≤T.	$A \le +85^{\circ}C$ for industrial and				
DC CHA	RACTERISTICS				0°C	≤ T.	\leq TA \leq +70°C for commercial				
		Operating voltage VDD range as described in DC spec Section 21.1 and									
		Section 2	1.2								
Param	Characteristic	Sym	Min	Тур	Max	Units	Conditions				
No.				†							
	Capacitive Loading Specs on Out- put Pins										
D100	OSC2 pin	Cosc2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.				
D101	All I/O pins and OSC2 (in RC mode)	Cio	-	-	50	pF					
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF					

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

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21.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

1. TppS2p	pS		3. Tcc:st	(I ² C specifications only)
2. TppS			4. Ts	(I ² C specifications only)
т				
F	Frequency		т	Time
Lowerca	se letters (pp) and their m	eanings:	1	
рр				
CC	CCP1		osc	OSC1
ck	CLKOUT		rd	RD
CS	CS		rw	RD or WR
di	SDI		sc	SCK
do	SDO		SS	SS
dt	Data in		tO	TOCKI
io	I/O port		t1	T1CKI
mc	MCLR		wr	WR
Upperca	se letters and their meani	ngs:		
S				
F	Fall		Р	Period
Н	High		R	Rise
I	Invalid (Hi-impedance)		V	Valid
L	Low		Z	Hi-impedance
I ² C only				
AA	output access		High	High
BUF	Bus free		Low	Low
Tcc:st (I ² C specifications only)			
CC				
HD	Hold		SU	Setup
ST				
DAT	DATA input hold		STO	STOP condition
STA	START condition			
FIGURE 2	1-1: LOAD CONDITIO	ONS FOR DEVI	CE TIMING S	PECIFICATIONS
	Load condit	on 1		Load condition 2
		VDD/2		
		φ	1	
		\geq RL		Pin CL
		\geq		★
		•		Vss
	Pin		$RL = 464\Omega$	
		•		
		•00	CL = 50 pF	for all pins except OSC2/CLKOUT but including D and E outputs as ports
Note 1:	PORTD and PORTE are		15 nE	
	mented on the PIC16CR	53.	15 pF	for OSC2 output

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21.5 <u>Timing Diagrams and Specifications</u>

FIGURE 21-2: EXTERNAL CLOCK TIMING

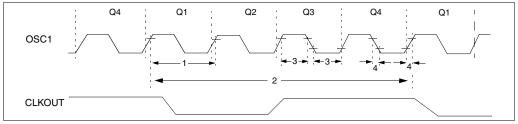


TABLE 21-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
	Fosc	External CLKIN Frequency	DC	_	4	MHz	XT and RC osc mode
		(Note 1)		—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency	DC	_	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	_	_	ns	XT and RC osc mode
		(Note 1)	250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period	250	—	—	ns	RC osc mode
		(Note 1)	250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μS	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	200	Тсү	DC	ns	Tcy = 4/Fosc
3*	TosL,	External Clock in (OSC1) High or	100	_	_	ns	XT oscillator
	TosH	Low Time	2.5	—	—	μs	LP oscillator
			15			ns	HS oscillator
4*	TosR,	External Clock in (OSC1) Rise or	—	—	25	ns	XT oscillator
	TosF	Fall Time	—	—	50	ns	LP oscillator
			-	—	15	ns	HS oscillator

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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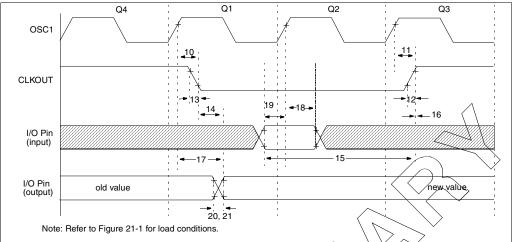


TABLE 21-3: CLKOUT AND I/O TIMING REQUIREMENTS

				\sim \setminus				
Param	Sym	Characteristic	<	/m/	Tỳpt	∨ Max	Units	Conditions
No.			$ \longrightarrow $		\checkmark			
10*	TosH2ckL	OSC1↑ to CLKOUT↓	<u>, ()</u>	$\langle \mathcal{F} \rangle$	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		$\backslash - \checkmark$	75	200	ns	Note 1
12*	TckR	CLKOUT rise time	$\sim 1 M / \sim$	\searrow	35	100	ns	Note 1
13*	TckF	CLKOUT fall time	$\langle \gamma \rangle $	-	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid	$\left(\left(\left(A \right) \right) \right)$	—	—	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT	$///\sim$	Tosc + 200	_	-	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT 1	\langle / \rangle	0		—	ns	Note 1
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out val	id 🔪	—	50	150	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port input	P1C16CR63/R65	100	—	_	ns	
		invalid (I/O in hold time)	PIC16LCR63/R65	200	—	_	ns	
19*	TioV2osH	Port input valid to OSC11 (I/Q in	setup time)	0	—	—	ns	
20*	TioR	Port output rise time	PIC16CR63/R65	—	10	40	ns	
		\frown	PIC16LCR63/R65	—	—	80	ns	
21*	TioF	Port output fall time	PIC16CR63/R65	—	10	40	ns	
		$\bigvee \land \searrow$	PIC16LCR63/R65	_	—	80	ns	
22††*	Tinp	INT pin high or low time	•	Тсү	—	_	ns	
23††*	Trbp	RB7:RB4 change INT high or low	time	Тсү	—	_	ns	

* These parameters are characterized but not tested.

† Data in "Txp" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

tt These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

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FIGURE 21-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

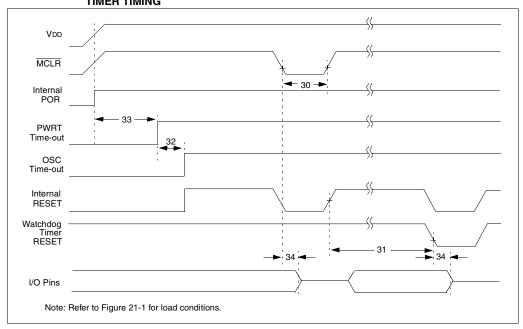






 TABLE 21-4:
 RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2	—		μs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	-	1024 Tosc		—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	Tioz	I/O Hi-impedance from MCLR Low or WDT reset	I	_	2.1	μs	
35	TBOR	Brown-out Reset Pulse Width	100	—		μs	V DD \leq BVDD (D005)

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 21-6: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

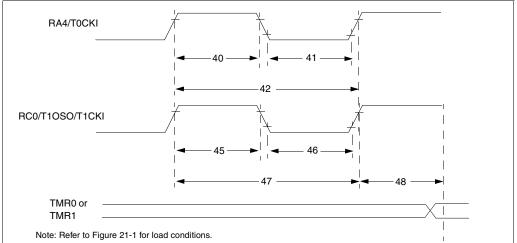


TABLE 21-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
40*	Tt0H	·····		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet
				With Prescaler	10	—	_	ns	parameter 42
41*	Tt0L	N		No Prescaler	0.5TCY + 20	-	-	ns	Must also meet
				With Prescaler	10	_		ns	parameter 42
42*	Tt0P			No Prescaler	TCY + 40	_	—	ns	
				With Prescaler	Greater of: 20 or <u>Tcy + 40</u> N	-	_	ns	N = prescale value (2, 4,, 256)
45*	Tt1H	T1CKI High Time	Synchronous, P	rescaler = 1	0.5TCY + 20	-	_	ns	Must also meet
		-	Synchronous,	PIC16 C 6X	15		—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	-	ns	
			Asynchronous	PIC16 C 6X	30		—	ns	
				PIC16 LC 6X	50	_	—	ns	-
46*	Tt1L	T1CKI Low Time	Synchronous, Prescaler = 1		0.5TCY + 20		—	ns	Must also meet
			Synchronous,	PIC16 C 6X	15	—	—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	-	ns	
			Asynchronous	PIC16 C 6X	30	-	—	ns	
				PIC16 LC 6X	50		—	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16 C 6X	<u>Greater of:</u> 30 OR <u>TCY + 40</u> N	_	_	ns	N = prescale value (1, 2, 4, 8)
				PIC16 LC 6X	<u>Greater of:</u> 50 OR <u>TCY + 40</u> N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16 C 6X	60	_	—	ns	
				PIC16 LC 6X	100	-	_	ns	
	Ft1		put frequency range by setting bit T1OSCEN)		DC	-	200	kHz	
48	TCKEZtmr1	Delay from external	clock edge to tin	ner increment	2Tosc	-	7Tosc	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 21-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)

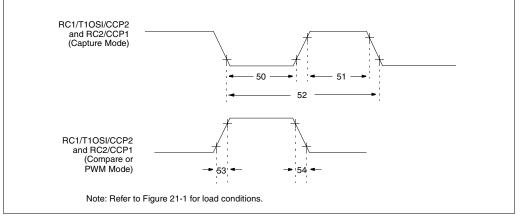


TABLE 21-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Param No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2	No Prescaler		0.5TCY + 20	—	_	ns	
		input low time	With Prescaler	PIC16CR63/R65	10	—	_	ns	
				PIC16LCR63/R65	20	—	_	ns	
51*	TccH	CCP1 and CCP2	No Prescaler		0.5Tcy + 20	—	_	ns	
		input high time	With Prescaler	PIC16CR63/R65	10	—	_	ns	
				PIC16LCR63/R65	20	_	_	ns	
52*	TccP	CCP1 and CCP2 in	nput period		<u>3Tcy + 40</u> N	—	_	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 and CCP2 c	utput rise time	PIC16CR63/R65	_	10	25	ns	
				PIC16LCR63/R65	_	25	45	ns	
54*	TccF	CCP1 and CCP2 c	utput fall time	PIC16CR63/R65	_	10	25	ns	
				PIC16LCR63/R65	_	25	45	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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FIGURE 21-8: PARALLEL SLAVE PORT TIMING (PIC16CR65)

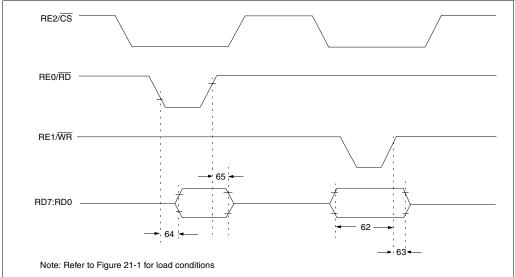


TABLE 21-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16CR65)

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions	
62*	TdtV2wrH	Data in valid before $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ (setu	in valid before \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} (setup time)				ns	
63*	TwrH2dtl	\overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} to data–in invalid (hold	\overline{R}^{\uparrow} or \overline{CS}^{\uparrow} to data-in invalid (hold PIC16 CR 65		_	—	ns	
		time)	PIC16LCR65	35	_	_	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid	$\overline{D}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid			80	ns	
65*	TrdH2dtl	\overline{RD}^{\uparrow} or \overline{CS}^{\uparrow} to data–out invalid		10	_	30	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

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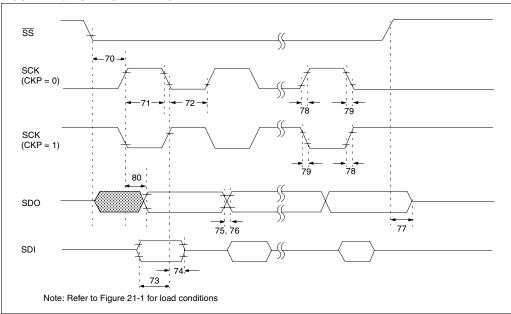


FIGURE 21-9: SPI MODE TIMING

TABLE 21-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{\text{SS}}\downarrow$ to SCK \downarrow or SCK \uparrow input	Тсү	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	_	_	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	_	ns	
75*	TdoR	SDO data output rise time		10	25	ns	
76*	TdoF	SDO data output fall time		10	25	ns	
77*	TssH2doZ	SS [↑] to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)		10	25	ns	
79*	TscF	SCK output fall time (master mode)		10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	_	_	50	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 21-10: I²C BUS START/STOP BITS TIMING

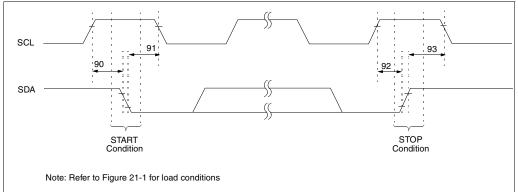


TABLE 21-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур	Max	Units	Conditions	
90*	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START	
		Setup time	400 kHz mode	600	—	—	113	condition	
91*	THD:STA	START condition	100 kHz mode	4000	—	—	ns	After this period the first clock	
		Hold time	400 kHz mode	600	—	_	115	pulse is generated	
92*	Tsu:sto	STOP condition	100 kHz mode	4700	—	_	ns		
		Setup time	400 kHz mode	600	—	—	115		
93	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns		
		Hold time	400 kHz mode	600	—	—	115		

* These parameters are characterized but not tested.

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FIGURE 21-11: I²C BUS DATA TIMING

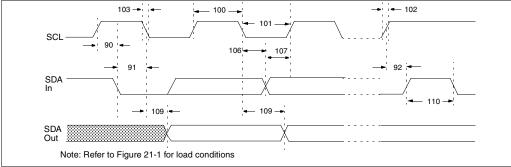


TABLE 21-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100*	Thigh	Clock high time	100 kHz mode	4.0	_	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	_		
101*	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	1.3	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	_		
102*	TR	SDA and SCL rise	100 kHz mode	_	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90*	TSU:STA	START condition	100 kHz mode	4.7	—	μS	Only relevant for repeated
		setup time	400 kHz mode	0.6		μS	START condition
91*	THD:STA	START condition hold	100 kHz mode	4.0		μS	After this period the first clock
		time	400 kHz mode	0.6	—	μS	pulse is generated
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μS	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92*	Tsu:sto	STOP condition setup	100 kHz mode	4.7	—	μS	
		time	400 kHz mode	0.6	—	μs	
109*	ΤΑΑ	Output valid from	100 kHz mode	—	3500	ns	Note 1
		clock	400 kHz mode	_	_	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free
			400 kHz mode	1.3		μs	before a new transmission can start
	Cb	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.
2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement Tsu:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

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FIGURE 21-12: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

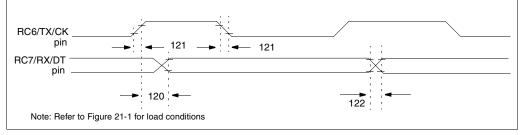


TABLE 21-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic	eristic				Units	Conditions
120*	TckH2dtV	SYNC XMIT (MASTER & SLAVE)	PIC16CR63/R65	—	—	80	ns	
		Clock high to data out valid	PIC16LCR63/R65	_	—	100	ns	
121*	121* Tckrf Clock out rise time and fall time		PIC16CR63/R65	_	—	45	ns	
		(Master Mode)	PIC16LCR63/R65	_	—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16CR63/R65	_	—	45	ns	
			PIC16LCR63/R65	—	—	50	ns	

* These parameters are characterized but not tested.

t: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 21-13: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

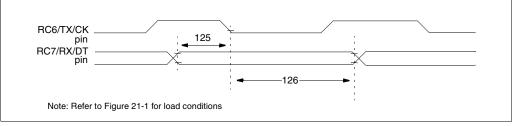


TABLE 21-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
125*	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK \downarrow (DT setup time)	15	_	_	ns	
126*	TckL2dtl	Data hold after CK \downarrow (DT hold time)	15	—	_	ns	

* These parameters are characterized but not tested.

+: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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22.0 ELECTRICAL CHARACTERISTICS FOR PIC16C66/67

Absolute Maximum Ratings ^(†)	
Ambient temperature under bias	55°C to +125°C
Storage temperature	65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, MCLR, and RA4)	
Voltage on VDD with respect to Vss	-0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0V to +14V
Voltage on RA4 with respect to Vss	0V to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of Vss pin	
Maximum current into VDD pin	250 mA
Input clamp current, Iik (VI < 0 or VI > VDD)	±20 mA
Output clamp current, Iok (Vo < 0 or Vo > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (Note 3) (combined)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (Note 3) (combined)	200 mA
Maximum current sunk by PORTC and PORTD (Note 3) (combined)	200 mA
Maximum current sourced by PORTC and PORTD (Note 3) (combined)	200 mA
Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - \sum IOH} + \sum {(VDD-VDD-VDD) + \sum IOH} + \sum {(VDD-VDD) + \sum IOH} + \sum {(VDD-VDD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum {(VD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VD-VD) + \sum IOH} + \sum {(VD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum {(VD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum IOH} + \sum {(VDD-VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD-VD) + \sum {(VD) + \sum {(VD-VD) + \sum {(VD) + \sum {(VD-VD) + \sum {(VD) + \sum {(VD) + \sum {(VD) + \sum {(VD) + \sum {(VD) + \sum {(V	VOH) x IOH} + Σ (VOI x IOL)

Note 1: Power dissipation is calculated as follows. Pdis = VDD X (IDD * 2 for f + 2 (VDD VOR) X IOF + 2(VDD VOR)

Note 3: PORTD and PORTE not available on the PIC16C66.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 22-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C66-04 PIC16C67-04	PIC16C66-10 PIC16C67-10	PIC16C66-20 PIC16C67-20	PIC16LC66-04 PIC16LC67-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.
ХТ	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V	.5V VDD: 4.5V to 5.5V VDD: 4.5V		Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V
	IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	IPD 1.5 μA typ. at 4.5V Freq: 10 MHz max.	IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	use in HS mode	IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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22.1 DC Characteristics: PIC16C66/67-04 (Commercial, Industrial, Extended) PIC16C66/67-10 (Commercial, Industrial, Extended) PIC16C66/67-20 (Commercial, Industrial, Extended)

DC CH		Standaı Operatir	•	•	e -40)°C ≤ ≥ 0°C	unless otherwise stated) $\leq TA \leq +125^{\circ}C$ for extended, $\leq TA \leq +85^{\circ}C$ for industrial and $\leq TA \leq +70^{\circ}C$ for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001 D001A	Supply Voltage	Vdd	4.0 4.5	-	6.0 5.5	> >	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	V	BODEN configuration bit is enabled
			3.7	4.0	4.4	V	Extended Range Only
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5	mA	XT, RC, osc config Fosc = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	mA	HS osc config Fosc = 20 MHz, VDD = 5.5V
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020 D021 D021A D021B	Power-down Current (Note 3, 5)	IPD	- - -	10.5 1.5 1.5 2.5	42 16 19 19	μΑ μΑ μΑ	VDD = 4.0V, WDT enabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -0°C to +70°C VDD = 4.0V, WDT disabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -40°C to +125°C
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

 $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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22.2 DC Characteristics: PIC16LC66/67-04 (Commercial, Industrial)

		Standa	rd Ope	rating	Condi	tions (u	Inless otherwise stated)
DC CHA	RACTERISTICS	Operatir	ng temp	perature			$TA \leq +85^{\circ}C$ for industrial and
	1				0°C		$TA \le +70^{\circ}C$ for commercial
Param No.	Characteristic	Sym	Min	Тур†	Мах	Units	Conditions
D001	Supply Voltage	Vdd	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	Svdd	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021	(Note 3, 5)		-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

 $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

22.3 DC Characteristics: PIC16C66/67-04 (Commercial, Industrial, Extended) PIC16C66/67-10 (Commercial, Industrial, Extended) PIC16C66/67-20 (Commercial, Industrial, Extended) PIC16LC66/67-04 (Commercial, Industrial)

		Standard Operating Conditions (unless otherwise stated)Operating temperature -40° C \leq TA \leq $+125^{\circ}$ C for extended, -40° C \leq TA \leq $+125^{\circ}$ C for extended,									
DC CHA	RACTERISTICS				-40°0		$A \le +85^{\circ}C$ for industrial and				
		.			0°C		$A \le +70^{\circ}C$ for commercial				
			ng voltage	VDC	range as	descrit	ped in DC spec Section 22.1				
Davam	Characteristic		Min	True	Мах	Units	Conditions				
Param No.	Characteristic	Sym	MIN	Тур †	wax	Units	Conditions				
	Input Low Voltage										
	I/O ports	VIL									
D030	with TTL buffer		Vss	-	0.15Vdd	V	For entire VDD range				
D030A			Vss	-	0.8V	V	$4.5V \leq V \text{DD} \leq 5.5V$				
D031	with Schmitt Trigger buffer		Vss	-	0.2Vdd	V					
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2VDD	V					
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	V	Note1				
	Input High Voltage										
	I/O ports	VIH		-							
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \le V_{DD} \le 5.5V$				
D040A			0.25VDD	-	Vdd	V	For entire VDD range				
			+ 0.8V								
D041	with Schmitt Trigger buffer		0.8Vdd	-	Vdd	v	For entire VDD range				
D042	MCLR		0.8VDD	-	Vdd	V					
D042A	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1				
D043	OSC1 (in RC mode)		0.9Vdd	-	Vdd	V					
D070	PORTB weak pull-up current	IPURB	50	250	400	μΑ	VDD = 5V, VPIN = VSS				
	Input Leakage Current (Notes 2, 3)										
D060	I/O ports	lı∟	-	-	±1	μA	$Vss \le VPIN \le VDD$, Pin at hi-impedance				
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \le VPIN \le VDD$				
D063	OSC1		-	-	±5	μA	Vss \leq VPIN \leq VDD, XT, HS and				
						•	LP osc configuration				
	Output Low Voltage						-				
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C				
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C				
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C				
D083A			-	-	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C				

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

	Applicable	Device	s 61 62	62A	R62 63 F	163 64	64A R64 65 65A R65 66 67
		Standa	rd Operat	ing (Condition	s (unle	ess otherwise stated)
			ng temper	•		•	TA \leq +125°C for extended,
	RACTERISTICS						$A \leq +85^{\circ}C$ for industrial and
00 0112					0°C		$A \leq +70^{\circ}C$ for commercial
			ng voltage tion 22.2	e Vdd	range as	descrit	ped in DC spec Section 22.1
Param	Characteristic	Sym	Min	Тур	Мах	Units	Conditions
No.		-		†			
	Output High Voltage						
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D090A			VDD-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D092A			VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, -40°С to +125°С
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin
	Capacitive Loading Specs on Out- put Pins						
D100	OSC2 pin	Cosc2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	Cio	-	-	50	pF	
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF	

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

22.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

• •			-	-
1. TppS2pp	pS		3. Tcc:st	(I ² C specifications only)
2. TppS			4. Ts	(I ² C specifications only)
т			-	
F	Frequency		т	Time
Lowerca	se letters (pp) and their	meanings:		
рр				
сс	CCP1		osc	OSC1
ck	CLKOUT		rd	RD
CS	CS		rw	RD or WR
di	SDI		SC	SCK
do	SDO		SS	SS
dt	Data in		tO	TOCKI
io	I/O port		t1	T1CKI
mc	MCLR		wr	WR
	se letters and their mea	inings:		
S				
F	Fall		Р	Period
Н	High		R	Rise
I	Invalid (Hi-impedanc	e)	V	Valid
L	Low		Z	Hi-impedance
I ² C only				
AA	output access		High	High
BUF	Bus free		Low	Low
TCC:ST (I ² C specifications only)			
СС				
HD	Hold		SU	Setup
ST				
DAT	DATA input hold		STO	STOP condition
STA	START condition			
FIGURE 2	2-1: LOAD CONDI	TIONS FOR DEV	ICE TIMING SE	PECIFICATIONS
	Load cond			Load condition 2
		N (2		
		VDD/2		
				Ζ
			P	
	<u> </u>	Ĵ	P	
	×	Ĵ	P	rin CL Vss
	Pin	Ĵ		
	Pin	RL	RL = 464Ω	
	Pin	RL	RL = 464Ω CL = 50 pF f	for all pins except OSC2/CLKOUT
Note 1:	PORTD and PORTE a	RL CL Vss	RL = 464Ω CL = 50 pF f	Vss

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

22.5 <u>Timing Diagrams and Specifications</u>

FIGURE 22-2: EXTERNAL CLOCK TIMING

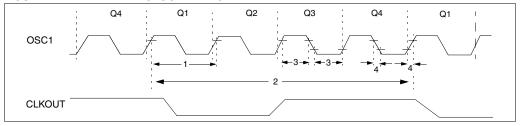


TABLE 22-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC	_	4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	—	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	_	_	ns	XT and RC osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period	250	—	—	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	TCY	Instruction Cycle Time (Note 1)	200	Тсү	DC	ns	Tcy = 4/Fosc
3*	TosL,	External Clock in (OSC1) High or	100	_	_	ns	XT oscillator
	TosH	Low Time	2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR,	External Clock in (OSC1) Rise or	—	_	25	ns	XT oscillator
	TosF	Fall Time	—	—	50	ns	LP oscillator
			-	—	15	ns	HS oscillator

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



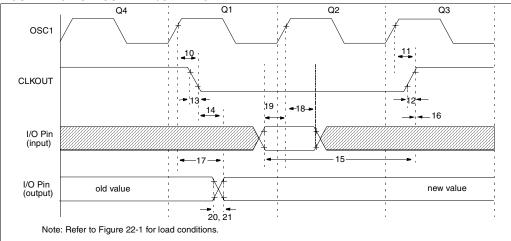


TABLE 22-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Мах	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		_	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	OSC1↑ to CLKOUT↑			200	ns	Note 1
12*	TckR	CLKOUT rise time		—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		—	_	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	Port in valid before CLKOUT ↑			—	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT 1	0	—	—	ns	Note 1	
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out va	lid	—	50	150	ns	
18*	TosH2iol	OSC1 [↑] (Q2 cycle) to Port input	PIC16 C 66/67	100	—	—	ns	
		invalid (I/O in hold time)	PIC16 LC 66/67	200	_	_	ns	
19*	TioV2osH	Port input valid to OSC1 [↑] (I/O in	setup time)	0	—	_	ns	
20*	TioR	Port output rise time	PIC16 C 66/67	—	10	40	ns	
			PIC16LC66/67	—	—	80	ns	
21*	TioF	Port output fall time	PIC16 C 66/67	—	10	40	ns	
			PIC16 LC 66/67		—	80	ns	
22††*	Tinp	INT pin high or low time	Тсү	—	—	ns		
23††*	Trbp	RB7:RB4 change INT high or low	Тсү	—	—	ns		

* These parameters are characterized but not tested.

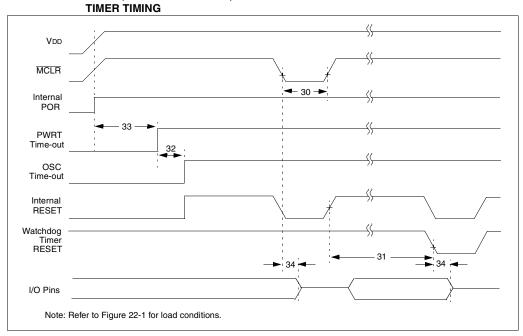
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

tt These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 22-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP







RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, TABLE 22-4: AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2	—		μs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period		1024 Tosc		_	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	Tioz	I/O Hi-impedance from MCLR Low or WDT reset		—	2.1	μs	
35	TBOR	Brown-out Reset Pulse Width	100	—	_	μs	$VDD \le BVDD$ (D005)

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 22-6: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

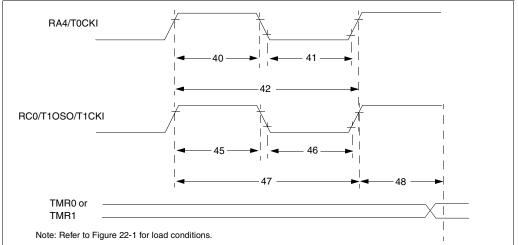


TABLE 22-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

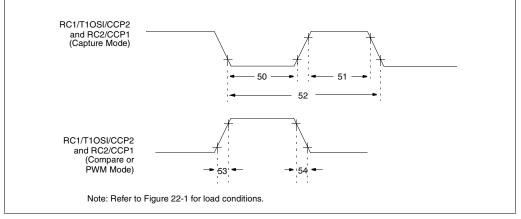
Param No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse V	Vidth	No Prescaler	0.5TCY + 20	-	—	ns	Must also meet
				With Prescaler	10	-	—	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse W	/idth	No Prescaler	0.5TCY + 20	-	-	ns	Must also meet
				With Prescaler	10	-	—	ns	parameter 42
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	-	ns	
				With Prescaler	Greater of:	—	—	ns	N = prescale value
					20 or <u>TCY + 40</u>				(2, 4,, 256)
45*	Tt1H	TAOKI Link Time	0		N 0.5Tcy + 20				Must also meet
45"	ITIH	T1CKI High Time	Synchronous, P	PIC16C6X	0.51CY + 20 15		_	ns	parameter 47
			Synchronous, Prescaler =	PIC16 C 6X	25	-	_	ns	
			2,4,8	PICIOLCOX	25	-	_	ns	
			Asynchronous	PIC16 C 6X	30	-	—	ns	
				PIC16 LC 6X	50	—	—	ns	Ī
46*	Tt1L	T1CKI Low Time	Synchronous, P		0.5TCY + 20	-	—	ns	Must also meet
			Synchronous,	PIC16 C 6X	15	—	—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	-	ns	
			Asynchronous	PIC16 C 6X	30	_	—	ns	
				PIC16 LC 6X	50	-	—	ns	Ī
47*	Tt1P	T1CKI input period	Synchronous	PIC16 C 6X	<u>Greater of:</u> 30 OR <u>TCY + 40</u> N	-	_	ns	N = prescale value (1, 2, 4, 8)
				PIC16 LC 6X	<u>Greater of:</u> 50 OR <u>TCY + 40</u> N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16 C 6X	60	—	_	ns	
				PIC16 LC 6X	100	_	-	ns	
	Ft1		nput frequency range I by setting bit T1OSCEN)		DC	-	200	kHz	
48	TCKEZtmr1	Delay from external	clock edge to tin	ner increment	2Tosc	-	7Tosc	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 22-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)





Parameter No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2	No Prescaler		0.5TCY + 20	—	_	ns	
		input low time	With Prescaler	PIC16 C 66/67	10	—	_	ns	
				PIC16 LC 66/67	20	—	—	ns	
51*	TccH	CCP1 and CCP2	No Prescaler		0.5TCY + 20	_	_	ns	
		input high time	With Prescaler	PIC16 C 66/67	10	—	_	ns	
				PIC16 LC 66/67	20	_	_	ns	
52*	TccP	CCP1 and CCP2 in	nput period		<u>3Tcy + 40</u> N	—	-	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 and CCP2 of	output rise time	PIC16 C 66/67	—	10	25	ns	
				PIC16 LC 66/67	_	25	45	ns	
54*	TccF	CCP1 and CCP2 of	output fall time	PIC16 C 66/67	_	10	25	ns	
			PI	PIC16LC66/67	—	25	45	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 22-8: PARALLEL SLAVE PORT TIMING (PIC16C67)

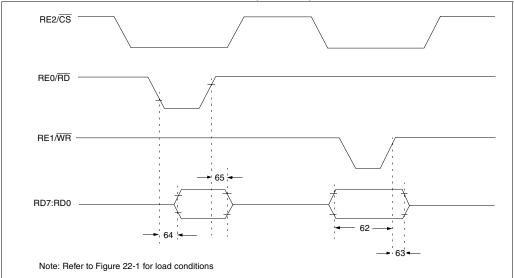


TABLE 22-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C67)

Parameter No.	Sym	Characteristic	Characteristic			Max	Units	Conditions
62*	TdtV2wrH	Data in valid before $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ (setup time)		20	_	—	ns	
				25	_	-	ns	Extended Range Only
63*	TwrH2dtl	$\overline{\text{WR}}$ for $\overline{\text{CS}}$ for data–in invalid (hold	PIC16 C 67	20	_	_	ns	
		time)	PIC16 LC 67	35	_	—	ns	
64	TrdL2dtV	$\overline{\text{RD}}\downarrow$ and $\overline{\text{CS}}\downarrow$ to data–out valid		-	_	80	ns	
					_	90	ns	Extended Range Only
65*	TrdH2dtl	\overline{RD}^{\uparrow} or \overline{CS}^{\uparrow} to data–out invalid			—	30	ns	

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

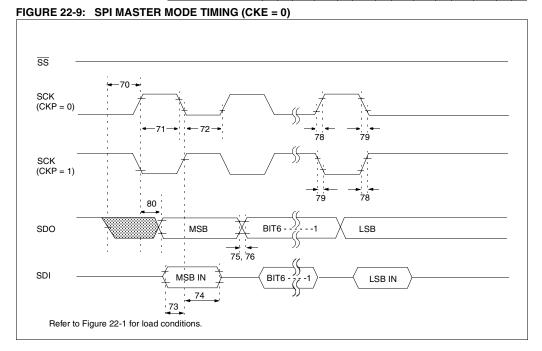
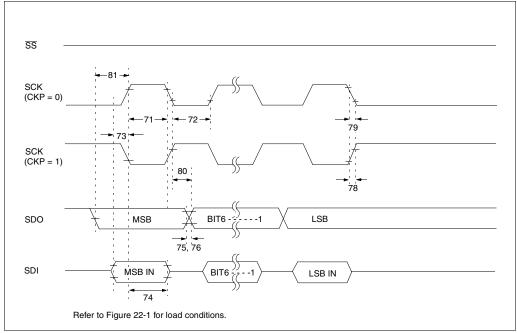


FIGURE 22-10: SPI MASTER MODE TIMING (CKE = 1)



 Applicable Devices
 61
 62
 62A
 R62
 63
 R63
 64
 64A
 R64
 65
 65A
 R65
 66
 67

FIGURE 22-11: SPI SLAVE MODE TIMING (CKE = 0)

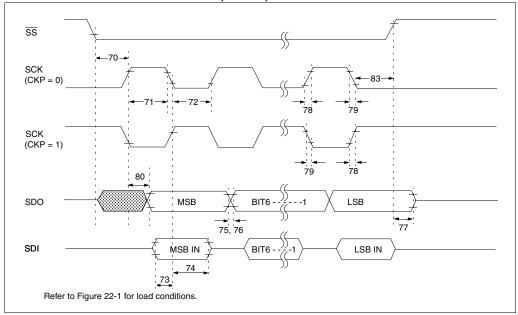
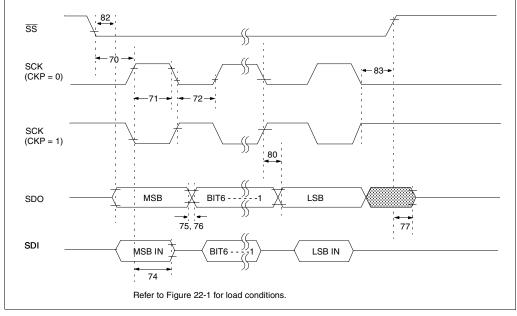


FIGURE 22-12: SPI SLAVE MODE TIMING (CKE = 1)



Annulla shita Davida sa	01	00	004	DOO	00	DOO	04	044	D04	05	054	DOF	00	07
Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

Parameter No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
70*	70* TssL2scH, SS↓ to SCK↓ or SCK↑ input TssL2scL		Тсү	—	_	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	_	-	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	_	_	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
75*	TdoR	SDO data output rise time	_	10	25	ns	
76*	TdoF	SDO data output fall time	_	10	25	ns	
77*	TssH2doZ	SS↑ to SDO output hi-impedance	10	_	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	_	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge	Тсү	_	_	ns	
82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge	—	_	50	ns	
83* TscH2ssH, SS ↑ after SCK edge TscL2ssH		1.5Tcy + 40	_	—	ns		

TABLE 22-8: SPI MODE REQUIREMENTS

*

These parameters are characterized but not tested. Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

 Applicable Devices
 61
 62
 62A
 R62
 63
 R63
 64
 64A
 R64
 65
 65A
 R65
 66
 67

FIGURE 22-13: I²C BUS START/STOP BITS TIMING

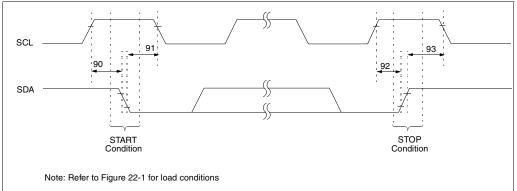


TABLE 22-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур	Max	Units	Conditions
90*	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START
		Setup time	400 kHz mode	600	—	_	110	condition
91*	THD:STA	START condition	100 kHz mode	4000	—	_	ns	After this period the first clock
		Hold time	400 kHz mode	600	—	_	115	pulse is generated
92*	TSU:STO	STOP condition	100 kHz mode	4700	—	_	ns	
		Setup time	400 kHz mode	600	—	—	115	
93	THD:STO	STOP condition	100 kHz mode	4000	—	_	ns	
		Hold time	400 kHz mode	600	—	—	115	

* These parameters are characterized but not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 22-14: I²C BUS DATA TIMING

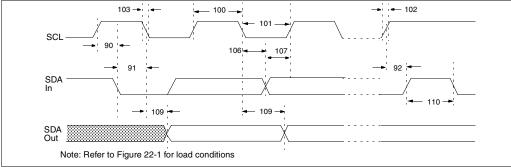


TABLE 22-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100*	Thigh	Clock high time	100 kHz mode	4.0	-	μS	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	_		
101*	TLOW	Clock low time	100 kHz mode	4.7	_	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	1.3	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5Tcy	—		
102*	TR	SDA and SCL rise	100 kHz mode	—	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	_	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90*	TSU:STA	START condition	100 kHz mode	4.7	_	μS	Only relevant for repeated
		setup time	400 kHz mode	0.6	_	μS	START condition
91*	THD:STA	START condition hold	100 kHz mode	4.0	—	μS	After this period the first clock
		time	400 kHz mode	0.6	—	μS	pulse is generated
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μS	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92*	Tsu:sto	STOP condition setup	100 kHz mode	4.7	—	μS	
		time	400 kHz mode	0.6	—	μs	
109*	ΤΑΑ	Output valid from	100 kHz mode	—	3500	ns	Note 1
		clock	400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	μS	Time the bus must be free
			400 kHz mode	1.3	_	μs	before a new transmission can start
	Cb	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.
2: A fast-mode (400 kHz) l²C-bus device can be used in a standard-mode (100 kHz) l²C-bus system, but the requirement

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement Tsu:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

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FIGURE 22-15: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

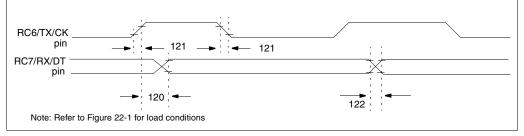


TABLE 22-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
120*	TckH2dtV	SYNC XMIT (MASTER & SLAVE)	PIC16 C 66/67	—	—	80	ns	
		Clock high to data out valid	PIC16 LC 66/67	—	—	100	ns	
121*	Tckrf	Clock out rise time and fall time	PIC16 C 66/67	_	—	45	ns	
		(Master Mode)	PIC16LC66/67	_	—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16 C 66/67	—	—	45	ns	
			PIC16LC66/67	—	—	50	ns	

* These parameters are characterized but not tested.

t: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 22-16: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

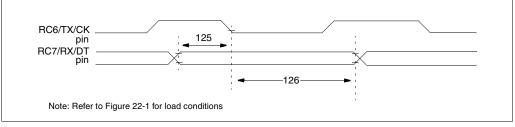


TABLE 22-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
125*	TdtV2ckL	$\frac{\text{SYNC RCV (MASTER \& SLAVE)}}{\text{Data setup before CK} \downarrow (\text{DT setup time})}$	15	_	_	ns	
126*	TckL2dtl	Data hold after CK \downarrow (DT hold time)	15	_	_	ns	

* These parameters are characterized but not tested.

+: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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23.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR: PIC16C62, PIC16C62A, PIC16CR62, PIC16C63, PIC16C64, PIC16C64A, PIC16CR64, PIC16C65A, PIC16C66, PIC16C67

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables the data presented are outside specified operating range (i.e., outside specified VDD range). This is for information only and devices are guaranteed to operate properly only within the specified range.

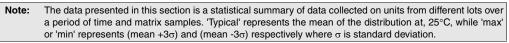
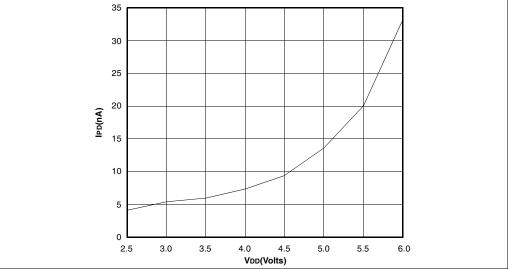
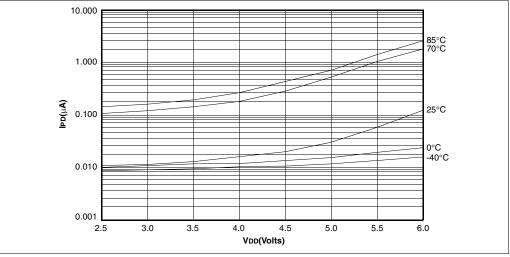


FIGURE 23-1: TYPICAL IPD vs. VDD (WDT DISABLED, RC MODE)



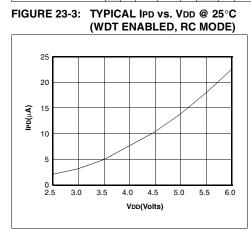




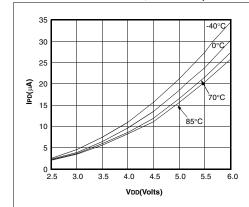
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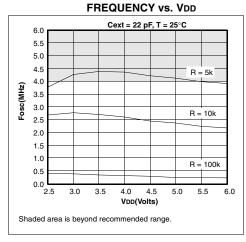


FIGURE 23-5: TYPICAL RC OSCILLATOR

FIGURE 23-6: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

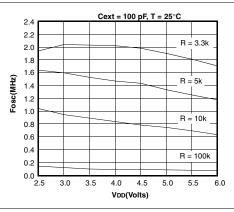
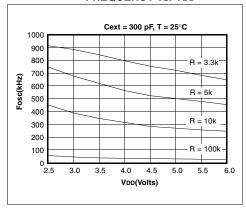


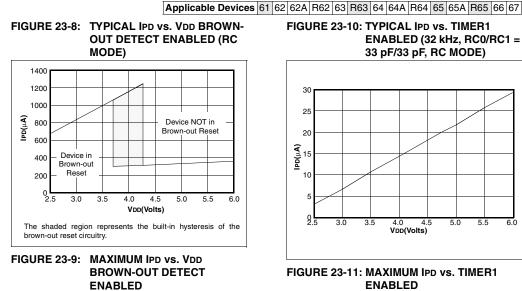
FIGURE 23-7: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD



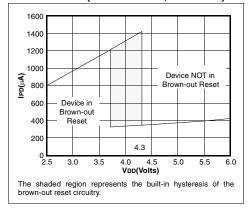
Data based on matrix samples. See first page of this section for details.

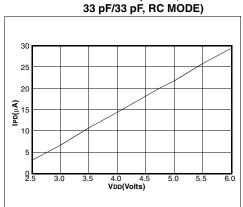
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ENABLED (32 kHz, RC0/RC1 =



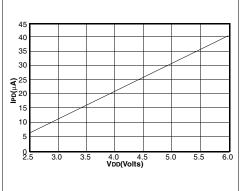
(85°C TO -40°C, RC MODE)







pF, 85°C TO -40°C, RC MODE)

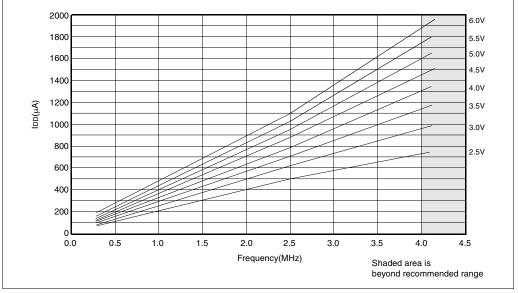


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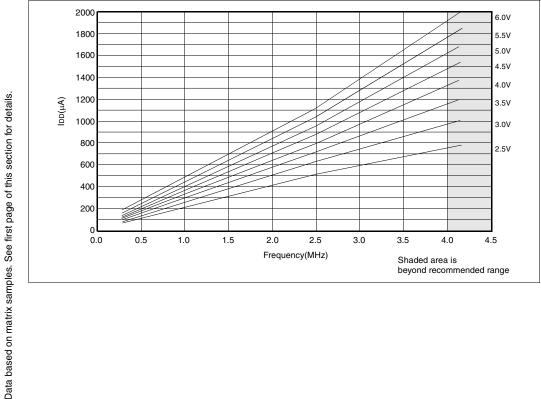
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Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 23-12: TYPICAL IDD vs. FREQUENCY (RC MODE @ 22 pF, 25°C)

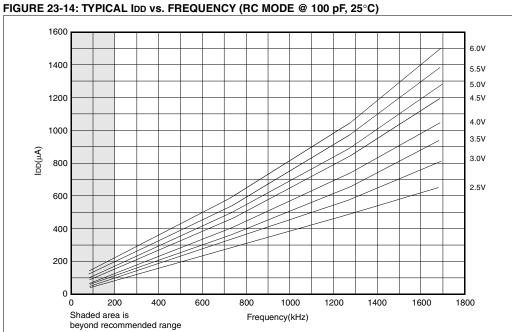


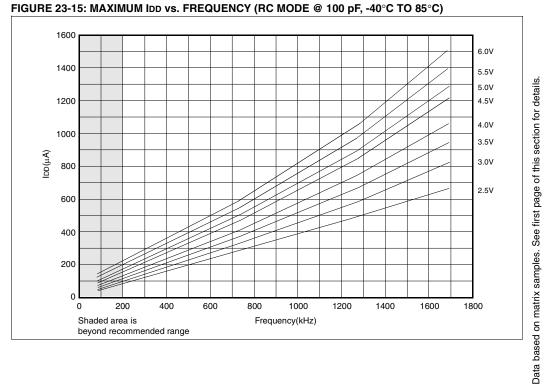




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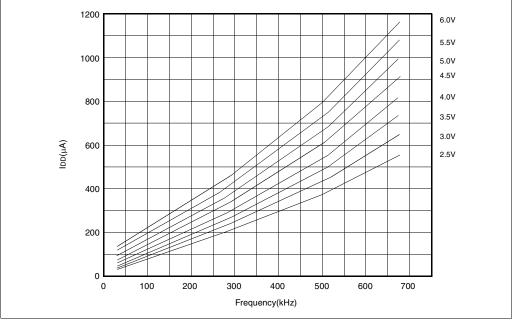


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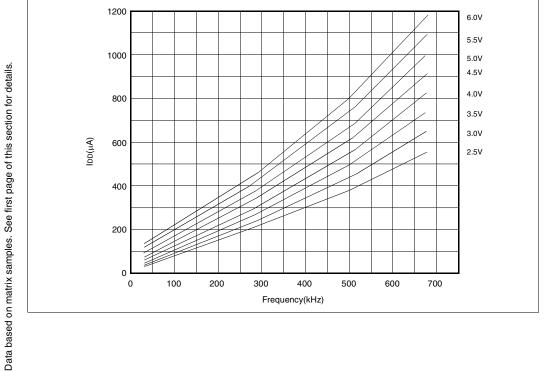
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Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

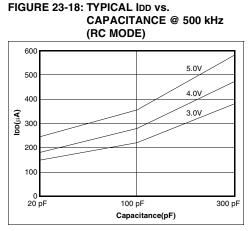
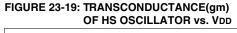


TABLE 23-1: RC OSCILLATOR FREQUENCIES

Cext	Bext	Average				
Cexi	nexi	Fosc @ 5V, 25°C				
22 pF	5k	4.12 MHz	± 1.4%			
	10k	2.35 MHz	± 1.4%			
	100k	268 kHz	± 1.1%			
100 pF	3.3k	1.80 MHz	± 1.0%			
	5k	1.27 MHz	± 1.0%			
	10k	688 kHz	± 1.2%			
	100k	77.2 kHz	± 1.0%			
300 pF	3.3k	707 kHz	± 1.4%			
	5k	501 kHz	± 1.2%			
	10k	269 kHz	± 1.6%			
	100k	28.3 kHz	± 1.1%			

The percentage variation indicated here is part to part variation due to normal process distribution. The variation indicated is ± 3 standard deviation from average value for VDD = 5V.



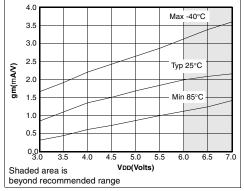
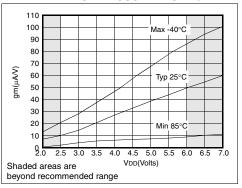
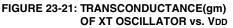
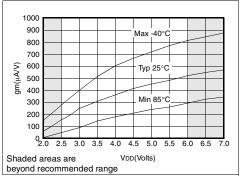


FIGURE 23-20: TRANSCONDUCTANCE(gm) OF LP OSCILLATOR vs. VDD







Data based on matrix samples. See first page of this section for details.

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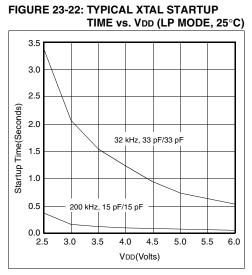
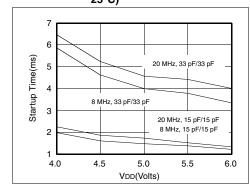


FIGURE 23-23: TYPICAL XTAL STARTUP TIME vs. Vdd (HS MODE, 25°C)



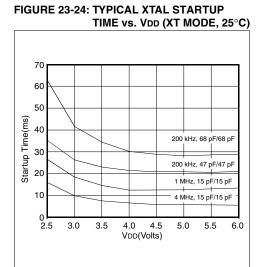


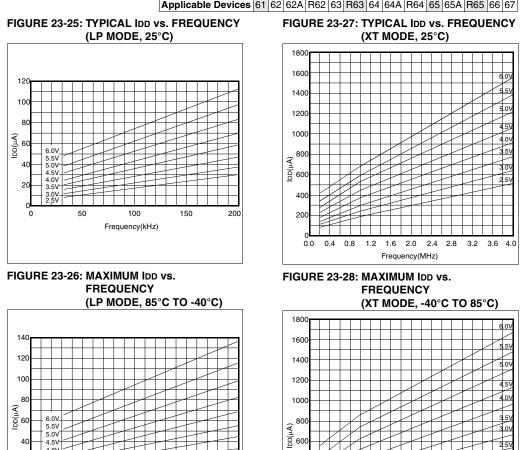
 TABLE 23-2:
 CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
Crystals Used			
20 64-	Enson C 00		

Used		
32 kHz	Epson C-001R32.768K-A	± 20 PPM
200 kHz	STD XTL 200.000KHz	± 20 PPM
1 MHz	ECS ECS-10-13-1	± 50 PPM
4 MHz	ECS ECS-40-20-1	± 50 PPM
8 MHz	EPSON CA-301 8.000M-C	± 30 PPM
20 MHz	EPSON CA-301 20.000M-C	± 30 PPM

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400

200

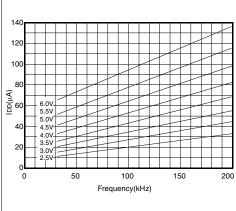
0.0 0.4 0.8

1.2

1.6 2.0 2.4

Frequency(MHz)

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



Data based on matrix samples. See first page of this section for details.

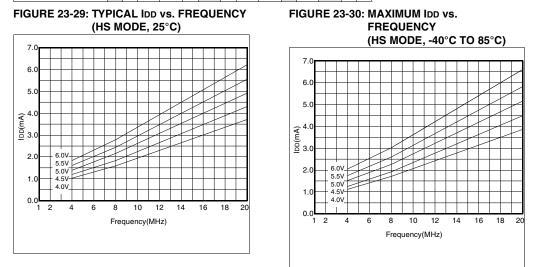
3.0

3.2 3.6 4.0

2.8

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 Applicable Devices
 61
 62
 62A
 R62
 63
 R63
 64
 AAA
 R64
 65
 65A
 R65
 66
 67



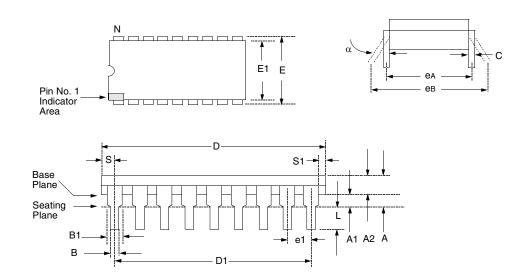
Data based on matrix samples. See first page of this section for details.

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24.0 PACKAGING INFORMATION

24.1 18-Lead Plastic Dual In-line (300 mil) (P)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

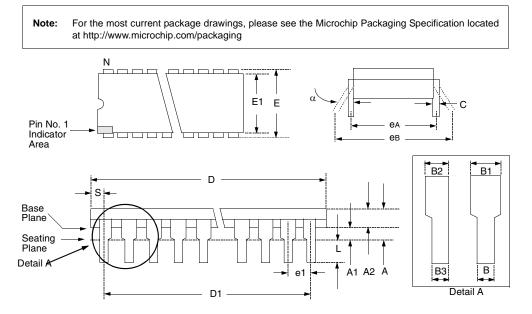


Package Group: Plastic Dual In-Line (PLA)							
		Millimeters		Inches			
Symbol	Min	Max	Notes	Min	Max	Notes	
α	0°	10°		0°	10°		
А	-	4.064		_	0.160		
A1	0.381	_		0.015	_		
A2	3.048	3.810		0.120	0.150		
В	0.355	0.559		0.014	0.022		
B1	1.524	1.524	Reference	0.060	0.060	Reference	
С	0.203	0.381	Typical	0.008	0.015	Typical	
D	22.479	23.495		0.885	0.925		
D1	20.320	20.320	Reference	0.800	0.800	Reference	
Е	7.620	8.255		0.300	0.325		
E1	6.096	7.112		0.240	0.280		
e1	2.489	2.591	Typical	0.098	0.102	Typical	
eA	7.620	7.620	Reference	0.300	0.300	Reference	
eB	7.874	9.906		0.310	0.390		
L	3.048	3.556		0.120	0.140		
Ν	18	18		18	18		
S	0.889	_		0.035	_		
S1	0.127	_		0.005	_		

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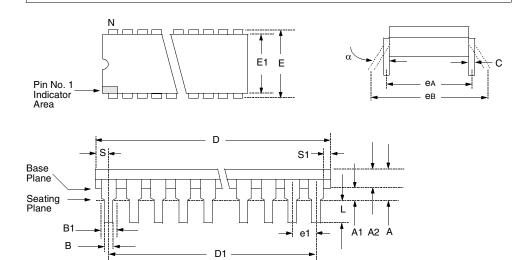
24.2 28-Lead Plastic Dual In-line (300 mil) (SP)



	Package Group: Plastic Dual In-Line (PLA)						
		Millimeters		Inches			
Symbol	Min	Max	Notes	Min	Мах	Notes	
α	0°	10°		0°	10°		
Α	3.632	4.572		0.143	0.180		
A1	0.381	-		0.015	-		
A2	3.175	3.556		0.125	0.140		
В	0.406	0.559		0.016	0.022		
B1	1.016	1.651	Typical	0.040	0.065	Typical	
B2	0.762	1.016	4 places	0.030	0.040	4 places	
B3	0.203	0.508	4 places	0.008	0.020	4 places	
С	0.203	0.331	Typical	0.008	0.013	Typical	
D	34.163	35.179		1.385	1.395		
D1	33.020	33.020	Reference	1.300	1.300	Reference	
E	7.874	8.382		0.310	0.330		
E1	7.112	7.493		0.280	0.295		
e1	2.540	2.540	Typical	0.100	0.100	Typical	
eA	7.874	7.874	Reference	0.310	0.310	Reference	
eB	8.128	9.652		0.320	0.380		
L	3.175	3.683		0.125	0.145		
Ν	28	28		28	28		
S	0.584	1.220		0.023	0.048		

24.3 40-Lead Plastic Dual In-line (600 mil) (P)

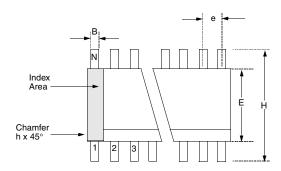
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

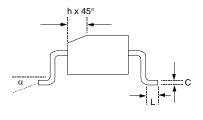


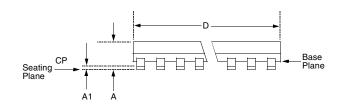
	Package Group: Plastic Dual In-Line (PLA)						
		Millimeters		Inches			
Symbol	Min	Мах	Notes	Min	Max	Notes	
α	0°	10°		0°	10°		
А	_	5.080		_	0.200		
A1	0.381	_		0.015	_		
A2	3.175	4.064		0.125	0.160		
В	0.355	0.559		0.014	0.022		
B1	1.270	1.778	Typical	0.050	0.070	Typical	
С	0.203	0.381	Typical	0.008	0.015	Typical	
D	51.181	52.197		2.015	2.055		
D1	48.260	48.260	Reference	1.900	1.900	Reference	
E	15.240	15.875		0.600	0.625		
E1	13.462	13.970		0.530	0.550		
e1	2.489	2.591	Typical	0.098	0.102	Typical	
eA	15.240	15.240	Reference	0.600	0.600	Reference	
eB	15.240	17.272		0.600	0.680		
L	2.921	3.683		0.115	0.145		
Ν	40	40		40	40		
S	1.270	_		0.050	-		
S1	0.508	-		0.020	_		

24.4 <u>18-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)</u>

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



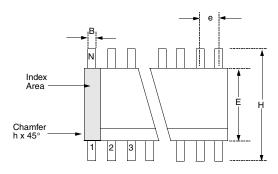


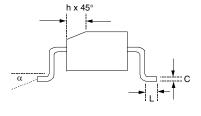


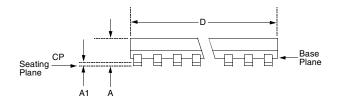
	Package Group: Plastic SOIC (SO)						
		Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes	
α	0°	8°		0°	8°		
А	2.362	2.642		0.093	0.104		
A1	0.101	0.300		0.004	0.012		
В	0.355	0.483		0.014	0.019		
С	0.241	0.318		0.009	0.013		
D	11.353	11.735		0.447	0.462		
E	7.416	7.595		0.292	0.299		
е	1.270	1.270	Reference	0.050	0.050	Reference	
Н	10.007	10.643		0.394	0.419		
h	0.381	0.762		0.015	0.030		
L	0.406	1.143		0.016	0.045		
Ν	18	18		18	18		
CP	-	0.102		-	0.004		

24.5 <u>28-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)</u>

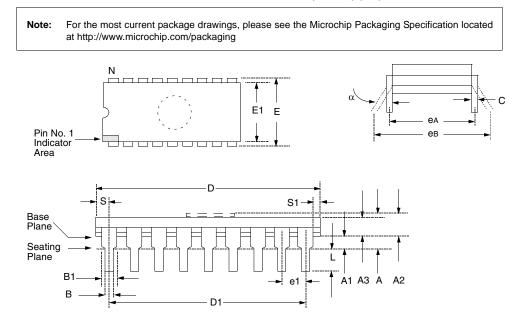
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging







	Package Group: Plastic SOIC (SO)						
	Millimeters			Inches			
Symbol	Min	Мах	Notes	Min	Max	Notes	
α	0°	8°		0°	8°		
Α	2.362	2.642		0.093	0.104		
A1	0.101	0.300		0.004	0.012		
В	0.355	0.483		0.014	0.019		
С	0.241	0.318		0.009	0.013		
D	17.703	18.085		0.697	0.712		
E	7.416	7.595		0.292	0.299		
е	1.270	1.270	Typical	0.050	0.050	Typical	
Н	10.007	10.643		0.394	0.419		
h	0.381	0.762		0.015	0.030		
L	0.406	1.143		0.016	0.045		
Ν	28	28		28	28		
CP	-	0.102		_	0.004		

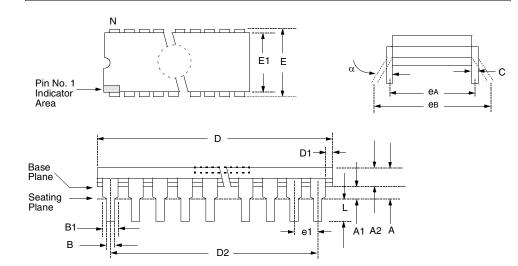


24.6 <u>18-Lead Ceramic CERDIP Dual In-line with Window (300 mil) (JW)</u>

	Package Group: Ceramic CERDIP Dual In-Line (CDP)						
		Millimeters			Inches		
Symbol	Min	Мах	Notes	Min	Max	Notes	
α	0°	10°		0°	10°		
А		5.080		_	0.200		
A1	0.381	1.778		0.015	0.070		
A2	3.810	4.699		0.150	0.185		
A3	3.810	4.445		0.150	0.175		
В	0.355	0.585		0.014	0.023		
B1	1.270	1.651	Typical	0.050	0.065	Typical	
С	0.203	0.381	Typical	0.008	0.015	Typical	
D	22.352	23.622		0.880	0.930		
D1	20.320	20.320	Reference	0.800	0.800	Reference	
Е	7.620	8.382		0.300	0.330		
E1	5.588	7.874		0.220	0.310		
e1	2.540	2.540	Reference	0.100	0.100	Reference	
eA	7.366	8.128	Typical	0.290	0.320	Typical	
eB	7.620	10.160		0.300	0.400		
L	3.175	3.810		0.125	0.150		
Ν	18	18		18	18		
S	0.508	1.397		0.020	0.055		
S1	0.381	1.270		0.015	0.050		

24.7 <u>28-Lead Ceramic CERDIP Dual In-line with Window (300 mil)) (JW)</u>

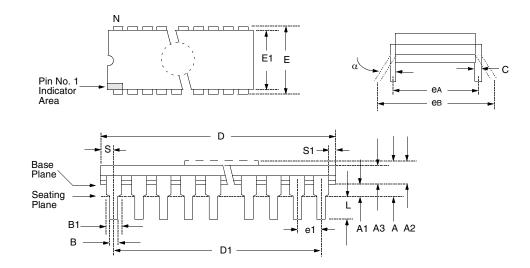
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Package Group: Ceramic CERDIP Dual In-Line (CDP)						
		Millimeters			Inches		
Symbol	Min	Мах	Notes	Min	Max	Notes	
α	0°	10°		0°	10°		
А	3.30	5.84		.130	0.230		
A1	0.38	_		0.015	_		
A2	2.92	4.95		0.115	0.195		
В	0.35	0.58		0.014	0.023		
B1	1.14	1.78	Typical	0.045	0.070	Typical	
С	0.20	0.38	Typical	0.008	0.015	Typical	
D	34.54	37.72		1.360	1.485		
D2	32.97	33.07	Reference	1.298	1.302	Reference	
E	7.62	8.25		0.300	0.325		
E1	6.10	7.87		0.240	0.310		
е	2.54	2.54	Typical	0.100	0.100	Typical	
eA	7.62	7.62	Reference	0.300	0.300	Reference	
eB	—	11.43		_	0.450		
L	2.92	5.08		0.115	0.200		
Ν	28	28		28	28		
D1	0.13	_		0.005	_		

24.8 40-Lead Ceramic CERDIP Dual In-line with Window (600 mil) (JW)

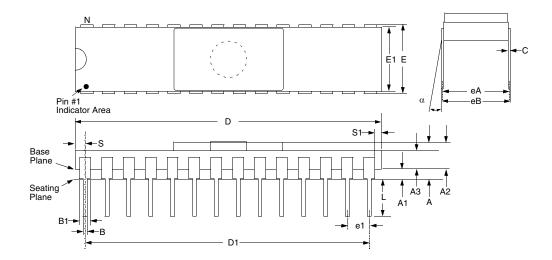
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Package Group: Ceramic CERDIP Dual In-Line (CDP)							
		Millimeters			Inches			
Symbol	Min	Max	Notes	Min	Max	Notes		
α	0°	10°		0°	10°			
А	4.318	5.715		0.170	0.225			
A1	0.381	1.778		0.015	0.070			
A2	3.810	4.699		0.150	0.185			
A3	3.810	4.445		0.150	0.175			
В	0.355	0.585		0.014	0.023			
B1	1.270	1.651	Typical	0.050	0.065	Typical		
С	0.203	0.381	Typical	0.008	0.015	Typical		
D	51.435	52.705		2.025	2.075			
D1	48.260	48.260	Reference	1.900	1.900	Reference		
E	15.240	15.875		0.600	0.625			
E1	12.954	15.240		0.510	0.600			
e1	2.540	2.540	Reference	0.100	0.100	Reference		
eA	14.986	16.002	Typical	0.590	0.630	Typical		
eB	15.240	18.034		0.600	0.710			
L	3.175	3.810		0.125	0.150			
N	40	40		40	40			
S	1.016	2.286		0.040	0.090			
S1	0.381	1.778		0.015	0.070			

24.9 28-Lead Ceramic Side Brazed Dual In-Line with Window (300 mil) (JW)

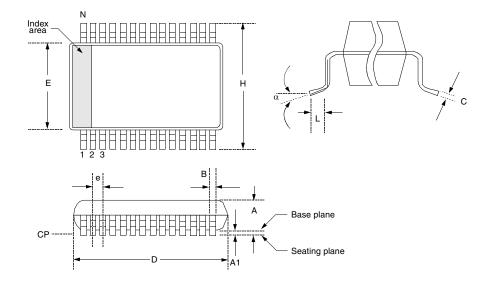
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Package Group: Ceramic Side Brazed Dual In-Line (CER)						
0	Millimeters			Inches			
Symbol	Min	Max	Notes	Min	Max	Notes	
α	0°	10°		0°	10°		
Α	3.937	5.030		0.155	0.198		
A1	1.016	1.524		0.040	0.060		
A2	2.921	3.506		0.115	0.138		
A3	1.930	2.388		0.076	0.094		
В	0.406	0.508		0.016	0.020		
B1	1.219	1.321	Typical	0.048	0.052		
С	0.228	0.305	Typical	0.009	0.012		
D	35.204	35.916		1.386	1.414		
D1	32.893	33.147	Reference	1.295	1.305		
E	7.620	8.128		0.300	0.320		
E1	7.366	7.620		0.290	0.300		
e1	2.413	2.667	Typical	0.095	0.105		
eA	7.366	7.874	Reference	0.290	0.310		
eB	7.594	8.179		0.299	0.322		
L	3.302	4.064		0.130	0.160		
N	28	28		28	28		
S	1.143	1.397		0.045	0.055		
S1	0.533	0.737		0.021	0.029		

24.10 28-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)

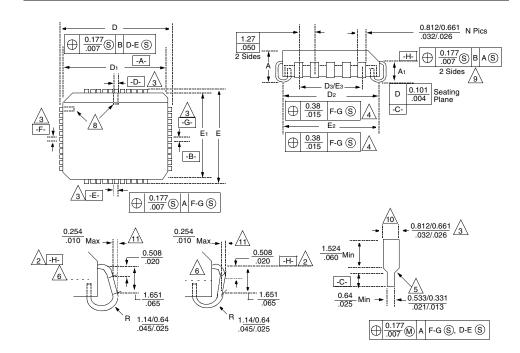
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Packag	je Group: Plasti	c SSOP		
		Millimeters			Inches	
Symbol	Min	Max	Notes	Min	Мах	Notes
α	0°	8°		0°	8°	
А	1.730	1.990		0.068	0.078	
A1	0.050	0.210		0.002	0.008	
В	0.250	0.380		0.010	0.015	
С	0.130	0.220		0.005	0.009	
D	10.070	10.330		0.396	0.407	
E	5.200	5.380		0.205	0.212	
е	0.650	0.650	Reference	0.026	0.026	Reference
Н	7.650	7.900		0.301	0.311	
L	0.550	0.950		0.022	0.037	
Ν	28	28		28	28	
CP	-	0.102		-	0.004	

24.11 44-Lead Plastic Leaded Chip Carrier (Square) (PLCC)

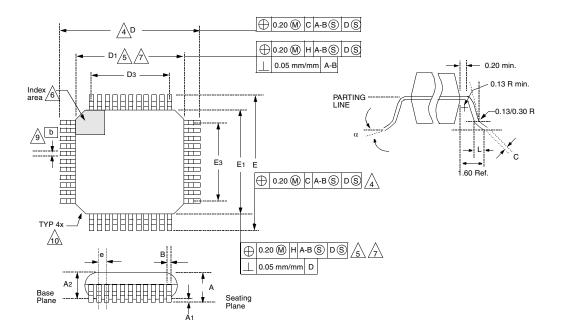
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



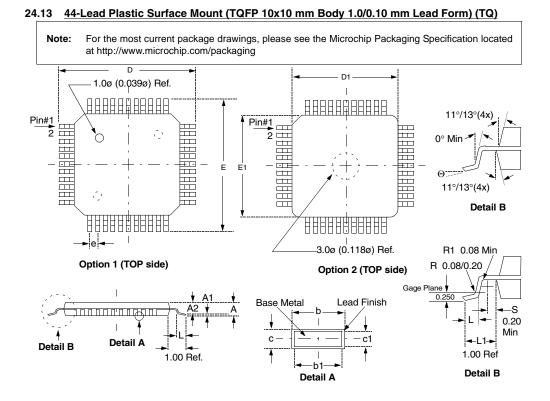
	Package Group: Plastic Leaded Chip Carrier (PLCC)							
		Millimeters		Inches				
Symbol	Min	Max	Notes	Min	Мах	Notes		
А	4.191	4.572		0.165	0.180			
A1	2.413	2.921		0.095	0.115			
D	17.399	17.653		0.685	0.695			
D1	16.510	16.663		0.650	0.656			
D2	15.494	16.002		0.610	0.630			
D3	12.700	12.700	Reference	0.500	0.500	Reference		
E	17.399	17.653		0.685	0.695			
E1	16.510	16.663		0.650	0.656			
E2	15.494	16.002		0.610	0.630			
E3	12.700	12.700	Reference	0.500	0.500	Reference		
N	44	44		44	44			
CP	_	0.102		-	0.004			
LT	0.203	0.381		0.008	0.015			

24.12 44-Lead Plastic Surface Mount (MQFP 10x10 mm Body 1.6/0.15 mm Lead Form) (PQ)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Package Group: Plastic MQFP							
		Millimeters			Inches			
Symbol	Min	Max	Notes	Min	Мах	Notes		
α	0°	7°		0°	7 °			
А	2.000	2.350		0.078	0.093			
A1	0.050	0.250		0.002	0.010			
A2	1.950	2.100		0.768	0.083			
b	0.300	0.450	Typical	0.011	0.018	Typical		
С	0.150	0.180		0.006	0.007			
D	12.950	13.450		0.510	0.530			
D1	9.900	10.100		0.390	0.398			
D3	8.000	8.000	Reference	0.315	0.315	Reference		
E	12.950	13.450		0.510	0.530			
E1	9.900	10.100		0.390	0.398			
E3	8.000	8.000	Reference	0.315	0.315	Reference		
е	0.800	0.800		0.031	0.032			
L	0.730	1.030		0.028	0.041			
Ν	44	44		44	44			
CP	0.102	_		0.004	_			



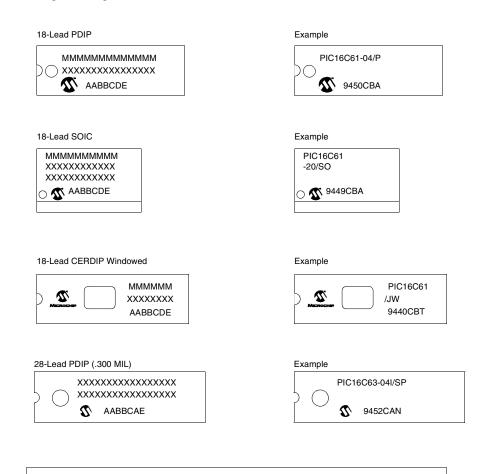
	Package Group: Plastic TQFP						
	Millimeters			Inches			
Symbol	Min	Max	Notes	Min	Max	Notes	
А	1.00	1.20		0.039	0.047		
A1	0.05	0.15		0.002	0.006		
A2	0.95	1.05		0.037	0.041		
D	11.75	12.25		0.463	0.482		
D1	9.90	10.10		0.390	0.398		
E	11.75	12.25		0.463	0.482		
E1	9.90	10.10		0.390	0.398		
L	0.45	0.75		0.018	0.030		
е	0.80	BSC		0.031 BSC			
b	0.30	0.45		0.012	0.018		
b1	0.30	0.40		0.012	0.016		
С	0.09	0.20		0.004	0.008		
c1	0.09	0.16		0.004	0.006		
N	44	44		44	44		
Θ	0°	7 °		0°	7 °		

Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25m/m (0.010") per side. D1 and E1 dimensions including mold mismatch.

2: Dimension "b" does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08m/m (0.003")max.

3: This outline conforms to JEDEC MS-026.

24.14 Package Marking Information



Legend:	MMM	Microchip part number information			
	XXX	Customer specific information*			
	AA	Year code (last 2 digits of calender year)			
	BB	Week code (week of January 1 is week '01')			
	C D ₁	Facility code of the plant at which wafer is manufactured. C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A. Mask revision number for microcontroller			
	D2	Mask revision number for EEPROM			
	E	Assembly code of the plant or country of origin in which part was assembled.			
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.				

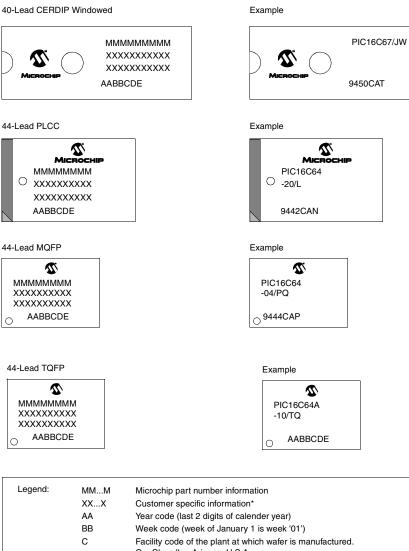
Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

Package Marking Information (Cont'd) 28-Lead SOIC Example ММММММММММММММХХ PIC16C62-20/S0111 xxxxxxxxxxxxxxxxxxxx S AABBCAE 🕥 9515SBA 28-Lead CERDIP Skinny Windowed Example xxxxxxxxxxxxxx PIC16C62/JW Q) XXXXXXXXXXXXXXXX \mathcal{Q} AABBCDE 9517SBT 28-Lead Side Brazed Skinny Windowed Example XXXXXXXXXXXX PIC16C66/JW XXXXXXXXXXXX $\overline{\mathcal{Q}}$ $\overline{\mathcal{Q}}$ AABBCDE 9517CAT 28-Lead SSOP Example XXXXXXXXXXXXX PIC16C62 XXXXXXXXXXXXX 20I/SS025 🔊 ААВВСАЕ 5 9517SBP Example 40-Lead PDIP PIC16C65-04/P ММММММММММММ ***** AABBCDE 9510CAA $\overline{\mathcal{M}}$ MICROCHIP Legend: MM...M Microchip part number information XX...X Customer specific information* Year code (last 2 digits of calender year) AA BB Week code (week of January 1 is week '01') Facility code of the plant at which wafer is manufactured. С C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A. D1 Mask revision number for microcontroller Assembly code of the plant or country of origin in which Е part was assembled. In the event the full Microchip part number cannot be marked on one Note: line, it will be carried over to the next line thus limiting the number of available characters for customer specific information. Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office.

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For QTP devices, any special marking adders are included in QTP price.

Package Marking Information (Cont'd)



Legend:	MMM	Microchip part number information
	XXX	Customer specific information*
	AA	Year code (last 2 digits of calender year)
	BB	Week code (week of January 1 is week '01')
	С	Facility code of the plant at which wafer is manufactured. C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A.
	D ₁ E	Mask revision number for microcontroller Assembly code of the plant or country of origin in which part was assembled.
Note:	line, it will be	he full Microchip part number cannot be marked on one carried over to the next line thus limiting the number of racters for customer specific information.

Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

APPENDIX A: MODIFICATIONS

The following are the list of modifications over the PIC16C5X microcontroller family:

- Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
- 2. A PC high latch register (PCLATH) is added to handle program memory paging. PA2, PA1, PA0 bits are removed from STATUS register.
- 3. Data memory paging is redefined slightly. STA-TUS register is modified.
- Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
- 5. OPTION and TRIS registers are made addressable.
- 6. Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. Reset vector is changed to 0000h.
- 9. Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
- 10. Wake-up from SLEEP through interrupt is added.
- Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT), are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt on change feature.
- 13. Timer0 pin is also a port pin (RA4/T0CKI) now.
- 14. FSR is made a full 8-bit register.
- "In-circuit programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, Vss, VPP, RB6 (clock) and RB7 (data in/out).
- Power Control register (PCON) is added with a Power-on Reset status bit (POR).(Not on the PIC16C61).
- 17. Brown-out Reset has been added to the following devices:
 - PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/ 67.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

- 1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
- 4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change reset vector to 0000h.

APPENDIX C: WHAT'S NEW

Added PIC16CR63 and PIC16CR65 devices.

Added PIC16C66 and PIC16C67 devices. The PIC16C66/67 devices have 368 bytes of data memory distributed in 4 banks and 8K of program memory in 4 pages. These two devices have an enhanced SPI that supports both clock phase and polarity. The USART has been enhanced.

When upgrading to the PIC16C66/67 please note that the upper 16 bytes of data memory in banks 1,2, and 3 are mapped into bank 0. This may require relocation of data memory usage in the user application code.

Q-cycles for instruction execution were added to Section 14.0 Instruction Set Summary.

APPENDIX D: WHAT'S CHANGED

Minor changes, spelling and grammatical changes.

Divided SPI section into SPI for the PIC16C66/67 (Section 11.3) and SPI for all other devices (Section 11.2).

Added the following note for the USART. This applies to all devices except the PIC16C66 and PIC16C67.

For the PIC16C63/R63/65/65A/R65 the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information or use the PIC16C66/67.

APPENDIX E: REVISION E

January 2013 - Added a note to each package drawing.

APPENDIX F: PIC16/17 MICROCONTROLLERS

F.1 PIC12CXXX Family of Devices

		PIC12C508	PIC12C509	PIC12C671	PIC12C672
Clock	Maximum Frequency of Operation (MHz)	4	4	4	4
Memory	EPROM Program Memory	512 x 12	1024 x 12	1024 x 14	2048 x 14
wemory	Data Memory (bytes)	25	41	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0
renpherais	A/D Converter (8-bit) Channels	—	—	4	4
	Wake-up from SLEEP on pin change	Yes	Yes	Yes	Yes
	I/O Pins	5	5	5	5
	Input Pins	1	1	1	1
Features	Internal Pull-ups	Yes	Yes	Yes	Yes
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Number of Instructions	33	33	35	35
	Packages	8-pin DIP, SOIC	8-pin DIP, SOIC	8-pin DIP, SOIC	8-pin DIP, SOIC

All PIC12C5XX devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC12C5XX devices use serial programming with data pin GP1 and clock pin GP0.

F.2 PIC14C000 Family of Devices

		PIC14C000
Clock	Maximum Frequency of Operation (MHz)	20
	EPROM Program Memory (x14 words)	4K
Memory	Data Memory (bytes)	192
including and a second s	Timer Module(s)	TMR0 ADTMR
Peripherals	Serial Port(s) (SPI/I ² C, USART)	I ² C with SMBus Support
	Slope A/D Converter Channels	8 External; 6 Internal
	Interrupt Sources	11
	I/O Pins	22
	Voltage Range (Volts)	2.7-6.0
eatures	In-Circuit Serial Programming	Yes
	Additional On-chip Features	Internal 4MHz Oscillator, Bandgap Reference,Temperature Sensor, Calibration Factors, Low Voltage Detector, SLEEP, HIBERNATE, Comparators with Programmable References (2)
	Packages	28-pin DIP (.300 mil), SOIC, SSOP

F.3 PIC16C15X Family of Devices

		PIC16C154	PIC16CR154	PIC16C156	PIC16CR156	PIC16C158	PIC16CR158
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
	EPROM Program Memory (x12 words)	512	—	1K	—	2К	—
Memory	ROM Program Memory (x12 words)	—	512	—	1K	—	2К
	RAM Data Memory (bytes)	25	25	25	25	73	73
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0	TMR0
	I/O Pins	12	12	12	12	12	12
	Voltage Range (Volts)	3.0-5.5	2.5-5.5	3.0-5.5	2.5-5.5	3.0-5.5	2.5-5.5
Features	Number of Instructions	33	33	33	33	33	33
	Packages	18-pin DIP, SOIC; 20-pin SSOP					

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.

F.4 PIC16C5X Family of Devices

		PIC16C52	PIC16C54	PIC16C54A	PIC16CR54A	PIC16C55	PIC16C56
Clock	Maximum Frequency of Operation (MHz)	4	20	20	20	20	20
	EPROM Program Memory (x12 words)	384	512	512	—	512	1K
Memory	ROM Program Memory (x12 words)	_	—	—	512	-	—
	RAM Data Memory (bytes)	25	25	25	25	24	25
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0	TMR0
	I/O Pins	12	12	12	12	20	12
	Voltage Range (Volts)	2.5-6.25	2.5-6.25	2.0-6.25	2.0-6.25	2.5-6.25	2.5-6.25
Features	Number of Instructions	33	33	33	33	33	33
	Packages	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin DIP, SOIC, SSOP	18-pin DIP, SOIC; 20-pin SSOP

		PIC16C57	PIC16CR57B	PIC16C58A	PIC16CR58A
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20
	EPROM Program Memory (x12 words)	2K	_	2К	—
Memory	ROM Program Memory (x12 words)	—	2K	—	2К
	RAM Data Memory (bytes)	72	72	73	73
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0
	I/O Pins	20	20	12	12
	Voltage Range (Volts)	2.5-6.25	2.5-6.25	2.0-6.25	2.5-6.25
eatures	Number of Instructions	33	33	33	33
	Packages	28-pin DIP, SOIC, SSOP	28-pin DIP, SOIC, SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC 20-pin SSOP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer (except PIC16C52), selectable code protect and high I/O current capability.

F.5 PIC16C55X Family of Devices

		PIC16C554	PIC16C556 ⁽¹⁾	PIC16C558
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2K
lemory	Data Memory (bytes)	80	80	128
	Timer Module(s)	TMR0	TMR0	TMR0
eripherals	Comparators(s)	_	—	—
	Internal Reference Voltage	—	—	—
	Interrupt Sources	3	3	3
	I/O Pins	13	13	13
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0
eatures	Brown-out Reset	_	—	—
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C5XX Family devices use serial programming with clock pin RB6 and data pin RB7. Note 1: Please contact your local Microchip sales office for availability of these devices.

F.6 PIC16C62X and PIC16C64X Family of Devices

		PIC16C620	PIC16C621	PIC16C622	PIC16C642	PIC16C662
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2К	4K	4K
	Data Memory (bytes)	80	80	128	176	176
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0
Peripherals	Comparators(s)	2	2	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes	Yes	Yes
	Interrupt Sources	4	4	4	4	5
	I/O Pins	13	13	13	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	3.0-6.0	3.0-6.0
Fastures	Brown-out Reset	Yes	Yes	Yes	Yes	Yes
Features	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin PDIP, SOIC, Windowed CDIP	40-pin PDIP, Windowed CDIP; 44-pin PLCC, MQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C62X and PIC16C64X Family devices use serial programming with clock pin RB6 and data pin RB7.

F.7 PIC16C7XX Family of Devces

		PIC16C710	PIC16C71	PIC16C711	PIC16C715	PIC16C72	PIC16CR72 ⁽¹⁾
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
	EPROM Program Memory (x14 words)	512	1K	1K	2К	2К	—
Memory	ROM Program Memory (14K words)	_	_	-	—	_	2К
	Data Memory (bytes)	36	36	68	128	128	128
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
Peripherals	Capture/Compare/ PWM Module(s)	—	—	-	—	1	1
	Serial Port(s) (SPI/I ² C, USART)	_	_	_	—	SPI/I ² C	SPI/I ² C
	Parallel Slave Port	—	—	—	—	—	—
	A/D Converter (8-bit) Channels	4	4	4	4	5	5
	Interrupt Sources	4	4	4	4	8	8
	I/O Pins	13	13	13	13	22	22
	Voltage Range (Volts)	3.0-6.0	3.0-6.0	3.0-6.0	3.0-5.5	2.5-6.0	3.0-5.5
Features	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	_	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP

		PIC16C73A	PIC16C74A	PIC16C76	PIC16C77
Clock	Maximum Frequency of Oper- ation (MHz)	20	20	20	20
Memory	EPROM Program Memory (x14 words)	4K	4K	8K	8K
	Data Memory (bytes)	192	192	368	368
	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
Peripherals	Capture/Compare/PWM Mod- ule(s)	2	2	2	2
	Serial Port(s) (SPI/I ² C, USART)	SPI/I ² C, USART	SPI/I ² C, USART	SPI/I ² C, USART	SPI/I ² C, USART
	Parallel Slave Port	—	Yes	—	Yes
	A/D Converter (8-bit) Channels	5	8	5	8
	Interrupt Sources	11	12	11	12
	I/O Pins	22	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
Features	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	Yes	Yes	Yes
	Packages	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C7XX Family devices use serial programming with clock pin RB6 and data pin RB7. Note 1: Please contact your local Microchip sales office for availability of these devices.

F.8 PIC16C8X Family of Devices

		PIC16F83	PIC16CR83	PIC16F84	PIC16CR84
Clock	Maximum Frequency of Operation (MHz)	10	10	10	10
	Flash Program Memory	512	—	1K	-
	EEPROM Program Memory	—	—	—	-
Memory	ROM Program Memory	—	512	—	1K
	Data Memory (bytes)	36	36	68	68
	Data EEPROM (bytes)	64	64	64	64
Peripher- als	Timer Module(s)	TMR0	TMR0	TMR0	TMR0
	Interrupt Sources	4	4	4	4
	I/O Pins	13	13	13	13
Features	Voltage Range (Volts)	2.0-6.0	2.0-6.0	2.0-6.0	2.0-6.0
	Packages	18-pin DIP, SOIC	18-pin DIP, SOIC	18-pin DIP, SOIC	18-pin DIP, SOIC

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C8X Family devices use serial programming with clock pin RB6 and data pin RB7.

F.9 PIC16C9XX Family Of Devices

		PIC16C923	PIC16C924
Clock	Maximum Frequency of Operation (MHz)	8	8
Manager	EPROM Program Memory	4K	4K
Memory	Data Memory (bytes)	176	176
	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	1	1
Peripherals	Serial Port(s) (SPI/I ² C, USART)	SPI/I ² C	SPI/I ² C
	Parallel Slave Port	_	—
	A/D Converter (8-bit) Channels	—	5
	LCD Module	4 Com, 32 Seg	4 Com, 32 Seg
	Interrupt Sources	8	9
	I/O Pins	25	25
	Input Pins	27	27
	Voltage Range (Volts)	3.0-6.0	3.0-6.0
Features	In-Circuit Serial Programming	Yes	Yes
	Brown-out Reset	—	—
	Packages	64-pin SDIP ⁽¹⁾ , TQFP; 68-pin PLCC, Die	64-pin SDIP ⁽¹⁾ , TQFP; 68-pin PLCC, Die

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C9XX Family devices use serial programming with clock pin RB6 and data pin RB7.

F.10 PIC17CXXX Family of Devices

		PIC17C42A	PIC17CR42	PIC17C43	PIC17CR43	PIC17C44
Clock	Maximum Frequency of Operation (MHz)	33	33	33	33	33
	EPROM Program Memory (words)	2K	_	4K	_	8K
Memory	ROM Program Memory (words)	-	2К	—	4K	_
	RAM Data Memory (bytes)	232	232	454	454	454
Peripherals	Timer Module(s)	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3
	Captures/PWM Module(s)	2	2	2	2	2
	Serial Port(s) (USART)	Yes	Yes	Yes	Yes	Yes
	Hardware Multiply	Yes	Yes	Yes	Yes	Yes
	External Interrupts	Yes	Yes	Yes	Yes	Yes
	Interrupt Sources	11	11	11	11	11
	I/O Pins	33	33	33	33	33
Features	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	Number of Instructions	58	58	58	58	58
	Packages	40-pin DIP; 44-pin PLCC, MQFP, TQFP				

		PIC17C752	PIC17C756
Clock	Maximum Frequency of Operation (MHz)	33	33
	EPROM Program Memory (words)	8K	16K
Memory	ROM Program Memory (words)	—	—
	RAM Data Memory (bytes)	454	902
Peripherals	Timer Module(s)	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3
	Captures/PWM Module(s)	4/3	4/3
	Serial Port(s) (USART)	2	2
	Hardware Multiply	Yes	Yes
	External Interrupts	Yes	Yes
	Interrupt Sources	18	18
	I/O Pins	50	50
Features	Voltage Range (Volts)	3.0-6.0	3.0-6.0
	Number of Instructions	58	58
	Packages	64-pin DIP; 68-pin LCC, 68-pin TQFP	64-pin DIP; 68-pin LCC, 68-pin TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.

PIN COMPATIBILITY

Devices that have the same package type and VDD, Vss and $\overline{\text{MCLR}}$ pin locations are said to be pin compatible. This allows these different devices to operate in the same socket. Compatible devices may only requires minor software modification to allow proper operation in the application socket (ex., PIC16C56 and PIC16C61 devices). Not all devices in the same package size are pin compatible; for example, the PIC16C62 is compatible with the PIC16C63, but not the PIC16C55.

Pin compatibility does not mean that the devices offer the same features. As an example, the PIC16C54 is pin compatible with the PIC16C71, but does not have an A/D converter, weak pull-ups on PORTB, or interrupts.

TABLE F-1: PIN COMPATIBLE DEVICES

Pin Compatible Devices	Package
PIC12C508, PIC12C509, PIC12C671, PIC12C672	8-pin
PIC16C154, PIC16CR154, PIC16C156, PIC16CR156, PIC16C158, PIC16CR158, PIC16C52, PIC16C54, PIC16C54A, PIC16C56, PIC16C58A, PIC16CR58A, PIC16C554, PIC16CR58A, PIC16C554, PIC16C556, PIC16C558 PIC16C620, PIC16C621, PIC16C622 PIC16C641, PIC16C642, PIC16C661, PIC16C662 PIC16C710, PIC16C71, PIC16C711, PIC16C715 PIC16F83, PIC16CR83, PIC16F84A, PIC16CR84	18-pin, 20-pin
PIC16C55, PIC16C57, PIC16CR57B	28-pin
PIC16CR62, PIC16C62A, PIC16C63, PIC16CR63, PIC16C66, PIC16C72, PIC16C73A, PIC16C76	28-pin
PIC16CR64, PIC16C64A, PIC16C65A, PIC16CR65, PIC16C67, PIC16C74A, PIC16C77	40-pin
PIC17CR42, PIC17C42A, PIC17C43, PIC17CR43, PIC17C44	40-pin
PIC16C923, PIC16C924	64/68-pin
PIC17C756, PIC17C752	64/68-pin

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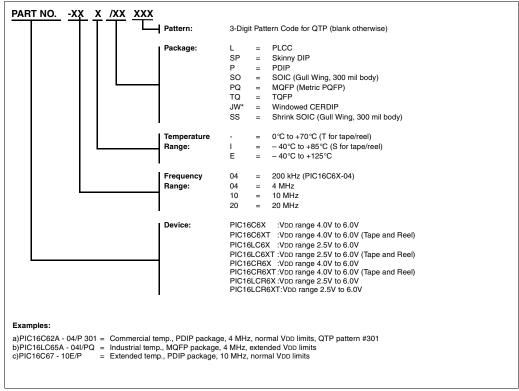
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